

A Report to the ITS Standards Community ITS Standards Testing Program

FINAL TEST REPORT

For Advanced Transportation Controller Type 2070 (ATC 2070) and the Intelligent Transportation Systems (ITS) Roadside Cabinet as Deployed by Harris County, Texas

By

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Prepared for

USDOT – ITS Joint Program Office

Battelle Work Order: BA34020

Task No.: 6.2

June 27, 2008

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Technical Report Documentation Page

1. Report No.	2. Government Accession No.	3. Recipient's Catalog No.
4. Title and Subtitle Final Report for ITS Standards Testing of ATC 2070 and ITS Cabinet as deployed in Harris County, TX		5. Report Date June 27, 2008
		6. Performing Organization Code
7. Author(s)		8. Performing Organization Report
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9. Performing Organization Name and Address		10. Work Unit No. (TRAIS)
Battelle Memorial Institute		
505 King Ave.		11. Contract or Grant No.
Columbus, OH 43201		DTFH61-02-C-00134; Task BA34020
12. Sponsoring Agency Name and Address		13. Type of Report and Period Covered
United States Department of Transportation		Final Report
ITS Joint Program Office		14. Sponsoring Agency Code
1200 New Jersey Avenue, S.E.		HOIT-1
Washington, DC 20590		
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16. Abstract

This Final Report includes all of the findings and recommendations resulting from Battelle's static review, detailed interviews and onsite testing activity related to the ITS Standards deployed and currently in use for transportation management systems, specifically, traffic signal control, in Harris County, TX. The standards reviewed include the Advanced Transportation Controller Standard for the Type 2070 Controller, v02.03, dated March 12, 2004 and the ITS Cabinet Standard v01.02.17b, dated November 16, 2006.

The outcome of this effort, through a series of both subjective and objective evaluation criteria, is to determine the suitability, effectiveness and interoperability and interchangeability, of the standard, and to provide this feedback to the standards development organizations that are drafting the standards. This testing effort is not an evaluation of the site's conformance to the standard and should not be construed as such.

17. Key Words		18. Distribution Statement		
Intelligent Transportation Systems, ITS Standards, Harris County, ATC, 2070, ITS Cabinet, Advanced Transportation Controller		No restrictions. This document is available to the public.		
19. Security Classif. (of this report) 20. Security Classif.		(of this page)	21. No. of Pages	22. Price
Unclassified	Unclassified		290	N/A

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1.0 Introduction

This report provides the results and findings of the ITS Standards Test Program as gathered from both the interview questionnaire and the field testing, and assessment and evaluation of the Advanced Transportation Controller Type 2070 (ATC 2070) and the Intelligent Transportation Systems (ITS) Roadside Cabinet as deployed by Harris County, Texas as part of the Greater Houston Transportation and Emergency Management Center (HCTX). This report fulfils the work product specified in Task 6.2 of Work Order BA34020. This material is based upon work supported by the Federal Highway Administration (FHWA) under contract number DTFH61-02-C-00134. Any opinions, findings, conclusions, or recommendations expressed in this publication are those of the author(s) and do not necessarily reflect the views of the Federal Highway Administration.

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2.0 Background

2.1 ITS Standards Testing Program

The U.S. Department of Transportation (USDOT) has created the Intelligent Transportation Systems (ITS) Standards Test Program, whose objective is to assess a standard's performance and evaluate the ability of the standard to accomplish interoperability and interchangeability in ITS deployments. The ITS Standards Test Team (ISTT) has been contracted by USDOT, in cooperation with the Standards Development Organizations (SDO) and USDOT, to evaluate the coverage and approach used by the site in deploying standards, and conduct both detailed static analysis and hands-on testing of the standard as used at the site.

2.2 Standards of Interest

This report contains the results from the evaluation and field testing of a specific subset of ITS standards applicable to traffic/transportation controllers in the form of the Advanced Transportation Controller and supporting hardware. The primary standards of interest for ITS standards testing in Harris County (HCTX) are the ATC 2070 and the ITS Cabinet. While these standards both continue to be refined, a specific version was chosen for this evaluation. These standards are enumerated in detail in Table 2.1.

Identification	Title	Version	Date
ATC 2070	Advanced Transportation Controller (ATC) Standard for the Type 2070 Controller	02.03	March 12, 2004
ITS Cabinet Standard	Intelligent Transportation System (ITS) Standard Specification for Roadside Cabinets	01.02.17b	November 16, 2006

Table 2.1. Standards of Interest

2.3 The Harris County Site

Harris County (HCTX), as part of the Greater Houston Transportation and Emergency Management Center, has deployed products based on both the Advanced Transportation Controller Type 2070 and the Intelligent Transportation System Cabinet standards. The ATC 2070 and ITS Cabinet provide the physical connection to intersection control signals and sensors, such as inductive loops and traffic signals, and provide command and control of hundreds of intersections in the Greater Houston area, with Ethernet connectivity and monitoring at Houston HCTX's offices, where data is collected and warehoused.

The site lead for this effort was Mr. Ron Johnson. Mr. Johnson is the Quality Control manager for the traffic division of Harris Co., where he is intimately involved in the County's procurement, installation, and maintenance of ATC-based intersections. In addition to this current role, Mr. Johnson was previously the Chief Engineer for one of the major 2070 controller

vendors. He has been involved in the standard process for nearly 20 years, starting with several of the early NEMA devices and continuing to this day as an active participant in the ATC 2070, ITS Cabinet, and ATC v5.2b standards.

Supporting HCTX as their software integrator, as well as a vendor of ATC and ITS Cabinet hardware, is ITS Siemens. Mr. Dave Miller represented Siemens, and, similar to Mr. Johnson, has numerous years in the standards development process.

Lastly, Mr. Herasmo Iniguez, who represented the ATC working groups, but is also a chief engineer with the California Department of Transportation, was a participant and witness to the activities. Mr. Iniguez, in addition to being an expert with the ATC 2070 application software and environment, is responsible for overseeing CalTrans testing and acceptance procedures for ATC-related products.

These three individuals collectively bring more than 50 years of experience to this standards development process and clearly could be considered subject matter experts in this area.

3.0 Standards Testing - Overview

3.1 Scope of the Test

These tests address the specific observable and testable features of the two ITS standards as they are embodied in the intersection control as deployed in Harris County. The test is not a system acceptance test or stress test, which seeks to compare behavior of the test items to functional or contractual requirements. Rather, this test seeks to compare the usage of the test items to their intended usage described in the standard and identify the reasons for any variations.

3.2 Testing Goals

The overall goal of the ITS Standards Testing Program is to assess and evaluate the suitability, effectiveness, interoperability and interchangeability of ITS standards. To best focus on the process to assess and evaluate ITS standards, the test team has identified these three key elements as essential in understanding whether or not a particular standard is ready for field use. These three high-level categorical elements for assessment and evaluation are defined and expanded in the following discussion.

3.2.1 Suitability

The dimension of suitability addresses those aspects of a standard that make it appropriate for a given purpose, easy to understand and use, or the contrary. This also includes issues and measurements relating to a standard's completeness and coverage when defining all aspects of the problem domain and providing access to, and control of, the appropriate technologies. The impact of an unsuitable standard tends to happen early in the system development life-cycle by needlessly complicating or subverting the choice from suitable alternative standards. The evaluation of suitability will be based on quantitative and qualitative analysis of the standards, structured questionnaire responses, and product capabilities, requirements, and design tradeoffs.

3.2.2 Effectiveness

The dimension of effectiveness addresses those aspects of a standard that make its use an appropriate means to achieve the intended or desired effect. This also includes issues relating to how well the features of the standard enable a reasonable and effective implementation in terms of performance requirements and other such operational and maintenance criteria. The impact of an ineffective standard will tend to happen during design and implementation of the system in terms of excessive resource requirements, negative effects on schedule, product performance, etc. The evaluation of effectiveness will be based on quantitative and qualitative analysis of the standards, structured questionnaire responses, operational use, and results from test trials.

3.2.3 Interoperability and Interchangeability

The dimension of interoperability addresses those aspects of a standard that support the ability of systems to provide services to and accept services from other systems and to use the services so exchanged to enable them to operate effectively together. This necessitates that interoperability goes beyond the mere exchange of data and requires that the data exchanged must be usable by

the other system. Further, interoperability is extended to interchangeability when characterized by standardized interfaces. The impact of standards that do not support interoperability and interchangeability will tend to occur during the integration with other systems. The evaluation of interoperability and interchangeability will be based on quantitative and qualitative analysis of the standards, logical characteristics of any external interfaces, and detailed examination of the syntactic and semantic content exchanged across those interfaces.

3.3 Testing Process Outline

This section presents an outline of the steps followed in the conduct of the ITS standards testing of the ATC 2070 and ITS Cabinet standards. The test process steps outlined in Table 3.1 describe the effort for determining what data and information would be identified and collected and where and how that collection would be accomplished.

Step	Description	Expected Outcome
Establish and Verify Standards Baseline	 Examine implementation and project documentation. Research and examine standards schemas, compile a list of specific versions, and identify standard and custom implementations. 	This process step furnishes what can be termed a "static analysis", which provides an assessment of the content of the standard without regard to how the specific site may (or may not) be using it.
Interview Users, Vendors, and System Integrators	Conduct structured, guided interviews using a prepared questionnaire developed from examination of the baseline standards content.	This process step provides direct evidence about how a site perceives its use of the standard, particularly in areas where the specifications allowed for flexibility.
Conduct On-Site Testing	 Conduct a controlled experiment using well-defined and documented test conditions. Test all standard functions and features accessible through the implementation and all exception conditions. 	This process step provides direct evidence of how a site (and the vendors to a site) actually used the standard, particularly with regard to deployed devices that ostensibly meet the standard.

Table 3.1. Test Process Steps

3.3.1 Establish and Verify Standards Baseline

This step in the process supplements the baseline knowledge of the standards content. It is an essential step to quantify a site's use of the standard to support the decision to proceed with full test planning and conduct. The test team qualitatively and quantitatively verified the degree of the use and conformance with the standards of interest. This process includes static examination of standards and examination of technical documentation obtained from vendor/developers. This static analysis is the basis for the development of the detailed site interview questionnaire.

HCTX provided a complete package of documentation and specifications as they related to the procurement and implementation of the ATC 2070 and ITS Cabinet. As HCTX is in a somewhat

unique situation, serving as both a deployer of standards-based equipment and also as a major contributor to the standards process, the amount of documentation, other than the specifications themselves, are somewhat limited. As stated by the site, the standards reflect the procurement documentation used to satisfy their needs.

During the initial site survey conducted in February of 2007, physical identification of the equipment (ATC 2070 and the ITS Cabinet) was made at the HCTX site and functional operation in a laboratory environment was confirmed.

3.3.1.1 ATC 2070 Standard Coverage

The ATC 2070 standard allows for four basic permutations of controller configuration: 1) 2070V, 2) 2070L, 3) 2070LC, and 4) 2070 NEMA. Harris County utilizes the 2070L version of the ATC. This configuration allows for the following replaceable modules to also be examined:

Type 2070-1B Single Board CPU Module with Serial Hub

Type 2070-2B Field I/O Module

Type 2070-3B Front Panel Module, Display B

Type 2070-4A Power Supply Module, 10 Amps

3.3.1.2 ITS Cabinet Coverage

The ITS Cabinet specification consists of physical specifications to support mounting and wiring of external inputs and outputs, as well as identifies the necessary power and serial bus connections needed to interconnect devices. It is available in three different housing assemblies, identified as Type 1, Type 2, etc. In addition to these core housing assembly components, the cabinet standard specifies a series of interchangeable input and output assemblies as well as power and serial interface units.

Harris County deploys all three housing assembly sizes as well as most combinations of interchangeable assemblies.

3.3.2 Interview Users, Vendors, and System Integrators

This step includes structured technical interviews conducted at the vendor/contractor facilities and follow-up by phone. Interview questionnaires are prepared in advance and are derived from the static examination of the standards and system documentation. Although the questionnaires primarily consisted of questions related to the vendor's implementation of the standards, they also included questions directed to programmatic issues and agency needs. These interviews aid in the understanding of the vendor's implementation and address at least three potential categories of issues:

- 1) Issues related to exceptional conditions discovered by the developer.
- 2) Subjective and qualitative coverage and data collection for assessment of non-testable technical features.
- 3) Verification of standards content baseline prior to the commitment of resources to the more specific and extensive field testing.

The initial interview questionnaire for the ATC 2070 and ITS Cabinet standards testing was conducted in Houston, TX at the HCTX offices in August of 2007. Three (3) people were interviewed using the questionnaire developed for this process. These people, identified below, contributed information and opinions for this report. They represented three (3) different stakeholders in the process including public sector deployer, and in fact, also helped generate the standards under review. The text of the questionnaire, along with the responses from the various participants, is included in Appendix A of this document.

Upon completion of these interviews, the results were reviewed and a document of preliminary findings was generated. These findings have been further clarified over time via additional question and answer discussions with HCTX and on-site testing. These findings, both general and specific, are described in the findings section of this report.

3.3.3 Conduct On-Site Testing

This step includes structured, controlled experiment using well-defined and documented test conditions. The documentation is the standard itself, and the test conditions mimic those found as the devices under test are deployed. The intent is to test a representative sample of the types of standard functions and features accessible through the implementation and as many exception conditions as possible given timing of the site visit.

Table 3.2 shows the timeline of the events that were carried out in conducting the interview questionnaire and the device testing.

Event	Time and Place	Attendees
	Houston, TX August 1 – 2, 2007	Ron Johnson – HCTX
		Herasmo Iniguez – CalTrans
Questionnaire		Dave Miller – Siemens
		Tom Timcho – ISTT
		Wilt Alston – ISTT
	Houston, TX December 3 – 6, 2007	Ron Johnson – HCTX
		Herasmo Iniguez – CalTrans
Testing		Dave Miller – Siemens
		Tom Timcho – ISTT
		Wilt Alston – ISTT

Table 3.2. Standards Testing Events

3.4 On-Site Testing Approach

This section summarizes the specific approach used to conduct the on-site portion of the standards testing activity. A cursory assessment of the specifications found in Appendix B would show that only a fraction of the requirement clauses found in the documents has been tested. In order to determine how to test the standard, a multifaceted process was followed:

The entire document was broken down into separate clauses, each clause reflecting what could be called a requirement.

- 1. Each of these clauses was placed in a table similar to the tables shown in Appendix B.
- 2. Each of these clauses was evaluated as being quantifiable via performance testing, inspection, or analysis. These descriptions were intended to describe how each of the requirements could, under ideal conditions, be verified.
- 3. Each of these clauses was then evaluated in terms of what purpose it served in the standard (in other words, what requirement did it define) and how one might verify conformance with the clause. This "first pass," which classified each requirement as either "Design," "Performance," or "Procurement," was performed by the ITS Standards Test Team (ISTT) and was completed without insight from any of the key implementers who would be available during the subsequent interviews and testing exercises.
- 4. The ISTT then led HCTX site team, Johnson, Iniguez, and Miller, through the full standards requirement table, modifying the designations between "Design," "Procurement," and "Performance" with the goal to derive a list of items designated as "Performance" that were both indicative of the use of the standard by Harris County and able to actually be analyzed, demonstrated, inspected, or tested while on-site for the testing visit.
- 5. The items that remained on the list after this process are included in the table in Appendix B of this document. The methodology above resulted in seventy-three (73) verifiable requirements for the ATC 2070 and eighty-one (81) verifiable requirements for the ITS Cabinet. These requirements provided an excellent cross-section of the types of items specified in the standard.

3.5 On-Site Testing Results

The on-site testing was performed December 3-6, 2007 at the offices of HCTX using the test steps located in Appendix B and described in the previous section. The same key stakeholders from the interview phase were also involved in the testing process.

The results of the testing, along with pertinent comments, are included in Appendix B of this document.

3.6 On-Site Testing Analysis

Upon completion of the on-site testing, the results were compiled and the findings, both general and specific, and the recommendations of the ISTT were generated and documented. The summary of these findings are included in the next sections. The details are included in the Appendices of this Final Report.

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4.0 Observations and Findings

This section presents the general test findings derived and determined from examination, interpretation, and analysis of all test data and information. It is organized into general findings that relate to the standards and specific findings that relate to a specific section or paragraph of each document

4.1 General Findings

As previous identified, the ISTT goal was to evaluate the standards in terms of their ability to satisfy the transportation community in terms of suitability, effectiveness, interoperability and interchangeability.

Taking the results shown in the following sections together and evaluating the overall performance of the standard, particularly with regard to its ability to accomplish interoperability and interchangeability given the approach used by the site in deploying standards, the following conclusions are apparent.

- The devices implemented as per the standard by various vendors were interoperable and interchangeable. The standard accomplishes its goals in this regard. It could therefore be said that the standards are complete, clear, effective, and suitable for the deployments visited.
- There were seven (7) specific instances (out of 73) in the verification of the ATC 2070 and seven (7) specific instances (out of 81) in the verification of the ITS Cabinet where the deployed devices did not reflect a strict adherence to the standard. Those instances did not negatively affect the deployment of the devices in terms of interoperability or interchangeability.
- The vendors delivering the various devices implemented as per the standard appear to be able to follow the directions, requirements, and specifications presented in the standard to provide devices that meet the needs of the users deploying those devices.
- There appears to be some amount of "legacy" or "historical" information included in the standard which is intended to support backward compatibility. Neither HCTX nor CalTrans made use of the legacy information, and as such, it could not be examined for suitability, effectiveness, or support of interoperability or interchangeability.
- There appears to be some amount of subjective description in the standard. Generally, these requirements are intended to address concerns such as "workmanship" or "good manufacturing processes" and therefore an objective specification is difficult to provide. The sites deploying the devices work around these issues by working closely with each vendor to provide additional understanding required to meet the standard, if needed.
- There are situations where a requirement stated in the text conflicts with a specification identified on the drawings. Either a statement that indicates the precedence should be included or this redundant specification should be removed.
- The Testing section should be reviewed for applicability to the devices described herein. It seems that this was adopted from another standard, but not fully tailored to the specific

- needs of these devices. The intent is good, but compliance to it may be impossible to achieve, and if no vendors complies, the value is questionable.
- The inclusion of both design and procurement-related items in the standard is questionable. We recommend that they be moved to a companion volume, or at a minimum, clearly indicate that these are design or procurement items and should be treated as such.

4.2 Results – Static Evaluation

This section summarizes the findings resulting from a static evaluation of the standard, completed by ISTT staff before visiting the site to conduct the interview phase or the testing phase of the ITS standards testing for the ATC 2070 and ITS Cabinet standards. The "raw data" for these results may be found in Appendix B. These findings are listed as found in the Appendix with identifying section numbers as shown, with no additional grouping, except for the fact that the ATC 2070 and the ITS Cabinet are listed in separate tables.

4.2.1 ATC 2070

11
15
3.1.9 Daughter Boards
Components are allowed to be mounted under the daughter board.
Drop from the standard.
13
15
3.2.1 Components – General
When a component is of such special design that it precludes the purchase of identical
components from any wholesale distributor or component manufacturer, one spare
duplicate component shall be furnished with each 20, or fraction thereof, components used.
This appears to be a procurement standard and could be dropped from a design standard.
Drop from the standard.
69
19
3.2.14.1 Wiring, Cabling, and Harnesses
Conductors within an encased harness have no color requirements.
This could be covered via a blanket statement in the front of the standard.
Drop from the standard.
70
19
3.2.14.1 Wiring, Cabling, and Harnesses
Printed circuit motherboards are to be used where possible to eliminate or reduce cabinet
wiring.
What does "where possible" mean and how is it quantified?
Drop from the standard.
•

Item	122
Page	23
Paragraph	3.3.5 Workmanship
Clause	Workmanship shall conform to the requirements of this specification and be in accordance
	with the highest industry standards.
Comment	While it is unassailable that high quality is necessary, how is a vendor to determine that
	"the highest" quality has been met?
Recommendation	Drop from the standard.
Item	123
Page	23
Paragraph	3.4.1 Human Engineering
Clause	The equipment shall be engineered for simplicity, ease of operation and maintenance.
Comment	
Recommendation	Drop from the standard.
Item	129
Page	24
Paragraph	3.4.2 Design Engineering
Clause	The design shall take into consideration the protection of personnel from all dangerous
	voltages.
Comment	What does "take into consideration" mean and how is it verified?
Recommendation	Drop from the standard.
Item	159
Page	23
Paragraph	3.5.4 Jumpers
Clause	Jumpers are not allowed unless called out in the specifications or approved by the AGENCY.
Comment	As a requirement, this provides little guidance.
Recommendation	Drop from the standard or reword to state that jumpers are not allowed.
	J
Item	206
Page	54
Paragraph	4.2.3.5 Flash Memory
Clause	The MCB shall be equipped with all necessary circuitry for writing to the FLASH Memory under program control.
Comment	Why would the MCB not be equipped to accomplish such a standard function?
Recommendation	Drop from the standard.
Item	271
Page	63
Paragraph	4.2.7.2.5.1 CPU Module Software – Drivers and Descriptors
Clause	The preferred method of accessing serial device drivers is through os setstat() and
	os_getstat(). The os_ss_size() and os_gs_size() interface may not be required by future
	versions of this specification and is therefore not recommended for new development.
Comment	What is the value of stating the "preferred" method? The use of the term "may not be
	required" does not, on the surface, seem to fit with the recommendation against further new
	development.
Recommendation	Drop from the standard or reword.

Item	351
Page	73
Paragraph	4.2.7.7.2 CPU Module Software – Drivers and Descriptors
Clause	If the agency feels that knowledge of the source code and/or access to the source code is necessary for the purchase of Type 2070 ATCs, then they are referred to forthcoming guidance documents for provisions which should be included in a procurement specification to protect the interests of both the Manufacturer and the Agency.
Comment	Why is "agency" not in all caps, as per AGENCY in other places? This is very poorly worded. It is difficult to ascertain what this note refers to or accomplishes.
Recommendation	Drop from the standard or reword.
Item	369
Page	74
Paragraph	4.3.5.2 Other Module Circuit Functions
Clause	This feature is required to operate with the Type 210 Monitor Unit only.
Comment	Unclear as to why this is in the standard.
Recommendation	Drop from the standard or reword.
Item	566
Page	91
Paragraph	4.4.5.10 Front Panel Assembly – FPA Controller
Clause	Tab Stops shall be configurable at all columns.
Comment	Unclear as to why tab stops are being specified in a standard.
Recommendation	Drop from the standard.
Item	646
Page	99
Paragraph	N/A
Clause	Line drivers/receivers shall be socket mounted or surface mounted.
Comment	What other mounting options exist? If drivers can be mounted either way, why is it specified?
Recommendation	Drop from the standard.
Item	715
Page	106
Paragraph	6.4.4 Module Power Supply
Clause	The standard contains this language: "Specification 4.5.6 POWER SUPPLY REQUIREMENTS except Specification 4.5.3. In the previous section, the standard specifies that Specification 4.5.3 applies.
Comment	Confusingly worded.
Recommendation	Clarify.

4.2.2 ITS Cabinet

Item	14
Page	15
Paragraph	3.1.9 Daughter Boards
Clause	Components are allowed to be mounted under the daughter board.
Comment	
Recommendation	Drop from the standard.

Item	16
Page	15
Paragraph	3.2.2 Components – General
Clause	When a component is of such special design that it precludes the purchase of identical
	components from any wholesale distributor or component manufacturer, one spare
	duplicate component shall be furnished with each 20, or fraction thereof, components used.
Comment	This appears to be a procurement standard and could be dropped from a design standard.
Recommendation	Drop from the standard.
Item	129
Page	23
Paragraph	3.4.2 Design Engineering
Clause	The circuit design shall include such compensation as is necessary to overcome adverse
	effects due to temperature in the specified environmental range.
Comment	What does this specification mean?
Recommendation	Drop from the standard.
	100
Item	132
Page	24
Paragraph	3.4.3 Generated Noise
Clause	No item, component, or subassembly shall emit a noise level sufficient to interfere with processing and communication functions of the controller circuits.
Comment	At what noise level does interference occur?
Recommendation	Reword and clarify, providing an actual limit or requirement.
Recommendation	Reword and clarify, providing an actual limit of requirement.
Item	124
Page	23
Paragraph	3.4.1 Human Engineering
Clause	The equipment shall be engineered for simplicity, ease of operation, and maintenance.
Comment	
Recommendation	Drop from the standard.
Item	130
Page	23
Paragraph	3.4.2 Design Engineering
Clause	The design shall take into consideration the protection of personnel from all dangerous
Ciause	voltages.
Comment	What does "take into consideration" actually mean and how is it assessed?
Recommendation	Drop from the standard or provide an actual requirement.
Item	160
Page	26
Paragraph	3.5.4 Jumpers
Clause	Jumpers are not allowed unless called out in the specifications or approved by the AGENCY.
Comment	As a requirement, this provides little guidance.
Recommendation	Drop from the standard or reword to state that jumpers are not allowed.
T4	004
Item	804 132
Page	
Paragraph Clause	5.4.1 General Requirements The method of isolation shall be based upon a design which shall provide reliable
Clause	operation.
Comment	These words amount to suggestions that cannot be quantified in any way.
Recommendation	Drop from the standard or reword to provide a measurable requirement.
	1 F

Item	815
Page	133
Paragraph	5.5.1 General Requirements
Clause	The method of isolation shall be based upon a design that provides reliable operation.
Comment	These words amount to suggestions that cannot be quantified in any way.
Recommendation	Drop from the standard or reword to provide a measurable requirement.

4.3 Results – Questionnaire

This section summarizes the findings resulting from the interview questionnaire phase of the ITS standards testing for the ATC 2070 and ITS Cabinet standards. The "raw data" for these results may be found in Appendix A. These findings are categorized into six (6) groups as they relate to:

- General Questions (ATC 2070 and ITS Cabinet): Completeness, Clarity, Effectiveness, Suitability, References, Terms and Definitions, Figures and Tables;
- General Questions (ATC 2070): Components, Mechanical, Quality Control, Electrical, Environment, and Testing;
- Controller-Specific Questions (ATC 2070): CPU Module, Field I/O Module, Drawings;
- General Questions (ITS Roadside Cabinet): All Areas;
- Cabinet-Specific Questions (ITS Roadside Cabinet): Transfer Relay Unit, Cabinet Monitor Unit, Serial Interface Unit, Drawings.

4.3.1 General Questions (ATC 2070 and ITS Cabinet): Completeness

Item	1.1.
Page	General Questions 1.2
Paragraph	N/A
Comment	The standard incorporates legacy requirements both in function and form factor, including, but not limited to, traffic control software programs and the types of components used in the cabinet system, e.g., switchbacks relays, etc. Furthermore, when these legacy items change in form factor, there may be a need to update the standard. Currently, some percentage of the legacy information is imbedded in the standard, although how much, is difficult to assess.
Recommendation	Remove legacy information from the standard if it serves no purpose going forward.
Item	1.2.
Th.	Company Occasion 1.2
Page	General Question 1.3
Page Paragraph	N/A
	N/A There are few tasks that the implementers would like to accomplish that are not covered by the standard, although some exist. For example, HCTX is currently investigating the use of a series of less complex boxes, which might hang on poles. It is not clear how this new requirement would change the existing standard, given the need for different packaging and cabinet form factor.
Paragraph	N/A There are few tasks that the implementers would like to accomplish that are not covered by the standard, although some exist. For example, HCTX is currently investigating the use of a series of less complex boxes, which might hang on poles. It is not clear how this new requirement would change the existing standard, given the need for different packaging

Item	1.3.
Page	General Question 1.7
Paragraph	N/A
Comment	The power supply functionality (as mentioned regarding the burgeoning use of LEDs) and
	the modem capability, since these implementers only use Ethernet capability, are examples
	of specified capability that is not needed now and might not be needed going forward.
Recommendation	Consider inclusion of LED-based signal heads in future versions of the standard.

4.3.2 General Questions (ATC 2070 and ITS Cabinet): Clarity

Item	2.1.
Page	General Question 2.1
Paragraph	N/A
Comment	Although the standards are complete, proper implementation does require the use of other standards. For example, specific guidelines for roads and traffic control, including how to lay out the lanes in an intersection and industry standards for electronics, AREMA, etc. are needed to properly implement the standards. Aside: Mr. Johnson (HCTX) mentioned that it was important for people to actually visit CalTrans to observe what they do, as a way to mitigate any misunderstanding from only reading the standard. The premise that the best way to avoid mistakes either in implementation or understanding and gain the requisite "informative knowledge" was to visit CalTrans, was mentioned several times.
Recommendation	Incorporate a recommendation that users of the standard seek guidance from "best of breed" implementers, such as Caltrans, possible through the USDOT Standards deployment support efforts.
Item	2.2.
Page	General Question 2.4
Paragraph	N/A
Comment	While no examples of any such areas were given, there may be areas of the standards that are not understandable. The implementers have been actively resolving these areas, via the same iterative process as the standard was developed using.
Recommendation	Continue the current process with regard to resolving these on-going issues.
T.	
Item	2.3.
Page	General Question 2.5
Paragraph Comment	N/A There had been messages or elements of the standards that were open ended or could be interpreted in more than one way, but the implementers closed the bulk of them over the iterative process that they've been on for so long. Aside: There appear to be items specified in the standard that have hidden or implied reasons. For example, if the material for the front latch is changed, the form factor of the latch will be different, and interoperability may be compromised. The standard says, "Use material XXX" without giving a specific reason. It is not clear how such information might be better communicated, if at all.
Recommendation	Incorporate explanatory or expansive text, specifically for providing context in situations such as the door handle, throughout the standard.

4.3.3 General Questions (ATC 2070 and ITS Cabinet): Effectiveness

Item	3.1.
Page	General Question 3.4
Paragraph	N/A
Comment	The standards provide a level of detail sufficient to procure the specified systems.
	However, there is still a quantity of "implied knowledge" required to use the standard
	properly. Both Mr. Johnson and Mr. Iniguez admitted that if one was in need of detail
	upon what to buy, he would need not only the standard, but also some other—as yet
	unspecified—understanding of what might be needed for a particular implementation.
Recommendation	Incorporate a recommendation that users of the standard seek guidance from "best of
	breed" implementers, such as Caltrans. See response for 2.1 above.

4.3.4 General Questions (ATC 2070 and ITS Cabinet): Suitability

Item	4.1.
Page	General Question 4.1
Paragraph	N/A
Comment	The use of the standards simplified the life cycle processes for requirements, design, build,
	evaluate and deploy.
Recommendation	None.

4.3.5 General Questions (ATC 2070 and ITS Cabinet): References

Item	5.1.
Page	General
Paragraph	N/A
Comment	The references to other external documents or material listed in the standards were complete and useable, likely due to the fact that the developers actually hired a professional editor.
Recommendation	None.
Item	5.2.
Page	General
Paragraph	N/A
Comment	There was no discussion of superfluous references, and it is believed that none exist.
Recommendation	None.
Item	5.3.
Page	General
Paragraph	N/A
Comment	In using the standard, the implementers admitted that they did consult some external references and that one has to be conversant with external references in order to make best use of the standard. There are issues buried in the standard that relate to experience the implementers have gained because this standard specifies a "legacy" item and reflects the lessons learned thereof. CalTrans noted that most of the external references are industry standards, and so one needs to understand those to properly use the standard. Nevertheless, it seems clear that as implementers who are also standard developers, the people interviewed for this testing process were not really equipped to generally address the concern of implied knowledge since they had such a long experience with both the standard and the implementation of it.
Recommendation	Clearly identify which standards are Informative versus Normative, and if possible, include
	specific statements as to the body of knowledge the specific referenced standard contributes to the understanding/implementation of this standard.

4.3.6 General Questions (ATC 2070 and ITS Cabinet): Terms and Definitions

Item	6.1
Page	General
Paragraph	N/A
Comment	Due to the iterative nature of the standard and the fact that the interviewees were both
	developers and implementers, it was deemed unnecessary to ask if the glossaries of terms,
	definitions, and acronyms met their needs in understanding and using the standards.
	However, during testing, it was discovered that some key 'measureable' characteristics of
	the standard were only embodied in the glossary.
Recommendation	Ensure that no requirements of the standard are found solely in the glossary.

4.3.7 General Questions (ATC 2070 and ITS Cabinet): Figures and Tables

Item	7.1
Page	General Question 7.2
Paragraph	N/A
Comment	There are not any figures or tables terms that need to be added or revised.
Recommendation	None. (Note that this question, as answered during the interview portion of the testing, was found to be incorrect during the actual testing portion where several illustrations were found to not match the text in the standard.)

4.3.8 General Questions (ATC 2070): Components

Item	8.1
Page	15
Paragraph	3.2.2.1 Electronic Components
Comment	The reference to socket mounts and the allowance of them is another legacy issue in the standard. The socket mounts were used historically, since the level of maintenance required it. This wording of the standard simply leaves a "door open" for an implementer to use socket mounts if needed.
Recommendation	Drop from standard.
Item Page	8.1. 15
Paragraph	3.2.2.4 Electronic Components
Comment	The requirement that components be easily accessible, replaceable and identifiable for testing and maintenance is another legacy issue. Such a requirement was an issue with using daughter boards and non-surface mounted parts. Given that ICs now cannot typically be replaced, accessibility of the type provided by socket mounts is likely not that important.
Recommendation	Drop from standard.
Item	8.3
Page	18
Paragraph	3.2.10 Fuses
Comment	The fuse (there is only one) in the device can be described as easily accessible and removable without use of tools.
Recommendation	The reason for this requirement, the small amount of time available to service a device, might provide beneficial context to the standard.

Item	8.4
Page	18
Paragraph	3.2.10 Fuses
Comment	It was not clear upon what criterion (or criteria) anyone could be expected to base the
	characterization of "easily accessible" and it was clear that no obvious objective criteria
	was in place, either in the standard nor the minds of the implementers.
Recommendation	Provide an objective requirement, possibly in terms of force needed.

4.3.9 General Questions (ATC 2070): Mechanical

Item	9.1
Page	19
Paragraph	3.2.14 Wiring, Cabling, and Harnesses
Comment	The requirement that all the harnesses in the device be "neat, firm and properly bundled" is subjective, although the intent is to insure that there is no obstruction for serviceability. One of the goals of the standard is to insure that everything is of "the highest workmanship and quality" and poorly bundled cables do not reflect high workmanship. These statements are "boilerplate" requirements, intended to insure a high-quality device.
Recommendation	Provide an objective requirement, or drop from standard.
Item	9.2
Page	General
Paragraph	N/A
Comment	No objective criterion is currently used to communicate the cable requirement but the recurring theme of workmanship was deemed sufficient for these purposes, even though it is subjective.
Recommendation	Provide an objective requirement, or provide an example drawing, or drop from standard.
Item	9.3
Page	22
Paragraph	3.3.1 Assemblies
Comment	It is expected that the requirement that all assemblies in the device are modular, easily replaceable and incorporate plug-in capability for their associated devices or PCB will be met if the vendor follows the dimensions found in the standard. It is not clear that this expectation is not based upon implied knowledge resulting from so much time invested in developing and iterating the standard while implementing it.
Recommendation	Provide an objective requirement, or provide an example drawing, or drop from standard.
Idam	0.4
Item	9.4
Page	
Paragraph Comment	3.3.1 Assemblies Such criteria as "easily replaceable" are part and parcel with developing a high-quality
Comment	device.
Recommendation	Provide an objective requirement, or provide an example, or drop from standard.
Kecommendation	1 rovide an objective requirement, or provide an example, or drop from standard.
Item	9.5
Page	23
Paragraph	3.3.4.2 Model and Serial Numbers
Comment	Characterizing the permanent label affixed to the inside near and center floor of the Type 2070 unit chassis as "easy to read" reflects quality workmanship and therefore requires no further explanation. Any subjectivity could be eliminated with the use of a picture.
Recommendation	Provide an objective requirement, or provide an example drawing, or drop from standard.

Item	9.6
Page	General
Paragraph	N/A
Comment	Such criteria as "easy to read" are part and parcel with developing a high-quality device.
Recommendation	Provide an objective requirement, or provide an example drawing, or drop from standard.
Item	9.7
Page	24
Paragraph	3.4.1.3 Human Engineering
Comment	In order to understand what the standard refers to when it says "the PCBs in the device slide smoothly in their guides while being inserted into or removed from the frame and fit snugly into the plug-in PCB connectors." Caltrans has developed requirements that are less subjective and may be of value to be considered. Aside: This requirement is intended to address "workmanship" as the overriding consideration. The implementers kept going back to "why" a particular requirement was placed in the standard—in effect defending the standard and justifying it—but the intent of the questions about how subjective criteria were measured was to understand the "what" of the standard, and how it could be quantified, communicated, and objectively known. This is the result of interviewing the developers of the standard about how they implement the standard.
Recommendation	Incorporate a recommendation that users of the standard seek guidance from "best of breed" implementers, such as Caltrans, or provide another reference that more objectively addresses the workmanship requirements implied in the standard.
Item	9.9
Page	General
Paragraph	N/A
Comment	A special tool is used to verify that the resistance between any two isolated, independent conductor paths is at least 100 MegOhms when a 500 VDC potential is applied. That tool is not mentioned in the standard, although this apparent oversight may simply reflect "common knowledge" for such an application.
Recommendation	Make a direct reference to the tool required to make this measurement.
Item	9.10
Page	25
Paragraph	3.5.1.4.3 Design, Fabrication, and Mounting No active methodology for verifying the quality of all the golden joints on each PCP is
Comment	No active methodology for verifying the quality of all the solder joints on each PCB is used. Instead, overall performance, or field failures, trigger an investigation that generally find cold solder joints on the offending PCB. As ISO covers many of the GMP criteria implied in the standard, ISO could also be referenced, but it is currently not cited. The conflict with this approach—using ISO specifications—is that the devices are sometimes being manufactured by small companies for whom meeting the general requirements of ISO would be an undue burden. As a consequence, some ISO-type requirements are included and the implementers work with the vendor to understand how to meet them.
Recommendation	If the solder joints will not be verified in any event, but only the performance of the device will be assessed, having this requirement serves no purpose. Drop from the standard.

4.3.10 General Questions (ATC 2070): Quality Control

Item	10.1
Page	27
Paragraph Paragraph	3.6.1 Components
Comment	Lot sampling all components is not routinely done. If failures occur, verification via lot
Comment	sampling may occur as a result.
Recommendation	Either include requirement that vendor produce documentation that shows this is met, or
Recommendation	drop requirement.
	arop requirement.
Item	10.5
Page	27
Paragraph	3.6.2 Subassembly, Unit, or Module
Comment	Electrical, environmental and timing compliance testing on each module, unit, printed
	circuit or subassembly is not generally required although the standard cites it. In some
	cases the failure rate of delivered modules is monitored to determine if the devices perform
	at higher than a 3% failure rate. If not, then the devices are sampled at an even higher rate.
	In other cases, where devices are not purchased in "lots" (contracted delivery of devices)
	ATC 2070 are installed directly in the field. Only in the event of failures are devices tested
	against the standard to determine if those devices are meeting the requirements.
Recommendation	Either include requirement that vendor produce documentation that shows this is met, or
	drop requirement.
Item	10.7
Page	27
Paragraph	3.6.2 Subassembly, Unit, or Module
Comment	Components are not tested as a complete controller assembly, although the standard
	requires it. This is another requirement that is specified in the standard but not followed
	until a problem is detected.
Recommendation	Either include requirement that vendor produce documentation that shows this is met, or
	drop requirement.
Item	10.9
	27
Page	1 = 1
Paragraph	3.6.2 Subassembly, Unit, or Module
Comment	Housing, chassis, and connection terminals are not typically expected for mechanical
	sturdiness, at least not on a routine basis. Mr. Johnson mentioned that they probably would perform such an inspection during the approval process, but even then not on every single
	Limit
	unit. Asida: Mr. Johnson noted that HCTY does not require the yendar to produce any reports of
	Aside : Mr. Johnson noted that HCTX does not require the vendor to produce any reports of
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Recommendation	Aside : Mr. Johnson noted that HCTX does not require the vendor to produce any reports of findings, contrary to what the standard seems to require. His point of view is that requiring the vendor to produce paperwork is of limited value, since the vendor could have simply created it out of thin air. If an item begins to fail, he can always go back and test it against the specification.
Recommendation	Aside: Mr. Johnson noted that HCTX does not require the vendor to produce any reports of findings, contrary to what the standard seems to require. His point of view is that requiring the vendor to produce paperwork is of limited value, since the vendor could have simply created it out of thin air. If an item begins to fail, he can always go back and test it against the specification. Either include requirement that vendor produce documentation that shows this is met, or
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Item Page	Aside: Mr. Johnson noted that HCTX does not require the vendor to produce any reports of findings, contrary to what the standard seems to require. His point of view is that requiring the vendor to produce paperwork is of limited value, since the vendor could have simply created it out of thin air. If an item begins to fail, he can always go back and test it against the specification. Either include requirement that vendor produce documentation that shows this is met, or drop requirement. 10.14
Item Page Paragraph	Aside: Mr. Johnson noted that HCTX does not require the vendor to produce any reports of findings, contrary to what the standard seems to require. His point of view is that requiring the vendor to produce paperwork is of limited value, since the vendor could have simply created it out of thin air. If an item begins to fail, he can always go back and test it against the specification. Either include requirement that vendor produce documentation that shows this is met, or drop requirement. 10.14 27 3.6.2 Subassembly, Unit, or Module
Item Page	Aside: Mr. Johnson noted that HCTX does not require the vendor to produce any reports of findings, contrary to what the standard seems to require. His point of view is that requiring the vendor to produce paperwork is of limited value, since the vendor could have simply created it out of thin air. If an item begins to fail, he can always go back and test it against the specification. Either include requirement that vendor produce documentation that shows this is met, or drop requirement. 10.14 27 3.6.2 Subassembly, Unit, or Module The equipment is visually and physically inspected to assure proper placement, mounting,
Item Page Paragraph	Aside: Mr. Johnson noted that HCTX does not require the vendor to produce any reports of findings, contrary to what the standard seems to require. His point of view is that requiring the vendor to produce paperwork is of limited value, since the vendor could have simply created it out of thin air. If an item begins to fail, he can always go back and test it against the specification. Either include requirement that vendor produce documentation that shows this is met, or drop requirement. 10.14 27 3.6.2 Subassembly, Unit, or Module The equipment is visually and physically inspected to assure proper placement, mounting, and compatibility of subassemblies, as would be expected by GMP. In some cases a
Item Page Paragraph	Aside: Mr. Johnson noted that HCTX does not require the vendor to produce any reports of findings, contrary to what the standard seems to require. His point of view is that requiring the vendor to produce paperwork is of limited value, since the vendor could have simply created it out of thin air. If an item begins to fail, he can always go back and test it against the specification. Either include requirement that vendor produce documentation that shows this is met, or drop requirement. 10.14 27 3.6.2 Subassembly, Unit, or Module The equipment is visually and physically inspected to assure proper placement, mounting, and compatibility of subassemblies, as would be expected by GMP. In some cases a check-list and test-plan for this inspection, neither of which is required by the standard, is
Item Page Paragraph	Aside: Mr. Johnson noted that HCTX does not require the vendor to produce any reports of findings, contrary to what the standard seems to require. His point of view is that requiring the vendor to produce paperwork is of limited value, since the vendor could have simply created it out of thin air. If an item begins to fail, he can always go back and test it against the specification. Either include requirement that vendor produce documentation that shows this is met, or drop requirement. 10.14 27 3.6.2 Subassembly, Unit, or Module The equipment is visually and physically inspected to assure proper placement, mounting, and compatibility of subassemblies, as would be expected by GMP. In some cases a

Tarre	10.17
Item	10.17
Page	27
Paragraph	3.6.3 Pre-delivery Repair
Comment	The process for handling defects or deficiencies found by the inspection system involving mechanical structure or wiring include returning the items through the manufacturing process or special repair process for correction is defined as part of the warranty process.
Recommendation	Either include requirement that vendor produce documentation that shows this is met, or drop requirement.
Item	10.19
Page	27
Paragraph	3.6.3 Pre-delivery Repair
Comment	Although the standard specifies that PCB's should not be flow soldered a second time, it seems clear that the manufacturers do not have to provide any proof since the recipients of the devices wouldn't know how many times a board has been soldered anyway. It is not clear that this requirement should be in the standard.
Recommendation	Drop from the standard.
Item	10.20
Page	27
Paragraph	3.6.3 Pre-delivery Repair
Comment	Given that there is no way to tell how many times a board has been soldered, this requirement is simply a means by which to preclude errors before they happen. By setting this type of requirement, if the devices exhibit problems, those receiving the devices have a legitimate reason to question the vendor regarding this area.
Recommendation	Drop from the standard.

4.3.11 General Questions (ATC 2070): Electrical, Environment, and Testing

Item	11.1
Page	28
Paragraph	3.7.3 Testing Certification
Comment	HCTX does not follow the ATC 2070 standard with regard to requiring the generation of quality control/final testing reports, since they feel it would be of little value and not necessarily disclosing any information. Caltrans does require a report on the controller, but tests everything anyway. Given HCTX's impression (which is not necessarily inaccurate) and Caltrans' normal practice, it is not clear that requirements relating to reports add any value.
Recommendation	None at present, but it could be argued that this requirement is unnecessary, particularly since HCTX does not require it and since Caltrans tests everything regardless of the submission of a report.
Item	11.3
Page	28
Paragraph	3.7.3 Testing Certification
Comment	For Siemens, all test reports delivered generally include Design Acceptance testing of all supplied components. For the other implementers, the answer was as noted above.
Recommendation	None.
Item	11.5
Page	28
Paragraph	3.7.3 Testing Certification
Comment	Some implementers do not require reports, so the requirement that those reports include physical and functional testing of all modules and items is moot for them.
Recommendation	None.

Item	11.7
Page	28
Paragraph	3.7.3 Testing Certification
Comment	Some implementers do not require reports, so the requirement that those reports include
	environmental testing report(s) for all equipment is moot for them.
Recommendation	None.
Item	11.9
Page	30
Paragraph	3.7.5.2.2 Low-Repetition High-Energy Transients
Comment	Some implementers follow the ATC 2070 standard with regard to high-energy and high
	repetition transients, completing all tests that are non-destructive. Some implementers do
	not require reports, so the requirement that those reports include high-energy and high
	repetition transients is moot for them.
Recommendation	None.
T.	
Item	11.11
Page	30
Paragraph	3.7.5.2.2 Low-Repetition High-Energy Transients
Comment	Given the maturity of the standard and the involvement the interviewees had in its
	development, the question regarding transients and power service is irrelevant. It is
	unknown if the answer would be similar for users who did not also play such a substantial
	role in its development.
Recommendation	None.
T4	11 12
Item	11.13
Page	31
Paragraph Comment	3.7.5.5 Temperature and Humidity Given the maturity of the standard and the involvement the interviewees had in its
Comment	
Comment	development, the question regarding temperature and humidity testing is irrelevant. It is
Comment	development, the question regarding temperature and humidity testing is irrelevant. It is unknown if the answers be similar for users of the standard who did not also play such a
	development, the question regarding temperature and humidity testing is irrelevant. It is unknown if the answers be similar for users of the standard who did not also play such a substantial role in its development.
Recommendation	development, the question regarding temperature and humidity testing is irrelevant. It is unknown if the answers be similar for users of the standard who did not also play such a
Recommendation	development, the question regarding temperature and humidity testing is irrelevant. It is unknown if the answers be similar for users of the standard who did not also play such a substantial role in its development. None.
Recommendation Item	development, the question regarding temperature and humidity testing is irrelevant. It is unknown if the answers be similar for users of the standard who did not also play such a substantial role in its development. None. 11.15
Recommendation Item Page	development, the question regarding temperature and humidity testing is irrelevant. It is unknown if the answers be similar for users of the standard who did not also play such a substantial role in its development. None. 11.15 32
Recommendation Item Page Paragraph	development, the question regarding temperature and humidity testing is irrelevant. It is unknown if the answers be similar for users of the standard who did not also play such a substantial role in its development. None. 11.15 32 3.7.6 Test Facilities
Recommendation Item Page	development, the question regarding temperature and humidity testing is irrelevant. It is unknown if the answers be similar for users of the standard who did not also play such a substantial role in its development. None. 11.15 32 3.7.6 Test Facilities None of the implementers follows the standard with regard to performing environmental
Recommendation Item Page Paragraph	development, the question regarding temperature and humidity testing is irrelevant. It is unknown if the answers be similar for users of the standard who did not also play such a substantial role in its development. None. 11.15 32 3.7.6 Test Facilities None of the implementers follows the standard with regard to performing environmental testing themselves, but all expect that the vendors who deliver devices will meet the
Recommendation Item Page Paragraph Comment	development, the question regarding temperature and humidity testing is irrelevant. It is unknown if the answers be similar for users of the standard who did not also play such a substantial role in its development. None. 11.15 32 3.7.6 Test Facilities None of the implementers follows the standard with regard to performing environmental testing themselves, but all expect that the vendors who deliver devices will meet the standard in this regard.
Recommendation Item Page Paragraph	development, the question regarding temperature and humidity testing is irrelevant. It is unknown if the answers be similar for users of the standard who did not also play such a substantial role in its development. None. 11.15 32 3.7.6 Test Facilities None of the implementers follows the standard with regard to performing environmental testing themselves, but all expect that the vendors who deliver devices will meet the
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Item	11.23 – 11.26
Page	38
Paragraph	3.7.8 Vibration Test
Comment	Given the maturity of the standard and the involvement the interviewees had in its development, questions regarding vibration testing procedures are irrelevant. It is unknown if the answers be similar for users who did not also play such a substantial role in its development.
Recommendation	None.
Item	11.27 – 11.30
Page	40
Paragraph	3.7.9 Shock (Impact) Test
Comment	Given the maturity of the standard and the involvement the interviewees had in its development, questions regarding shock testing are irrelevant. It is unknown if the answers be similar for users who did not also play such a substantial role in its development.
Recommendation	None.
Item	11.31 – 11.34
Page	43
Paragraph	3.7.11 Cabinet Assembly Tests
Comment	Given the maturity of the standard and the involvement the interviewees had in its development, questions regarding cabinet assembly testing are irrelevant. It is unknown if the answers would be similar for users who did not also play such a substantial role in its development. Aside : Caltrans is the only authority who has created an "acceptance test" for verifying the operation of the overall unit. It is not clear how HCTX verifies the overall operation of a unit, outside the Caltrans "DAT" test, which HCTX does not routinely use. Mr. Johnson suggested that Caltrans become a <i>de facto</i> certifying body for the industry. It is not clear that the standard provides real value with regard to all the testing requirements which are included in it.
Recommendation	Consider dropping this section from the standard.
Item	11.35
Page	45
Paragraph	3.7.13 Cabinet Monitor Unit Tests
Comment	A number of the specific areas of testing outlined in the ATC 2070 standard reflect that they are "under consideration." HCTX noted two things about these sections. One, they perform discrete tests for individual components, and therefore there are no guidelines for this area. Two, these sections should be deleted since much of the information in them is carry-over from a prior version of the standard.
Recommendation	Drop from the standard.

4.3.12 Controller-Specific Questions (ATC 2070): CPU Module

Item	12.1
Page	51
Paragraph	4.2 Type 2070-1 CPU Module
Comment	None of the interviewees prepared a separate software design specification, in addition to the software design specifications listed in the ATC 2070 standard. Again, the use of the DAT, developed by Caltrans, was mentioned during the discussions. The DAT is actually called out in Section 4.2.7.5.1. There was disagreement between Mr. Johnson and Mr. Iniguez as to if the DAT is always "required" versus never left in a 2070 controller. One of the users, in fact, one of the key users at HCTX, had never used the DAT. It appears that now HCTX will begin, as a result of this discussion and interview, to use the DAT. Either way, the wording in the standard needs to be modified to reflect the state-of-the-art, including the use of a DAT, from where it comes, and how it is used. Although Caltrans has supervised the development of the DAT, it is apparently a product derived from a number of manufacturers.
Recommendation	Recommend inclusion of DAT in delivered software.

4.3.13 Controller-Specific Questions (ATC 2070): Field I/O Module

Item	13.1
Page	74
Paragraph	4.3.4.3 Parallel I/O Ports
Comment	The use of the terminology "glitch" with regard to the performance of a Parallel I/O Ports output circuit has been cleaned up. Apparently, v02.03, which the ISTT had been given to evaluate, was not the latest internal version, which is v02.06. This later version reflects some improvements, of which this is one.
Recommendation	Ensure 'glitch' is defined.
Item	13.9
Page	89
Paragraph	4.4.4 Display
Comment	HCTX created their own system design specification relative to the types of items specified in the Display Section, 4.4.4, portion of the standard, despite the fact that the standard included a simple design specification.
Recommendation	Recommend that HCTX-specific items be considered for inclusion in future standard.

4.3.14 Controller-Specific Questions (ATC 2070): Drawings

Item	14.1
Page	97 and Beyond
Paragraph	4.7 Chapter Details (Drawings)
Comment	All interviewees felt the drawings were clear and provided the appropriate amount of
	information. They mentioned that the current drawing structure reflects the fact that the
	current standard reflects the end of a long iteration process.
	Aside : It is clear that interviewing the developer(s) of the standard is not suitable for
	addressing many of these questions in an objective way. The amount of "implied
	knowledge" inherent in the standard cannot be ascertained via these interviews.
Recommendation	A detailed review of all drawings by a manufacturing engineer could benefit deficiency
	identification and eliminate the legacy knowledge issues.

Item	14.2
Page	97 and Beyond
Paragraph	4.7 Chapter Details (Drawings)
Comment	Mr. Iniguez noted that all manufacturers normally submit drawings additional to the
	drawings shown in the standard, drawings that the implementer will use to verify that what
	the vendor is going to produce will meet the standard. Mr. Johnson noted that a
	manufacturer must place all the items on the front, and exactly where need not be specified
	by the standard. Given the number of items, they can only end up in certain places.
	Aside : This represented the first time in the interview process where the need for implied
	knowledge, knowledge not provided by the standard would be needed by a manufacturer,
	and that a manufacture would have to produce information not specifically cited by the
	standard. Mr. Iniguez noted that the vendor should submit s theory of operation, but this
	requirement is not described in the standard. It was not clear, even in follow-up
	questioning, how a manufacturer could be expected know to submit such an item.
Recommendation	None. (While it is outside the scope of this review, it is worth noting that the V5.2 ATC
	standard includes a theory of operation section.)

4.3.15 General Questions (ITS Roadside Cabinet): All Areas

Item	17
Page	General
Paragraph	N/A
Comment	All questions in this section were deemed unnecessary as they had been answered in previous sections. Furthermore, given the fact that the standard being tested is the result of many, many iterations—resulting in what could only be termed a "legacy" product—and is being employed by the developers, such questions as these will provide little, if any, additional insight into the standard's effectiveness.
Recommendation	None.

4.3.16 Cabinet-Specific Questions (ITS Roadside): Transfer Relay Unit

Item	21.1
Page	41
Paragraph	4.3.1.6 Model 204 Flasher Unit
Comment	Regarding the question on experimentally verifying that the flasher unit circuitry would operate in an open-circuit condition without load for 10 years minimum, several findings were apparent. Mr. Johnson mentioned that they install a 2 microfarad capacitor in the circuit because it was impractical to operate without load. This section should be updated to reflect that the capacitor is needed in some cases. This requirement is currently being met due to the existence of cabinets that have been running in the field for over 10 years. That does not address the standard and how one would meet this requirement <i>a priori</i> .
Recommendation	Update this section to include a reference to the 2 microfarad capacitor mentioned above by Mr. Johnson.
Item	21.2
Page	41
Paragraph	4.3.1.6 Model 204 Flasher Unit
Comment	In explaining how they approach the 10 year requirement, Mr. Miller mentioned that his organization brought in a guy to do a MTBF to predict these requirements.
Recommendation	This requirement and others like it should be reflected in the "boilerplate" of the standard, using an MTBF premise.

Item	21.4
Page	42
Paragraph	4.3.2 Model 205 Flash Transfer Relay Unit
Comment	None of the interviewees had actually experimentally verified that the switch would perform a minimum of 100,000 operations while switching a tungsten load of 1000 Watts at 70 degrees C. Mr. Johnson noted that the intent of this requirement should be to determine if the flasher could work all day flashing continuously. What is needed is a "reasonable expectation" for the timing. Despite this understanding, it remains unclear how an implementer with less experience with the standard would use this requirement.
Recommendation	Construct the requirement to identify the operational needs that must be met and not specific, 'arbitrary' value.
T	21.7
Item	21.7
Page	42
Paragraph	4.3.2 Model 205 Flash Transfer Relay Unit
Comment	The requirement, to experimentally verify that the DPDT contact points were capable of switching 20 Amperes or one Kilowatt Tungsten Load at 120 VAC per contact at least 100,000 operations without contact welding or excessive burning, pitting or cavitations, was called a "design criteria" by Mr. Johnson, but he was unaware if his organization actually determined if the devices met the criteria. Mr. Iniguez noted that this requirement represents the "expected rating" of the device, as opposed to the output of a test. The standard currently specifies that this requirement be experimentally verified.
Recommendation	Modify the standard to illustrate that this is a design standard and not an experimental requirement.

4.3.17 Cabinet-Specific Questions (ITS Roadside): Cabinet Monitor Unit

Item	22.1
Page	42
Paragraph	4.4 Model 212 ITS Cabinet Monitor Unit (CMU)
Comment	None of the interviewees prepared an input message design specification in addition to the one listed in section 4.4 of the ITS Cabinet Monitor Unit standard. Mr. Miller noted that the detail in this section was a result of a previous decision to make sure it was possible to "mix and match" between CMU's and AMU's from different vendors, which was verified experimentally. Aside: There appears to be a need for a "white paper" that provides some insight about what HCTX has found in trying to reconfigure the ITS Cabinets for operation in specific cases.
Recommendation	None. It is possible that the white paper noted above would be useful, but it is not required at this time.

4.3.18 Cabinet-Specific Questions (ITS Roadside): Serial Memory Key, etc.

Item	23.1
Page	55 and Beyond
Paragraph	4.4.14 Monitor Unit Serial Memory Key
Comment	The interviewees implemented the monitor unit serial memory key as specified in section
	4.4.14 of the ITS Cabinet Monitor Unit standard.
Recommendation	None.

Item	24.1
Page	General
Paragraph	4.4.15 CMU Connector
Comment	The interviewees implemented the pin-outs on the CMU Connector as specified in this
	section of the standard.
Recommendation	None.
Item	25.1
Page	General
Paragraph	4.4.16 Serial Bus #1 Frames
Comment	The interviewees implemented the byte format for the Serial Bus #1 Frames as specified in
	this section of the standard.
Recommendation	None.

4.3.19 Cabinet-Specific Questions (ITS Roadside): Serial Interface Unit

Item	26.1
Page	104
Paragraph	4.7.15.9.4 Tracking Functions Overview
Comment	Mr. Johnson noted that although the Tracking Functions and Complex Output Functions are implemented in his organization's devices as specified in the standard, he is not happy with the current behavior because the two features can generate output without a direct command from the controller. Mr. Miller felt this was not a valid fear since the programmer can choose to use this functionality or not. There are applications in the SIU that can influence the outputs regardless of what the controller says. The purpose of this functionality is to off-load work from the controller, which is beneficial, even though the use of this functionality could result in some loss of closed-loop control. It is not clear how this will be resolved going forward.
Recommendation	None, although it is worth noting that two key stake-holders differ in point of view about
	this portion of the standard.

4.3.20 Cabinet-Specific Questions (ITS Roadside): Detectors

Item	28.1
Page	127
Paragraph	5.2.1 General Requirements
Comment	The requirements in this section posited in terms of a "vehicle" passing over or remaining over loop wires embedded in the roadway, were verified via techniques developed as a result of the legacy nature of this specification. It is not clear how a new vendor would understand how this requirement should be verified.
Recommendation	None.

4.4 Results - On-Site Testing

This section summarizes the findings resulting from the testing phase of the ITS standards testing for the ATC 2070 and ITS Cabinet standards. The "raw data" for these results may be found in Appendix B. These findings are categorized into groups corresponding to the devices tested, across both devices, as they relate to:

- ATC Type 2070 General Requirements
- ATC Type 2070 Controller Requirements
- ATC Type 2070 CPU Requirements
- ATC Type 2070 Field I/O Module Requirements
- ATC Type 2070 Front Panel Assembly Requirements
- ATC Type 2070 Power Supply Module Requirements
- ATC Type 2070 VME Cage Assembly Requirements (No testable requirements.)
- ATC Type 2070 Peripheral Equipment Requirements (No testable requirements.)
- ATC Type 2070-2N NEMA Field I/O Module Requirements (No testable requirements.)
- ATC Type 2070-4N NEMA Power Supply Module Requirements (No testable requirements.)
- ATC Type 2070-8 NEMA Field I/O Module Requirements (No testable requirements.)
- ITS Cabinet General Requirements
- ITS Cabinet PC Board Requirements (No testable requirements.)
- ITS Cabinet Models 200 and 204 Requirements
- ITS Cabinet Model 200 Switch Pack Unit Requirements
- ITS Cabinet Model 204 Flasher Unit and Model 205 Flash Transfer Unit Requirements
- ITS Cabinet Model 212 Monitor Unit (CMU) Requirements
- ITS Cabinet Model 214 Auxiliary Monitor Unit (AMU) Requirements
- ITS Cabinet Model 216-12 & 216-24 Power Supply Unit Requirements
- ITS Cabinet Type 218 Serial Interface Unit (SIU) Requirements
- ITS Cabinet Loop Detector General Requirements
- ITS Cabinet Housing Requirements
- ITS Cabinet Rack Cage Requirements (No testable requirements)
- ITS Cabinet Assembly Requirements

4.4.1 ATC Type 2070 General Requirements

Item	50
Page	18
Paragraph	3.2.9.1 Load Circuit Breaker Auxiliary Internal Switches
Comment	ATC 2070 Requirement 50 (auxiliary switches) is apparently not applicable to the ATC
	2070 and actually referred to the ITS Cabinet.
Recommendation	Delete this clause from the standard.

Item	79		
Page	20		
Paragraph	3.2.14.6 Wiring, Cabling, and Harnesses		
Comment	ATC 2070 Requirement 79 (conductor color-coding) was not met by all examined products.		
	The standard specifies the use of the US color convention, but the device we examined		
	appeared to be using both the US standard as well as the European standard.		
Recommendation	Update the standard to reflect the European standard, or delete this clause entirely.		
Item	81		
Page	20		
Paragraph	3.2.15.2 Indicators		
Comment	ATC 2070 Requirement 81 (viewing angle) was not met. This requirement might actually		
	be too strenuous, but is clearly not being met by the devices currently implemented.		
Recommendation	Modify the standard to reflect the actual needs of the implementation.		

4.4.2 ATC Type 2070 Controller Requirements

All tested ATC 2070 requirements in this section of the standard were met and no findings were attributed to this portion of the standard.

4.4.3 ATC Type 2070 CPU Requirements

Item	189		
Page	52		
Paragraph	4.2.2.3 Type 2070 – 1B Configuration		
Comment	ATC 2070 Requirement 189 (LED labeling) was not met. The actual modules reflected the drawing, but not the text of this requirement. In other words, the drawing and the text in		
	the standard do not match.		
Recommendation	Correct the standard.		
Item	227		
Page	55		
Paragraph	4.2.6 Datakey		
Comment	ATC 2070 Requirement 227 (2 megabyte Datakey) was not met. HCTX doesn't use this size of key and never requested them from the manufacturer as a result.		
Recommendation	None.		
Item	304		
Page	68		
Paragraph	4.2.7.2.9 Network Requirements		
Comment	ATC 2070 Requirement 304 (boot image) was not met. It is not clear if the text at Section		
	4.2.7.2.9 and the text at section 4.2.7.2.10.4, which refer to the same file, are consistent.		
Recommendation	Correct the standard.		
	205		
Item	307		
Page	68		
Paragraph	4.2.7.2.10.1 Standard OS-9 File System Configuration		
Comment	ATC 2070 Requirement 307 (CD contents) was not met. Mr. Johnson didn't have a CD		
	and had never used one in this manner.		
Recommendation	This is again a procurement item, and should be handled accordingly. Correct the standard to reflect that this is a recommendation dependent upon the needs of the client and not a requirement.		

Item	313	
Page	68	
Paragraph	4.2.7.2.10.3 Standard OS-9 File System Configuration	
Comment	ATC 2070 Requirement 313 (utilities found in /CMDS directory) was not met. The utility	
	tsmon was not in the /CMDS directory and was instead found in the boot image.	
Recommendation	Correct the standard.	
Item	315	
Page	69	
Paragraph	4.2.7.2.10.4 Standard OS-9 File System Configuration	
Comment	ATC 2070 Requirement 315 (network utilities in the /CMDS directory) was not met. The utilities <i>tftpd</i> and <i>dtfpdc</i> were missing, due to an error between versions in Mr. Iniguez's CPU module drivers. (This is likely not a result of the standard, but simply an oversight within the case being examined.)	
Recommendation	None.	
Item	350	
Page	72	
Paragraph	4.2.7.7.1 Deliverables	
Comment	ATC 2070 Requirement 350 (CD contents) was not met, for reasons previously noted:	
	Mr. Johnson neither normally received a CD nor understood that he should.	
Recommendation	Correct the standard to reflect that this is a recommendation dependent upon the needs of the client and not a requirement.	

4.4.4 ATC Type 2070 Field I/O Module Requirements

Item	464		
Page	82		
Paragraph	4.3.9.2.4 Request Module Status		
Comment	ATC 2070 Requirement 464 (performance with Datakey) was deemed not applicable and appears to be a legacy requirement, included in the standard only so software may continue to be written for older Field I/O modules, but still work in newer ones.		
Recommendation	Add note to standard that Field I/O modules with Datakey are legacy and that this clause is only applicable in the case of their use.		
Item	465		
Page	82		
Paragraph	4.3.9.2.4 Request Module Status		
Comment	ATC 2070 Requirement 465 (performance with Datakey) was not tested for the same reason as given above.		
Recommendation	None.		
Item	466		
Page	82		
Paragraph	4.3.9.2.4 Request Module Status		
Comment	ATC 2070 Requirement 466 (performance with Datakey) was not tested for the same reason as given above.		
Recommendation	None.		

4.4.5 ATC Type 2070 Front Panel Assembly Requirements

All tested ATC 2070 requirements in this section of the standard were met and no findings were attributed to this portion of the standard.

4.4.6 ATC Type 2070 Power Supply Module Requirements

All tested ATC 2070 requirements in this section of the standard were met and no findings were attributed to this portion of the standard.

4.4.7 ATC Type 2070 VME Cage Assembly Requirements

This module/device presented no testable ATC 2070 requirements as the versions of the 2070 controller available for testing in HCTX did not utilize the VME Cage.

4.4.8 ATC Type 2070 Peripheral Equipment Requirements

This module/device presented no testable ATC 2070 requirements as the versions of the 2070 controller available for testing in HCTX did not require the use of the 2070 Peripheral Equipment.

4.4.9 ATC Type 2070-2N NEMA Field I/O Module Requirements

HCTX does not use the NEMA version of the controller, and as such, there were no testable ATC 2070 requirements.

4.4.10 ATC Type 2070-4N NEMA Power Supply Module Requirements

HCTX does not use the NEMA version of the controller, and as such, there were no testable ATC 2070 requirements.

4.4.11 ATC Type 2070-8 NEMA Field I/O Module Requirements

HCTX does not use the NEMA version of the controller, and as such, there were no testable ATC 2070 requirements.

4.4.12 ITS Cabinet General Requirements

Item	88		
Page	20		
Paragraph	3.2.15.1 Indicators		
Comment	ITS Cabinet Requirement 88 (LED color and design) was not met on at least a few older		
	modules present in the Harris County lab, but these modules were not in use in the field.		
	The operational need for this requirement was verified via demonstration with an older EDI		
	Switch Pack that was found in the lab.		
Recommendation	Add non-reflective to the text of the standard as the purpose is to ensure proper viewing		
	even in direct sunlight.		
Item	92		
Page	20		
Paragraph	3.2.16.1 Connectors – General		
Comment	ITS Cabinet Requirement 92 (mating connector keying) was not met for DB25, but		
	plugging this board into the wrong slot will not cause any type of hazard or equipment		
	damage. Generally, all situations where damage or hazard could occur were covered by		
	and met this requirement, but it isn't obvious without analyzing the design.		
Recommendation	Identify clearly those connectors in which this requirement is applicable.		

4.4.13 ITS Cabinet PC Board Requirements

This module/device presented no testable ITS Cabinet requirements.

4.4.14 ITS Cabinet Models 200 and 204 Requirements

Item	164	
Page	39	
Paragraph	4.1.1.2 Models 200 and 204 General	
Comment	ITS Cabinet Requirement 164 (screw head types) was not met. It is clear that the operational need—avoiding a serviceperson having to go back to his vehicle to obtain another type of screwdriver—was appropriate, but given that communication ports only come in slotted type screws, it is unlikely that this requirement can be or will be met.	
Recommendation	Delete this clause from the standard or at a minimum, specifically identify the allowable	
	screw head types, i.e., slotted, Phillips, or phil/slot and the expected size range, i.e., #0-#2.	

4.4.15 ITS Cabinet Model 200 Switch Pack Unit Requirements

Item	181	
Page	40	
Paragraph	4.2.1.5 Models 200 Switch Pack Unit General	
Comment	ITS Cabinet Requirement 181 (switch indication LED placement) was not met on any	
	device found in the lab at Harris County. Furthermore, it was not met on any of the newer	
	devices found in the lab, devices that had been "approved for use" by Caltrans. The typical	
	placement of the LEDs for all devices examined was ¾ inch apart, versus the 1 inch stated	
	in the standard.	
Recommendation	Correct the standard to reflect the dimensions being used.	

4.4.16 ITS Cabinet Model 204 Flasher Unit and Model 205 Flash Transfer Unit Requirements

All tested ITS Cabinet requirements in this section of the standard were met and no findings were attributed to this portion of the standard.

4.4.17 ITS Cabinet Model 212 Monitor Unit (CMU) Requirements

All tested ITS Cabinet requirements in this section of the standard were met and no findings were attributed to this portion of the standard.

4.4.18 ITS Cabinet Model 214 Auxiliary Monitor Unit (AMU) Requirements

All tested ITS Cabinet requirements in this section of the standard were met and no findings were attributed to this portion of the standard.

4.4.19 ITS Cabinet Model 216-12 & 216-24 Power Supply Unit Requirements

All tested ITS Cabinet requirements in this section of the standard were met and no findings were attributed to this portion of the standard.

4.4.20 ITS Cabinet Type 218 – Serial Interface Unit (SIU) Requirements

Item	552	
Page	92	
Paragraph	4.7.14.7 Serial Ports	
Comment	ITS Cabinet Requirement 552 (port labeling) was not met. The standard appears to be discrepant, since the ports are neither identified nor labeled as specified in the text as shown on the drawings in the standard.	
Recommendation	mendation Correct the standard so that the drawings and the text match the currently-implemented	
	devices.	
Item	553	
Page	92	
Paragraph	4.7.14.7 Serial Ports	
Comment	ITS Cabinet Requirement 553 (port labeling) was not met. The standard appears to be discrepant, since the ports are neither identified nor labeled as specified in the text as shown on the drawings in the standard.	
Recommendation	Correct the standard so that the drawings and the text match the currently-implemented devices.	

4.4.21 ITS Cabinet Loop Detector General Requirements

All tested ITS Cabinet requirements in this section of the standard were met and no findings were attributed to this portion of the standard.

4.4.22 ITS Cabinet Housing Requirements

All tested ITS Cabinet requirements in this section of the standard were met and no findings were attributed to this portion of the standard.

4.4.23 ITS Cabinet Rack Cage Requirements

This module/device presented no testable requirements.

4.4.24 ITS Cabinet Assembly Requirements

Item	950	
Page	154	
Paragraph	6.4.1.6 Connector Sockets	
Comment	ITS Cabinet Requirement 950 (socket mounting dimension) was not met. The dimension was correct, but the wording was inverted. The verbiage should say, "7.50 from the back panel to the front panel of the unit" versus what is shown in the standard.	
Recommendation	Correct the standard	

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5.0 Conclusion

As stated in the Section 3.0 of this final report, the overall goal of the ITS Standards Testing Program is to assess and evaluate the suitability, effectiveness, interoperability and interchangeability of standards. The measure of these three key elements is essential in understanding whether or not a particular standard is ready for field use. The conclusion is therefore stated in terms of these measures.

5.1 Suitability

In terms of suitability, while the standard doesn't explicitly define user requirements, which we have identified as a finding, through the interview and testing process, the ISTT was satisfied that the products produced as a result of the standards do indeed meet the needs of the deploying agency. The test site, Harris Co., TX, represents a major consumer of devices built to these standards. As noted in the Introduction, the individuals cited for these conclusions – Mr. Johnson, representing HCTX, and Mr. Iniguez, representing both CalTrans and the working group – have numerous years of experience in this area and would both be considered experts in this subject matter. As such, their acceptances of the standard support the conclusion of suitability.

5.2 Effectiveness

In terms of effectiveness, the standards fully meet the measure of effectiveness in that they are an effective solution to satisfy the needs of the user; however, there is some concern in the ability of newcomers to this community to easily grasp and adhere to these standards. These standards represent an evolutionary process that has involved many stakeholders over many years and has its origins in similar, but more site-specific standards. Thru years of refinement, these standards have come to represent the best practices and capabilities of a consortium of stakeholders. These are all positive contributions to the standard.

What has not been fully determined is the ability of a newcomer to, without ambiguity, design, and build devices that conform to the standard, and provide for the end-user agency needs. While it is was not within the scope of this specific effort, it might be of interest to USDOT and the working groups to interview a vendor and/or agency who does not have the lengthy background in order to uncover any findings along this path.

5.3 Interoperability and Interchangeability

In terms of interoperability and interchangeability, over the course of evaluation and testing, we had the opportunity to witness first hand, product from multiple vendors configured into systems that performed their intended function. Furthermore, we were able to witness hot-swapping of components from multiple vendors, again, with no exceptions to their intended purpose. This capability was quite impressive and ultimately, was the major driver for the creation of these standards, and proof positive as to the benefits standardization can bring.

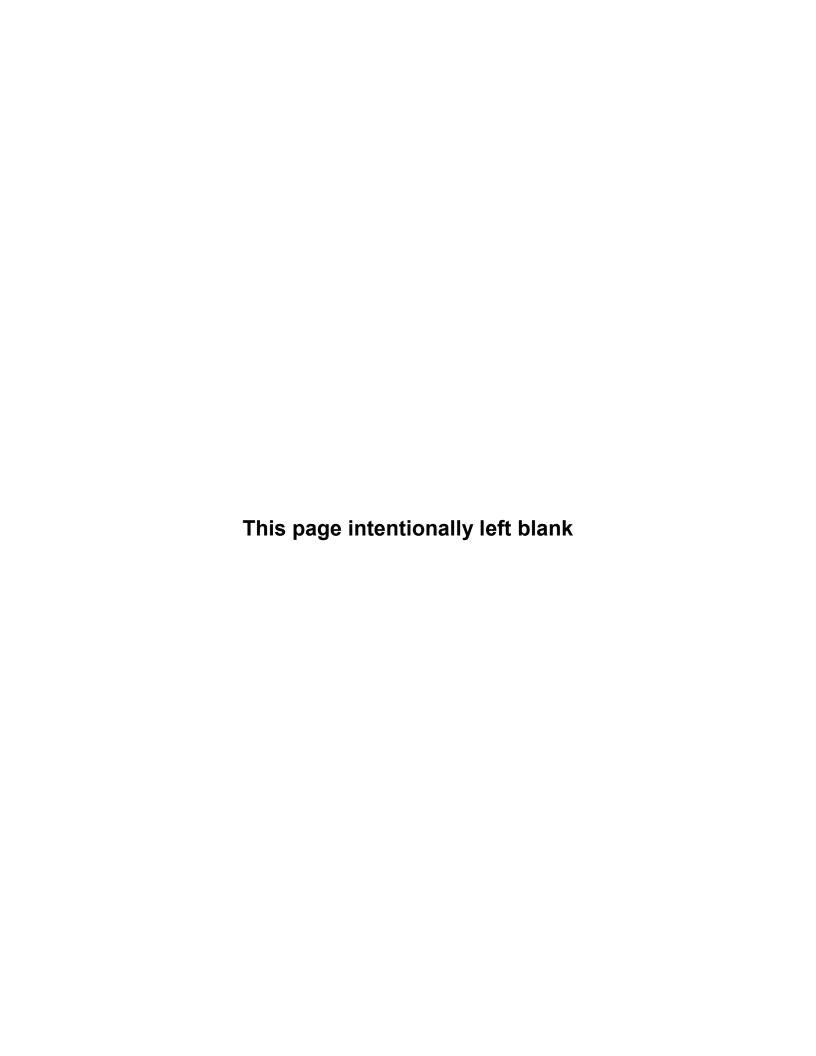
5.4 Other Key Observations

As a next step, in order to assure conformance to the standard can be met, and for the benefit of the newcomer to the standards community, and to correct the deficiencies in the standard, we offer the following thoughts:

- Use of the Systems Engineering Process to produce user needs is of value and should be employed throughout the system life cycle. The standard could benefit from the inclusion of a tailored requirements verification matrix, which would aid the agency and vendors in determining the type and method for how to satisfy each of the requirements embodied within the standard. The ISTT, thru its analysis process, has generated a first pass of this type of matrix, as shown in Appendix B. While it is by no means 100% accurate, we attempted to both identify the requirement type, but also the method (analysis, demonstration, inspection, and test) to verify conformance to the requirements.
- A thorough review of all drawings should be conducted to ensure that they are consistent with the text and that duplicate, sometime conflicting requirements are corrected.
- Subjective statements should be examined and removed, or at a minimum, qualified as such.
- Separating design and procurement items from actual performance requirements should be considered.
- The Test Section Area (Section 3.0) should be corrected to truly represent the needs and requirements for the device, or should be removed.

The bottom line, based on the limited testing, but strong historical evidence and thorough interviews, is that the ATC 2070 and ITS Cabinet Standards do indeed meet the goals of the ITS Standards program and should be considered a success for satisfying the stakeholder needs. The majority of the findings contained herein are minor, and have more to do with documentation errors and inconsistencies than they actually have to do with substantive implementations or errors in design against the features of the standard.

Appendix A: ATC 2070 / ITS Cabinet Interview Questionnaire



General Questions

1. C	1. Completeness		
1.1.	Were there other standards used?	HCTX: Such as NETC, there are specific guidelines for roads and traffic control, including how to lay out the lanes in an intersection. CalTrans: There are also industry standards for electronics, AREMA, etc.	This question, while asked, was not on the printed copies of the questionnaire.
1.2.	Are their any legacy requirements, over and above what is included in the standard that should be included in a standard?	HCTX: Two kinds of things, traffic control software programs and components used in the cabinet system, e.g., switchbacks relays, etc. When these legacy items change in form factor, we may have to actually update the standard.	The legacy standards are currently imbedded in the standard, sort of an unspoken portion of the standard?
1.3.	Are there any tasks that you'd like to accomplish that are not covered by the standard?	HCTX: We are currently looking at a series of less complex boxes, which might hang on poles. How do we handle that, since we'd need different packaging?	The form factor for the ITS cabinet would not work in this case.
1.4.	Are there other customizations that you have to implement to get the items covered by the standard to fit?	HCTX: Yes. The impact of going to LED signals, for example, effects the form factor in the cabinet, due to things like amperage, etc.	Equipment designed to run at 10 amps simply doesn't run well at 1 amp or less. This is more of a cabinet issue versus a controller issue.
1.5.	Is there capability in the 2070 that you choose not to use?	HCTX: Not really.	

1.6.	What configurations of 2070 have you deployed?	HCTX: We're using LN, versus NEMA cabinets. We're basically using a 2070 with a field I/O module, but we don't use the modem stuff, since we're mostly Ethernet. CalTrans: We only use the L version.	The Ethernet capability and the use of serial versus parallel interface seem pretty important.
1.7.	Are there any things in the standard that you cannot envision ever using?	HCTX: The answer is, most of the power supply stuff (as mentioned regarding the burgeoning use of LEDs) and the modem capability, since we only use Ethernet capability, might be examples.	
2. (Clarity		
2.1.	Are the standards clear?	HCTX: How can we say different? I can show you a volume with many, many pages of comments during the early iterations of the standard. This leads to the current clarity. CalTrans: Because this is a specific standard for a specific industry, that makes this usage better. In fact, one of our goals was the clarity of standard. Siemens: There was a lot of interaction between vendors and standards creators to aid the clarity.	HCTX mentioned that it is important for people to actually visit CalTrans to "see" what they do.
2.2.	Are the standards unambiguous?	HCTX: No. Because of the process of iterative refinement, as noted above.	
2.3.	Are there any messages/frames/elements that are confusing or inappropriate in the standards?	HCTX: If anything, there might be too much detail in places.	

Response

2.4.	Were there any areas of the standards that	HCTX:	
	were not understandable? (their purpose or implementation)	Yes, but we're working on clearing them up, as mentioned above.	
2.5.	Were there any messages or elements of the standards that were open ended or could be interpreted in more than one way?	Siemens: Yes, there "were" but we closed a lot of them over the iterative process that we've been on for so long.	How do we convey the concept that one needs to "view" the process at a seasoned vendor like CalTrans, before they attempt to implement the standard. A recurring theme raised by Johnson, is that there is "informative knowledge" that a group planning to implement the standard would gain by, for example, visiting CalTrans and watching.
			There appear to be certain items specified in the standard that have hidden reasons. For example, HCTX related that if the material for the front latch is changed, the form factor of the latch is different, and interoperability is compromised. However, in the standard, it simply says, "use material XXX" without any mention of such a reason. How should such information be communicated, if at all?
2.6.	Were there any areas of the standards where you needed or sought guidance or clarification?	No.	
	• what's the data purpose/meaning		
	• how it is encoded		
	 units of measure 		
	• etc.		
3. E	Effectiveness		
3.1.	Are the standards effective in the exchange of information of a traffic management system to other centers or information	HCTX: Yes.	Mr. Johnson was not exactly sure what the question was intended to address. The ISTT pressed with "were there parts of the standard that led to over-
	service providers?	CalTrans: Yes.	design?" The answer was still no.

Response

3.2.	What area could messages/frames/elements be added or changed to improve the effectiveness of the standards in providing traffic management information?	HCTX: No. (When we selected Motorola processors chips there were some shortcomings, but that choice led us down an architecture path that we've followed, for better or worse.) Siemens: All I could think of might be that as we go along, we keep adding new drivers and support for additional serial speeds, etc.	
3.3.	Did the use of the ITS standards simplify the procurement specification process?	HCTX: Yes. (Harris County recently completed documentation for cataloging all our procurements. We used the standard for developing that document.)	
3.4.	To what level of detail were the ITS standards specified in procuring your system? • specific standards / versions • specific messages / data elements • etc.	HCTX: We actually look at the standard to determine what one might need, e.g., a 2070 with certain components, but you have to be more specific than saying "just give me a 2070." But it might be a weakness of the standard that a user is required to have some knowledge of what he needs, knowledge that is not necessarily in the standard itself. CalTrans: Everything we might need is specified in the standard, but we also refer to a particular version of the 2070, say an L version, which is also specified in standard.	The "L" version is specified on page 48-49 of the standard. It appears that if one was in need of detail upon what to buy, they would need to not only have the standard, but also some other, apparently unspecified understanding of what might be needed for their particular implementation. It appears that the customer might need to have understanding that cannot be acquired from reading the standard only! One also needs to determine where "user options" end and information suitable for a standard begins.
3.5.	Did the use of the ITS standards simplify your life cycle process for requirements, design, build, evaluate and deploy?	HCTX: Yes.	

Response

4. Suitability		
4.1. Are the messages/frames/elements suitable for implementation of the traffic management system?	Yes. HCTX: In some cases, this process cost more.	The issue was more due to the costs of developing the specification itself.
4.2. Are there any areas of the standard that seem either deficient or out of scope of its purpose?		Skipped.
4.3. Are there any messages/frames/elements that could be added or changed that would improve the suitability of the standard in providing traffic management information?		Skipped
4.4. Do you feel that there were any programmatic, technical or operational impacts on you (positive or negative) because of the use of the ITS standards?		Skipped
4.5. Did you adapt your operational needs to the standards? Were adaptation recognized as having a positive or negative effect?		Skipped
5. References		
5.1. Were the references to other external documents or material listed in the standards, if any, complete and useable?	Siemens: We tried to make sure that we had only normative references to specifications. In fact we hired an editor.	
5.2. Were there any superfluous references?		Skipped

5.3. Did you or members of your team consult any	HCTX:	Additional question from the ISTT:
of the external references and, if so, did they contribute positively to your understanding of the standards?	To some extent one has to be conversant with the external references.	I didn't see a "timing diagram" or anything like th How is that type of information specified? Additional embellishment from the ISTT: It seemed that you were very specific in the standard, displaying some implicit context that is not always provided in the standard. How is this conveyed? It seems clear that as implementers who are also standard developers, the guys that we interviewed are not really equipped to generally address this concern. Skipped.
the standards?	There are issues buried in the standard that relate to	Additional embellishment from the ISTT:
	experiences we've gained due to the fact this standard specifies a "legacy" item and reflects the "learnings" thereof.	standard, displaying some implicit context that is not always provided in the standard. How is this
	CalTrans:	conveyed?
	Most of the external references are industry standards, and so one needs to understand those to properly use the standard.	standard developers, the guys that we interviewed are not really equipped to generally address this
6. Terms and Definitions		
6.1. Did the glossaries of terms, definitions and acronyms meet your needs in understanding and using the standards?		Skipped.
6.2. Are there any definitions, terms or acronyms that need to be added or revised?		Skipped.
6.3. Were there any superfluous definitions, terms or acronyms?		Skipped.
7. Figures and Tables		
7.1. Did the figures and tables in the standards aid in	HCTX:	A recurring theme throughout this process was the
your understanding of the standard and its intended use?	In the cabinet area specifically, no. We've been careful to include all that is needed, including pictures if needed. Deployment forced the addition of some of the pictures we now have.	fact that the current standard reflects a lot of iteration.
7.2. Are there any figures or table, terms that need	HCTX:	
to be added or revised?	Not really.	

Response

ATC Type 2070 General Requirements Questions

8. (3. Components		
8.1.	Do you use socket mounts for any devices?	CalTrans:	Another legacy issue!
		The socket mounts were used at one time, since the level of maintenance level required it.	This part of the standard simply leaves a "door open" for an implementer to use sockets if needed.
		HCTX:	
		In the 170 world, the program was put on a memory chip that required a socket. In today's world a socket is not needed, really. Additionally, the early drivers were "current hogs" so sockets were required.	
8.2.	If not, why not?		Skipped.
8.3.	Would you characterize your components as easily accessible, replaceable and identifiable for testing and maintenance?	HCTX:	"With the advent of surface-mount technology this
		This was an issue with using daughter boards and non-surface mounted parts. Given that ICs cannot really be replaced any more, accessibility is likely not that important anymore.	requirement is easier / harder to judge?"
		CalTrans:	
		It might be that these types of specs are not as applicable.	
8.4.	Upon what criterion (or criteria) do you base this characterization?		Skipped.
8.5.	Would you describe all the fuses in the	CalTrans:	The user requirement is that things be serviceable in
	device as easily accessible and removable without use of tools?	This issue relates to the fact that the amount of time required to service a device is small, or has to be.	a relatively fast timeframe.
8.6.	Upon what criterion (or criteria) do you	CalTrans:	There appears to be implied knowledge at work
	base this characterization?	We don't have fuses on individual components, but the requirement is about the speed of being able to service the device. There is only one fuse in the 2070 anyway.	here. There were not any obvious objective criteria at work here.

9. N	D. Mechanical (1:16:30)		
9.1.	Would you characterize all the harnesses in the device as neat, firm and properly bundled?	HCTX: That one is subjective. The problem is that if one doesn't bundle stuff properly there is obstruction for serviceability. What I've seen in some places is the use of pictures	Many of these are "boilerplate" statements, intended to create a high-quality device.
		to illustrate what "properly bundled" looks like. CalTrans:	
		The other part of this requirement is that we state in other places that everything is to be of "the highest workmanship and quality" and clearly poorly bundled cables do not reflect high workmanship.	
9.2.	Upon what criterion (or criteria) do you base this characterization?		The interviewees offered no way to put this in objective terms, but felt pretty strongly that the recurring theme of workmanship was sufficient for these purposes, even though it might appear to be subjective.
9.3.	Would you say that all assemblies in the device are modular, easily replaceable and incorporate plug-in capability for their associated devices or PCBs?	HCTX: We spec the location of devices. If you follow those dimensions, the assemblies will be easily replaceable.	
9.4.	Upon what criterion (or criteria) do you base this characterization?	Same as above.	
9.5.	Would you characterize the permanent label affixed to the inside near and center floor of the Type 2070 unit chassis as "easy to read"?	CalTrans: The issue goes back, and this applies even to the previous one, to QPL, i.e., quality workmanship. HCTX: You could get around this by using a picture.	
9.6.	Upon what criterion (or criteria) do you base this characterization?	Same as above.	

9.7.	Would you say that the PCBs in the device slide smoothly in their guides while being inserted into or removed from the frame and fit snugly into the plug-in PCB connectors?	HCTX: We're depending upon a relatively tight fit to keep these modules from slipping out. This is also another reason why a person would benefit from attending the CalTrans "course." If the dimensions are right, one shouldn't have a problem anyway. CalTrans: And if someone refers to this and calls us on it, we will likely fall back on the issue of "workmanship" and leave it at that.	The interviewees kept going back to "why" and justifying it, but these questions are trying to understand the "what" and how it is measured, quantified, communicated, and objectively known.
9.8.	Upon what criterion (or criteria) do you base this characterization?		
9.9.	How do you verify that the resistance between any two isolated, independent conductor paths is at least 100 Megohms when a 500 VDC potential is applied?	HCTX: There is a special tool used for measuring this.	
9.10.	Do you verify the quality of all the solder joints on each PCB?	HCTX: Most times, we notice that when modules start to fail, one can find cold solder joints on it. Again, if one examines the ISO requirements he can find a definition that is pertinent for this specification.	If ISO covers a bunch of these types of GMP, then maybe ISO should be referenced, but it is currently not cited. The conflict with this approach, is that the devices are being manufactured by small companies for whom meeting the requirements of ISO would be an undue burden. As a consequence, some of the ISO-type requirements are included and the implementers simply work with the vendor to understand how to meet it.
9.11.	If not, why not?		
10. Q	uality Control		
10.1.	Did you lot sample all components?	HCTX: We don't require this, but we expect devices to work and if they don't we may require some verification here.	

Response

10.2.	If not, why not?		
10.3.	Did you sample at a rate higher than on a lot-by-lot basis?		
10.4.	If so, why?		
10.5.	Did you complete electrical, environmental and timing compliance testing on each module, unit, printed circuit or subassembly?	CalTrans: We monitor the failure rate to determine if the devices perform at higher than a 3% failure rate. If they do not, we sample higher. HCTX: We don't buy devices in "lots" since we use a contractor. We send devices directly to the field and expect them to work. We do bring every controller in to see if it works, although we don't test them as explained. However, if devices begin to fail, we need to the specification to determine if they are meeting the requirements.	
10.6.	If not, why not?		
10.7.	Did you test components as a complete controller assembly?	HCTX: No.	
10.8.	If not, why not?		
10.9.	Did you inspect housing, chassis, and connection terminals for mechanical sturdiness?	HCTX: We probably will during the approval process, but not every single one. We do not require the vendor to produce any report of his findings.	Mr. Johnson's point of view is that requiring the vendor to produce paperwork is of limited value, since the vendor could have simply created it out of thin air. However, if an item begins to fail, he can always test it against the specification.
10.10.	If not, why not?		
10.11.	Did you electrically test harnessing to sockets for proper wiring sequence?	HCTX: Yes.	

10.12.	If so, on what periodicity did you conduct these tests, and how did you arrive at it?	HCTX: 100% Siemens: If you didn't test at this level, you would have a failure and not know where to start.	There is a lot of detail in the specification for the purpose of helping vendors be able to produce good product.
10.13.	If not, why not?		
10.14.	Did you visually and physically inspect the equipment shall to assure proper placement, mounting, and compatibility of subassemblies?	HCTX: Yes. This also a part of GMP.	CalTrans has a check-list and test-plan for this that is not included in the standard. Harris County uses CalTrans as a de facto qualifying body.
10.15.	If so, on what periodicity did you conduct this inspection, and how did you arrive at it?		
10.16.	If not, why not?		
10.17.	Does your process for handling defects or deficiencies found by the inspection system involving mechanical structure or wiring include returning the items through the manufacturing process or special repair process for correction?	HCTX: Yes.	This is defined as part of the warranty issues. If the device is out of warranty, I am at a loss.
10.18.	If not, why not?		
10.19.	Under what conditions do you allow PCB flow soldering a second time?	HCTX: We don't address this since we wouldn't know how many times a board has been soldered anyway!	It is not clear if this should be in the standard or not, and interviewing the clients did not make this issue any clearer.
10.20.	Are there any conditions under which you allow a PCB to be flow soldered more than twice?	HCTX: We have no way to tell how many times a board has been soldered, but we are trying to preclude errors before they happen by setting criteria like this. However, if I get into problems, I have a legitimate reason to question this area.	
10.21.	If not, why not?		
10.22.	If so, why?		

Response

11. El	11. Electrical, Environment, and Testing (3:53:25)		
11.1.	Did you follow the ATC 2070 standard with regard to generating quality control / final testing reports?	HCTX: I don't require a report. I think we need to do more in this area. CalTrans requires a report on the controller. CalTrans: Yes.	There is a perception by HCTX that no one would ever submit a test report reflecting any failures anyway. As such, he doesn't feel that receiving a set of test reports adds any value. Why is this requirement and requirements like it, in the standard? Since CalTrans tests everything anyway, it could be argued that the standard's requirement for testing reports seems superfluous. However, California is unique in this regard.
11.2.	If not, why not?		
11.3.	Specifically, did your reports include: Design Acceptance testing of all supplied components?	Siemens: Yes. HCTX: Same as above.	
11.4.	If not, why not?		
11.5.	Specifically, did your reports include: Physical and functional testing of all modules and items?	Siemens: Same as above. HCTX: Same as above.	
11.6.	If not, why not?		
11.7.	Specifically, did your reports include: Environmental testing report(s) for all equipment?	Siemens: Same as above. HCTX: Same as above.	
11.8.	If not, why not?		

11.9.	Did you follow the ATC 2070 standard with regard to high-energy and high repetition transients?	Siemens: We do all the tests that are non-destructive. HCTX: Same as above. CalTrans: Same as above.	It is clear that this standard is <u>very</u> mature, so many of these questions are irrelevant.
11.10.	If not, why not?		
11.11.	Do you believe that the ATC 2070 standard fully covered the important factors with regard to transients and power service?	Same as above.	
11.12.	If not, why not?		
11.13.	Did you follow the ATC 2070 standard with regard to temperature and humidity testing?	Same as above.	
11.14.	If not, why not?		
11.15.	Do you believe that the ATC 2070 standard fully covered the relevant and/or correct factors with regard to temperature and humidity testing?	Same as above.	
11.16.	If not, why not?		
11.17.	In selecting your instrumentation for conducting the environmental tests, what criteria did you follow?	HCTX: You need a pretty sophisticated chamber to even accomplish these tests. And given the fact that we require a time cycle and other things, you really need a high quality chamber.	
11.18.	Did you follow the procedures outlined in the ATC 2070 standard fully for your environmental testing, or did you modify them?	Same as above.	
11.19.	Why or why not?		
11.20.	If so, what specific changes, or types of changes did you make?	Same as above.	

11 21	Can you provide a full report for each of the	Same as above.	Follow-Up Question:
11.21.	environmental tests you ran and relate it to the relevant portions of the ATC 2070 standard?	Siemens: For manufacturing, it doesn't look like a formal report, but more a check-list of all the tests run.	Let's say you noticed that several of the controllers you've installed from a given vendor fail on a particularly cold day. How do you respond? HCTX:
			Well, it's a warranty item. If it fails I call the manufacturer to fix it and I expect him to fix it. I still likely wouldn't ask for a test report.
			(Again, if test reports aren't required why are they "required"?)
11.22.	Of what value, if any, were the environmental procedures listed in the ATC 2070 standard?	Same as above.	
11.23.	Did you follow the procedures outlined in the ATC 2070 standard fully for your vibration testing, or did you modify them?	Same as above.	
11.24.	Why or why not?		
11.25.	Can you provide a full report for each of the vibration tests you ran and relate it to the relevant portions of the ATC 2070 standard?	Same as above.	
11.26.	Of what value, if any, were the vibration testing procedures listed in the ATC 2070 standard?	Same as above.	
11.27.	Did you follow the procedures outlined in the ATC 2070 standard fully for your shock testing, or did you modify them?	Same as above.	
11.28.	Why or why not?		
11.29.	Can you provide a full report for each of the shock tests you ran and relate it to the relevant portions of the ATC 2070 standard?	Same as above.	

11.30.	Of what value, if any, were the shock testing procedures listed in the ATC 2070 standard?	Same as above.	
11.31.	Did you follow the procedures outlined in the ATC 2070 standard fully for your cabinet assembly testing, or did you modify them?	Same as above.	
11.32.	Why or why not?		
11.33.	Can you provide a full report for each of the cabinet assembly tests you ran and relate it to the relevant portions of the ATC 2070 standard?	Same as above.	Side issue for all testing: CalTrans is the only authority who has created an "acceptance test" for verifying the operation of the overall unit. It is not clear how HCTX verifies the overall operation of a unit, outside this CalTrans "DAT" test. HCTX seemed to feel that it makes sense for CalTrans to become a "certification laboratory" for the industry. Otherwise it is not clear that the standard provides real value with regard to all these testing requirements.
11.34.	Of what value, if any, were the cabinet assembly testing procedures listed in the ATC 2070 standard?	Same as above.	
11.35.	A number of the specific areas of testing outlined in the ATC 2070 standard reflect that they are "under consideration." How did you approach meeting these portions of the ATC 2070 standard?	HCTX: We perform discrete tests for individual components, and therefore there are no guidelines for this area. These sections need to go away. Much of this is simply a carry-over from a prior version.	

Response

ATC Type 2070 Controller-Specific Requirements Questions

12. T	12. Type 2070-1 CPU Module (5:11:54)			
12.1.	Did you prepare a separate software design specification, in addition to the software design specifications listed in the ATC 2070 standard?	Siemens: No. HCTX: No.	Again, the use of the DAT, developed by CalTrans, was mentioned during the discussions. The DAT is actually called out in Section 4.2.7.5.1. There was disagreement between Mr. Johnson (HCTX) and Mr. Iniguez as to if the DAT is always "required" versus never left in a 2070 controller. One of the users, in fact, one of the key users at HCTX had never used the DAT. It appears that now HCTX will begin, as a result of this discussion and interview, to use the DAT. Either way, the wording in the standard needs to be reworded to reflect the state-of-the-art, including the use of a DAT, from where it comes, and how it is used. Although CalTrans has supervised the development of the DAT, it is a product derived from a number of manufacturers.	
12.2.	Why or why not?			
12.3.	Did you find that the software design specifications listed in the ATC 2070 standard were adequate to design and build the device in question?	HCTX: Yes.		
12.4.	Why or why not?			
12.5.	Does the first executable file in the boot image of the default directory, designated as "Sysgo", operate as specified in the ATC 2070 standard?	HCTX: Yes, with the caveat that we currently do not use the DAT, as per the previous discussions.		
12.6.	Why or why not?			

13. Type 2070-2 Field I/O Module (FI/O)	13. Type 2070-2 Field I/O Module (FI/O)			
13.1. What definition did you use for the terminology "glitch" with regard to th performance of a Parallel I/O Ports ou circuit?		Apparently, v02.03, which the ISTT had been given to evaluate, was not the latest "internal" version, which is v02.06. This later version reflects some improvements, of which this is one.		
13.2. Why did you use this definition?				
13.3. Did you follow the standard's recommendation with regard to the creand supply of options with additional features, defined as:	eation HCTX: For reasons of standardizing, we do not want deviation from the things we list.			
Option 3A – FPA controller, two keyboa AUX switch, alarm bell and Display A	rds,			
Option 3B – FPA controller, two keyboar AUX switch, alarm bell and Display B	rds,			
Option 3C – System Serial Port 6 Lines, isolated and vectored to Connector C60S.				
13.4. If not, why not?				
13.5. If so, are you clear about the purpose specification? (What is it?)	of this HCTX: Same as above.			
13.6. How did you meet, or verify that you this keyboard specification? "Key contacts shall be hermetically sealed have a design life of over one million operations, shall be rated for the current a voltage levels used, and shall stabilize wit milliseconds following contact closure."	Yes.			
13.7. Did you follow the ATC 2070 standar regard to all the details in the Display Section 4.4.4?	d with HCTX: Yes.			

Question		On .	Response	Remarks / Analysis / Action Items
	13.8.	Was the section Display Section 4.4.4 of the	HCTX:	In the view of HCTX, much of this stuff is

13.8.	Was the section Display Section 4.4.4 of the ATC 2070 standard helpful to you in your development?	HCTX: Yes.	In the view of HCTX, much of this stuff is important because this "is a functional display" so changes will effect usage.
13.9.	Did you also create your own system design specification relative to the types of items specified in the Display Section, 4.4.4, portion of the ATC 2070 standard?	HCTX: Yes.	
13.10.	Why or why not?		
13.11.	Did you follow the ATC 2070 standard with regard to all the details in the Power Supply section?	Siemens: Yes.	One of the underlying premises used in developing the standard was the belief that it is better to put as much detail in the standard itself, and avoid the user having to look in some other document to find answers he might need. The key user from HCTX noted that "as long as I knew what I was doing" I could follow the specification and get what I was after. It is not clear what "know what I was doing" means in a more general sense.
13.12.	Was the Power Supply section of the ATC 2070 standard helpful to you in your development?		
13.13.	Did you also create your own system design specification relative to the types of items specified in the Power Supply section of the ATC 2070 standard?		
13.14.	Why or why not?		

14. C	hapter Details – Drawings – (Type 2070 Cor	atroller)	
14.1.	Exactly what use did you make of the drawings listed in this section?	HCTX: When we use three decimal places, we are specifying a more important specification, but that is not actually spelled out in the standard. CalTrans: We don't normally specify the "off-the-shelf" parts, such as the keyboard too closely.	Again, the current drawing structure reflects the fact that the current standard reflects the end of a long iteration process. It is also pretty clear that interviewing the developer of the standard is not suitable for addressing many of these questions in an objective way. It is also pretty clear that because of this challenge, the amount of "implied knowledge" inherent in the standard cannot be ascertained via these interviews!
14.2.	Did you generate your own drawings similar to these?	CalTrans: All manufacturers normally submit lots of drawings that we can use to verify that what they are going to produce will meet our needs. HCTX: The basic thought process is that a manufacturer must place all the items on the front, and exactly where is not specified by the standard but given the number of items, they can only end up in certain places.	This represents the first time in the entire interview process where it was admitted that the standard did not provide all information needed or produced by a manufacturer and that a manufacture would have to produce additional information.
14.3.	Why or why not?	CalTrans: For example, they should submit s theory of operation, but such is not described in the standard. (Follow up question: Then how does a manufacturer know to submit one?)	It seems pretty clear that items like a theory of operation are required by the client, but not specified in the standard.
15. C	hapter Details – Drawings – (Type 2070-6 A	& B)	
15.1.	Exactly what use did you make of the drawings listed in this section?		Skipped due to mature nature of standard.
15.2.	Did you generate your own drawings similar to these?		Skipped due to mature nature of standard.
15.3.	Why or why not?		

16. C	16. Chapter Details – Drawings – (NEMA Module)			
16.1.	Exactly what use did you make of the drawings listed in this section?		Skipped due to mature nature of standard.	
16.2.	Did you generate your own drawings similar to these?		Skipped due to mature nature of standard.	
16.3.	Why or why not?			

ITS Roadside Cabinet General Requirements Questions

17. C	17. Components			
17.1.	Do you use socket mounts for any devices?		These questions were deemed unnecessary as they have been answered in previous sections. Furthermore, given the fact that the standard being tested is the result of many, many iterations — resulting in what could only be termed a "legacy" product — and is being employed by the developers anyway, such questions as these will provide little, if any, feedback on the standard's appropriateness.	
17.2.	If not, why not?			
17.3.	Would you characterize your components as easily accessible, replaceable and identifiable for testing and maintenance?	Same as above.		
17.4.	Upon what criterion (or criteria) do you base this characterization?	Same as above.		
17.5.	Would you describe all the fuses in the device as easily accessible and removable without use of tools?	Same as above.		

17.6.	Upon what criterion (or criteria) do you base this characterization?	Same as above.	
17.7.	Did you experimentally verify that the life of all components, operating continuously (24 hours per-day, 365 days per-year) in their circuit application, was ten years or longer?	Same as above.	
17.8.	If so, how did you verify this?	Same as above.	
17.9.	If not, why not?		
18. M	echanical		
18.1.	Would you characterize all the harnesses in the device as neat, firm and properly bundled?	Same as above.	
18.2.	Upon what criterion (or criteria) do you base this characterization?	Same as above.	
18.3.	Would you say that all assemblies in the device are modular, easily replaceable and incorporate plug-in capability for their associated devices or PCBs?	Same as above.	
18.4.	Upon what criterion (or criteria) do you base this characterization?	Same as above.	
18.5.	Would you characterize the permanent label affixed to the inside near and center floor of the Type 2070 unit chassis as "easy to read"?	Same as above.	
18.6.	Upon what criterion (or criteria) do you base this characterization?	Same as above.	

Response

18.7.	Would you say that the PCBs in the device slide smoothly in their guides while being inserted into or removed from the frame and fit snugly into the plug-in PCB connectors?	Same as above.	
18.8.	Upon what criterion (or criteria) do you base this characterization?	Same as above.	
18.9.	How do you verify that the resistance between any two isolated, independent conductor paths is at least 100 Megohms when a 500 VDC potential is applied?	Same as above.	
18.10.	Do you verify the quality of all the solder joints on each PCB?	Same as above.	
18.11.	If not, why not?		
19. Qı	uality Control		
19.1.	Did you lot sample all components?	Same as above.	
19.2.	If not, why not?		
19.3.	Did you sample at a rate higher than on a lot-by-lot basis?	Same as above.	
19.4.	If so, why?		
19.5.	Did you complete electrical, environmental and timing compliance testing on each module, unit, printed circuit or subassembly?	Same as above.	
19.6.	If not, why not?		
19.7.	Did you test components as a complete controller assembly?	Same as above.	
19.8.	If not, why not?		

Response

Same as above. Same				
9.11. Did you electrically test harnessing to sockets for proper wiring sequence? 9.12. If so, on what periodicity did you conduct these tests, and how did you arrive at it? 9.13. If not, why not? 9.14. Did you visually and physically inspect the equipment shall to assure proper placement, mounting, and compatibility of subassemblies? 9.15. If so, on what periodicity did you conduct this inspection, and how did you arrive at it? 9.16. If not, why not? 9.17. Does your process for handling defects or deficiencies found by the inspection system involving mechanical structure or wiring include returning the items through the manufacturing process or special repair process for correction? 9.18. If not, why not? 9.19. Under what conditions do you allow PCB flow soldering a second time? 9.20. Are there any conditions under which you allow a PCB to be flow soldered more than twice? 9.21. If not, why not?	19.9.	connection terminals for mechanical	Same as above.	
sockets for proper wiring sequence? 9.12. If so, on what periodicity did you conduct these tests, and how did you arrive at it? 9.13. If not, why not? 9.14. Did you visually and physically inspect the equipment shall to assure proper placement, mounting, and compatibility of subassemblies? 9.15. If so, on what periodicity did you conduct this inspection, and how did you arrive at it? 9.16. If not, why not? 9.17. Does your process for handling defects or deficiencies found by the inspection system include returning the items through the manufacturing process or special repair process for correction? 9.18. If not, why not? 9.19. Under what conditions do you allow PCB flow soldering a second time? 9.20. Are there any conditions under which you allow a PCB to be flow soldered more than twice? 9.21. If not, why not?	19.10.	If not, why not?		
these tests, and how did you arrive at it? 19.13. If not, why not? 19.14. Did you visually and physically inspect the equipment shall to assure proper placement, mounting, and compatibility of subassemblies? 19.15. If so, on what periodicity did you conduct this inspection, and how did you arrive at it? 19.16. If not, why not? 19.17. Does your process for handling defects or deficiencies found by the inspection system involving mechanical structure or wiring include returning the items through the manufacturing process or special repair process for correction? 19.18. If not, why not? 19.19. Under what conditions do you allow PCB flow soldering a second time? 19.20. Are there any conditions under which you allow a PCB to be flow soldered more than twice? 19.21. If not, why not?	19.11.		Same as above.	
9.14. Did you visually and physically inspect the equipment shall to assure proper placement, mounting, and compatibility of subassemblies?	19.12.		Same as above.	
equipment shall to assure proper placement, mounting, and compatibility of subassemblies? 19.15. If so, on what periodicity did you conduct this inspection, and how did you arrive at it? 19.16. If not, why not? 19.17. Does your process for handling defects or deficiencies found by the inspection system involving mechanical structure or wiring include returning the items through the manufacturing process or special repair process for correction? 19.18. If not, why not? 19.19. Under what conditions do you allow PCB flow soldering a second time? 19.20. Are there any conditions under which you allow a PCB to be flow soldered more than twice? 19.21. If not, why not?	19.13.	If not, why not?		
this inspection, and how did you arrive at it? 19.16. If not, why not? 19.17. Does your process for handling defects or deficiencies found by the inspection system involving mechanical structure or wiring include returning the items through the manufacturing process or special repair process for correction? 19.18. If not, why not? 19.19. Under what conditions do you allow PCB flow soldering a second time? 19.20. Are there any conditions under which you allow a PCB to be flow soldered more than twice? 19.21. If not, why not?	19.14.	equipment shall to assure proper placement, mounting, and compatibility of	Same as above.	
9.17. Does your process for handling defects or deficiencies found by the inspection system involving mechanical structure or wiring include returning the items through the manufacturing process or special repair process for correction? 19.18. If not, why not? 19.19. Under what conditions do you allow PCB flow soldering a second time? 19.20. Are there any conditions under which you allow a PCB to be flow soldered more than twice? 19.21. If not, why not?	19.15.			
deficiencies found by the inspection system involving mechanical structure or wiring include returning the items through the manufacturing process or special repair process for correction? 19.18. If not, why not? 19.19. Under what conditions do you allow PCB flow soldering a second time? 19.20. Are there any conditions under which you allow a PCB to be flow soldered more than twice? 19.21. If not, why not?	19.16.	If not, why not?		
19.19. Under what conditions do you allow PCB flow soldering a second time? 19.20. Are there any conditions under which you allow a PCB to be flow soldered more than twice? 19.21. If not, why not? Same as above.	19.17.	deficiencies found by the inspection system involving mechanical structure or wiring include returning the items through the manufacturing process or special repair	Same as above.	
flow soldering a second time? 19.20. Are there any conditions under which you allow a PCB to be flow soldered more than twice? 19.21. If not, why not? Same as above.	19.18.	If not, why not?		
allow a PCB to be flow soldered more than twice? 19.21. If not, why not?	19.19.		Same as above.	
	19.20.	allow a PCB to be flow soldered more than	Same as above.	
19.22. If so, why?	19.21.	If not, why not?		
	19.22.	If so, why?		

Response

20. El	20. Electrical, Environment, and Testing			
20.1.	Did you follow the ITS Roadside Cabinet standard with regard to generating quality control / final testing reports?	Same as above.		
20.2.	If not, why not?			
20.3.	Specifically, did your reports include: Design Acceptance testing of all supplied components?	Same as above.		
20.4.	If not, why not?			
20.5.	Specifically, did your reports include: Physical and functional testing of all modules and items?	Same as above.		
20.6.	If not, why not?			
20.7.	Specifically, did your reports include: Environmental testing report(s) for all equipment?	Same as above.		
20.8.	If not, why not?			
20.9.	Did you follow the ITS Roadside Cabinet standard with regard to high-energy and high repetition transients?	Same as above.		
20.10.	If not, why not?			
20.11.	Do you believe that the ITS Roadside Cabinet standard fully covered the important factors with regard to transients and power service?	Same as above.		
20.12.	If not, why not?			
20.13.	Did you follow the ITS Roadside Cabinet standard with regard to temperature and humidity testing?	Same as above.		
20.14.	If not, why not?			

20.15.	Do you believe that the ITS Roadside Cabinet standard fully covered the relevant and/or correct factors with regard to temperature and humidity testing?	Same as above.	
20.16.	If not, why not?		
20.17.	In selecting your instrumentation for conducting the environmental tests, what criteria did you follow?	Same as above.	
20.18.	Did you follow the procedures outlined in the ITS Roadside Cabinet standard fully for your environmental testing, or did you modify them?	Same as above.	
20.19.	Why or why not?		
20.20.	If so, what specific changes, or types of changes did you make?	Same as above.	
20.21.	Can you provide a full report for each of the environmental tests you ran and relate it to the relevant portions of the ITS Roadside Cabinet standard?	Same as above.	
20.22.	Of what value, if any, were the environmental procedures listed in the ITS Roadside Cabinet standard?	Same as above.	
20.23.	Did you follow the procedures outlined in the ITS Roadside Cabinet standard fully for your cabinet assembly testing, or did you modify them?	Same as above.	
20.24.	Why or why not?		
20.25.	Can you provide a full report for each of the cabinet assembly tests you ran and relate it to the relevant portions of the ITS Roadside Cabinet standard?	Same as above.	

Response

Question	Response	Remarks / Analysis / Action Items
20.26. Of what value, if any, were the cabinet assembly testing procedures listed in the ITS Roadside Cabinet standard?	Same as above.	

ITS Roadside Cabinet Auxiliary Cabinet-Specific Requirements Questions

21. Model 204 Flasher Unit and Model 205 Flash Transfer Relay Unit				
21.1.	21.1. Did you experimentally verify that the flasher unit circuitry would operate in an open-circuit condition without load for 10 years minimum?	HCTX: We actually installed a 2 microfarad capacitor because it was impractical to operate without load. We really don't do this, but we might.	This section apparently should be updated to reflect that the capacitor is needed, but it was not clear from our discussions.	
			It also seems pretty clear that this requirement is simply being met because there exist cabinets that have been running for over 10 years.	
21.2.	21.2. If so, how did you verify this?	Siemens:	This requirement and others like it should be reflected in the "boilerplate" of the standard, using an MTBF premise.	
		We brought in a guy to do a MTBF to predict these requirements. So when the initial ones came out we did actually need an MTBF specification.		
21.3.	If not, why not?			
21.4.	Did you experimentally verify that the switch would perform a minimum of 100,000 operations while switching a tungsten load of 1000 Watts at 70 degrees C?	HCTX: This seems like a good test to run, but these parameters, in terms of the number of operations.	The intent of this requirement should be to determine if the flasher could work all day flashing continuously. What is needed is a "reasonable expectation" for the timing.	
21.5.	If so, how did you verify this?			
21.6.	If not, why not?			

21.7.	Did you experimentally verify that the DPDT contact points were capable of switching 20 Amperes or one Kilowatt Tungsten Load at 120 VAC per contact at least 100,000 operations without contact welding or excessive burning, pitting or cavitations?	HCTX: This is an actual design criterion. I'll have to determine if we resolved this, because I'm not sure. CalTrans: This is the "expected rating" of the device, as opposed to the output of a test.	It's not clear what the result of this discussion was, but it was clear that that the standard needs some work in this area.
21.8.	If so, how did you verify this?		
21.9.	If not, why not?		
22. M	odel 212 ITS Cabinet Monitor Unit (CMU)		
22.1.	Did you prepare an input message design specification, in addition to the one listed in section 4.4 of the ITS Cabinet Monitor Unit standard?	Siemens: The detail in this unit is a result of a previous decision to make sure we could "mix and match" between CMU's and AMU's from different vendors. (If the same vendor always delivered the two units, we wouldn't need to be so detailed about the protocol.) We actually had a person build a CMU using the standard and it worked as expected, which verifies that the information is as needed.	There appears to be a need for a "white paper" that provides some insight about what HCTX has found in trying to reconfigure the ITS Cabinets to get them to work in certain situations.
22.2.	Why or why not?		
22.3.	Did you find that the message format specifications listed in section 4.4 of the ITS Cabinet Monitor Unit standard were adequate to design and build the device in question?	Same as above. Siemens: We originally did not have all this detail in the standard, but actually added it because the number of things we needed the CMU to do increased.	CMU also stand for "conflict monitor" and actually monitors the controller for conflicts. This leads to the intersection being put into "flash" without a person being able to tell why via the monitor. It is not clear how this should be addressed.
22.4.	Why or why not?		

Remarks / Analysis / Action Items

Response

Question

memory key as specified in section 4.4.14 of the ITS Cabinet Monitor Unit standard? 23.2. Why or why not? 24. CMU Connector 24.1. Did you use the pin-outs as specified in this section of the standard? 24.2. Why or why not? 25. Serial Bus #1 Frames 25.1. Did you use the byte format as specified in this section of the standard? 25.2. Why or why not? 26. Type 218 – Serial Interface Unit (SIU) 26.1. Did you design and implement Tracking Functions and Complex Output Functions as specified in the standard? 26.1. Did you design and implement Tracking Functions and Complex Output Functions as specified in the standard? 27. These two features can be implemented without direct output from the controller. This is a behavior of the field output that I'm not very happy with. I've been arguing for years that I don't want these two features. Siemens: The programmer can choose to use this functionality or not. As such this is not a valid fear.	23. Moi	nitor Unit Serial Memory Key		
24. CMU Connector 24.1. Did you use the pin-outs as specified in this section of the standard? 24.2. Why or why not? 25. Serial Bus #I Frames 25.1. Did you use the byte format as specified in this section of the standard? 25.2. Why or why not? 26. Type 218 - Serial Interface Unit (SIU) 26.1. Did you design and implement Tracking Functions and Complex Output Functions as specified in the standard? 26.1. Did you design and implement Tracking Functions and Complex Output Functions as specified in the standard? 27. These two features can be implemented without direct output from the controller. This is a behavior of the field output that I'm not very happy with. I've been arguing for years that I don't want these two features. 28. Siemens: The programmer can choose to use this functionality or not. As such this is not a valid fear.	1	memory key as specified in section 4.4.14	Yes. CalTrans:	
24.1. Did you use the pin-outs as specified in this section of the standard? 24.2. Why or why not? 25. Serial Bus #1 Frames 25.1. Did you use the byte format as specified in this section of the standard? 26.2. Why or why not? 26. Type 218 – Serial Interface Unit (SIU) 26.1. Did you design and implement Tracking Functions and Complex Output Functions as specified in the standard? 4 HCTX: These two features can be implemented without direct output from the controller. This is a behavior of the field output that I'm not very happy with. I've been arguing for years that I don't want these two features. Siemens: The programmer can choose to use this functionality or not. As such this is not a valid fear.	23.2.	Why or why not?		
24.2. Why or why not? 25. Serial Bus #1 Frames 25.1. Did you use the byte format as specified in this section of the standard? 26. Type 218 - Serial Interface Unit (SIU) 26.1. Did you design and implement Tracking Functions and Complex Output Functions as specified in the standard? BHCTX: These two features can be implemented without direct output from the controller. This is a behavior of the field output that I'm not very happy with. I've been arguing for years that I don't want these two features. Siemens: The programmer can choose to use this functionality or not. As such this is not a valid fear. The programmer can choose to use this functionality or not. As such this is not a valid fear.	24. CM	IU Connector		
25. Serial Bus #1 Frames 25.1. Did you use the byte format as specified in this section of the standard? 26. Type 218 – Serial Interface Unit (SIU) 26.1. Did you design and implement Tracking Functions and Complex Output Functions as specified in the standard? 4 HCTX: These two features can be implemented without direct output from the controller. This is a behavior of the field output that I'm not very happy with. I've been arguing for years that I don't want these two features. Siemens: The programmer can choose to use this functionality or not. As such this is not a valid fear.			Same as above.	
25.1. Did you use the byte format as specified in this section of the standard? 26. Type 218 – Serial Interface Unit (SIU) 26.1. Did you design and implement Tracking Functions and Complex Output Functions as specified in the standard? BY These two features can be implemented without direct output from the controller. This is a behavior of the field output that I'm not very happy with. I've been arguing for years that I don't want these two features. Siemens: The programmer can choose to use this functionality or not. As such this is not a valid fear.	24.2.	Why or why not?		
this section of the standard? 25.2. Why or why not? 26. Type 218 – Serial Interface Unit (SIU) 26.1. Did you design and implement Tracking Functions and Complex Output Functions as specified in the standard? These two features can be implemented without direct output from the controller. This is a behavior of the field output that I'm not very happy with. I've been arguing for years that I don't want these two features. Siemens: The programmer can choose to use this functionality or not. As such this is not a valid fear.	25. Seri	ial Bus #1 Frames		
26.1. Did you design and implement Tracking Functions and Complex Output Functions as specified in the standard? HCTX: These two features can be implemented without direct output from the controller. This is a behavior of the field output that I'm not very happy with. I've been arguing for years that I don't want these two features. Siemens: The programmer can choose to use this functionality or not. As such this is not a valid fear. There are applications in the SIU that can influence the outputs regardless of what the controller says. The purpose of this functionality is to off-load work from the controller. This could result in some loss of closed-loop control.			Same as above.	
26.1. Did you design and implement Tracking Functions and Complex Output Functions as specified in the standard? HCTX: These two features can be implemented without direct output from the controller. This is a behavior of the field output that I'm not very happy with. I've been arguing for years that I don't want these two features. Siemens: The programmer can choose to use this functionality or not. As such this is not a valid fear. There are applications in the SIU that can influence the outputs regardless of what the controller says. The purpose of this functionality is to off-load work from the controller. This could result in some loss of closed-loop control.	25.2.	Why or why not?		
Functions and Complex Output Functions as specified in the standard? These two features can be implemented without direct output from the controller. This is a behavior of the field output that I'm not very happy with. I've been arguing for years that I don't want these two features. Siemens: The programmer can choose to use this functionality or not. As such this is not a valid fear.	26. Typ	oe 218 – Serial Interface Unit (SIU)		
]	Functions and Complex Output Functions as	These two features can be implemented without direct output from the controller. This is a behavior of the field output that I'm not very happy with. I've been arguing for years that I don't want these two features. Siemens: The programmer can choose to use this functionality	the outputs regardless of what the controller says. The purpose of this functionality is to off-load work from the controller. This could result in some loss
	26.2.	Why or why not?		

Question		Response	
26.3.	For example, in the case of a Tracking Function, does the implementation you used for the transmission of a definition follow this requirement:	Skipped.	
26.4.	For example, in the case of a Tracking Function, does the implementation you used for the transmission of a definition follow this requirement:	Skipped.	
26.5.	Did you exactly follow the block diagrams shown in Section 4.7.20 of the standard?	Skipped.	
26.6.	If not, why not?		
27. C	abinet Details – Drawings		
27.1.	Exactly what use did you make of the drawings listed in this document?	Previously answered.	
27.2.	Did you generate your own drawings similar to those listed?	Previously answered.	
27.3.	Why or why not?		

ITS Roadside Cabinet Detector Sensor Units, Elements & Isolators Requirements Questions

Question Response Remarks / Analysis / Action Items

28. M	28. Model 222 & 224 Loop Detector Sensor Unit			
28.1.	Requirements in this section are posited in terms of a "vehicle" passing over or remaining over loop wires embedded in the roadway. How did you verify these requirements?	HCTX: We know how to do this because, again, it's a legacy issue.		
28.2.	If you did not use an actual vehicle, how are you sure you met the requirements?	Skipped.		

Questi	ion	Response	Remarks / Analysis / Action Items
28.3.	What does the terminology, "AGENCY licensed motor vehicles" refer to?	Skipped.	
29. M	agnetic Detector		
29.1.	Exactly how did you verify that the sensing element used in this device was "moisture proof"?	Skipped.	
29.2.	Exactly how did you verify that the sensing element would detect a car traveling at all speeds between three and 80 miles per hour?	HCTX: We actually use a car.	

ITS Roadside Cabinet System Requirements Questions

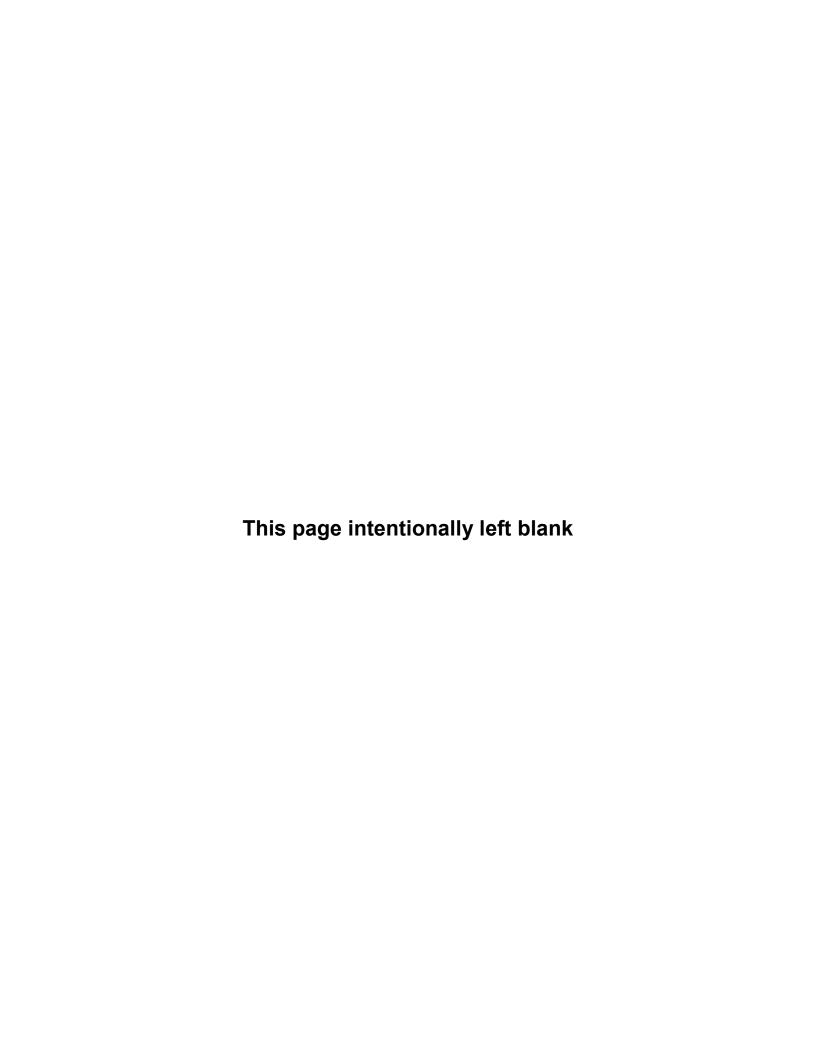
Question Response Remarks / Analysis / Action Items

30. Cabinet Cage Configuration Drawings				
30.1.	Exactly what use did you make of the drawings listed in this section?	Previously answered.		
30.2.	Did you generate your own drawings similar to these?	Previously answered.		
30.3.	Why or why not?			
31. C	abinet Details Drawings			
31.1.	Exactly what use did you make of the drawings listed in this section?	Previously answered.		
31.2.	Did you generate your own drawings similar to these?	Previously answered.		
31.3.	Why or why not?			

32. Cabinet Housing Construction			
32.1.	Did you exactly follow the standard with regard to the construction of cabinet system housings?	Previously answered.	
32.2.	Why or why not?		
32.3.	If you deviated from the standard, what specific changes did you make?	Previously answered.	



Appendix B: ATC 2070 / ITS Cabinet Tested Requirements



B.1 ATC Type 2070 General Requirements

#	Requirement (Standard Document Section)	Document Section Pass Fail	Comments	Test Type	Requirement Type
1	All sharp edges and corners shall be rounded and free of any burrs.	3.1.6 Metals		Inspection	Design
7	Within the circuit of any device, module, or Printed Circuit Board (PCB), electrical isolation shall be provided between DC logic ground, equipment ground and the AC conductor.	3.1.6 Metals		Performance Test	Design
8	They [the DC logic ground and AC conductor] shall be electrically isolated from each other by 500 megohms, minimum, when tested at the input terminals with 500 VDC.	3.1.6 Metals		Analysis	Design
9	Keyboards and LCD/LED Displays are considered daughter boards. Daughter boards shall be mechanically secured with a minimum of four spacers/metal screws.	3.1.6 Metals	It is sufficient to specify that the daughter boards are mechanically secured. Specifying the number of screws is not necessary and creates a useless requirement.	Inspection	Design
10	Connectors shall be either Flat Cable or PCB Headers.	3.1.6 Metals		Inspection	Design
11	Components are allowed to be mounted under the daughter board.	3.1.9 Daughter Boards	This requirement provides no value.	Drop from the standard.	Design
14	The electronic circuit design shall be such that all components of the same generic type, regardless of manufacturer, shall function equally in accordance with the specifications.	3.2.1 Components – General		Inspection	Design
15	No device shall be socket mounted unless specifically called out.	3.2.2 Components - Electronic		Inspection	Design
16	No component shall be operated above 80% of its maximum rated voltage, current or power ratings.	3.2.2 Components – Electronic	This is a procurement requirement and has nothing to do with the design of the cabinet.	Analysis	Design
17	Digital components shall not be operated above 3% over their nominal voltage, current or power ratings.	3.2.2 Components – Electronic		Analysis	Design
19	The design life of all components, operating for twenty-four hours a day and operating in their circuit application, shall be ten years or longer.	3.2.2 Components – Electronic		Analysis	Design
20	Components shall be arranged so they are easily accessible, replaceable and identifiable for testing and maintenance.	3.2.2 Components – Electronic	Poorly worded standard. Easily replaceable means what exactly?	Inspection	Design
21	Where damage by shock or vibration exists, the component shall be supported mechanically by a clamp, fastener, retainer, or hold-down bracket.	3.2.2 Components – Electronic	How is the possibility for damage by shock or vibration quantified?	Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
24	The DC and AC voltage ratings as well as the dissipation factor of a capacitor shall exceed the worst-case design parameters of the circuitry by 150%. Capacitor encasements shall be resistant to cracking, peeling and discoloration.	3.2.3 Capacitors			Analysis	Design
25	All capacitors shall be insulated and shall be marked with their capacitance values and working voltages.	3.2.3 Capacitors			Inspection	Design
26	Electrolytic capacitors shall not be used for capacitance values of less than 1.0 microfarad and shall be marked with polarity.	3.2.3 Capacitors			Inspection	Design
28	Under 1 Watt potentiometers shall be used only for trimmer type function.	3.2.4 Potentiometers			Inspection	Design
29	The potentiometer power rating shall be at least 100% greater than the maximum power requirements of the circuit.	3.2.4 Potentiometers			Analysis	Design
31	All resistors shall be insulated and shall be marked with their resistance values.	3.2.5 Resistors			Inspection	Design
32	Resistance values shall be indicated by the EIA color codes, or stamped value.	3.2.5 Resistors			Inspection	Design
34	Special ventilation or heat sinking shall be provided for all 2-watt or greater resistors.	3.2.5 Resistors			Inspection	Design
35	They [all resistors] shall be insulated from the PCB.	3.2.5 Resistors			Inspection	Design
37	All metal oxide semiconductor components shall contain circuitry to protect their inputs and outputs against damage due to high static voltages or electrical fields.	3.2.6 Semiconductor Devices			Inspection	Design
38	Device pin "1" locations shall be properly marked on the PCB adjacent to the pin.	3.2.6 Semiconductor Devices			Inspection	Design
41	Each triac with a designed circuit load of greater than 0.5 Amperes at 120 VAC shall be mounted to a heat sink with thermal conductive compound or material, in addition to being mechanically secured.	3.2.8 Triacs			Inspection	Design
44	Contacts shall be silver alloy and enclosed in an arc quenching chamber.	3.2.9 Circuit Breakers			Inspection	Design
45	Overload tripping shall not be influenced by an ambient air temperature range of from -18 degrees C to 50 degrees C.	3.2.9 Circuit Breakers		It appears that this requirement "sneaked in" from the re-use of cabinet boilerplate. There are no circuit breakers in the ATC 2070.	Performance Test	Design
46	The minimum Interrupting Capacity shall be 5,000 amperes, RMS when the breaker is secondary to a UL approved fuse or primary circuit breaker and both breakers in concert provide the rated capacity.	3.2.9 Circuit Breakers			Performance Test	Design
47	For circuit breakers 80 amperes and above, the minimum interrupting capacity shall be 10,000 amperes, RMS.	3.2.9 Circuit Breakers			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
49	The Load Circuit Breakers used to power Switch Packs shall have auxiliary switches.	3.2.9 Circuit Breakers			Inspection	Design
51	All Fuses that are resident in a bayonet style fuse holder shall have the fuse size rating labeled on the holder or on the panel adjacent to the holder.	3.2.10 Fuses			Inspection	Design
54	The switch contact resistance shall be 100 milliohms maximum at 2 milliamperes, 30 VDC.	3.2.11 Switches			Analysis	Design
63	Screw size [for the terminal blocks] is called out under the associated file, panel or assembly.	3.2.12 Terminal Blocks			Inspection	Design
64	Provided the connectors mate, screw lug cam driven devices or crimp pin connectors shall be allowable if the interface is part of a harness.	3.2.13 Screw Lug and Cam Driven Connectors		Is specifying an exact gauge of wire appropriate? Maybe 22-gauge wire is a minimum size.	Inspection	Design
66	Harnesses shall be neat, firm and properly bundled with external protection.	3.2.14 Wiring, Cabling, and Harnesses		Words like "neat" are subjective in a standard and are both un-testable and undefined.	Inspection	Design
67	They [wiring harnesses] shall be tie-wrapped and routed to minimize crosstalk and electrical interference.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design
68	Each harness shall be of adequate length to allow any conductor to be connected properly to its associated connector or termination point.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design
69	Conductors within an encased harness have no color requirements.	3.2.14 Wiring, Cabling, and Harnesses		Does this specification add any value?	Drop from the standard.	Design
70	Printed circuit motherboards are to be used where possible to eliminate or reduce cabinet wiring.	3.2.14 Wiring, Cabling, and Harnesses		What does "where possible" mean and how is it quantified?	Drop from the standard.	Design
72	Wiring shall be routed to prevent conductors from being in contact with metal edges.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design
73	Wiring shall be arranged so that any removable assembly may be removed without disturbing conductors not associated with that assembly.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design
74	All conductors, except those that can be readily traced, shall be labeled.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design
75	Labels attached to each end of the conductor shall identify the destination of the other end of the conductor.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design
77	The insulation shall be polyvinyl chloride with a minimum thickness of 10 mils or greater.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
80	All indicators and character displays shall be readily visible at a radius of up to 4 feet within the cone of visibility when the indicator is subjected to 97,000 lux (9,000 footcandles) of white light with the light source at 45 degrees (+/-2 degrees) to the front panel.	3.2.15 Indicators and Character Displays			Performance Test	Design
82	All indicators shall be self-luminous.	3.2.15 Indicators and Character Displays			Inspection	Design
85	Indicators supplied on equipment requiring handles shall be mounted such that a horizontal clearance shall be provided.	3.2.15 Indicators and Character Displays		How much clearance? Is the amount of clearance important?	Inspection	Design
86	Liquid Crystal Displays (LCD) shall be readable at temperatures of -20 degrees C to +70 degrees C.	3.2.15 Indicators and Character Displays			Performance Test	Design
87	All controller unit functions are required to operate at temperatures of –37 degrees C to +74 degrees C.	3.2.15 Indicators and Character Displays			Performance Test	Design
89	The mating connectors shall be designated as the connector number and male/female relationship, such as C1P (plug or PCB edge connector) and C1S (socket).	3.2.16 Connectors			Inspection	Design
91	The terminal block shall be a barrier type with 6-32, 0.25 inches or longer, nickel plated brass binder head screws.	3.2.16 Connectors			Inspection	Design
92	Each terminal shall be permanently identified as to its function.	3.2.16 Connectors			Inspection	Design
93	Pin and socket contacts for connectors shall be beryllium copper construction subplated with 1.27 microns nickel and plated with 0.76 microns gold.	3.2.16 Connectors			Inspection	Design
94	Pin diameter shall be 0.0618 inches.	3.2.16 Connectors			Inspection	Design
99	The PCB 22/44 Connector shall have 22 independent contacts per side; dual sided with 0.156 inch contact centers.	3.2.16 Connectors			Inspection	Design
101	All terminal connectors shall be crimped using a Controlled-Cycle type crimping tool.	3.2.16 Connectors		Manufacturing specification. (There is no way to ascertain if this requirement was met after-the-fact.)	Inspection	Design
102	Each flat cable connector shall be designed for use with 26 AWG cable; shall have dual cantilevered phosphor bronze contacts plated with 0.00015 inches of gold over 0.00005 inches of nickel; and shall have a current rating of 1 Ampere minimum and an insulation resistance of 5 Megohms minimum.	3.2.16 Connectors			Inspection Performance Test	Design
103	Each PCB header post shall be 0.025 inches square by 0.3425 inches high from the plane of the PCB to the end of the pin; shall be mounted on 0.10 inch centers; and shall be tempered hard brass plated with 0.00015 inches of gold over 0.00005 inches of nickel.	3.2.16 Connectors			Inspection	Design
104	Each PCB header socket block shall be nylon or diallyl phthalate.	3.2.16 Connectors			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
105	Each PCB header socket contact shall be removable, but crimp-connected to its conductor.	3.2.16 Connectors			Inspection	Design
107	Each PCB header socket contact shall be brass or phosphor bronze plated with 0.0015 inches of gold over 0.00005 inches of nickel.	3.2.16 Connectors			Inspection	Design
109	All assemblies shall be modular, easily replaceable and incorporate plug-in capability for their associated devices or PCBs.	3.3.1 Assemblies		Words like, "easily replaceable" are subjective and untestable.	Inspection	Design
110	Assemblies shall be provided with two guides for each plug-in PCB or associated device (except relays).	3.3.1 Assemblies			Inspection	Design
111	The guides shall extend to within 0.75 inches from the face of either the socket or connector and front edge of the assembly.	3.3.1 Assemblies			Inspection	Design
112	If Nylon guides are used, the guides shall be securely attached to the file or assembly chassis.	3.3.1 Assemblies			Inspection	Design
113	All screw type fasteners shall utilize locking devices or locking compounds except for finger screws, which shall be captive.	3.3.2 Locking Devices			Inspection	Design
114	No components, traces, brackets or obstructions shall be within 0.125 inches of the board edge (guide edges).	3.3.3 PCB Design and Connectors			Inspection	Design
115	The manufacturer's name or logo, model number, serial number, and circuit issue or revision number shall appear and be readily visible on all PCBs.	3.3.3 PCB Design and Connectors			Inspection	Design
116	The manufacturer's model number and circuit issue or revision number shall appear on the rear panel of all equipment supplied (where such panel exists).	3.3.4 Model and Serial Numbers			Inspection	Design
117	In addition to any assignment of model numbers by the manufacturer, the TYPE number shall be displayed on the front panel in bold type, at least 0.25 inches high.	3.3.4 Model and Serial Numbers			Inspection	Design
121	Workmanship shall conform to the requirements of this specification and be in accordance with the highest industry standards.	3.3.5 Workmanship			Drop from the standard.	Design
122	The following tolerances shall apply, except as specifically shown on the plans or in these specifications:	3.3.6 Tolerances			Inspection	Design
	TYPE DIMENSIONAL TOLERANCE					
	Sheet Metal +/-0.0525 inch					
	PCB +0 inch, - 0.010 inch					
	Edge Guides +/-0.015 inch					
	*Note: These dimensional tolerances do not apply to material gauge or thickness.					

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
123	The equipment shall be engineered for simplicity, ease of operation and maintenance.	3.4.1 Human Engineering			Drop from the standard.	Design
125	PCBs shall slide smoothly in their guides while being inserted into or removed from the frame and shall fit snugly into the plug-in PCB connectors.	3.4.1 Human Engineering			Inspection	Design
126	PCBs shall require a force no less than 5 pounds-force or greater than 50 pounds-force for insertion or removal.	3.4.1 Human Engineering			Analysis	Design
127	The design shall be inherently temperature compensated to prevent abnormal operation.	3.4.2 Design Engineering		What does "inherently temperature compensated" mean?	Analysis	Design
				I think their try to refer to using natural convection for cooling rather than using a fan since a fan is not fail-safe. The standard should say that more clearly.		
128	The circuit design shall include such compensation as is necessary to overcome adverse effects due to temperature in the specified environmental range.	3.4.2 Design Engineering			Analysis	Design
129	The design shall take into consideration the protection of personnel from all dangerous voltages.	3.4.2 Design Engineering		What does "take into consideration" mean and how is it verified?	Drop from the standard.	Design
131	No item, component or subassembly shall emit a noise level sufficient to interfere with processing and communication functions of the controller circuits.	3.4.3 Generated Noise		What noise level is "sufficient to interfere" exactly? No pass/fail criteria anyway.	Performance Test	Design
133	PCB design shall be such that when a component is removed and replaced, no damage is done to the board, other components, conductive traces or tracks.	3.5.1 Design, Fabrication, and Mounting		140 puss/full effectia ally way.	Performance Test	Design
136	Inter-component wiring shall be by laminated copper clad track having a minimum weight of 0.2 ounces per square foot with adequate cross section for current to be carried.	3.5.1 Design, Fabrication, and Mounting			Inspection	Design
137	All copper tracks shall be plated or soldered to provide complete coverage of all exposed copper tracks.	3.5.1 Design, Fabrication, and Mounting			Inspection	Design
138	Jumper wires to external PCB components shall be from plated-through padded holes and as short as possible.	3.5.1 Design, Fabrication, and Mounting		"As short as possible" is a nebulous requirement.	Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
144	Semiconductor devices that dissipate more than 250 milliwatts or cause a temperature rise of 10 degrees C or more shall be mounted with spacers, transipads or heat sinks to prevent contact with the PCB.	3.5.1 Design, Fabrication, and Mounting			Analysis	Design
145	When completed, all residual flux shall be removed from the PCB.	3.5.1 Design, Fabrication, and Mounting		This is okay, but should be worded differently. This reads like a manufacturing step. Maybe it should just say that the PCB shall be free of all residual flux.	Inspection	Design
146	The resistance between any two isolated, independent conductor paths shall be at least 100 Megohms when a 500 VDC potential is applied.	3.5.1 Design, Fabrication, and Mounting		Wouldn't the 100 Mohms would be 100 Mohms regardless of the VDC applied. What is the point of specifying 500 VDC? Should the VDC specification be removed? It makes testing a lot more difficult and possibly destructive.	Performance Test	Design
148	Where less than 0.25 inches lateral separation is provided between the PCB (or the components of a PCB) and any metal surface, a 0.0625 inches (+/-0.0005 inches) Thick Mylar (polyester) plastic cover shall be provided on the metal to protect the PCB.	3.5.1 Design, Fabrication, and Mounting			Inspection	Design
149	Each PCB connector edge shall be chamfered at 30 degrees from board side planes.	3.5.1 Design, Fabrication, and Mounting			Inspection	Design
150	The key slots shall also be chamfered so that the connector keys are not extracted upon removal of board or jammed upon insertion.	3.5.1 Design, Fabrication, and Mounting			Inspection	Design
151	The key slots shall be 0.045 inches (+/- 0.005 inches) for 0.1 inches spacing and 0.055 inches (+/- 0.005 inches) for 0.156 inches spacing.	3.5.1 Design, Fabrication, and Mounting			Inspection	Design
152	Hand soldering shall comply with Military Specification MIL-STD-2000.	3.5.2 Soldering		Need to dig up this specification.	Inspection	Design
156	Wherever clinching is not used, a method of holding the components in the proper position for the flow process shall be provided.	3.5.2 Soldering		This requirement cannot be verified after-the-fact.	Inspection	Design
157	If exposure to the temperature bath is of such a time-temperature duration, as to come within 80% of any component's maximum specified time-temperature exposure, that component shall be hand soldered to the PCB after the flow process has been completed.	3.5.2 Soldering		This is a manufacturing process requirement rather than a design requirement.	Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
158	Definitions for the purpose of this section on PCBs shall be taken from MIL-P-55110D Section 3.3 and any current addendum.	3.5.3 Definitions		Need to dig up this specification.	Inspection	Design
50	The auxiliary switches shall "open" when the load breaker has tripped and the system will transfer the power from the Main Contactor to the Flash or Blank condition.	3.2.9 Circuit Breakers	n/a	This is a cabinet specification and should not be in this standard.	Performance Test	Performance
52	Fuses shall be easily accessible and removable without use of tools.	3.2.10 Fuses	P	Words such as, "easily accessible" are not of value in a standard, since they can neither be defined nor measured.	Inspection	Performance
65	For field termination, screw lug and cam driven assemblies are interchangeable for field wiring termination, provided they both accommodate 22-gauge wire on the inputs and 22-gauge wire on	3.2.13 Screw Lug and Cam Driven	n/a	Can the 22-gauge specification be expressed in terms of performance?	Inspection	Performance
	the outputs.	Connectors age 3.2.14 Wiring Cabling		Note: It is not clear that this clause is applicable.		
71	Wiring containing AC shall be bundled separately or shielded separately from all DC logic voltage control circuits.	3.2.14 Wiring, Cabling, and Harnesses	P		Inspection	Performance
79	Conductor color identification shall be as follows: AC- circuits - white Equip. Ground - solid green or continuous green color with 1 or more yellow stripes. DC logic ground - continuous white with a red stripe. AC+ circuits - continuous black or black with colored stripe. DC logic ungrounded or signal - any color not specified.	3.2.14 Wiring, Cabling, and Harnesses	P/F	The standard is apparently using a US convention, but the AC power cord on the Eagle 2070L that we examined did not exhibit US standard and seems to meet European color coding schemes.	Inspection	Performance
81	All indicators and character displays shall have a minimum 90 degrees cone of visibility with its axis perpendicular to the panel on which the indicator is mounted.	3.2.15 Indicators and Character Displays	F	The Eagle 2070 we examined did not meet this requirement. It is likely that this specification is too strenuous anyway. It might be that this requirement should be split for indicators and displays.	Performance Test	Performance
84	Each LED indicator shall be white or clear when off.	3.2.15 Indicators and Character Displays	P		Inspection	Performance
88	Connectors shall be keyed to prevent improper insertion of the wrong connector where equipment damage or operator injury may result.	3.2.16 Connectors	P	On the Eagle 2070, nothing is keyed, but you can't break anything or get hurt, so it meets the standard.	Inspection	Performance

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
118	A permanent label shall be affixed to the inside near and center floor of the Type 2070 unit chassis when viewed from the front.	3.3.4 Model and Serial Numbers	P	Might this requirement be better communicated by including a font size?	Inspection	Performance
119	The label shall display the unit's serial number.	3.3.4 Model and Serial Numbers			Inspection	Performance
120	The number shall be permanent and easy to read.	3.3.4 Model and Serial Numbers	P	Words like "easy to read" are undefined and as such, un-testable.	Inspection	Performance
124	Knobs shall be a minimum of 0.5 inches in diameter and a minimum separation of 0.5 inches edge to edge.	3.4.1 Human Engineering	P		Inspection	Performance
130	No item, component or subassembly shall emit an audible noise level exceeding the peak level of 55 dBa when measured at a distance of one meter away from its surface, except as otherwise noted.	3.4.3 Generated Noise	P	Tested with a sound meter obtained from Siemens.	Performance Test	Performance
2	Sheet shall be 63 gauge American Standard (0.060-inch) minimum thick Type 3003-H14 or Type 5052-H32 ASTM Designation B209 aluminum alloy. Rod, Bar and Extruded shall be Type 6061-T6, or equal.	3.1.6 Metals		This appears to be a manufacturing or manufacturer specification. What specific, measurable, performance standard is met by using a particular thickness or type of material?	Inspection	Procurement
3	Sheet shall be annealed or one-quarter-hard complying with the ASTM Designation: A666 for Type 304, Grades A or B, stainless steel sheet.	3.1.6 Metals			Inspection?	Procurement
4	Sheet, Rod, Bar and Extruded shall be Type 1018/1020.	3.1.6 Metals		What performance requirement is addressed by this standard?	Inspection?	Procurement
5	All cold roll steel shall be plated. All plating shall be either cadmium plating meeting the requirements of Federal Specification QQ-P-416C, Type 2 Class l or zinc plating meeting the requirements of ASTM B633-85 Type II SC4.	3.1.6 Metals		Need to dig up this specification.	Inspection	Procurement
6	All bolts, nuts, washers, screws, hinges and hinge pins shall be stainless steel unless otherwise specified.	3.1.6 Metals			Inspection	Procurement
12	All components shall be second sourced and shall be of such design, fabrication, nomenclature or other identification as to be purchased from a wholesale distributor or from the component manufacturer, except as follows:	3.2.1 Components – General		Manufacturing and/or supply chain specification. What performance requirement is addressed by this standard?	Inspection	Procurement
13	When a component is of such special design that it precludes the purchase of identical components from any wholesale distributor or component manufacturer, one spare duplicate component shall be furnished with each 20, or fraction thereof, components used.	3.2.1 Components – General		This is a procurement requirement and has nothing to do with a design standard.	Drop from the standard.	Procurement

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
18	No component shall be provided where the manufactured date is three years older than the contract award date.	3.2.2 Components – Electronic			Analysis	Procurement
22	The Manufacturer shall submit detailed engineering technical data on all components at the request of the AGENCY.	3.2.2 Components – Electronic		This specifies a documentation task for the manufacturer that has no affect on the cabinet design.	Analysis	Procurement
23	The Manufacturer shall certify that the component application meets the requirements of this standard.	3.2.2 Components – Electronic		Procurement requirement.	Analysis	Procurement
27	Potentiometers with ratings from 1 to 2 watts shall meet Military Type RV4 requirements.	3.2.4 Potentiometers		Need to dig up this specification.	Analysis	Procurement
30	Fixed carbon film, deposited carbon, or composition insulated resistors shall conform to the performance requirements of Military Specifications MIL-R-11F or MIL-R-22684.	3.2.5 Resistors		Need to dig up this specification.	Inspection	Procurement
33	The value of the resistors shall not vary by more than 5% between -37 degrees C and 74 degrees C.	3.2.5 Resistors			Analysis	Procurement
36	All transistors, integrated circuits, and diodes shall be a standard type listed by EIA and clearly identifiable.	3.2.6 Semiconductor Devices		Need to dig up this specification.	Inspection	Procurement
39	All power transformers and inductors shall have the manufacturer's name or logo and part number clearly and legibly printed on the case or lamination.	3.2.7 Transformers and Inductors			Inspection	Procurement
40	All transformers and inductors shall have their windings insulated, shall be protected to exclude moisture, and their leads color coded with an approved EIA color code or identified in a manner to facilitate proper installation.	3.2.7 Transformers and Inductors		Need to dig up this specification.	Inspection	Procurement
42	Circuit breakers shall be listed by UL or ETL.	3.2.9 Circuit Breakers			Inspection	Procurement
43	The trip and frame sizes shall be plainly marked (marked on the breaker by the manufacturer), and the ampere rating shall be visible from the front of the breaker.	3.2.9 Circuit Breakers			Inspection	Procurement
48	Circuit breakers shall be the trip-free type with medium trip delay characteristic (Carlingswitch Time Delay Curve #24 or equal).	3.2.9 Circuit Breakers		Need to dig up this specification.	Analysis	Procurement
53	Dual-inline-package, quick snap switches shall be rated for a minimum of 30,000 operations per position at 50 milliamperes, 30 VDC.	3.2.11 Switches			Inspection	Procurement
55	The contacts shall be gold over brass.	3.2.11 Switches			Inspection	Procurement
56	The switch contacts shall be rated for a minimum of 1 ampere resistive load at 120 VAC and shall be silver over brass (or equal).	3.2.11 Switches			Inspection	Procurement
57	The switch shall be rated for a minimum of 40,000 operations.	3.2.11 Switches			Inspection	Procurement

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
58	The switch contacts shall be rated for a minimum of 5 amperes resistive load at 120 VAC or 28 VDC and shall be silver over brass (or equal).	3.2.11 Switches			Inspection	Procurement
59	The switch shall be rated for a minimum of 40,000 operations.	3.2.11 Switches			Inspection	Procurement
60	Ratings shall be the same as CONTROL, except the contact rating shall be a minimum of 10 amperes at 125 VAC.	3.2.11 Switches			Inspection	Procurement
61	The terminal blocks shall be barrier type, rated at 20 amperes and 600 VAC RMS minimum.	3.2.12 Terminal Blocks			Inspection	Procurement
62	The terminal screws shall be 0.3125 inches minimum length nickel plated brass binder head type with screw inserts of the same material.	3.2.12 Terminal Blocks			Inspection	Procurement
76	All conductors shall conform to MIL-W-16878E/1 or better and shall have a minimum of 19 strands of copper.	3.2.14 Wiring, Cabling, and Harnesses		Need to dig up these specifications.	Inspection	Procurement
78	Where insulation thickness is 15 mils or less, the conductor shall conform to MIL-W-16878/17.	3.2.14 Wiring, Cabling, and Harnesses		Why is insulation less than 15 mils allowed?	Inspection	Procurement
83	All indicators shall have a rated life of 100,000 hours minimum.	3.2.15 Indicators and Character Displays			Inspection	Procurement
90	Type T connector shall be a single row, 10 position, feed through terminal block.	3.2.16 Connectors			Inspection	Procurement
95	All pin and socket connectors shall use the AMP #601105-1 or #91002-1 contact insertion tool and the AMP #305183 contact extraction tool.	3.2.16 Connectors		Are they actually specifying a particular tool to be used for assembly? This is an assembly procedure not a design requirement.	Inspection	Procurement
0.5				Why is a specific tool specified?		_
96	Edge connectors shall have bifurcated gold-plated contacts.	3.2.16 Connectors			Inspection	Procurement
97	The PCB receptacle connector shall meet or exceed the following:	3.2.16 Connectors			Performance Test	Procurement
	Operating Voltage: 600 VAC (RMS)					
	Current Rating: 5.0 Amperes					
	Insulation Material: Diallyl Phthalate or Thermoplastic					
	Insulation Resistance: 5,000 Megohms					
	Contact Material: Copper alloy plated with 0.00005 inches of nickel and 0.000015 inches of gold					
	Contact Resistance: 0.006 Ohm maximum					
98	The two-piece PCB connector shall meet or exceed the DIN 41612.	3.2.16 Connectors		Need to dig up this specification.	Inspection	Procurement

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
100	Each wire terminal shall be solderless with PVC insulation and a heavy duty short - locking spade type connector.	3.2.16 Connectors		The type of crimping tool is an assembly procedure, not a design requirement. The crimping tool is specified due to the likelihood that improper crimps will result in poor connections. It could possibly be specified in a more direct manner.	Inspection	Procurement
106	The Manufacturer shall list the part number of the extraction tool recommended by its manufacturer.	3.2.16 Connectors			Inspection	Procurement
108	The surge suppression device shall comply with ANSI/IEEE C62.41 (100 Kilohertz Ring Wave, the 1.2/50 microseconds – 8/20 Combination Wave and the EFT Burst) at voltages and currents specified at "Location Category B2" and at "Test Severity" level III (i.e. up to 4.0 Kilovolts, open-circuit).	3.2.17 Surge Protection Device		Need to dig up this specification.	Inspection	Procurement
132	All contacts on PCBs shall be plated with a minimum thickness of 0.00003 inches gold over a minimum thickness of 0.000075 inches nickel.	3.5.1 Design, Fabrication, and Mounting			Inspection	Procurement
134	Fabrication of PCBs shall be in compliance with Military Specification MIL-P-13949, except as follows:	3.5.1 Design, Fabrication, and Mounting		Need to dig up this specification.	Inspection	Procurement
135	NEMA FR-4 glass cloth base epoxy resin copper clad laminates 0.0625 inches minimum thickness shall be used.	3.5.1 Design, Fabrication, and Mounting			Inspection	Procurement
139	All PCBs shall conform to Section 3.3 of Military Specification MIL-P-13949G. Grade of Pits and Dents shall be of Grade B quality (3.5.1.3) or better.	3.5.1 Design, Fabrication, and Mounting		Need to dig up this specification.	Inspection	Procurement
140	The class of permissible bow or twist shall be Class C (Table V) or better.	3.5.1 Design, Fabrication, and Mounting			Inspection	Procurement
141	The class of permissible warp or twist shall be Class A (Table II) or better.	3.5.1 Design, Fabrication, and Mounting			Inspection	Procurement

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
142	Sections 4.2 through 6.6 of Military Specification MIL-P-13949G (inclusive) shall be omitted except as referenced in previous sections of this specification.	3.5.1 Design, Fabrication, and Mounting		Need to dig up this specification.	Inspection	Procurement
143	The mounting of parts and assemblies on the PCB shall conform to Military Specification MIL-STD-275E, except as follows:	3.5.1 Design, Fabrication, and Mounting		Need to dig up this specification. Something missing?	Inspection	Procurement
147	All PCBs shall be coated with a moisture resistant coating.	3.5.1 Design, Fabrication, and Mounting			Inspection	Procurement
153	Automatic flow soldering shall be a constant speed conveyor system with the conveyor speed set at optimum to minimize solder peaks or points.	3.5.2 Soldering		This is a manufacturing process requirement rather than a design requirement. The soldering process is specified due to the likelihood that poor solder points will result in poor connections. It could possibly be specified in a more direct manner. The quality of the solder points is not directly testable. As such, determining if this standard has been met becomes an exercise in verifying the performance of the board supplier. Is the quality of the vendor an item for a standard?	Inspection	Procurement
154	Temperature [during soldering] shall be controlled to within +/- 8 degrees C of the optimum temperature.	3.5.2 Soldering		This requirement cannot be verified after-the-fact.	Inspection	Procurement
155	The soldering process shall result in the complete coverage of all copper runs, joints and terminals with solder except that which is covered by an electroplating process.	3.5.2 Soldering			Inspection	Procurement
159	Jumpers are not allowed unless called out in the specifications or approved by the AGENCY.	3.5.4 Jumpers			Drop from the standard.	Procurement

B.2 ATC Type 2070 Controller Requirements

#	Requirement (Standa	rd Document Sectio	n)			Document Section	Pass Fail	Comments	Test Type	Requirement Type							
162	It is noted that the Pow requirements of the use					4.1.4 Power Fail and Power Restoration Operation		Aside from being poorly-worded, the value of this specification is suspect. Was it found that most developers of type 2070 controllers were supplying units that had power failure restoration operation that was different than the user required? If not, why specify this?	Analysis	Design							
163	2070 UNIT module / assembly power limitations shall be as follows:					4.1.5 Power Limitations		Given the rigor of these requirements, it would be expected	Inspection	Design							
	Types	+5VDC	+12VDC ISO	+12VDC ser	-12 VDC ser			that each device noted could be		!							
	МСВ	750 milliamperes					measured for adherence to the specification. However, how is one to test a limitation in a non-destructive manner?										
	TRANS BD	750 milliamperes															
	2070-2A FI/O	250 milliamperes	750 milliamperes														
	2070-2B FI/O	250 milliamperes	500 milliamperes														
	2070-3A&B FPA	500 milliamperes		50 milliamperes	50 milliamperes												
	2070-3C FPA	100 milliamperes		50 milliamperes	50 milliamperes												
	2070-5 VME Cage	5.0 amperes		200 milliamperes	200 milliamperes												
	2070-6 All Comm	500 milliamperes		100 milliamperes	100 milliamperes												
	2070-7 All Comm	250 milliamperes		50 milliamperes	50 milliamperes												

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
164	All circuitry associated with the EIA-485 Communications links shall be capable of reliably passing a minimum of 1.0 megabits per second. Isolation circuitry shall be by opto- or capacitive-coupled isolation technologies.	4.1.6 EIA-485 Communications Circuitry			Inspection Performance Test	Design
165	Through-hole EIA-485 Line Drivers/Receivers, when used, shall be socket mounted.	4.1.7 EIA-485 Line Drivers/Receiver			Inspection	Design
166	Surface mounted drivers/receiver shall be acceptable.	4.1.7 EIA-485 Line Drivers/Receiver		If surface mounted drivers are acceptable, why are socket mounted drivers specified? Worthless requirement, as currently worded.	Inspection	Design
168	A 100-Ohm Termination Resistor shall be provided across each Differential Line Receiver Input.	4.1.7 EIA-485 Line Drivers/Receiver			Inspection	Design
173	Sockets for devices (called out to be socket mounted) shall be "xx" pin AUGAT 500/800 series AG10DPC or equal.	4.1.8 Sockets		Manufacturing specification.	Inspection	Design
174	SP5and SP3 SDLC frame address assignments (Command/Response) are as follows: \[\begin{array}{c ccccccccccccccccccccccccccccccccccc	4.1.9 SDLC			Performance Test	Design
167	EIA-485 Line Drivers/Receivers shall not draw more than 35 milliamperes in active state and 20 milliamperes in inactive state per channel.	4.1.7 EIA-485 Line Drivers/Receiver			Analysis	Design
169	The MOTHERBOARD's control signals (e.g., SP1-RTS) shall be active, or asserted, when the positive terminal (e.g., SP1-RTS+) is a lower voltage than its corresponding negative terminal (e.g., SP1-RTS-).	4.1.7 EIA-485 Line Drivers/Receiver			Performance Test	Design
170	A control signal is inactive when its positive terminal voltage is higher than its negative terminal.	4.1.7 EIA-485 Line Drivers/Receiver	P		Performance Test	Performance
171	Receive and transmit data signals shall be read as a "1" when the positive terminal's (e.g., SP1-TXD+) voltage is higher than its corresponding negative terminal (e.g., SP1-TXD-).	4.1.7 EIA-485 Line Drivers/Receiver	P		Performance Test	Performance

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
172	A data value is "0" when its positive terminal's (e.g., SP1-TXD+) voltage is lower than its negative terminal (e.g., SP1-TXD-).	4.1.7 EIA-485 Line Drivers/Receiver	Р		Performance Test	Performance
160	The composition weight shall not exceed 25 pounds.	4.1.2 General – Unit Configurations		This requirement could refer to road-side constraints, but it still seems odd.	Inspection	Procurement
161	The CHASSIS Top and Bottom, Internal Structure Supports, Back Plane Mounting Surface, Module Plates, Power Supply Enclosure, and Front Panel shall be made of 63 gauge minimum aluminum sheet. The CHASSIS Side panels shall be 80 gauge minimum sheet.	4.1.3 Metalwork		This appears to be a manufacturing or manufacturer specification. What specific, measurable, performance standard is met by using a particular thickness or type of material?	Inspection	Procurement

B.3 ATC Type 2070 CPU Requirements

#	Requirement (Standard Document Section)	Document Section Pass Fail	Comments	Test Type	Requirement Type
177	The module shall meet all the requirements listed under this section and Chapter Details 4.7 except for the following:	4.2.1 Type 2070 – 1B Configuration	From the wording of the sections following, this is very confusing. The words, "except as specified below" are much clearer.	Inspection	Design
178	The VME software and hardware bus requirements shall not apply nor do the MCB and Board Interface Harness physical requirements.	4.2.1 Type 2070 – 1B Configuration		Inspection	Design
179	A Dual SCC Device (asynch/synch) and associated circuitry shall be furnished to provide two additional system serial ports.	4.2.1 Type 2070 – 1B Configuration		Inspection	Design
180	The Dual SCC1 shall be assigned to the System Serial Port SP1 meeting all requirements called out for SP1.	4.2.1 Type 2070 – 1B Configuration		Inspection	Design
181	The Dual SCC2 shall be assigned as System Serial Port SP8.	4.2.1 Type 2070 – 1B Configuration		Analysis	Design
182	The SP8 and associated circuitry shall interface with the MC68360 address and data structure and serially be connected to the external world via the DB 25 Pin C13S Connector located on the module front panel.	4.2.1 Type 2070 – 1B Configuration		Inspection	Design
183	The SP8 shall meet all SP2 Port requirements including EIA 485 Drivers / receivers and synchronous data rate of 614.4 kilobits per second.	4.2.1 Type 2070 – 1B Configuration		Inspection Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
184	The 68360 SCC1 shall be reassigned to ETHERNET (ENET) Network meeting ETHERNET 10 MBPS IEEE 802.3 (TP) 10 BASE T Standard Requirements, both hardware and software.	4.2.1 Type 2070 – 1B Configuration			Analysis	Design
185	The four network lines shall be used to route ETHERNET across the MOTHERBOARD to the "A" Connectors.	4.2.1 Type 2070 – 1B Configuration			Inspection	Design
186	DC Grounding plane around the network connectors and lines shall be provided.	4.2.1 Type 2070 – 1B Configuration			Inspection	Design
187	Network Lines shall be assigned as: Network 1 = ENET TX+, Network 2 = ENET TX-, Network 3 = ENET RX+, and Network 4 = ENET RX	4.2.1 Type 2070 – 1B Configuration			Inspection	Design
188	The conditioned ETHERNET shall be brought out on RJ 45 C14S Connector mounted on the CPU-1B Front Panel.	4.2.1 Type 2070 – 1B Configuration			Inspection	Design
191	The MCB shall be a 3U VME bus compliant board and contain a system controller, an A24-D16 interface, a Master & Slave bus interface, a Multilevel VMEbus Arbiter, a FAIR VMEbus Requester, a system clock driver, and BTO (64).	4.2.3 Main Controller Board (MCB)			Inspection	Design
192	The CONTROLLER Device shall be a Motorola MC68360 or equal, clocked at 24.576 MHz minimum.	4.2.3 Main Controller Board (MCB)			Inspection	Design
193	The Fast IRQ Service System is reserved for AGENCY use only.	4.2.3 Main Controller Board (MCB)			Cannot be verified.	Design
194	The Interrupts shall be configured as follows: Level 7 –VMEbus IRQ7 Level 6 –VMEbus IRQ6 ACFAIL Level 5 – VMEbus IRQ5 CPU Module Counters / Time vectored), Serial Interface Interrupts Level 4 –VMEbus IRQ4 Level 3 –VMEbus IRQ3 Level 2 –VMEbus IRQ2 Level 1 –VMEbus IRQ1 The Memory Address Organization shall be configured as follows:	4.2.3 Main Controller Board (MCB) 4.2.3 Main Controller			Analysis	Design Design
173	8000 0000 – 80FF FFFF STANDARD 9000 0000 – 9000 FFFF SHORT	Board (MCB)			1 11111 y 515	Design
196	16 megabytes of contiguous address space for each specified memory (DRAM, SRAM and FLASH) shall be allocated on an even boundary.	4.2.3 Main Controller Board (MCB)			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
197	The SRAM and FLASH memories shall be accessed through the OS-9 Operating System's File Manager, or approved equivalent.	4.2.3 Main Controller Board (MCB)			Analysis	Design
198	The address of each memory block shall be specified by the manufacturer and provided with the documentation.	4.2.3 Main Controller Board (MCB)			Inspection	Design
199	When the incoming +5 VDC falls below its operating level, the SRAM shall drop to its standby state; and the SRAM and TOD Clock shall shift to the +5 VDC Standby Power.	4.2.3 Main Controller Board (MCB)			Performance Test	Design
200	[After the switch to Standby Power] An on-board circuit shall sense the +5 VDC Standby Power and shift to an On-board CPU Power Source.	4.2.3 Main Controller Board (MCB)			Performance Test	Design
201	When the incoming +5 VDC rises to within its operating level, the appropriate MCB Circuitry shall shift from standby power to incoming +5 VDC.	4.2.3 Main Controller Board (MCB)		What is meant by "the appropriate MCB Circuitry"?	Performance Test	Design
				No one in the room knew what "appropriate" referred to.		
202	A minimum of 8 megabytes of DRAM Memory, organized in 32-bit words, shall be provided.	4.2.3 Main Controller Board (MCB)			Inspection	Design
203	A minimum of 1 megabyte of SRAM is required, of which 512 KiloBytes minimum shall be available for Agency use as a RAM drive (R0).	4.2.3 Main Controller Board (MCB)			Inspection	Design
204	The time from the presentation of valid RAM address, select lines, and data lines to the RAM device to the acceptance of data by the RAM device shall not exceed 80 nanoseconds and shall be less as required to fulfill zero wait state RAM device write access under all operational conditions.	4.2.3 Main Controller Board (MCB)			Inspection Performance Test	Design
205	A minimum of 8 megabytes of FLASH Memory, organized in 16- or 32-bit words, shall be provided.	4.2.3 Main Controller Board (MCB)			Inspection	Design
206	The MCB shall be equipped with all necessary circuitry for writing to the FLASH Memory under program control.	4.2.3 Main Controller Board (MCB)		Why would the MCB not be equipped to accomplish such a standard function?	Drop from the standard.	Design
207	No more than 1 megabyte of FLASH Memory shall be used for Boot Image (List) and a minimum of 7 megabytes shall be available for AGENCY use.	4.2.3 Main Controller Board (MCB)			Inspection	Design
208	Flash Memory shall have a minimum rated capacity of 100,000 read/write cycles and be industrial grade or better.	4.2.3 Main Controller Board (MCB)			Performance Test	Design
209	A software settable hardware Time-of-Day (TOD) clock shall be provided.	4.2.3 Main Controller Board (MCB)			Inspection	Design
210	It [the software settable clock] shall, under on-board standby power, maintain an accuracy of +/-1 minute per 30 days at 25 degrees C (77 degrees F).	4.2.3 Main Controller Board (MCB)			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
211	The clock shall be aligned to a minimum fractional second resolution of 10 milliseconds and shall track seconds, minutes, hours, day of month, month, and year.	4.2.3 Main Controller Board (MCB)			Inspection	Design
212	A software-driven CPU RESET signal (Active LOW) shall be provided to reset other controller systems.	4.2.3 Main Controller Board (MCB)			Performance Test	Design
213	The signal output shall be driver capable of sinking 30 milliamperes at 30 VDC.	4.2.3 Main Controller Board (MCB)			Performance Test	Design
214	Execution of the program module "CPURESET" in the boot image shall assert the CPU RESET signal once.	4.2.3 Main Controller Board (MCB)			Performance Test	Design
215	An open-collector output, capable of sinking 30 milliamperes at 30 VDC, shall be provided to drive the Front Panel Assembly CPU Activity LED INDICATOR.	4.2.3 Main Controller Board (MCB)			Inspection	Design
216	The OS-9 Operating System TICK Timer shall be derived from each transition of LINESYNC with a tick rate of 120 ticks per second.	4.2.3 Main Controller Board (MCB)			Analysis Performance Test	Design
217	The SRAM and TOD Clock Circuitry, under Standby mode, shall draw no more than 8 microamperes at 2.5 VDC and 35 degrees C.	4.2.3 Main Controller Board (MCB)			Performance Test	Design
218	An On-board Capacitor supply shall hold up SRAM and TOD or a minimum of 7 days.	4.2.3 Main Controller Board (MCB)			Performance Test	Design
219	The Transition Board shall provide a 1 KiloOhm pull-up resistor for the A2 & A3 installed lines.	4.2.4 Transition Board			Inspection	Design
220	If the DC Ground is not present (slot not occupied) at the CPU EIA-485 line drivers/receivers, the drivers/receivers shall be disabled (inactive).	4.2.4 Transition Board			Performance Test	Design
221	A SHIELDED INTERFACE HARNESS shall be provided. It shall include MCB and Transition Board connectors with strain relief, lock latch, mating connectors, and harness conductors.	4.2.5 Shielded Interface Harness			Inspection	Design
222	A minimum of 25 mm of slack shall be provided.	4.2.5 Shielded Interface Harness			Inspection	Design
223	No power shall be routed through the harness.	4.2.5 Shielded Interface Harness			Inspection	Design
224	The harness shall be 100% covered by an aluminum mylar foil and an extruded black 0.8 mm PVC jacket or equal.	4.2.5 Shielded Interface Harness			Inspection	Design
226	Power shall not be applied to the receptacle if the key is not present.	4.2.6 Datakey			Performance Test	Design
228	The Datakey shall be temperature rated for -40 to +80 degrees C operation.	4.2.6 Datakey			Inspection	Design
229	The Datakey shall be black in color.	4.2.6 Datakey			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
230	The Datakey shall be initialized to the format and default values defined below.	4.2.6 Datakey			Inspection	Design
233	The data format in the CPU Datakey header for the Latitude and Longitude fields shall comply with IEEE/ANSI 754-1985 STD.	4.2.6 Datakey			Inspection	Design
234	All the other fields shall follow a Big Endian Format as implemented by Motorola CPUs.	4.2.6 Datakey			Inspection	Design
238	Supplied modules shall be re-entrant, address independent, and shall not contain self-modifying code.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis Inspection	Design
239	Device drivers which require extensions to the standard OS-9 libraries shall use the _os_getstat() and _os_setstat() functions.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis Inspection	Design
240	When PB2070.param2.pointer is used, PB2070.param1 should be loaded with the size of what PB2070.param2.pointer is referencing.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis Inspection	Design
241	When calling _os_getstat() or _os_setstat(), all reserved or unused parameters and fields in PB2070 should be loaded with 0 (zero).	4.2.7 CPU Module Software – Drivers and Descriptors		What purpose does the sample code in the standard serve?	Analysis	Design
244	Access to the MC68360 internal timers shall be provided through the following device descriptors: Descriptor names for each timer: timer1 = access to MC68360's internal timer #1 timer2 = access to MC68360's internal timer #2 timer3 = access to MC68360's internal timer #3 timer4 = access to MC68360's internal timer #4 timer12 = access to MC68360's internal timer #1 & #2 (cascaded) timer34 = access to MC68360's internal timer #3 & #4 (cascaded)	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
246	Timer Standard OS-9 Function Calls: error_code _os_open (char *timer_desc_name, path_id *path); error_code _os_read (path_id path, void *timer_value, u_int32 *size); Note: Prior to calling _os_read(), size must be loaded with the value 4 and timer value must be pointed to a u_int32os_read() shall read the current timer value and load it into timer_value as μS x 100. error_code _os_close (path_id path).	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
247	Timer Extension to Standard OS-9 Function Calls: error_code _os_setstat(path_id path, SS_2070, PB2070 *pb)	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
248	The timer drivers shall support the following modes using the SS_2070 _os_setstat() option code and a custom parameter block structure:	4.2.7 CPU Module Software – Drivers and Descriptors				Design
249	 a) Send signal after specified time interval. Sets timer to zero and schedules individual one-shot signal. Pb→code = SS2070_Timer_Sig (0x1000); /* request for one-shot signal */ pb.param1 = signal; /* signal code to send (0 = do not send a signal and cancel any pending signals) */" pb→param2.param = period; /* timer period in microseconds x 100 */ 	4.2.7 CPU Module Software – Drivers and Descriptors		This appears to be a code sample. Why is this in a standard?	Analysis	Design
250	 b) Send recurring periodic signal. Sets timer to zero and schedules repeating periodic signal. Pb→code = SS2070_Timer_Cyc (0x1001); /* request for periodic signal */ pb.param1 = signal; /* signal code to send (0 = do not send a signal and cancel any pending signals) */" pb→param2.param = period; /* timer period in microseconds x 100 */ 	4.2.7 CPU Module Software – Drivers and Descriptors		This appears to be a code sample. Why is this in a standard?	Analysis	Design
251	c) Start timer. Start the timer if stopped. Timer will free run in a periodic mode, starting at the current timer value as its initial value and timer's maximum allowable time as its timer period (6.5535 seconds for timers 1-4 and 429496.7295 seconds for timers 12 and 34). Timer will not send a signal and any pending signals will be cancelled. Timer mode will be SS2070_Timer_Start. Pb.code = SS2070_Timer_Start (0x1002); /* start timer if stopped */"	4.2.7 CPU Module Software – Drivers and Descriptors		This appears to be a code sample. Why is this in a standard?	Analysis	Design
252	d) Stop timer. Leaves current value in timer. Cancels any pending signals. Pb→code = SS2070_Timer_Stop (0x1003); /* stop timer if running */	4.2.7 CPU Module Software – Drivers and Descriptors		This appears to be a code sample. Why is this in a standard?	Analysis	Design
253	 e) Reset timer. Stops timer if running, resets timer value to zero, and cancels any pending signals. Pb→code = SS2070 Timer Reset (0x1004); /* reset timer (stop and zero) */ 	4.2.7 CPU Module Software – Drivers and Descriptors		This appears to be a code sample. Why is this in a standard?	Analysis	Design
254	Timer Extension to Standard OS-9 Function Calls: error_code _os_getstat(path_id path, SS_2070, PB2070 *pb)	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design

#	Requirement (Standard Docume	nt Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
255	The timer driver will support the for and custom parameter block structu	ollowing function using the SS_2070 _os_getstat() option code are:	4.2.7 CPU Module Software – Drivers and Descriptors				Design
256	pb→param1 = sizeof(Timer_s pb→param2.pointer = Timer_s	x1C) /* Request timer status data */ tatus)	4.2.7 CPU Module Software – Drivers and Descriptors		This appears to be a code sample, as well as some specific coding techniques. Why is this in a standard?	Analysis	Design
	pb→param2.pointer→period	/* timer period in microseconds x 100 if SS2070_Timer_Sig or SS2070 Timer Cyc, 0 otherwise */					
257	All timer periods are specified in u microseconds.	nits of hundreds of microseconds, i.e. a timer period of $7 = 700$	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
258	The minimum allowed timer period shall be 500 microseconds.	4.2.7 CPU Module Software – Drivers and Descriptors		What does this have to do with a standard? Why is this specified?	Analysis	Design
259	The maximum timer period for timers 1-4 shall be 6.5535 seconds (0xFFFF).	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
260	The maximum timer period for timer12 and timer34 shall be 429496.7295 seconds (0xFFFFFFF).	4.2.7 CPU Module Software – Drivers and Descriptors		What does this have to do with a standard? Why is this specified?	Analysis	Design
261	The driver shall return error E\$Param from _os_setstat() if the requested timer period is outside the allowable range.	4.2.7 CPU Module Software – Drivers and Descriptors		What does this have to do with a standard? Why is this specified?	Performance Test Analysis	Design
262	Access and control to the CPU Datakey shall be provided through the following descriptor name: <u>Descriptor Name</u> datakey = access to the CPU Datakey	4.2.7 CPU Module Software – Drivers and Descriptors		What does this have to do with a standard? Why is this specified?	Inspection	Design
264	Access and control to the CPU Datakey shall be provided through the following functions:	4.2.7 CPU Module Software – Drivers and Descriptors				Design
265	<pre>Function Calls error_code _os_open (char *datakey_desc_name, path_id *path); error_code _os_close (path_id path); error_code _os_read (path_id path, void *data_buffer, u_int32 *data_size); error_code _os_write (path_id path, void *control, u_int32 *data_size); error_code _os_seek(path_id path, u_int32 position); sets read / write offset error_code = _os_ss_erase(path_id path, u_int32 num_sec_erase); /*erases sector(s) if pointer is on a block boundary, returns E\$PARAM error if not on a boundary */" error_code = _os_gs_pos(path_id path, u_int32 *position); /* gets current file pointer position */</pre>	4.2.7 CPU Module Software – Drivers and Descriptors		What does this have to do with a standard? Why is this specified?	Inspection	Design
	error_code = _os_gs_pos(path_id path,u_int32 *position); /* gets current file pointer					

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
266	Error Codes Returned by Function Calls E\$NotRdy if datakey is not inserted E\$Seek if Offset plus *data_size is beyond end of CPU Datakey. E\$EOF if upon read or write, the last byte of CPU Datakey has previously been processed."	4.2.7 CPU Module Software – Drivers and Descriptors		What does this have to do with a standard? Why is this specified?	Inspection	Design
267	Use of SCF to implement the Datakey driver is not allowed.	4.2.7 CPU Module Software – Drivers and Descriptors		What does this have to do with a standard? Why is this specified?	Inspection	Design
268	The asynchronous serial communications device drivers shall support the six flow control modes (FCM#) described below: 0) No Flow Control Mode 1) Manual Flow Control Mode 2) Auto-CTS Flow Control Mode 3) Auto-RTS Flow Control Mode 4) Fully Automatic Flow Control Mode 5) Dynamic Flow Control Mode	4.2.7 CPU Module Software – Drivers and Descriptors		What does CTS stand for? As with other portions of this section of the standard, this seems rather specific for a standard.	Analysis	Design
269	The serial device driver shall be able to set user options via _os_setstat() and return status via _os_getstat().	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
270	To support legacy application programs, the device driver shall also be able to set user options via _os_ss_size() and to return status via _os_gs_size(): error_code_os_setstat(path_id path, SS_2070, void *pb); error_code_os_getstat(path_id path, SS_2070, void *pb); error_code_os_ss_size(path_id path, u_int32 size); error_code_os_gs_size(path_id path, u_int32 *size)	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design

#	Requirem	ent (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
271	The _os_ss	red method of accessing serial device drivers is through _os_setstat() and _os_getstat(). s_size() and _os_gs_size() interface may not be required by future versions of this on and is therefore not recommended for new development.	4.2.7 CPU Module Software – Drivers and Descriptors		What is the value of stating the "preferred" method? The use of the term "may not be required" does not, on the surface, seem to fit with the recommendation against further new development.	Drop from the standard.	Design
272	defined as	subcodes to be passed in pb—code and the data to be contained in pb—param1 are follows. Pb—param2 is unused here and should be set to 0 (zero). For _os_ss_size() s_size(), the size argument is the same format as pb—param1.	4.2.7 CPU Module Software – Drivers and Descriptors		What does this have to do with a standard? Why is this specified?	Analysis	Design
273	The suppor	rted _os_setstat() / _os_ss_size() options shall be as follows:	4.2.7 CPU Module Software – Drivers and Descriptors				Design
274		e passed in pb→code is SS2070_OFC (0x23). sed in pb→param1 is defined as follows: Description	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
275	a) continued. Variable MRBLR (68360 SCC) To reduce the IRQ handler overhead, the 68360 SCC driver shall use variable MRBLR as follows. If SS2070_OFC bit 12 is set to 1, the MRBLR shall be fixed at 16 for all baud rates. Variable MRBLR is not required for SP1 or SP8 on the 2070-1B CPU Module. Baud Rate 1200 1 2400 2 4800 4 9600 8 19200 & Higher 16	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
276	a) continued. TODR (68360 SCC only) TODR requests processing a new TX buffer immediately. To reduce impact on other serial channel operations, SS2070_OFC bit 11 may be set to 1 to prevent assertion of TODR. TODR is not required for SP1 or SP8 on the 2070-1B CPU Module.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
277	b) Subcode passed in pb→code is SS2070_IFC (0x22). Data passed in pb→param1 is defined as follows: Bits Description 31-11 Reserved for Future Use. 10 DCD must be asserted to receive data (default=0; 0=NO; 1=YES). 9-8 Reserved for Future Use. 7-0 Subcode = SS2070 IFC (0x22).	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
278	c) Subcode passed in pb→code is SS2070_Ssig (0x1A). 1. If CTS is currently negated and bits 16 – 31 are not all 0: Setting the SS2070_Ssig parameter block bit 11 (send when CTS is asserted) will cause the controller to send a one-shot signal as soon as CTS is asserted. Setting the SS2070_Ssig parameter block bit 12 (send when CTS is negated) will cause the controller to send a one-shot signal immediately.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
279	c) continued. 2. If CTS is currently asserted and bits 16 – 31 are not all 0:	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
280	c) continued. 3. If both bits 11 and 12 of the SS2070_Ssig parameter block are set, and bits 16 – 31 are not all 0: The controller will send a one-shot signal upon the next change of CTS state. Data passed in pb→param1 is defined as follows: Bits Description 31-16 A signal number to be sent to calling process when the state of an input changes. 15-13 Reserved for Future Use. 12 Send signal when CTS is de-asserted. 11 Send signal when CTS is asserted. 10-8 Reserved for Future Use. 7-0 Subcode = SS2070_Ssig (0x1A).	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
281	The supported _os_getstat()_ / _os_gs_size() options shall be as follows:	4.2.7 CPU Module Software – Drivers and Descriptors				Design
282	a) Subcode passed in pb→code is GS2070_Status (0x1C). Data returned in pb→param1 is defined as follows: Bits Description 31-16 Current unfilled transmit buffer character count of the serial device driver. 15-11 Reserved for Future Use. 10-8 Current Flow Control Mode Number (FCM#). 7 Reserved for Future Use. 6 Overrun error − 0=no error; 1=error has occur since last GS2070_Status call. 5 Frame error − 0=no error; 1=error has occur since last GS2070_Status call. 4 Parity error − 0=no error; 1=error has occur since last GS2070_Status call. 3-2 Reserved for Future Use. 1 DCD state − 0=de-asserted; 1=asserted. 0 CTS state − 0=de-asserted; 1=asserted.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
283	Device drivers compliant with the OS-9 SCFMAN shall be provided for CPU Activity LED Indicator and Day Light Savings time correction features.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
284	The descriptor names shall be as follows: led = access to CPU Activity LED Indicator dstclock = access to Daylight Savings Time Clock correction	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
285	The standard OS-9 SCFMAN library calls and their functions are as follows: error_code _os_open (char *desc_name, path_id	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
286	Leap Year and Daylight Savings Time (DST) Adjustments – The OS-9 System clock / calendar shall automatically be adjusted to account for DST and leap years.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
289	Setting Hardware Clock from OS-9 System Clock – Opening the descriptor shall cause the driver to synchronize the clock to a minimum of 10 milliseconds resolution.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
290	Setting Hardware Clock from OS-9 System Clock – The driver shall compensate for any time elapsed during the process of updating the hardware clock.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
291	Setting OS-9 System Clock from Hardware Clock – At system power up, the OS-9 system TOD clock/calendar shall automatically be updated from the hardware TOD clock.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
292	Setting OS-9 System Clock from Hardware Clock – The clocks shall be synchronized to a minimum of 10 milliseconds resolution.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
293	The current sector of FLASH being written shall first be backed up in SRAM.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
294	The backup sector copy shall be invalidated when FLASH write operation is completed.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
295	In case of power failure, the FLASH driver shall detect the presence of the valid backup sector copy in SRAM and shall read sector data from the valid backup sector copy.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
296	A user write operation shall restore the valid backup sector copy first.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
297	Execution of the program module, "FLRESTORE," in the Boot Image shall also restore the valid backup sector copy to FLASH drive after a specified delay.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
298	"FLRESTORE" shall accept a delay parameter in seconds ranging from 0 to 600 seconds.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
299	The default delay factor is 30 seconds. No more that 150 KB of SRAM shall be dedicated to this purpose.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
300	Power loss or other interruption while writing to the FLASH drive may cause FLASH drive file and/or disk corruption. It is therefore strongly recommended that the FLASH drive be used to hold controller applications only.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
301	MODEL 2070-1A and 2070-1B CPU modules shall include the following set of standard OS-9 networking modules in the operating system boot image, sufficient to support network configuration, startup, and ftp and telnet servers:	4.2.7 CPU Module Software – Drivers and Descriptors		This seems rather specific for a standard. Why is it included?	Inspection	Design
	spip, ip0, sptcp, tcp0 spudp, udp0, spraw, raw0, spenet, enet, netdb (dns version), ipstart, ifconfig, route, ndbmod, ftpd, ftpdc, telnetd, telnetdc, pkman, pkdrvr, pk, pks, ping, dhcp.					
309	Execute permission shall be included in the attributes of all files in the /CMDS directory.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
310	/SYS shall contain a default "password" file following the standard OS-9 password file format.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
311	A username "super" with password "user" shall be defined in the password file.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
318	The modules shall be configured with the network default values as defined in Section 4.2.6 (Datakey).	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
320	The netcfg utility shall also provide command line options to allow the user to write and display the network parameters in the Datakey header, write and display the Startup Override byte in the Datakey header, and copy a script or executable file from disk to the Datakey following the header.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
322	The netcfg utility shall reside in /CMDS.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
323	The PPP and SLIP descriptors shall have baud rates and ports set as follows and shall reside in the /CMDS/BOOTOBJS directory: hdlc0 and spsl0 configured to use /sp1 and 38400 bits per second hdlc1 and spsl1 configured to use /sp2 and 115200 bits per second hdlc2 and spsl2 configured to use /sp3 and 115200 bits per second hdlc3 and spsl3 configured to use /sp4 and 38400 bits per second	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
324	A set of example configuration files consistent with the above networking modules shall be provided in the /ETC directory.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
325	The /ETC directory shall contain the following text files: hosts, hosts.equiv, networks, protocols, services, inetd.conf, resolv.conf, hosts.conf, rpc, interfaces.conf, routes.conf. makefile, nfs.map, nfsd.map	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
326	The provided software shall boot OS-9 from SYSRESET.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
327	The entire program shall be resident in FLASH Memory.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
328	The asynchronous serial port descriptors shall be configured with the following defaults: 8-bit word, 1 stop bit, no parity, no pause, Xon and Xoff both OFF. Port SP4 shall have echo enabled, all other ports shall have no echo.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
329	Default speeds for the asynchronous serial port shall be as defined in Figure 4-7-7.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
330	Hardware initialization, preliminary self-test, OS-9 initialization (except Extended Memory Test), and forking OPEXEC shall be completed in less than 2.0 seconds.	4.2.7 CPU Module Software – Drivers and Descriptors		This requirement seems arbitrary, and unlikely to be verified.	Performance Test	Design
331	The boot image init module shall be configured with the default directory name as /f0wp and sysgo as the first executable module.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
332	In the executable module, sysgo, the backspace command applies to the current line, regardless of auto-wrap or autoscroll.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
333	ACFAIL/POWER DOWN transitions shall generate an interrupt.	4.2.7 CPU Module Software – Drivers and Descriptors			Performance Test	Design
334	The interrupt generated during ACFAIL/POWER DOWN transitions shall update an OS-9 event named "ACFAIL".	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
335	The "ACFAIL" event shall set a value 1 indicating an ACFAIL condition occurred for the DOWN transition and set 0 indicating non-ACFAIL condition for the HIGH transition.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
336	The IRQ7 and auto-vector 31(7) shall not be used to update the "ACFAIL" event.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
337	In addition, the ACFAIL condition shall generate the OS-9 auto-vector 30(6) interrupt service.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
338	Each interrupt service installed shall exit with the "Carry Bit" set allow OS9 to propagate the ACFAIL interrupt.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
339	The Manufacturer shall supply an interrupt handler at priority 255 that acknowledges and clears the interrupt.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
340	Priority 1 shall be reserved for the OS-9 system.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
341	A Long Out is defined as ACFAIL transition to LOW follow[ed] by a SYSRESET going LOW.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
342	The SYSRESET going HIGH shall be followed by an operating system reboot.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis Performance Test	Design
343	A Manufacturer may include an error handling routine to save troubleshooting data regarding initialization, power-up test abnormalities and other error conditions.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis Inspection	Design
344	If used, the error report shall be stored in the file /r0/ErrorReport and shall not exceed 11 kilobytes in size.	4.2.7 CPU Module Software – Drivers and Descriptors		Does this mean that the error report is optional?	Analysis	Design
345	When required, a DAT Program shall be provided resident in the Type 2070 ATC Unit as the application program.	4.2.7 CPU Module Software – Drivers and Descriptors		What does "when required" mean in the context of a standard? Why would an optional item be specified in a standard?	Analysis	Design
346	A Utility Program shall be provided that would allow the user to upgrade (re-flash) the Boot Image as defined in section 4.2.7.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
347	This utility shall provide the capabilities for upgrading the Operating System and drivers when available by the manufacturer.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
348	The Utility Program shall provide the capability for the user to dynamically upgrade the Boot Image via the command prompt.	4.2.7 CPU Module Software – Drivers and Descriptors			Analysis	Design
349	The Manufacturer shall also provide a copy in CD Memory of all files originally stored in the flash drive /f0 so that they can be reloaded as needed.	4.2.7 CPU Module Software – Drivers and Descriptors				Design
351	If the agency feels that knowledge of the source code and/or access to the source code is necessary for the purchase of Type 2070 ATC's, then they are referred to forthcoming guidance documents for provisions which should be included in a procurement specification to protect the interests of both the Manufacturer and the Agency.	4.2.7 CPU Module Software – Drivers and Descriptors		Why is "agency" not in all caps, as per AGENCY in other places? This is very poorly worded. It is difficult to ascertain what this note refers to or accomplishes.	Drop from the standard.	Design
352	OS-9 compliant header files shall be provided with all driver modules.	4.2.7 CPU Module Software – Drivers and Descriptors			Inspection	Design
175	The TYPE 2070-1B CPU shall be a single board module meeting the 2X WIDE board requirements.	4.2.1 Type 2070 – 1B Configuration	P	This is a standard VME specification, but is shown on the drawing 4-7-6.	Inspection	Performance
189	Four LEDs labeled "TX, RX, TX Collision and TX Status" shall be mounted on the front panel signifying ETHERNET operational conditions.	4.2.1 Type 2070 – 1B Configuration	F	The actual modules reflected the drawing, but not the text of this requirement.	Inspection Performance Test	Performance
190	The 2070-1B CPU shall not draw more than 1.00 Amperes of +5VDC and 500 milliamperes of ISO+12 VDC.	4.2.1 Type 2070 – 1B Configuration		Might the word "module" be better used here?	Performance Test	Performance
225	A DATAKEY Receptacle (KC4210, KC4210PCB or equal) shall be provided and mounted on the CPU module front panel (or the Transition Board of Type 1A).	4.2.6 Datakey	P		Inspection	Performance
227	The Manufacturer shall supply a 2 megabyte Memory Size Datakey (SFK2Mb or equal) with each MODEL 1A TB (Transition Board) or 1B CPU module unless specified otherwise.	4.2.6 Datakey	F	HCTX doesn't use this size of key and never receives them from the manufacturer.	Inspection	Performance

#	Requirement	(Standard Document Section	n)		Document Section	Pass Fail	Comments	Test Type	Requirement Type
231	When program	nmed, the memory on the key	of header version 1 sh	all be organized as follows:	4.2.6 Datakey	P	The Key Type did not come back as	Inspection	Performance
	Bytes	Description		Default Values			specified when we read a Datakey installed on a 2070 at the CalTrans'		
	1-2	16 bit Frame Check Sequents as defined in clause 4.6.2 of This FCS is calculated across	of ISO/IEC 3309.				site.		
	3	3 Key Type 4 Header Version 5-8 Latitude 9-12 Longitude 13-14 Controller ID 15-16 Communication drop number 17-20 IP Address 21-24 Subnet Mask 25-28 Default Gateway		See table below					
	4			1					
	5-8			0.0					
	9-12			0.0					
	13-14			0xFFFF					
	15-16			0xFFFF					
	17-20			10.20.70.51					
	21-24			255.255.255.0					
	25-28			10.20.70.254					
	29	Startup Override		0xFF					
	30-64	Reserved for Agency use		All bytes set to 0xFF					
	65 to End	User Data		All bytes set to 0xFF					
232	When program following table	nmed, Byte 3 of the header sha e:	all contain the Key Ty	pe value as defined in the	4.2.6 Datakey	P		Inspection	Performance
	Кеу Тур	pe Model No.	Memory Size	Sector Size					
	1	DK1000	1 Kilobyte	1 Byte					
	2	LCK16000	16 Kilobytes	1 Byte					
	3	SFK2Mb	2 megabytes	64 Kilobytes					
	4	TBD	4 megabytes	64 Kilobytes					
	5	TBD	8 megabytes	64 Kilobytes					
235	The CPU Mod kernel edition	lule shall be supplied with Rad #372 or later.	lisys/Microware OS-9	Version 3.2, or later, with	4.2.7 CPU Module Software – Operating System	Р	Verified via Mr. Iniguez's PC over the Internet.	Inspection	Performance

#	Requirem	ent (Standard	Document Sect	tion)			Document Section	Pass Fail	Comments	Test Type	Requirement Type
236	 Embedd Sequent Stacked Pipe File Random 	ed OS-9 Real T ial Character Fi Protocol File M e Manager (PIP Block File Ma	le Manager (SC Ianager (SPF) EMAN) nager (RBF)				4.2.7 CPU Module Software – Operating System	P	Verified via Mr. Iniguez's PC over the Internet.	Inspection	Performance
237	+	d Library (CSL) e shall include to Date Tmode Del Format Mdir Rename Build	the following ut Deiniz Edt Ident Deheck Mfree Procs Setime	ility modules: Devs List Iniz Login Pd Unlink Merge	Free Load Irqs Link Makdir Sleep	Copy Deldir Events Kermit Save Xmode	4.2.7 CPU Module Software – Operating System	P	Verified via Mr. Iniguez's PC over the Internet.	Inspection	Performance
242		all be provided shall apply: FLASH FLASH FLASH FLASH SRAM I SRAM I	drive non- drive OS-9 Drive as /f0 Drive as /f0 Drive non- Drive as /r0	volatile, writea default device but, write pro except forma volatile ramdis but format er	able e for /f0 otection t enabled ok aabled	mories. The following	4.2.7 CPU Module Software – Drivers and Descriptors	P	Verified via Mr. Iniguez's PC over the Internet.	Analysis	Performance
243	A driver to	handle each of	the four interna	al timers under	the OS-9 Kerne	l shall be provided.	4.2.7 CPU Module Software – Drivers and Descriptors	Р	Verified via Mr. Iniguez's PC over the Internet.	Analysis	Performance
287	SCFMAN	shall be provide		nardware TOD		npatible with the OS-9 to be updated from the	4.2.7 CPU Module Software – Drivers and Descriptors	P	Verified via Mr. Iniguez's PC over the Internet.	Inspection	Performance

#	Requirement (Standar	d Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
288	Setting Hardware Clock from OS-9 System Clock – The descriptor name shall be "ClockUpdate."		4.2.7 CPU Module Software – Drivers and Descriptors	P	Verified via Mr. Iniguez's PC over the Internet.	Inspection	Performance
302	The boot image shall incontain the following enter the following e	Plude a default inetdb module with a module revision of zero. It shall tries only: 127.0.0.1 me 0 IP 1 ICMP 2 IGMP 6 TCP 17 UDP 13312/tcp ndpd 13568/tcp nppd 7/tcp 7/udp 20/tcp 20/udp 21/tcp 21/udp 23/tcp 23/udp 42/tcp 42/udp 69/tcp 69/udp	4.2.7 CPU Module Software – Drivers and Descriptors	P	Verified via Mr. Iniguez's PC over the Internet. The image shown on the controller he Telenet'd into had several other entries than are listed here.	Inspection	Performance
303	The boot image shall inc	clude a default inetdb2 module with a module revision of zero.	4.2.7 CPU Module Software – Drivers and Descriptors	P	Verified via Mr. Iniguez's PC over the Internet.	Inspection	Performance

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
304	It [the boot image of inetdb2 module] shall contain the following entry only: Interfaces enet0 binding /spqe0/enet (no address, netmask, or broadcast)	4.2.7 CPU Module Software – Drivers and Descriptors	F	Verified via Mr. Iniguez's PC over the Internet. There is an apparent conflict between this entry and 4.2.7.2.10.4.	Inspection	Performance
305	On the MODEL 2070-1B CPU module, an OS-9 SPF Ethernet hardware driver and descriptor for the 68360 (SCC1) shall be provided in the operating system Boot Image. The descriptor shall be named spqe0.	4.2.7 CPU Module Software – Drivers and Descriptors	P	Verified via Mr. Iniguez's PC over the Internet.	Inspection	Performance
306	A setup utility or script shall be provided to copy the directories and files from the CD to the /f0 flash drive on a controller.	4.2.7 CPU Module Software – Drivers and Descriptors	P	The utility in this question is "Kermit" and we verified that it is present.	Inspection	Performance
307	The following set of files shall be provided on a PC-readable CD to allow a 2070 to be configured with a typical OS-9 development system file configuration: /CMDS, /CMDS/BOOTOBJS, /ETC and /SYS.	4.2.7 CPU Module Software – Drivers and Descriptors	F	We could not verify this requirement due to the fact that Mr. Johnson didn't have a CD and had apparently also never used one in this way.	Inspection	Performance
308	/CMDS, /CMDS/BOOTOBJS, /ETC and /SYS directories shall be used to organize the files.	4.2.7 CPU Module Software – Drivers and Descriptors	P	Verified via Mr. Iniguez's PC over the Internet.	Inspection	Performance
312	/SYS shall also contain the following four standard OS-9 network configuration shell script files: startspf, startnfs, loadspf and loadnfs.	4.2.7 CPU Module Software – Drivers and Descriptors	P		Inspection	Performance
313	The utilities tar, make, fixmod, login, tsmon, and mshell shall be included in the /CMDS directory.	4.2.7 CPU Module Software – Drivers and Descriptors	F	The utility tsmon could not be found in the /CMDS directory, but was located, instead, in the boot image.	Inspection	Performance

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
314	The following OS-9 modules should be included in the /CMDS/BOOTOBJS directory to allow for standard TCP/IP network communications using Ethernet Protocol over Ethernet hardware and/or Serial Line Internet Protocol (SLIP) or Point-to-Point Protocol over serial links:	4.2.7 CPU Module Software – Drivers and Descriptors	P	Verified via Mr. Iniguez's PC over the Internet.	Inspection	Performance
	 Drivers and Descriptors for PPP: spipcp, ipcp0, splcp, lpc0, sphdlc, hdlc0, hdlc1, hdlc2, hdlc3. 					
	2. Drivers and Descriptors for SLIP: spslip, spsl0, spsl1, spsl2, spsl3.					
	3. LAN Comm Pak modules: spenet, enet, spip, ip0, sptcp, tcp0, spudp, udp0, spraw, raw0, sproute, route0.					
	4. Telnet support modules: pkman, pkdvr, pk, pks.					
	5. Network Trap Handler: netdb_local, netdb_dns.					
	6. NFS Modules: nfs, nfsnul and nfs_devices.					
315	The following Network utilities shall be included in the /CMDS directory:	4.2.7 CPU Module Software – Drivers and Descriptors	F	Utilities tftpd and dtfpdc are both	Inspection	Performance
	arp, dhcp, ftpd, ftpdc, idbdump, idbgen, rpcdbgen, ifconfig, inetd, ipstart, ndbmod, netstat, ping, route, routed, telnet, telnetd, tftpd, tftpdc, telnetdc, hostname, nfsc, mount, rpcdump, nfsstat, exportfs, portmap, pppd, chat, pppauth, nfsd, mountd, and showmount.			missing, due to a mistake between versions.		
316	Default inetdb, inetdb2 and rpcdb modules shall be generated by the make utility via the use of a makefile and the network configuration files residing the /ETC directory.	4.2.7 CPU Module Software – Drivers and Descriptors	P	Verified via Mr. Iniguez's PC over the Internet, where we actually ran the utility.	Inspection	Performance
317	The generated inetdb, inetdb2 and rpcdb modules should be located in the /CMDS/BOOTOBJS directory.	4.2.7 CPU Module Software – Drivers and Descriptors	P		Inspection	Performance
319	A Utility Program named netcfg shall be provided. If the Datakey is present and valid, netcfg shall set the IP Address, Subnet Mask and Default Gateway of the enet0 interface when executed by a user at the command line.	4.2.7 CPU Module Software – Drivers and Descriptors	P	We ran this utility from the command line, but Mr. Iniguez's controller apparently didn't have a key installed.	Inspection	Performance
321	If the Datakey is not present or invalid, netcfg shall display an error and exit without altering any configuration.	4.2.7 CPU Module Software – Drivers and Descriptors	P	As per above.	Performance Test	Performance

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
350	The following items will be provided to the purchasing AGENCY on a CD disk readable by a PC compatible computer. 1. Specific hardware memory addresses, including FLASH, SRAM, and DRAM starting addresses, shall be specified and provided. Written documentation of addresses shall be in PDF form and will have the file name of "Memory Map.pdf" 2. Copy of all provided written manuals in PDF form. 3. RE-FLASH Utility and the procedures for its use in PDF form. The PDF documentation of the procedures shall have the file name of "Reflash Utility Procedures.pdf."	4.2.7 CPU Module Software – Drivers and Descriptors	n/a	Manufacturing specification. For reasons already noted, no CD was available.	Inspection	Performance
176	The module shall be furnished normally resident in MOTHERBOARD Slot A5.	4.2.1 Type 2070 – 1B Configuration			Inspection	Procurement

B.4 ATC Type 2070 Field I/O Module Requirements

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
353	The I/O Ports shall provide 64 bits of input using ground-true logic.	4.3.4 Parallel I/O Ports			Analysis	Design
354	Each input shall be read logic "1" when the input voltage at its field connector input is less than 3.5 VDC, and shall be read logic "0" when either the input current is less than 100 microamperes or the input voltage exceeds 8.5 VDC.	4.3.4 Parallel I/O Ports			Performance Test	Design
355	Each input shall have an internal pull-up to the Isolated +12 VDC and shall not deliver greater than 20 milliamperes to a short circuit to ground.	4.3.4 Parallel I/O Ports			Performance Test	Design
356	The I/O Ports shall provide 64 bits of output.	4.3.4 Parallel I/O Ports		Is "ground-true" logic important here? Why or why not? What is ground-true logic? It sounds like a brand name.	Analysis	Design
357	Inputs shall have the following characteristics: 1. A voltage between 0 and 4 volts shall be considered the Low (True/Operate) state. 2. A voltage greater than 8 volts shall be considered the High (False) state. 3. The transition from the Low state to High state (and vice versa) shall occur between 4 and 8 volts.	4.3.4 Parallel I/O Ports			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
358	Outputs shall have the following characteristics:	4.3.4 Parallel I/O Ports			Analysis	Design
	1. The Low (True/Operate) voltage shall be between 0 and 3 volts.					
	2. Current sinking capability in the Low state shall be at least 100 milliamperes.					
	3. With an external impedance of 100 kiloOhms or greater, the transition from 4 to 16 volts (and vice versa) shall be accomplished within 0.1 millisecond.					
	4. The High state impedance shall exceed 1 Megohms to 12 volts DC.					
359	Each output shall latch the data written and remain stable until either new data is written or the active-low reset signal.	4.3.4 Parallel I/O Ports			Performance Test	Design
360	Upon an active-low reset signal, each output shall latch a logic "0" and retain that state until a new writing.	4.3.4 Parallel I/O Ports			Performance Test	Design
361	The state of all output circuits at the time of Power Up or in Power Down state shall be open (logic 0).	4.3.4 Parallel I/O Ports			Performance Test	Design
362	It shall be possible to simultaneously assert all outputs within 100 microseconds of each other.	4.3.4 Parallel I/O Ports			Performance Test	Design
					Analysis	
363	An output circuit state not changed during a new writing shall not glitch when other output circuits are updated.	4.3.4 Parallel I/O Ports		What exactly is the definition of "glitch"? Either this word should be changed or the specification should be dropped from the standard. (Depending upon how the user of the standard verified this specification.)	Performance Test	Design
364	A maximum capacitive load of 100 picofarads shall be presented to the LINESYNC input signal.	4.3.5 Other Module Circuit Functions			Analysis	Design
365	The EIA-485 compliant differential LINESYNC signals shall be derived from the LINESYNC signal.	4.3.5 Other Module Circuit Functions		It is unclear what this specification means.	Analysis	Design
366	An External WDT "Muzzle" Jumper shall be provided on the board.	4.3.5 Other Module Circuit Functions			Inspection	Design
368	When the jumper is missing (open), the feature shall not apply.	4.3.5 Other Module Circuit Functions		If the standard requires a jumper, why would the performance without the jumper need to be specified.	Inspection	Design
369	This feature is required to operate with the Type 210 Monitor Unit only.	4.3.5 Other Module Circuit Functions		Unclear as to why this is in the standard.	Drop from the standard.	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
370	A WATCHDOG Circuit shall be provided.	4.3.5 Other Module Circuit Functions			Inspection	Design
371	The WATCHDOG Circuit shall be enabled by the FIELD I/O software at Power Up with a value of 100 milliseconds.	4.3.5 Other Module Circuit Functions		How can this requirement possibly be verified?	Analysis	Design
372	The enabled state of the WATCHDOG Circuit shall be machine readable and reported in the FI/O status byte.	4.3.5 Other Module Circuit Functions			Analysis	Design
373	Once enabled, the watchdog timer shall not be disabled without resetting the FI/O.	4.3.5 Other Module Circuit Functions			Analysis Performance Test	Design
374	Failure of the FI/O to reset the watchdog timer within the prescribed timeout shall result in a hardware reset.	4.3.5 Other Module Circuit Functions			Performance Test	Design
375	A synchronizable 1 kilohertz time reference shall be provided.	4.3.5 Other Module Circuit Functions			Inspection	Design
376	The synchronizable time reference shall maintain a frequency accuracy of +/-0.01% (+/-0.1 counts per second).	4.3.5 Other Module Circuit Functions			Analysis	Design
377	A 32-bit MILLISECOND COUNTER (MC) shall be provided for "timestamping."	4.3.5 Other Module Circuit Functions			Inspection	Design
378	Each 1 KHz reference interrupt shall increment the MC.	4.3.5 Other Module Circuit Functions			Analysis	Design
379	At Power Up, the FCU loss of communications timer shall indicate loss of communications until the user program sends the Request Module Status message to reset the "E" Bit and a subsequent set output command is processed.	4.3.5 Other Module Circuit Functions			Analysis Performance Test	Design
380	A LOGIC Switch shall be provided resident on the module board.	4.3.5 Other Module Circuit Functions			Inspection	Design
382	The purpose of the switch is to prevent multiple use of SP3.	4.3.5 Other Module Circuit Functions			Analysis	Design
384	System Serial Port 5 (SP5) EIA-485 signal lines shall enter the I/O Module and be split into two multi-drop isolated ports.	4.3.6 Serial Communications/Logic Circuitry			Analysis	Design
385	One [serial port line of SP5] shall be routed to the FCU and the other converted to EIA-485, then routed to Connector C12S.	4.3.6 Serial Communications/Logic Circuitry			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
386	System Serial Port 3 (SP3) EIA-485 signal lines shall enter the I/O module and be isolated, converted back to EIA-485 and then routed to connector C12S.	4.3.6 Serial Communications/Logic Circuitry			Inspection	Design
387	LINE SYNC and POWER DOWN lines shall be split and isolated, one routed to the FCU for shut down functions and the other changed to EIA-485; then routed to connector C12S for external module use.	4.3.6 Serial Communications/Logic Circuitry			Inspection	Design
388	CPU RESET and POWER UP (SYSRESET) lines shall be isolated and "OR'd" to form NRESET.	4.3.6 Serial Communications/Logic Circuitry			Inspection	Design
389	NRESET shall be used to reset FCU and other module devices.	4.3.6 Serial Communications/Logic Circuitry			Analysis	Design
390	NRESET shall also be converted to EIA-485 then routed to connector C12S.	4.3.6 Serial Communications/Logic Circuitry			Inspection	Design
391	If the Type 2070 module is a –2B, then routing to FCU doesn't apply.	4.3.6 Serial Communications/Logic Circuitry			Analysis	Design
392	Isolation is between internal +5 VDC / Ground #1 and +12 VDC ISO / VDC Ground #2.	4.3.6 Serial Communications/Logic Circuitry			Analysis	Design
393	+12 VDC ISO is for board power and external logic.	4.3.6 Serial Communications/Logic Circuitry			Analysis	Design
394	A Transition Buffer shall be provided capable of holding a minimum of 1024 recorded entries.	4.3.7 Buffers			Analysis	Design
395	The Transition Buffer shall default to empty.	4.3.7 Buffers			Performance Test	Design
396	There shall be two entry types (in the Transition Buffer): Transition and Rollover.	4.3.7 Buffers			Analysis	Design
397	The inputs (to the Transition Buffer) shall be monitored for state transition.	4.3.7 Buffers			Analysis	Design
398	At each transition (if the input has been configured to report transition), a transition entry shall be added to the Transition Buffer.	4.3.7 Buffers			Performance Test	Design
399	The MC shall be monitored for rollover.	4.3.7 Buffers			Analysis	Design

#	Requirement (Standard Document S	Sectio	n)								Document Section	Pass Fail	Comments	Test Type	Requirement Type
400	At each rollover transition (\$xxxx FFF Transition Buffer.	F - \$2	XXXX	0000	0), a 1	collov	ver er	try s	hall b	e added to the	4.3.7 Buffers		In order to test this, one needs to know what causes a roll-over and be able to create on during testing.	Performance Test	Design
401	For rollover entries, all bits of byte 1 a	re set	to in	dicat	te tha	t this	s is a	rollo	ver er	itry.	4.3.7 Buffers			Performance Test	Design
402	Transition Buffer blocks are sent to the	CPU	J moo	dule	upon	com	mano	l.			4.3.7 Buffers			Performance Test	Design
403	Upon confirmation of their reception,	he bl	ocks	shall	l be re	emov	ved fr	om t	he Tra	nsition Buffer.	4.3.7 Buffers			Analysis	Design
404	The entry types are depicted as follow Input Transition Entry	3:									4.3.7 Buffers			Analysis	Design
	Description	msb	,						lsb	Byte Number					
	Transition Entry Identifier	S			Inp	ut Nu	ımbe	•		1					
	MC Timestamp NLSB	X	X	X	X	X	X	X	X	2					
	MC Timestamp LSB	X	X	X	X	X	X	X	X	3					
	Millisecond Counter Rollover Entry Description msb lsb Byte Number									Byte Number					
	Rollover Entry Identifier	1	<u> </u>	1	1	1	1	1	lsb 1	1					
	MC Timestamp MSB	X	X	X	X	X	X	X	X	2					
	MC Timestamp NMSB	X	X	X	X	X	X	X	X	3					
405	Input scanning shall begin at I0 (bit 0) LSB to MSB.	and p	roce	ed to	the l	nighe	est nu	mbei	ed inp	out, ascending from	4.3.8 I/O Functions			Analysis	Design
406	Each complete input scan shall finish	vithin	ı 100	micr	rosec	onds					4.3.8 I/O Functions			Analysis	Design
														Performance Test	
407	Once sampled, the logic state of an inp	ut sha	all be	helc	d unti	l the	next	inpu	t scan	·	4.3.8 I/O Functions			Performance Test	Design
408	Each input shall be sampled 1,000 time	es per	seco	nd.							4.3.8 I/O Functions			Analysis	Design
409	The time interval between samples sha	ll be	1 mil	lisec	ond (+/-1	00 m	cros	econd	s).	4.3.8 I/O Functions			Analysis	Design
410	If configured to report, each input that input number, transition state, and time as an entry to the Transition Buffer.										4.3.8 I/O Functions		How can one view the Transition Buffer?	Analysis Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
411	If multiple inputs change state during one input sample, these transitions shall be entered into the Input Transition Buffer by increasing input number.	4.3.8 I/O Functions			Analysis Performance Test	Design
412	The Millisecond Counter shall be sampled within 10 microseconds of the completion of the input scan.	4.3.8 I/O Functions			Analysis	Design
413	If configured, the inputs shall be filtered by the FCU to remove signal bounce.	4.3.8 I/O Functions		What does "if configured" mean in this context? Why would the inputs not be configured?	Analysis	Design
414	The filtered input signals shall then be monitored for changes as noted.	4.3.8 I/O Functions			Analysis	Design
415	The filtering parameters for each input shall consist of Ignore Input Flag and the ON and OFF filter samples.	4.3.8 I/O Functions			Analysis	Design
416	If the Ignore Input flag is set, no input transitions shall be recorded.	4.3.8 I/O Functions			Analysis	Design
417	The ON and OFF filter samples shall determine the number of consecutive samples an input must be ON and OFF, respectively, before a change of state is recognized.	4.3.8 I/O Functions			Analysis	Design
418	If the change of state is shorter than the specified value, the change of state shall be ignored.	4.3.8 I/O Functions			Analysis Performance Test	Design
419	The ON and OFF filter values shall be in the range of 0 to 255.	4.3.8 I/O Functions			Analysis	Design
420	A filter value of 0, for either or both values, shall result in no filtering for this input.	4.3.8 I/O Functions			Analysis	Design
421	The default values for input signals after reset shall be as follows: Input Signals	4.3.8 I/O Functions			Inspection	Design
422	Simultaneous assertion of all outputs shall occur within 100 microseconds.	4.3.8 I/O Functions		What does this requirement mean?	Analysis Performance Test	Design
423	Each output shall be capable of being individually configured in state to ON, OFF, or a state synchronized with either phase of LINESYNC.	4.3.8 I/O Functions			Analysis	Design
424	The condition of the outputs shall only be "ON" if the FI/O continues to receive active communications from the CPU Module.	4.3.8 I/O Functions			Analysis	Design

#	Requirem	ent (Standar	d Document S	Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
425	to the OFF	condition, as		th the CPU Module for 2.0 seconds, all outputs shall revert tus byte shall be updated to reflect the loss of .	4.3.8 I/O Functions			Analysis Performance Test	Design
426	follows:	nd control bit Translation	ts in the CPU M	Module-FI/O frame protocol shall control each output as	4.3.8 I/O Functions		Can these bits be toggled independently, or via directed software control with some type of	Analysis	Design
	Case	Output Data Bit	Output Control Bit	Function			emulator?		
	A	0	0	Output in the OFF state					
	B 1 Output is a square wave, synchronized to the LINESYN signal. When LINESYNC is ON (1), the output is OFF, and when LINESYNC is OFF (0), the output is ON.								
	С	0	1	Output is a square wave, synchronized to the LINESYNC signal. When LINESYNC is ON (1), the output is ON, and when LINESYNC is OFF (0), the output is OFF					
	D	1	0	Output is in the ON state.					
427			orresponding ou otherwise confi	ttput shall be turned OFF if previously ON and if previously gured.	4.3.8 I/O Functions			Analysis	Design
428				C), all outputs to be changed shall be changed within 50 LINESYNC transition and shall remain in the same state	4.3.8 I/O Functions			Analysis	Design
		entire half cy		Envisor and share remain in the same state				Performance Test	
429			rresponding ou therwise config	tput shall be turned ON if previously OFF and if previously gured.	4.3.8 I/O Functions			Performance Test	Design
430	All output	s shall never	change state un	less configured to do so.	4.3.8 I/O Functions		"Never" is very, very difficult to test.	Analysis	Design
431	All interru	1	apable of async	chronous operation with respect to all processing and all	4.3.8 I/O Functions			Analysis	Design
432	MILLISEO	COND Interru	upt shall be acti	ivated by the 1 kilohertz reference once per millisecond.	4.3.8 I/O Functions			Analysis	Design
								Performance Test	
433	An MC tir	nestamp rollo	ver flag set by	MC rollover shall be cleared only on command.	4.3.8 I/O Functions			Analysis	Design
434			This interrupt	shall be generated by both the 0-1 and 1-0 transitions of the	4.3.8 I/O Functions			Analysis	Design
	LINESYN	C signal.						Performance Test	

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
435	The LINESYNC interrupt shall monitor the MC interrupt and set the MC error flag if there has not been an interrupt from the 1 kilohertz source for 0.5 seconds (>/=60 consecutive LINESYNC interrupts).	4.3.8 I/O Functions			Analysis	Design
436	The LINESYNC interrupt shall synchronize the 1 kilohertz time reference with the 0-1 transition of the LINESYNC signal once a second.	4.3.8 I/O Functions			Analysis Performance Test	Design
437	A LINESYNC error flag shall be set if the LINESYNC interrupt has not successfully executed for 0.5 seconds or longer (>/=500 consecutive millisecond interrupts).	4.3.8 I/O Functions			Analysis Performance Test	Design
438	A low-level communication service routine shall be provided to handle reception, transmission, and EIA-485 communication faults.	4.3.8 I/O Functions			Analysis	Design
439	The communication server shall automatically: For Transmission Generate the opening and closing flags Generate the CRC value Generate the abort sequence (minimum of 8 consecutive '1' bits) when commanded by the FCU Provide zero bit insertion For Receiving Detect the opening and closing flags Provide address comparison, generating an interrupt for messages addressed to the I/O Module, and ignoring messages not addressed to the I/O Module Strip out inserted zeros Calculate the CRC value, compare it to the received value, and generate an interrupt on an error Generate an interrupt if an abort sequence is received	4.3.8 I/O Functions			Analysis Performance Test	Design
440	The task shall be to process the command messages received from the CPU Module, prepare, and start response transmission.	4.3.8 I/O Functions			Analysis	Design
441	The response message transmission shall begin within 4 milliseconds of the received message.	4.3.8 I/O Functions			Analysis Performance Test	Design
442	The time from the receipt of message to the completion of the commanded task shall not exceed 70 milliseconds.	4.3.8 I/O Functions		Is there a list of tasks about which this applies?	Analysis Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
443	This task shall process the raw input data scanned in by the 1 ms interrupt routine, perform all filtering, and maintain the transition queue entries.	4.3.8 I/O Functions			Analysis	Design
444	All communication with the CPU Module shall be SDLC-compatible command-response protocol, support 0 bit stuffing, and operate at a data rate of 614.4 kilobits per second.	4.3.9 Data Communications Protocols			Analysis	Design
445	The CPU Module shall always initiate the communication and should the command frame be incomplete or in error, no FI/O response shall be transmitted.	4.3.9 Data Communications Protocols		Words such as "never" and "always" are difficult to test.	Analysis Performance Test	Design
446	The amount of bytes of a command or response is dependent upon the I/O Module identification.	4.3.9 Data Communications Protocols			Analysis	Design
447	The frame type shall be determined by the value of the first byte of the message.	4.3.9 Data Communications Protocols			Analysis	Design
448	The command frames type values 112-127 and associated response frame type values 240-255 are allocated to the manufacturer diagnostics.	4.3.9 Data Communications Protocols			Analysis	Design
449	All other frame types not called out are reserved.	4.3.9 Data Communications Protocols			Analysis	Design

#	Requirement	(Standard Do	cument Section)			Document Section	Pass Fail	Comments	Test Type	Requirement Type
450	The command Frame Types	-response Fran	ne Type values and message to	imes shall be as follo	ows:	4.3.9 Data Communications Protocols			Analysis	Design
	Module Command	I/0 Module Response	Description	Minimum Message Time	Maximum Message Time	Protocols				
	0-43	128-171	Reserved for NEMA TS-2							
	49	177	Request Module Status	250 microseconds	275 microseconds					
	50	178	MILLISECOND CTR. Mgmt.	222.5 microseconds	237.5 microseconds					
	51	179	Configure Inputs	344.5 microseconds	6.8750 milliseconds					
	52	180	Poll Raw Input Data	317.5 microseconds	320 microseconds					
	53	181	Poll Filtered Input Data	317.5 microseconds	320 microseconds					
	54	182	Poll Input Transition Buffer	300 microseconds	10.25 microseconds					
	55	183	Command Outputs	405 microseconds	410 microseconds					
	56	184	Reserved	340 microseconds	10.25 milliseconds					
	57	185	Reserved	340 microseconds	6.875 milliseconds					
	58	186	Configure Watchdog	222.5 microseconds	222.5 microseconds					
	59	187	Controller Identification	222.5 microseconds	222.5 microseconds					
	60	188	I/O Module Identification	222.5 microseconds	222.5 microseconds					
	61-62	189-190	Reserved (note below)							
	63	191	Poll variable length raw input	317.5 microseconds	320 microseconds					
	64	192	Variable length command outputs	405 microseconds	410 microseconds					
	65	193	Reserved (note below)							
	67	195	Reserved (note below)							

#	Requirement (Standard Docume	ent Section)		Document Section	Pass Fail	Comments	Test Type	Requirement Type
451	Messages 61 / 189, 62 / 190, 65 / 1	193, and 67 / 195 are reserved for ITS Cab	vinet Frame Types.	4.3.9 Data Communications Protocols		Software design specification.	Analysis	Design
452	Message 63 / Message 191 shall b response shall denote the followin	e the same as Message 52 / 180 except By g number of input data bytes.	te 2 of Message 180	4.3.9 Data Communications Protocols		Software design specification.	Analysis	Design
453		e as Message 55 / 183 except Byte 2 of the r of output data bytes, plus the following of		4.3.9 Data Communications Protocols		Software design specification. Poorly worded.	Analysis	Design
454	The Command shall be used to rec Command/response frames are as Request Module Status Command			4.3.9 Data Communications Protocols		Poorly worded. "This" command?	Analysis	Design
	Description	msb lsb	Byte Number					
	(Type Number = 49)	0 0 1 1 0 0 0 1	Byte 1					
	Reset Status Bits	P E K R T M L W	Byte 2					
455	Request Module Status Response			4.3.9 Data			Analysis	Design
	Description	msb lsb	Byte Number	Communications Protocols				
	(Type Number = 177)	1 0 1 1 0 0 0 1	Byte 1	Frotocois				
	System Status	P E K R T M L W	Byte 2					
	SCC Receive Error Count	Receive Error Count	Byte 3					
	SCC Transmit Error Count	Transmit Error Count	Byte 4					
	MC Timestamp MSB	MC Timestamp MSB	Byte 5					
	MC Timestamp NMSB	MC Timestamp NMSB	Byte 6					
	MC Timestamp NLSB	MC Timestamp NLSB	Byte 7					
	MC Timestamp LSB	MC Timestamp LSB	Byte 8					

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
456	The response status bits are defined as follows: P - Indicates FI/O hardware reset E - Indicates a communications loss of greater than 2 seconds K - Indicates the Datakey has failed or is not present R - Indicates that the EIA-485 receive error count byte has rolled over T - Indicates that the EIA-485 transmit error count byte has rolled over M - Indicates an error with the MC interrupt L - Indicates an error in the LINESYNC W - Indicates that the FI/O has been reset by the Watchdog	4.3.9 Data Communications Protocols			Analysis	Design
457	The FI/O status byte shall be updated (set to '1') to reflect the faults noted in clause 4.3.9.2.1.	4.3.9 Data Communications Protocols			Analysis	Design
458	Each status bit shall only be reset (set to '0') when the corresponding bit of the Request Module Status Command is a '1'.	4.3.9 Data Communications Protocols			Analysis	Design
459	The Request Module Status Response shall report the current status (subsequent to reset and sampling).	4.3.9 Data Communications Protocols			Analysis	Design
460	The FI/O shall count the number of errored frames the FI/O Communications Processor reports.	4.3.9 Data Communications Protocols			Analysis	Design
461	Separate counts shall be maintained for transmit and received frames.	4.3.9 Data Communications Protocols			Analysis	Design
462	When an individual count rolls over (255-0), the corresponding roll-over flag shall be set.	4.3.9 Data Communications Protocols			Analysis Performance Test	Design
463	FI/O modules with Datakey: On NRESET transition to High or immediately prior to any interrogation of the Datakey, the FI/O shall test the presence of the Key.	4.3.9 Data Communications Protocols			Analysis	Design

#	Requirement (Standard Docume	nt Sectio	on)								Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
467	The MC timestamp value shall be s	ampled	just p	orior	to th	e Re	ques	st Mo	odule S	Status Response.	4.3.9 Data Communications Protocols			Analysis	Design
468											4.3.9 Data Communications Protocols			Analysis	Design
469	The 'S' bit shall return status '0' on completion.										4.3.9 Data Communications Protocols			Performance Test	Design
470	The 32-bit value shall be loaded into	o the Mo	C at t	the n	ext 0)-1 tı	ansit	tion (of the l	LINESYNC signal.	4.3.9 Data Communications Protocols			Analysis	Design
471	The frames are as follows: Millisecond Counter Management Command										4.3.9 Data Communications Protocols			Analysis	Design
	Description	msb	sb lsb						lsb	Byte Number	Trotocois				
	(Type Number = 50)	0	0	1	1	0	0	1	0	Byte 1					
	New MC Timestamp MSB	X	X	X	X	X	X	X	X	Byte 2					
	New MC Timestamp NMSB	X	X	X	X	X	X	X	X	Byte 3					
	New MC Timestamp NLSB	X	X	X	X	X	X	X	X	Byte 4					
	New MC Timestamp LSB	X	X	X	X	X	X	X	X	Byte 5					
	Millisecond Counter Management .	Respons	е												
	Description	msb							lsb	Byte Number					
	(Type Number = 178)	1	0	1	1	0	0	1	0	Byte 1					
	Status	0	0	0	0	0	0	0	S	Byte 2					
472	The Configure Inputs command fra	me shall	be u	ised	to ch	ange	inpi	ut co	onfigur	ations.	4.3.9 Data Communications Protocols			Analysis	Design

#	Requirement (Standard Document	t Section)		Document Section	Pass Fail	Comments	Test Type	Requirement Type
473	The command-response frames are a Configure Inputs Command	as follows:		4.3.9 Data Communications Protocols			Analysis	Design
	Description	msb lsb	Byte Number	Frotocois				
	(Type Number = 51)	0 0 1 1 0 0 1 1	Byte 1					
	Number of Items (n)	n n n n n n n n	Byte 2					
	Item # - Byte 1	E Input Number	Byte 3(I-1)+3					
	Item # - Byte 2	Leading edge filter (e)	Byte 3(I-1)+4					
	Item # - Byte 3	Trailing edge filter I	Byte 3(I-1)+5					
	Configure Inputs Response							
	Description	msb lsb	Byte Number					
	(Type Number = 179)	1 0 1 1 0 0 1 1	Byte 1					
	Status	0 0 0 0 0 0 0 S	Byte 2					
474	Block field definitions shall be as for E Ignore Input Flag. "1	" = do not report transitions for this inpu	ıt,	4.3.9 Data Communications Protocols			Analysis	Design
	"0" = report transitio	ons for this input						
	e - samples which must	edge filter specifying the number of considered to large 1 to 255, 0 = disabled)	ecutive input nave entered to "0"					
	r - samples which must	dge filter specifying the number of conse be "1" before the input is considered to large 1 to 255, $0 = \text{disabled}$)						
	S - return status $S = 0$	on completion or '1' on input error out o	frange					
475	The Poll Raw Input Data frame shall inputs.	l be used to poll the FI/O for the current	unfiltered status of all	4.3.9 Data Communications Protocols			Analysis	Design
476	The response frame shall contain 8 b current input status.	bytes (2A) or 15 bytes (2B) of information	on indicating the	4.3.9 Data Communications Protocols			Analysis	Design

#	Requirement (Standard Document	Section	1)								Document Section	Pass Fail	Comments	Test Type	Requirement Type
477	The frames are as follows:										4.3.9 Data			Analysis	Design
	Poll Raw Input Data Command										Communications Protocols				
	Description	msb							lsb	Byte Number	Trotocois				
	(TypeNumber = 52)	0	0	1	1	0	1	0	0	Byte 1					
	Poll Raw Input Data Response (2076)	0-2A)													
	Description	msb							lsb	Byte Number					
	(Type Number = 180)	1	0	1	1	0	1	0	0	Byte 1					
	Inputs I0 (lsb) to I7 (msb)	Х	X	X	Х	X	X	X	X	Byte 2					
	Inputs I8 to I63	X	X	X	X	X	X	X	X	Bytes 3 to 9					
	MC Timestamp MSB	X	Х	X	X	X	X	X	X	Byte 10					
	MC Timestamp NMSB	X	X	X	X	X	X	X	X	Byte 11					
	MC Timestamp NLSB	X	X	X	X	X	X	X	X	Byte 12					
	MC Timestamp LSB	X	X	X	X	X	X	X	X	Byte 13					
	Poll Raw Input Data Response (2076)	0-8)													
	Description	msb							lsb	Byte Number					
	(Type Number = 180)	1	0	1	1	0	1	0	0	Byte 1					
	Inputs I0 (lsb) to I7 (msb)	X	X	X	X	X	X	X	X	Byte 2					
	Inputs I8 to I119	X	X	X	X	X	X	X	X	Bytes 3 to 16					
	MC Timestamp MSB	X	X	X	X	X	X	X	X	Byte 17					
	MC Timestamp NMSB	X	X	X	X	X	X	X	X	Byte 18					
	MC Timestamp NLSB	X	X	X	X	X	X	X	X	Byte 19					
	MC Timestamp LSB	X	X	X	X	X	X	X	X	Byte 20					
478	The Poll Filtered Input Data frame sinputs.	nall be us	sed to	o pol	ll the	FI/C	for	the	current	filtered status of all	4.3.9 Data Communications Protocols			Analysis	Design

#	Requirement (Standard Document Section)	Document Section Pass Fail	Comments	Test Type	Requirement Type
479	The response frame shall contain 8 bytes (2A) or 15 bytes (2B) of information indicating the current filtered status of the inputs.	4.3.9 Data Communications Protocols		Analysis	Design
480	Raw input data shall be provided in the response for inputs that are not configured for filtering.	4.3.9 Data Communications Protocols		Analysis	Design

#	Requirement (Standard Docume	nt Section	1)								Document Section	Pass Fail	Comments	Test Type	Requirement Type
481	The frames are as follows:										4.3.9 Data			Analysis	Design
	Poll Filter Input Data Command										Communications Protocols				
	Description	msb							lsb	Byte Number	Frotocols				
	(TypeNumber = 53)	0	0	1	1	0	1	0	1	Byte 1					
	Poll Filter Input Data Response (2	070-2A)													
	Description	msb							lsb	Byte Number					
	(Type Number = 180)	1	0	1	1	0	1	0	0	Byte 1					
	Inputs I0 (lsb) to I7 (msb)	X	X	Х	X	Х	X	Х	X	Byte 2					
	Inputs I8 to I63	Х	Х	Х	X	Х	X	Х	X	Bytes 3 to 9					
	MC Timestamp MSB	X	X	X	X	Х	X	X	X	Byte 10					
	MC Timestamp NMSB	X	Х	Х	X	х	X	Х	X	Byte 11					
	MC Timestamp NLSB	X	X	X	X	X	X	X	X	Byte 12					
	MC Timestamp LSB	Х	Х	Х	X	Х	X	X	X	Byte 13					
	Poll Filter Input Data Response (2 Description	070-8) msb							lsb	Byte Number					
	(Type Number = 181)	1	0	1	1	0	1	0	1	Byte 1					
	Inputs I0 (lsb) to I7 (msb)	X	X	X	X	Х	X	Х	X	Byte 2					
	Inputs I8 to I119	Х	Х	Х	Х	х	Х	Х	X	Bytes 3 to 16					
	MC Timestamp MSB	Х	X	Х	Х	х	Х	Х	X	Byte 17					
	MC Timestamp NMSB	Х	Х	Х	X	х	X	Х	X	Byte 18					
	MC Timestamp NLSB	Х	Х	Х	Х	Х	Х	Х	X	Byte 19					
	MC Timestamp LSB	X	X	Х	X	х	X	Х	X	Byte 20					
482	The Poll Input Transition Buffer fr buffer.	ame shall p	poll t	he F	I/O f	or th	ne co	nten	ts of th	ne input transition	4.3.9 Data Communications Protocols			Analysis	Design

#	Requirement (Standard Document	t Section	1)								Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
483	The response frame shall include a have occurred since the last interrog	three-byte gation.	info	rma	ition	fiel	d for	each	n of th	e input changes that	4.3.9 Data Communications Protocols			Analysis	Design
484	The frames are as follows:										4.3.9 Data			Analysis	Design
	Poll Input Transition Buffer Commo	and									Communications Protocols				
	Description	msb							lsb	Byte Number	Frotocois				
	(Type Number = 54)	0	0	1	1	0	1	1	0	Byte 1					
	Block Number	X	Х	X	X	X	Х	X	X	Byte 2					
	Poll Input Transition Buffer Respon	se msb							lsb	Byte Number					
	(Type Number = 182)	0	0	1	T 1	0	0	1	1	Byte 1					
	Block Number	X	X	X	X	Ť	X	X	X	Byte 2					
	Number of Entries	х	Х	х			X	X	Х	Byte 3					
	Item#	S			Inp	ut N	umb	er		Byte 3(I-1)+4					
	Item # MC Timestamp NLSB	х	X	X	х	X	X	X	Х	Byte 3(I-1)+5					
	Item # MC Timestamp LSB	х	Х	х	Х	х	X	X	Х	Byte 3(I-1)+6					
	Status	0	0	0	0	С	F	Е	G	Byte 3(I-1)+7					
	MC Timestamp MSB	X	X	Х	Х	х	X	X	X	Byte 3(I-1)+8					
	MC Timestamp NMSB	X	X	х	X	Х	X	X	х	Byte 3(I-1)+9					
	MC Timestamp NLSB	X	X	Х	X	х	X	X	X	Byte 3(I-1)+10					
	MC Timestamp LSB	Х	X	х	х	х	X	X	X	Byte 3(I-1)+11					
485	Each detected state transition for ea as it occurs.	ch active	input	t (se	e co	nfig	uratio	on da	ata) is	placed in the queue	4.3.9 Data Communications Protocols			Analysis	Design
486	The FI/O shall set the 'F' bit to '1' Buffer is full.	when atter	mptii	ng to	o rec	ord	a trai	nsitio	on and	the Transition	4.3.9 Data Communications Protocols			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
487	While the Transition Buffer is full, all subsequent entries shall be discarded.	4.3.9 Data Communications Protocols			Analysis	Design
488	Bit definitions are as follows: S - Indicates the state of the input after the transition C - Indicates the 255 transition entries limit has been exceeded F - Indicates the transition buffer limit has been exceeded G - Indicates the requested block number is out of monotonic increment sequence E - Same block number requested, E is set in response	4.3.9 Data Communications Protocols			Analysis	Design
489	The Block Number byte is a monotonically increasing number incremented after each command issued by the CPU Module.	4.3.9 Data Communications Protocols			Analysis	Design
490	When the FI/O Module receives this command, it shall compare the associated Block Number with the Block Number of the previously received command.	4.3.9 Data Communications Protocols			Analysis	Design
491	If the new Block Number is the same as the previously-sent Block Number, the previous buffer shall be re-sent to the CPU Module and the 'E' flag set in the status response frame.	4.3.9 Data Communications Protocols			Analysis	Design
492	If the new Block Number is not equal to the previous Block Number, the old buffer shall be purged and the next block of data sent.	4.3.9 Data Communications Protocols			Analysis	Design
493	If the block number is not incremented by one, the status G bit shall be set.	4.3.9 Data Communications Protocols			Analysis	Design
494	The block number received becomes the current number (even if out of sequence).	4.3.9 Data Communications Protocols			Analysis	Design
495	The Block Number byte sent in the response block shall be the same as that received in the command block.	4.3.9 Data Communications Protocols			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
496	Counter rollover shall be considered as a normal increment.	4.3.9 Data Communications Protocols			Analysis	Design
497	The Timestamp shall equal the MC value at the time the Poll Input Transition Buffer Response is generated.	4.3.9 Data Communications Protocols			Analysis	Design
498	The Set Outputs frame shall be used to command the FI/O to set the Outputs according to the data in the frame.	4.3.9 Data Communications Protocols			Analysis	Design
499	If there is any error configuring the outputs, the 'E' flag in the response frame shall be set to '1'.	4.3.9 Data Communications Protocols			Analysis	Design
500	If the LINESYNC reference has been lost, the 'L' bit in the response frame shall be set.	4.3.9 Data Communications Protocols			Analysis	Design
501	Loss of LINESYNC reference shall also be indicated in system status information.	4.3.9 Data Communications Protocols			Analysis	Design

#	Requirement (Standard Document S	Sectio	n)									Document Section	Pass Fail	Comments	Test Type	Requirement Type
502	The output bytes depend upon field I/O follows: Set Outputs Command	O mod	ule.	The	se co	mm	and a	ınd 1	respon	se frames are	e as	4.3.9 Data Communications Protocols			Analysis	Design
	Description		mst	,					lsl	Byte Ni	umber					
	(Type Number = 55)		0	0	1	1	0	1	1 1	Byte	e 1					
	Outputs O0 (lsb) to O7 (msb) Data		X	X	X	X	X :	X	x x	Byte	e 2					
	Outputs O8 to O103 Data		X	X	X	X	X :	X	x x	Bytes 3	to 14					
	Outputs O0 (lsb) to O7 (msb) Contro	ol	X	X	X	X	X :	X	x x	Byte	15					
	Outputs O8 to O103 Control		X	X	X	X	X :	X	x x	Bytes 10	6 to 27					
	Set Outputs Response															
	Description	msb							lsb	Byte Nu	mber					
	(Type Number = 183)	1	0	1	1	0	1	1	1	Byte	1					
	Status	0	0	0	0	0	0	L	Е	Byte	2					
503	The Configure Watchdog frames shall The Command and response frames ar Configure Watchdog Command	be us	ed to ollow	cha s:	nge t	he s	oftwa	are v	vatchd	og timeout v	alue.	4.3.9 Data Communications Protocols			Analysis	Design
	Description	msb							lsb	Byte Nu	mber					
	(Type Number = 58)	0	0	1	1	1	0	1	0	Byte	1					
	Timeout Value	X	Х	X	X	X	X	X	X	Byte	2					
	Configure Watchdog Response															
	Description	msb							lsb	Byte Nu	mber					
	(Type Number = 186)	1	0	1	1	1	0	1	0	Byte	1					
	Status	0	0	0	0	0	0	0	Y	Byte	2					
504	The timeout value shall be in the range	betw	een 1	0 to	100	mil	iseco	onds				4.3.9 Data Communications Protocols			Analysis	Design

#	Requirement (Standard Doce	cument Sec	tion)								Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
505	If the value is lower than 10, 1 assumed.	10 shall be a	assum	ied. I	f the	alue	is grea	ter than	n 100,	100 shall be	4.3.9 Data Communications Protocols			Analysis	Design
506	On receipt of this frame, the w and the "Y" bit set.	vatchdog tir	neout	valu	e shal	be c	hanged	l to the	value	in the message	4.3.9 Data Communications Protocols			Analysis	Design
507	The response frame bit (Y) sha not.	all indicate	a '1'	if the	watc	ndog	has be	en prev	viously	set and a '0' if	4.3.9 Data Communications Protocols			Analysis	Design
508	This is a legacy message comm	mand / resp	onse	for F	I/O m	odule	s with	Datake	ey resid	dent.	4.3.9 Data Communications Protocols			Analysis	Design
509	Upon command, a response fra on Request Module Status for	rame contain FI/O Status	ning t s Bit '	he 12 'K' d	28 byte efiniti	es of on.	the Da	takey S	See pre	vious sections	4.3.9 Data Communications Protocols			Analysis	Design
510	If "K" bit set, only the first two	o bytes sha	ll be 1	return	ned.						4.3.9 Data Communications Protocols			Analysis	Design
511	The Command and Response f Controller Identification Comm		as fol	lows:							4.3.9 Data Communications Protocols			Analysis	Design
	Description	m	sb					lsb	В	Byte Number	Frotocois				
	(TypeNumber = 59)		0	0 1	1	1	0 1	1		Byte 1					
	Controller Identification Respo	onse													
	Description	m	sb					lsb	B	Byte Number					
	(Type Number = 187)		1	0 1	1	1	0 1	1		Byte 1					
	Status		0	0 0	0	0	0 0			Byte 2					
	Datakey	2	X	X X	X	X	X X	X	В	sytes 3 to 130					
512	The I/O Module Identification Identification value.	n Command	fram	e sha	ll be ι	sed t	o reque	est the I	FI/O		4.3.9 Data Communications Protocols			Analysis	Design

#	Requirement (Standard Docu	ument Section)			Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
513	A response of "1" shall be returned Type 1 FI/O and "32 to 40" are	rned by 2070-2A, "2" by 2070-8, reserved for ITS Cabinets.	"3" is reserve	d for NEMA TS 2	4.3.9 Data Communications Protocols			Analysis	Design
514	The command and response fra Controller Identification Comm				4.3.9 Data Communications			Analysis	Design
	Description	msb	lsb	Byte Number	Protocols				
	(TypeNumber = 60)	0 0 1 1 1	1 0 0	Byte 1					
	Controller Identification Respo	nse							
	Description	msb	lsb	Byte Number					
	(Type Number = 188)	1 0 1 1 1	1 0 0	Byte 1					
	FI/O I D byte	x x x x x x	x x x	Byte 2					
367		ET transitions HIGH (FCU active (Connector C1, pin 103 – Monito s or due to CPU Command.			4.3.5 Other Module Circuit Functions	n/a	Because of the lack of an external power supply, this one was not conducted.	Performance Test	Performance
381	The switch shall function to dis C12S.	sconnect Serial Port 3 (SP3) from	the external w	vorld, Connector	4.3.5 Other Module Circuit Functions	P	On the Field I/O module, there is an actual mechanical switch that provides this functionality.	Inspection	Performance
383	An LED shall be provided on tactive and available at C12S.	he module front panel labeled "Sl	P3 ON". If LE	ED light ON, SP3 is	4.3.5 Other Module Circuit Functions	P	Verified as per above.	Performance Test	Performance
464	FI/O modules with Datakey: It interrogation shall take place.	f [the Datakey is] absent, Status B	Bit "K" shall bo	e set to '1' and no	4.3.9 Data Communications Protocols	n/a	This is a legacy requirement that is obsolete. It serves the purpose to allow software written for older Field I/O modules to work either way.	Performance Test	Performance
465	FI/O modules with Datakey: It to '1'.	f an error occurs during the interro	ogation, Status	s Bit "K" shall be set	4.3.9 Data Communications Protocols	n/a		Performance Test	Performance
466	FI/O modules without Datakey	: Status Bit "K" shall always be	set to '1'		4.3.9 Data Communications Protocols	n/a		Performance Test	Performance

B.5 ATC Type 2070 Front Panel Assembly Requirements

#	Requirement (Standard Document Section)	Document Section	Pass Fail Comments	Test Type	Requirement Type
	The Command Codes shall use the following conventions:				
517	Each key shall have an actuation force between 50 and 100 grams and provide a positive tactile indication of contact closure.	4.4.2 Front Panel Assembly – Keyboards	"Positive tactile indication" is a nebulous specification.	Performance Test	Design
518	Key contacts shall be hermetically sealed, have a design life of over one million operations, shall be rated for the current and voltage levels used, and shall stabilize within 5 milliseconds following contact closure.	4.4.2 Front Panel Assembly – Keyboards	Design life is a manufacturing specification.	Analysis	Design
521	Display A shall have 4 lines of 40 characters each with a minimum character dimension of 0.20 inches wide by 0.41 inches high and an electro – luminescent (EL) backlight.	4.4.4 Front Panel Assembly – Display		Inspection	Design
523	Each character shall be composed of a 5 x 7 dot matrix with a underline row or a 5 x 8 dot matrix.	4.4.4 Front Panel Assembly – Display		Analysis	Design
524	The viewing angle of the LCD shall be optimized for direct (90 degrees) viewing, +/-35 degrees vertical, +/-45 degrees horizontal.	4.4.4 Front Panel Assembly – Display		Analysis	Design
525	The LCD shall have variable contrast with a minimum ratio of 4:1.	4.4.4 Front Panel Assembly – Display		Analysis	Design
526	The LCD shall be capable of displaying, at any position on the Display, any of the standard ASCII characters as well as user-defined characters.	4.4.4 Front Panel Assembly – Display	What does "user-defined" mean and how would one know? It appears that the display only needs to handle a subset of the ASCII set.	Inspection	Design
528	The backlight and associated circuitry shall consume no power when in off state.	4.4.4 Front Panel Assembly – Display		Performance Test	Design
530	The contrast shall depend on the angular position of the potentiometer, which shall provide the entire contrast range of the LCD.	4.4.4 Front Panel Assembly – Display		Performance Test	Design
531	Cursor display shall be turned ON and OFF by command.	4.4.4 Front Panel Assembly – Display		Performance Test	Design
532	When [the Display is] ON, the cursor shall be displayed at the current cursor position.	4.4.4 Front Panel Assembly – Display		Performance Test	Design
533	When [the Display is] OFF, no cursor shall be displayed. All other cursor functions (positioning, etc.) shall remain in effect.	4.4.4 Front Panel Assembly – Display		Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
534	The FPA CONTROLLER shall function as the Front Panel Device controller interfacing with the CPU Module.	4.4.5 Front Panel Assembly – FPA Controller		What does this specification mean?	Analysis	Design
536	The momentary CONTROL switch shall be logic OR'd with the CPU RESET Line, producing a FPA RESET Output.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
537	 Upon FPA RESET being active or receipt of a valid Soft Reset display command, the following shall occur: 1. Auto-repeat, blinking, auto-wrap, and auto-scroll shall be set to OFF. 2. Each special character shall be set to ASCII SPC (space). 3. The tab stops shall be set to columns 9, 17, 25, and 33. 4. The backlight timeout value shall be set to 6 (60 seconds). 5. The backlight shall be extinguished. 6. The display shall be cleared (all ASCII SPC). 7. The FPA module shall transmit a power up string through /sp6 to the CPU once power is applied to the FPA, or the FPA hardware RESET BUTTON IS PUSHED. The string is "ESC [PU", hex value "1B 5B 50 55". 	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
538	When a keypress is detected, the appropriate key code shall be transmitted to SP6-RxD.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
539	If two or more keys are depressed simultaneously, no code shall be sent.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
540	If a key is depressed while another key is depressed, no additional code shall be sent.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
541	Auto-repeat shall be turned ON and OFF by command.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
542	When ON, the key code shall be repeated at a rate of 5 times per second starting when the key has been depressed continuously for 0.5 second, and shall terminate when the key is released or another key is pressed.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
543	When the AUX Switch is toggled, the appropriate AUX Switch code shall be transmitted to the CPU.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
544	The controller circuitry shall be capable of composing and storing eight special graphical characters on command, and displaying any number of these characters in combination with the standard ASCII characters.	4.4.5 Front Panel Assembly – FPA Controller			Analysis Performance Test	Design
545	Undefined characters shall be ignored.	4.4.5 Front Panel Assembly – FPA Controller		How can an undefined character be generated by the keyboard? If a character is undefined, how can this requirement be tested?	Analysis	Design
546	User-composed characters shall be represented in the communication protocol on Page 9-7-12.	4.4.5 Front Panel Assembly – FPA Controller		Error : Should be 4-7-12 and should be designated as "diagram number" not page.	Analysis	Design
547	P1 represents the special character number (1-8).	4.4.5 Front Panel Assembly – FPA Controller		What purpose does this clause serve in a standard?	Analysis	Design
548	Pn's represent columns of pixels from left to right.	4.4.5 Front Panel Assembly – FPA Controller		What purpose does this clause serve in a standard?	Analysis	Design
549	The most significant bit of each Pn represents the top pixel in a column and the least significant bit shall represent the bottom pixel.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
550	A logic '1' shall turn the pixel ON.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
551	There shall be a minimum of 5 Pn's for 5 columns of pixels in a command code sequence terminated by an "f."	4.4.5 Front Panel Assembly – FPA Controller			Inspection	Design
552	If the number of Pn's are more than the number of columns available on the LCD, the extra Pn's shall be ignored.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
553	P1 and all Pn's shall be in ASCII coded decimal characters without leading zero.	4.4.5 Front Panel Assembly – FPA Controller			Inspection	Design
554	Character overwrite mode shall be the only display mode supported.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
555	A displayable character received shall always overwrite the current cursor position on the Display.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
556	The cursor shall automatically move right one character position on the Display after each character write operation.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
557	When the rightmost character on a line (position 40) has been overwritten, the cursor position shall be determined based on the current settings of the auto-wrap mode.	4.4.5 Front Panel Assembly – FPA Controller			Analysis Performance Test	Design
558	Auto-wrap shall be turned ON & OFF by command.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
559	When ON, a new line operation shall be performed after writing to position 40.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
560	When OFF, upon reaching position 40, input characters shall continue to overwrite position 40.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
562	Cursor movement shall not affect the current display, other than blinking the cursor momentarily and periodically hiding the character at that cursor position.	4.4.5 Front Panel Assembly – FPA Controller			Analysis Performance Test	Design
563	Blinking characters shall be supported, and shall be turned ON and OFF by command.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
564	When ON, all subsequently received displayable characters shall blink at the rate of 1 Hertz with a 60% ON / 40% OFF duty cycle.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
565	It shall be possible to display both blinking and non-blinking characters simultaneously.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
566	Tab Stops shall be configurable at all columns.	4.4.5 Front Panel Assembly – FPA Controller		Why are Tab Stops being defined in a standard?	Drop from the standard.	Design
567	A tab stop shall be set at the current cursor position when a SetTabStop command is received.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
568	Tab Stop(s) shall be cleared on receipt of a ClearTabStop command.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
569	On receipt of the HT (tab) code, the cursor shall move to the next tab stop to the right of the cursor position.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
570	If no tab stop is set to the right of the current cursor position, the cursor shall not move.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
571	Auto-scroll shall be turned ON and OFF by command.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
572	When [Auto-scroll is] ON, a Line Feed or new line operation from the bottom line shall result in the display moving up one line.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
573	When [Auto-scroll is] OFF, a Line Feed or new line from the bottom line shall result in the top line clearing, and the cursor being positioned on the top line.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
574	The display shall have a buffer.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
575	The screen shall be refreshed from the buffer at a rate of no less than 20 times per second.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
576	The Display back light shall illuminate when any key is pressed and shall illuminate or extinguish by command.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
578	This time [the backlight extinguish time] shall be program selected by command, by a number in the range 0 to 63 corresponding to that number of 10-second intervals.	4.4.5 Front Panel Assembly – FPA Controller			Analysis Performance Test	Design
579	A value of 1 shall correspond to a timeout interval of 10 seconds.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
580	A value of 0 shall indicate no timeout.	4.4.5 Front Panel Assembly – FPA Controller			Performance Test	Design
582	 Parameters and Options: Parameters are depicted in both the ASCII and hexadecimal representations as the letter 'P' followed by a lower-case character or number. These are interpreted as follows: Pn: Value parameter, to be replaced by a value, using one ASCII character per digit without leading zeros. P1: Ordered and numbered parameter. One of a listed known parameters with a specified order and number (Continues with P2, P3, etc.) Px: Display column number (1-40), using one ASCII character per digit without leading zero. Py: Display line (1-4) one ASCII character	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
583	 ASCII Representation: Individual characters are separated by spaces; these are not to be interpreted as the space character, which is depicted by SPC. 	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
584	3. Hexadecimal Representation: Characters are shown as their hexadecimal values and will be in the range 0x00 to 0x7F (7 bits).	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
585	The Controller Circuit shall communicate via a SP6 asynchronous serial interface.	4.4.5 Front Panel Assembly – FPA Controller			Inspection	Design
586	The interface shall be configured for 38.4 kilobits per second, 8 data bits, 1 stop bit, and no parity.	4.4.5 Front Panel Assembly – FPA Controller			Analysis	Design
587	C50 ENABLE function when grounded by pins 1 and 5, shall be brought to Connectors A1, pin B21 for the purpose of disabling the module channel 2, (SP4).	4.4.5 Front Panel Assembly – FPA Controller			Inspection	Design
588	The Front Panel shall include an electronic bell to signal receipt of (0x07).	4.4.6 Front Panel Assembly – Electronic Bell			Performance Test	Design
589	The bell shall sound at 2,000 Hertz, with a minimum output rating of 85 dB upon receipt of (0x07).	4.4.6 Front Panel Assembly – Electronic Bell			Performance Test	Design
590	Receipt of all other characters and ESC codes shall continue during the time the bell sounds.	4.4.6 Front Panel Assembly – Electronic Bell			Analysis	Design
515	Two KEYBOARDS shall be provided, one with sixteen keys for hexadecimal alpha-numeric entry and the other with twelve keys to be used for cursor control and action symbol entry.	4.4.2 Front Panel Assembly – Keyboards	P		Inspection	Performance
516	Each key shall be engraved or embossed with its function character. Note: The operational need here is that the key designations should not wear off, no matter the amount of use.	4.4.2 Front Panel Assembly – Keyboards	P	Does "engraved" or "embossed" refer to the depth of the characters? The version we saw was perfectly smooth.	Inspection	Performance
519	The cathode of the CPU ACTIVE LED INDICATOR shall be electrically connected to the CPU Activity LED signal and shall be pulled up to +5 VDC.	4.4.3 CPU Active Indicator	P		Inspection	Performance
520	The DISPLAY shall consist of a Liquid Crystal Display (LCD), a backlight, and a contrast potentiometer control.	4.4.4 Front Panel Assembly – Display	P		Inspection	Performance
522	Display B shall have 8 lines of 40 characters each with minimum dimensions of 0.10 inches wide by 0.17 high and either LED or EL backlight.	4.4.4 Front Panel Assembly – Display	Р		Analysis	Performance
527	The backlight shall be turned on and off by the Controller Circuitry.	4.4.4 Front Panel Assembly – Display	Р		Performance Test	Performance

#	Requirement (Standard Document Section)	Document Section Pass Fail		Test Type	Requirement Type
529	A potentiometer shall control the LCD contrast with clockwise rotation increasing contrast.	4.4.4 Front Panel Assembly – Display		Inspection	Performance
535	A FPA RESET Switch shall be provided on the Assembly PCB.	4.4.5 Front Panel Assembly – FPA Controller		Inspection	Performance
561	Cursor positioning shall be non-destructive.	4.4.5 Front Panel Assembly – FPA Controller		Performance Test	Performance
577	The backlight shall extinguish when no key is pressed for a specified time.	4.4.5 Front Panel Assembly – FPA Controller	It is not clear if there is a default time for this requirement.	Performance Test	Performance

B.6 ATC Type 2070 Power Supply Module Requirements

#	Requirement (Standard Document Section)		<u>Pass</u> Fail	Comments	Test Type	Requirement Type
593	The Type 2070-4B Module shall meet the same requirements as the 2070-4A, except for 3.5 amperes of +5 VDC.	4.5.1 Power Supply Module – General			Analysis	Design
595	The LED DC POWER Indicators shall indicate all required DC voltages meet the following conditions: the +5 VDC is within 5% and the 12 VDC is within 8% of their nominal levels.	4.5.2 Power Supply Module – Module Front			Analysis	Design
596	Two 0.5-Ohm, 10-watt wire-wound power resistors with a 0.2 micro Henries inductance shall be provided (one on the AC+ Line & on the AC- Line).	4.5.3 Power Supply Module – Input Protection			Inspection	Design
597	Three 20 Joule surge arrestors shall be provided between AC+ to AC-, AC+ to EG, and AC- to EG. A 0.68 µF capacitor shall be placed between AC+ & AC- (between the resistor & arrestors).	4.5.3 Power Supply Module – Input Protection			Analysis	Design
598	+5 VDC STANDBY POWER shall be provided to hold up specified circuitry during the power down period.	4.5.4 +5VDC Standby Power			Analysis	Design
599	It [standby power] shall consist of the monitor circuitry, hold up capacitors, and charging circuitry.	4.5.4 +5VDC Standby Power			Analysis	Design
600	A charging circuit shall be provided, that under normal operation, shall fully charge and float the capacitors consistent with the manufacturers' recommendations.	4.5.4 +5VDC Standby Power			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
601	The Hold Up power requirements shall be a minimum constant drain of 600 microamperes at a range of +5 VDC to +2 VDC for over 600 minutes.	4.5.4 +5VDC Standby Power			Performance Test	Design
602	MONITOR CIRCUITRY shall be provided to monitor incoming AC Power for Power Failure and Restoration and LINESYNC generation.	4.5.5 Power Supply Module – Monitor Circuitry			Analysis	Design
603	The ACFAIL/POWER DOWN Output Lines shall go LOW (ground true) immediately upon Power Failure.	4.5.5 Power Supply Module – Monitor Circuitry			Analysis	Design
604	The Lines shall transition to HIGH at Power Restoration.	4.5.5 Power Supply Module – Monitor Circuitry			Analysis	Design
605	The Lines shall be driven separately.	4.5.5 Power Supply Module – Monitor Circuitry		Poorly written.	Inspection	Design
608	The Lines shall be driven separately.	4.5.5 Power Supply Module – Monitor Circuitry		Poorly written.	Inspection	Design
612	The output shall have drive sink capability of 16 milliamperes.	4.5.5 Power Supply Module – Monitor Circuitry		This is a performance requirement with little context. Why this specific capability is needed and how this Ma figure was arrived at is at question.	Analysis	Design
613	A 2 K-Ohm pull-up resistor shall be connected between the output and +5 VDC.	4.5.5 Power Supply Module – Monitor Circuitry			Inspection	Design
615	The LINESYNC shall continue until SYSRESET transitions LOW and begin when SYSRESET transitions HIGH.	4.5.5 Power Supply Module – Monitor Circuitry			Analysis	Design

#	Requirement (Star	ndard Document Section)		Document Section	Pass Fail	Comments	Test Type	Requirement Type
616	Voltage	Tolerances	I Minimum	I Maximum	4.5.6 Power Supply			Analysis	Design
	+5 VDC	+4.875 to +5.125 VDC	1.0 ampere	10.0 ampere- MODULE 2070-4A 3.5 ampere- MODULE 2070-4B	Requirements			Performance Test	
	+12 VDC Serial	+11. 4 to +12. 6 VDC	0.1 ampere	0.5 ampere					
	-12 VDC Serial	-11. 4 to -12. 6 VDC	0.1 ampere	0.5 ampere					
	+12 VDC	+11. 4 to +12. 6 VDC	0.1 AMP	1.0 AMP					
617		tion shall meet the table to ninimum loads called out		or voltage range of 90 to 135 VDC, neluding ripple noise.	4.5.6 Power Supply Requirements			Analysis	Design
618	Power Supply Effic	iency shall be 70% minim	um.		4.5.6 Power Supply Requirements		What does this standard mean relative to the performance of the device?	Analysis	Design
619	Power Supply Ripp whichever is greater		than 0.2% RMS	1% peak to peak or 50 millivolts,	4.5.6 Power Supply Requirements		What does this standard mean relative to the performance of the device?	Analysis	Design
620	Power Supply Outp	ut Overshoot shall be no g	greater than 5%,	all outputs.	4.5.6 Power Supply Requirements			Analysis	Design
621	Power Supply Over	voltage Protection shall be	e 130% Vout for	all outputs.	4.5.6 Power Supply Requirements			Analysis	Design
622	Power Supply Circu removal of fault.	uit protection shall be impl	lemented to prov	ride automatic recovery upon	4.5.6 Power Supply Requirements			Analysis	Design
623	Power Supply Cold	Start Inrush shall be less	than 25 amperes	at 115VAC.	4.5.6 Power Supply Requirements			Performance Test	Design
624		sient response shall be suc on a 50% Load change.	h that output vo	Itage back to within 1% in less than	4.5.6 Power Supply Requirements			Performance Test	Design
625	Power Supply Trans	sient response shall be suc	h that peak trans	sient not to exceed 5%.	4.5.6 Power Supply Requirements			Performance Test	Design
628	Power Supply Remototal line drop.	ote sense shall be impleme	ented such that +	5 VDC compensates 250 millivolts	4.5.6 Power Supply Requirements			Analysis	Design
629	Power Supply open	sense load protection requ	uired.		4.5.6 Power Supply Requirements		What does this mean?	Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
591	The Type 2070-4A Power Supply Module shall be independent, self contained Module, vented, and cooled by convection only.	4.5.1 Power Supply Module – General	Р		Analysis	Performance
592	The Module shall slide into the unit's power supply compartment from the back of the Chassis and be attached to the Backplane Mounting Surface by its four TSD #3 Devices.	4.5.1 Power Supply Module – General	P		Inspection	Performance
594	An "On/Off" POWER Switch, four LED DC Power Indicators, PS Receptacle POWER Connectors, and the Incoming AC Fuse protection shall be provided on the Module Front.	4.5.2 Power Supply Module – Module Front	Р		Inspection	Performance
606	The SYSRESET/POWERUP Output Lines shall transition to LOW 525 +/-25 milliseconds after ACFAIL/POWER DOWN transition to LOW.	4.5.5 Power Supply Module – Monitor Circuitry	P		Analysis Performance Test	Performance
607	The Lines shall transition to HIGH 225 +/-25 milliseconds after Power Restoration and the supply is fully recovered.	4.5.5 Power Supply Module – Monitor Circuitry	P		Analysis Performance Test	Performance
609	The monitor circuitry shall switch the +5 VDC Standby ON immediately upon Power Failure and isolate (OFF) the line at Power Up.	4.5.5 Power Supply Module – Monitor Circuitry	P		Analysis Performance Test	Performance
610	The 60 Hz Square Wave LINESYNC signal shall be generated by a crystal oscillator, which shall be synchronized to the 60-Hertz VAC incoming power line at 120 and 300 degrees.	4.5.5 Power Supply Module – Monitor Circuitry	P		Analysis	Performance
611	A continuous square wave signal shall be +5 VDC amplitude, 8.333 milliseconds half-cycle pulse duration, and 50 +/-1% duty cycle.	4.5.5 Power Supply Module – Monitor Circuitry	P		Analysis Performance Test	Performance
614	The monitor circuit shall compensate for missing pulses and line noise during normal operation.	4.5.5 Power Supply Module – Monitor Circuitry	P		Analysis	Performance
626	The power supply shall supply 30 watts minimum for 550 milliseconds after ACFAIL going LOW.	4.5.6 Power Supply Requirements	Р		Performance Test	Performance
627	The power supply shall be capable of holding up the Unit for two 500 milliseconds Power Loss periods occurring in a 1.5-second period.	4.5.6 Power Supply Requirements	P		Analysis Performance Test	Performance

B.7 ATC Type 2070 VME Cage Assembly Requirements

#	Requirement (Standard Document Section)		Pass Fail	Comments	Test Type	Requirement Type
630	The Chassis shall consist of the metal housing, Serial Motherboard, Back-plane Mounting Surface, Power Supply Module Supports, slot card guides, Wiring Harnesses, and Cover Plate(s).	4.6.1 VME Cage Assembly – General			Inspection	Design
631	All external screws shall be countersunk and shall be Phillips flat head stainless steel type.	4.6.1 VME Cage Assembly – General			Inspection	Design
632	The housing shall be treated with clear chromate and the slot designation labeled on the back-plane mounting surface above the upper slot card guide.	4.6.1 VME Cage Assembly – General			Inspection	Design
633	The Chassis shall be cooled by convection only.	4.6.1 VME Cage Assembly – General			Inspection	Design
634	The top and bottom pieces of the housing shall be slotted for vertical ventilation.	4.6.1 VME Cage Assembly – General			Inspection	Design
635	Serial Motherboard shall function as support for its connectors, A1 to A5 and FP, and as the interface between the CPU and the dedicated modules/Front Panel carrying both serial communications, logic, and power circuits.	4.6.2 VME Cage Assembly – Serial Motherboard			Analysis	Design
636	The PCB shall be multi-layered, with one layer plane assigned to DC Ground.	4.6.2 VME Cage Assembly – Serial Motherboard			Analysis	Design
637	A wiring harness PS2 shall be provided between the Type 2070-4 Power Supply and the Motherboard PCB (provide strain relief).	4.6.2 VME Cage Assembly – Serial Motherboard		Manufacturing specification. Appropriate for a standard?	Inspection	Design
638	Test points shall be provided on the FPA side of the Motherboard for PS2 lines.	4.6.2 VME Cage Assembly – Serial Motherboard			Inspection	Design
639	A wiring harness FP shall be provided, linking the Motherboard with the FPA.	4.6.2 VME Cage Assembly – Serial Motherboard		Manufacturing specification. Appropriate for a standard?	Inspection	Design
640	Type 2070-5 VME Cage Assembly shall consist of 3U five slot/connector VME Cage, Front Mounting Plate, and PS1 Harness.	4.6.3 Type 2070-5 VME Cage Assembly		Why is this part of a standard?	Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
641	The VME Cage shall conform to VME Standard IEEE P1014/D12 for 3U Cage. All slot/connectors shall be A24:D16 Interface.	4.6.3 Type 2070-5 VME Cage Assembly		Need to dig up this specification. Manufacturing specification. Appropriate for a standard?	Inspection	Design
642	The Type 2070 – 1A CPU Main Controller Board shall either be affixed to the Transition Board via at least four stand-off devices or mounted in a one slot VME board assembly (removable).	4.6.4 Type 2070-1A CPU Main Controller Board		Manufacturing specification. Appropriate for a standard?	Inspection	Design
643	A PS1L Harness shall be supplied with one end mating to the PS1 power supply connector and the other end mated to the MCB DIN Connector.	4.6.4 Type 2070-1A CPU Main Controller Board		Manufacturing specification. Appropriate for a standard?	Inspection	Design
644	The VME bus lines shall be terminated by a 100-Ohm resistor per line.	4.6.4 Type 2070-1A CPU Main Controller Board			Analysis	Design

B.8 ATC Type 2070 Peripheral Equipment Requirements

#	Requirement (Standard Document Section)	Document Section Pass Fail	Comments	Test Type	Requirement Type
	General Notes				
645	1. The 2070-6x and 2070-7x modules shall provide circuitry to disable its Channel 2 and EIA-232 control lines (TX, RX, RTS, CTS, and DCD) when a ground true state is present at Connector A1, Pin B21 (C50 Enable). The disable lines shall be pulled up on this module			Inspection	Design
646	Line drivers/receivers shall be socket mounted or surface mounted.		What other mounting options exist? If drivers can be mounted either way, why is it specified?	Drop from the standard.	
647	 Isolation circuitry shall be opto- or capacitive-coupled isolation technologies. Each modules's circuit shall be capable of reliably passing a minimum of 1.0 megabits per second. 		Manufacturing specification.	Analysis	Design
648	4. The Comm modules shall be "Hot" swappable without damage to circuitry or operations.		Can this be tested with damaging the modules?	Analysis Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
649	A fused isolated +5 VDC with a minimum of 100 milliamperes power supply shall be provided for external use. Option – Bourns MF – MSMD020 PTC (Positive Temperature Coefficient) Resettable Fuse, or approved equal, allowed.	5.1.1 2070-6 A & B – Power Requirements			Inspection	Design
650	Two LOGIC switches per circuit shall be provided (faceplate mounted).	5.1.2 2070-6 A & B – Logic Switches		Why two (2) versus three (3)?	Inspection	Design
651	One logic switch shall be used to vertically switch between Half-Duplex (Down) and Full-Duplex (Up).	5.1.2 2070-6 A & B – Logic Switches			Inspection	Design
652	In Half-Duplex mode, the Transmit connections shall be used for both Receive and Transmit.	5.1.2 2070-6 A & B – Logic Switches			Analysis	Design
653	A MODEM Enable switch shall be provided such that when in the UP Position shall enable MODEM and disable MODEM in the DOWN Position.	5.1.2 2070-6 A & B – Logic Switches			Inspection Analysis	Design
654	Two circuits, designated CIRCUIT #1 and CIRCUIT #2, shall be provided.	5.1.3 2070-6 A & B – Circuitry			Inspection	Design
655	Both circuit functions shall be identical, except for their Serial Communications Port and external connector (CIRCUIT #1 to SP1 [or SP3] and C2S Connector and CIRCUIT #2 to SP2 [or SP4] and C20S Connector).	5.1.3 2070-6 A & B – Circuitry			Analysis	Design
656	The Circuits shall convert the 2070 UNIT Motherboard SP EIA-485 signals to/from board TTL level signals, isolate and drive the converted EIA-232 Signals interfacing with their associated MODEM and external connector.	5.1.3 2070-6 A & B – Circuitry			Analysis	Design
657	Each CIRCUIT shall have a MODEM with the following requirements:	5.1.3 2070-6 A & B – Circuitry				Design
658	 Data Rate: Baud modulation of 300 to 1200 for Module 2070-6A and 0 to 600 for Module 2070-6B. 	5.1.3 2070-6 A & B – Circuitry			Analysis	Design
659	2. Modulation: Phase coherent frequency shift keying (FSK).	5.1.3 2070-6 A & B – Circuitry			Analysis	Design
660	3. Data Format: Asynchronous, serial by bit.	5.1.3 2070-6 A & B – Circuitry			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
661	4. Line & Signal Requirements: Type 3002 voice-grade, unconditioned Tone Carrier Frequencies (Transmit and Receive):2070-6A - 1.2 KHz MARK and 2.2 KHz SPACE, +/-1% tolerance. 2070-6B - 11.2 KHz MARK and 17.6 KHz SPACE, +/-1% tolerance. The operating band shall be (half power, -3 dB) between 1.0 KHz & 2.4 KHz for 2070-6A and 9.9 KHz & 18.9 KHz for 2070-6B.	5.1.3 2070-6 A & B – Circuitry			Analysis	Design
662	5. Transmitting Output Signal Level: 0, -2, -4, -6, and -8 dB (at 1.7 KHz for 2070-6A & 14.7 KHz for 2070-6B) continuous or switch selectable.	5.1.3 2070-6 A & B – Circuitry			Analysis	Design
663	6. Receiver Input Sensitivity: 0 to -40 dB.	5.1.3 2070-6 A & B – Circuitry			Analysis	Design
664	7. Receiver Bandpass Filter: Shall meet the error rate requirement specified below and shall provide 20 dB/octave, minimum active attenuation for all frequencies outside the operating band.	5.1.3 2070-6 A & B – Circuitry			Analysis	Design
665	8. Clear-to-Send (CTS) Delay: 11 +/-3 milliseconds.	5.1.3 2070-6 A & B – Circuitry			Performance Test	Design
666	9. Receive Line Signal Detect Time: 8 +/-2 milliseconds mark frequency.	5.1.3 2070-6 A & B – Circuitry			Performance Test	Design
667	10. Receive Line Squelch: 6.5 (+/-1) milliseconds, 0 milliseconds (OUT).	5.1.3 2070-6 A & B – Circuitry			Performance Test	Design
668	11. Soft Carrier Turn Off Time: 10 +/-2 milliseconds (0.9 kilohertz for 2070- 6A and 7.8 kilohertz for 2070-6B). When the RTS is unasserted, the carrier shall turn off or go to soft carrier frequency.	5.1.3 2070-6 A & B – Circuitry			Performance Test	Design
669	 Modem Recovery Time: Capable of receiving data within 22 milliseconds after completion of transmission. 	5.1.3 2070-6 A & B – Circuitry			Performance Test	Design
670	13. Error Rate: Shall not exceed 1 bit in 100 kilobits, with a signal-to-noise ratio of 16 dB measured with flat-weight over a 300 to 3,000 Hertz band.	5.1.3 2070-6 A & B – Circuitry			Performance Test	Design
671	 Transmit Noise: Less than -50 dB across 600-ohms resistive load within the frequency spectrum of 300 to 3,000 Hertz at maximum output. 	5.1.3 2070-6 A & B – Circuitry			Analysis	Design
672	15. Modem interface: EIA-232 Standards.	5.1.3 2070-6 A & B – Circuitry		Need to dig up this specification.	Analysis	Design
673	A CONTROL switch shall be provided on the module front panel to turn ON (Up) / OFF (Down) all module power.	5.1.4 2070-6 A & B – Control Switch			Inspection	Design

#	Requirement (Standard Document Section)	-	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
674	Two circuits, designated CIRCUIT #1 and CIRCUIT #2, shall be provided.	5.2.1 2070-7A & 7B – Circuitry			Inspection	Design
675	The functions [of the two separate circuits] are identical, except for the CPU Serial Communications Port and external connector (CIRCUIT #1 to SP1 [or SP3] and Connector C21S and CIRCUIT #2 to SP2 [or SP4] and Connector C22S).	5.2.1 2070-7A & 7B – Circuitry			Inspection Analysis	Design
676	Each circuit shall convert its EIA-485 signal lines (RX, TX, RTS, CTS and DCD) to / from board TTL Level Signals; isolate both signal and ground; and drive / receive external EIA-232 devices via C21 / C22 Connectors.	5.2.2 2070 -7A			Analysis	Design
677	Connectors shall be DB-9S type.			Manufacturing specification?	Inspection	Design
678	Each circuit EIA-485 signal lines, (RX, TX, TXC (I), TXC (O) and RXC) and associated signal ground shall be board terminated to matching drivers/receivers; isolated both signal and ground, and drive/receiver external EIA-485 devices via C21/C22 Connectors.	5.2.3 2070 - 7B			Analysis	Design
679	Connectors shall be DB-15S type.	5.2.3 2070 - 7B		Manufacturing specification?	Inspection	Design
680	Each circuit signal TX and RX line shall have an LED Indicator mounted on the front plate and labeled to function.	5.2.4 2070-7A & 7B – Indicators			Inspection	Design

B.9 ATC Type 2070-2N NEMA Field I/O Module Requirements

#	Requirement (Standard Document Section)	Document Section Pass Fail	Comments	Test Type	Requirement Type
681	The 2070-2N Field I/O Module provides a TS2-1 compatible SDLC interface via 2070 Serial Port 3, AC Power to the 2070 Unit and Fault Monitor Logic Output via 2070 Serial Port 5 and Output Frame Byte 9 Bit 6 to the NEMA TS2 Cabinet Monitor Unit (CMU).	6.2.1 Interfaces		Analysis	Design
682	The Module shall meet the 2070–2A Module Requirements with the following exceptions: No C1, C11 and C12 Connectors on the front panel of the module No 64 inputs / 64 outputs requirements Serial Port 5 routed to the FCU MPU Device only Serial Port 3 shall not have a disabling switch	6.2.2 Type 2070-2N Module Requirements		Inspection	Design
683	The module shall be a 4X type board / front panel with three connectors.	6.2.3 Physical		Inspection	Design
684	The connectors are 10 Pin Connector A, a NEMA 5-15 Receptacle and a 15 Pin DB 15S C14 Connector.	6.2.3 Physical		Inspection	Design

#	Require	ment (Standard Docu	ment Sect	ion)			Document Section	Pass Fail	Comments	Test Type	Requirement Type
685		g 2070 AC Power is denent Ground).	rived from	Connector A Pin C (A	AC+), Pin A	(AC-), and Pin H	6.2.4 Power			Inspection	Design
686	The pow	er is directly routed to	the NEMA	5-15 Receptacle.			6.2.4 Power			Inspection	Design
687	Connecto	or A shall intermate wit	th a NEMA	A TS2 Type 1 (MS310	6O-18-1S)	cable.	6.2.4 Power		"intermate"? What type of word is that?	Inspection	Design
688		ule shall isolate 2070 S EIA 485 drivers/receive					6.2.5 Serial Port 3 Isolation			Inspection	Design
689	The Port	shall be clocked at 153	3.6 kilobits	per second.			6.2.5 Serial Port 3 Isolation			Analysis	Design
690	An FCU Pin F for	output shall drive a ope use as a FAULT MON	en collecto NTOR Ou	or transistor whose output.	out shall be	routed to Connector A	6.2.6 FCU Output			Analysis	Design
691	The trans	sistor shall be capable of	of sinking 2	200 milliamperes at 30	VDC.		6.2.6 FCU Output			Analysis	Design
692	Connecto	ors A and C14 pin out a $pr A$	and functio	ons are as follows:			6.2.7 Connector Pin Assignments			Analysis	Design
	Pin	Function	Pin	Function	Pin	Function					
	A	AC Neutral	Е	NA	I	NA					
	В	NA	F	Fault Monitor J	NA						
	С	AC Line	G	DC#2 Ground							
	D	NA	Н	Equip Ground							
	Connecto	or C14S									
	Pin	Function	Pin	Finction	Pin	Function					
	1	TX Data+	6	DC Ground	11	TX Clock -					
	2	DC Ground	7	RX Clock +	12	Equip Ground					
	3	TX Clock+	8	DC Ground	13	RX Data -					
	4	DC Ground	9	TX Data -	14	NA					
	5	RX Data+	10	NA	15	RX Clock –					
693		ort 3 shall control the TS rame Command / Resp			col that mee	ets the NEMA TS2	6.2.8 TS2 BIU Control		Need to dig up this specification.	Analysis	Design

B.10 ATC Type 2070-4N NEMA Power Supply Module Requirements

#	Requirement (Standard Document Section)	Document Section Pass Fail	Comments	Test Type	Requirement Type
694	The 2070-4N Power Supply Module supports the NEMA TS1 and TS2 Standards. The module is identical to the 2070-4N (A and B) Power Supply Requirements except for the following:	6.3.1 Requirements			Design
695	1) The power cord shall have a 15 inch +/- 1 inch length as measured from the panel to the plug tips.	6.3.1 Requirements		Inspection	Design
696	2) The AC Power Fail voltage shall be 85VAC +/-2VAC.	6.3.1 Requirements		Inspection	Design
697	3) The AC Power Restore voltage shall be 90VAC +/-2VAC.	6.3.1 Requirements		Analysis	Design
698	4) The 2070-4N (A or B) power supply shall have proper marking Example "2070 4N (A or B)". A permanent sticker shall be an acceptable marking method.	6.3.1 Requirements		Inspection	Design

B.11 ATC Type 2070-8 NEMA Field I/O Module Requirements

#	Requirement (Standard Document Section)		Pass Comments	Test Type	Requirement Type
	The MODULE FRONT PANEL shall be furnished with the following:				
704	ON/OFF POWER Switch mounted vertically with ON in the UP position.	6.4.2 Module Front Panel		Inspection	Design
705	2. LED DC Power Indicator. The indicator shall indicate that the required + 5 VDC is within 5% and the +24 VDC is within 8%.	6.4.2 Module Front Panel		Analysis	Design
706	3. Incoming VAC fuse protection.	6.4.2 Module Front Panel		Inspection	Design
707	4. Two DB-25S COMM connectors labeled "EX1" & "EX2."	6.4.2 Module Front Panel		Inspection	Design
708	5. Four NEMA Connectors A, B, C, & D.	6.4.2 Module Front Panel		Inspection	Design
709	A permanent LABEL shall be affixed to the Front Panel.	6.4.3 Label		Inspection	Design
710	The label shall display the unit's serial number.	6.4.3 Label		Inspection	Design
711	The number shall be permanent and easy to read.	6.4.3 Label	"Easy to read" is a poor specification.	Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
712	A MODULE POWER SUPPLY shall be provided and located on the right side of the module as viewed from the front.	6.4.4 Module Power Supply			Inspection	Design
713	The supply shall provide the necessary module internal circuitry DC power plus 2.0 Amperes minimum of +24 VDC for external logic, detector inputs, and output load control.	6.4.4 Module Power Supply			Analysis	Design
714	The supply shall [also] meet the following requirements:	6.4.4 Module Power Supply				Design
715	The standard contains this language: "Specification 4.5.6 POWER SUPPLY REQUIREMENTS except Specification 4.5.3. In the previous section, the standard specifies that Specification 4.5.3 applies.	6.4.4 Module Power Supply		There is confusion in the specification.	Obtain clarification.	Design
716	Two 0.5-Ohm, 10-watt wire-wound power resistors with a 0.2 micro Henries inductance shall be provided (one on the AC+ Line & on the AC- Line).	6.4.4 Module Power Supply			Inspection	Design
717	Three 20 Joule surge arrestors shall be provided between AC+ to AC-, AC+ to EG, and AC- to EG. A 0.68 µF capacitor shall be placed between AC+ & AC- (between the resistor & arrestors).	6.4.4 Module Power Supply			Analysis	Design
719	Line / Load Regulation shall meet the table tolerance values for voltage range of 90 to 135 VDC, the maximum and minimum loads called out in the table and including ripple noise.	6.4.4 Module Power Supply			Analysis	Design
720	Power Supply Efficiency shall be 70% minimum.	6.4.4 Module Power Supply		What does this standard mean relative to the performance of the device?	Analysis	Design
721	Power Supply Ripple and Noise shall be less than 0.2% RMS, 1% peak to peak or 50 millivolts, whichever is greater.	6.4.4 Module Power Supply		What does this standard mean relative to the performance of the device?	Analysis	Design
722	Power Supply Output Overshoot shall be no greater than 5%, all outputs.	6.4.4 Module Power Supply			Analysis	Design
723	Power Supply Overvoltage Protection shall be 130% Vout for all outputs.	6.4.4 Module Power Supply			Analysis	Design
724	Power Supply Circuit protection shall be implemented to provide automatic recovery upon removal of fault.	6.4.4 Module Power Supply			Analysis	Design
725	Power Supply Cold Start Inrush shall be less than 25 amperes at 115VAC.	6.4.4 Module Power Supply			Performance Test	Design
726	Power Supply Transient response shall be such that output voltage back to within 1% in less than 500 microseconds on a 50% Load change.	6.4.4 Module Power Supply			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
730	Power Supply Remote sense shall be implemented such that +5 VDC compensates 250 millivolts total line drop.	6.4.4 Module Power Supply			Analysis	Design
731	Power Supply open sense load protection required.	6.4.4 Module Power Supply		What does this mean?	Analysis	Design
732	DC Voltage tolerances shall be +/-3%.	6.4.4 Module Power Supply			Analysis	Design
733	The supplied INCOMING AC POWER shall be derived from Connector A Pins "p" (AC+) and "U" (AC Neutral).	6.4.5 Incoming AC Power			Inspection	Design
734	External +24 VDC shall be at Connector A, Pin "B" and Connector D Pin "NN."	6.4.5 Incoming AC Power			Inspection	Design
735	AC Power for the 2070 receptacle shall be tapped off from the secondary side of the ON Switch / Fuse configuration.	6.4.5 Incoming AC Power			Inspection	Design
736	A MODULE PC Boards shall be mounted vertically.	6.4.6 Module PC Boards			Inspection	Design
737	Power Down, NRESET, and LINESYNC shall be routed to the module via C12 Connector.	6.4.7 Power Down, NRESET, and LINESYNC			Inspection	Design
738	The state of the module output ports at the time of Power Down transition to LOW State and until NRESET goes HIGH shall be an open circuit.	6.4.7 Power Down, NRESET, and LINESYNC			Analysis	Design
739	The requirements from section 4.3 are repeated here for clarity, with all exceptions, as described in the standard.	6.4.8 Compliance with Type 2070-2 Field I/O Requirements				Design
740	Parallel Ports, consisting of 118 Bits of Input and 102 bits of Output, shall be provided.	6.4.8.1 Parallel I/O Ports		The requirements between Sections 6.4.8 and Section 6.4.9 are copied from Section 4.3, as specified in the Standard, and numbered to fit.	Analysis	Design
743	The I/O Ports shall provide 64 bits of output.	6.4.8.1 Parallel I/O Ports		Is "ground-true" logic important here? Why or why not? What is ground-true logic? It sounds like a brand name.	Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
744	Inputs shall have the following characteristics: 1. A voltage between 0 and 4 volts shall be considered the Low (True/Operate) state. 2. A voltage greater than 8 volts shall be considered the High (False) state. 3. The transition from the Low state to High state (and vice versa) shall occur between 4	6.4.8.1 Parallel I/O Ports			Analysis	Design
745	and 8 volts. Outputs shall have the following characteristics: 1. The Low (True/Operate) voltage shall be between 0 and 3 volts. 2. Current sinking capability in the Low state shall be at least 100 milliamperes. 3. With an external impedance of 100 kiloOhms or greater, the transition from 4 to 16 volts (and vice versa) shall be accomplished within 0.1 millisecond. 4. The High state impedance shall exceed 1 Megohms to 12 volts DC.	6.4.8.1 Parallel I/O Ports			Analysis	Design
749	It shall be possible to simultaneously assert all outputs within 100 microseconds of each other.	6.4.8.1 Parallel I/O Ports			Performance Test Analysis	Design
751	The LINESYNC signal is incoming in differential logic.	Other Module Circuit Functions			Analysis	Design
752	A maximum capacitive load of 100 picofarads shall be presented to the LINESYNC input signal.	Other Module Circuit Functions			Analysis	Design
753	An External WDT "Muzzle" Jumper shall be provided on the board.	Other Module Circuit Functions			Inspection	Design
755	When the jumper is missing (open), the feature shall not apply.	Other Module Circuit Functions		If the standard requires a jumper, why would the performance without the jumper need to be specified.	Inspection	Design
756	This feature is required to operate with the Type 210 Monitor Unit only.	Other Module Circuit Functions		Unclear as to why this is in the standard.	Analysis	Design
757	A WATCHDOG Circuit shall be provided.	Other Module Circuit Functions			Inspection	Design
758	The WATCHDOG Circuit shall be enabled by the FIELD I/O software at Power Up with a value of 100 milliseconds.	Other Module Circuit Functions			Analysis	Design
759	The enabled state of the WATCHDOG Circuit shall be machine readable and reported in the FI/O status byte.	Other Module Circuit Functions			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
762	A synchronizable 1 kilohertz time reference shall be provided.	Other Module Circuit Functions			Inspection	Design
763	The synchronizable time reference shall maintain a frequency accuracy of +/-0.01% (+/-0.1 counts per second).	Other Module Circuit Functions			Analysis	Design
764	A 32-bit MILLISECOND COUNTER (MC) shall be provided for "timestamping."	Other Module Circuit Functions			Inspection	Design
765	Each 1 KHz reference interrupt shall increment the MC.	Other Module Circuit Functions			Analysis	Design
767	A LOGIC Switch shall be provided resident on the module board.	Other Module Circuit Functions			Inspection	Design
768	The switch shall function to disconnect Serial Port 3 (SP3) from the external world, Connector C12S.	Other Module Circuit Functions			Inspection	Design
769	The purpose of the switch is to prevent multiple use of SP3.	Other Module Circuit Functions			Analysis	Design
770	An LED shall be provided on the module front panel labeled "SP3 ON".	Other Module Circuit Functions			Inspection	Design
772	The module shall interface with the 2070-2B Field I/O module via HAR 1 Harness meeting EIA-485 Requirements.	6.4.8.2 Serial Communications Circuitry		Is this a specific standard that we can find?	Analysis	Design
773	All signal lines shall be isolated.	6.4.8.2 Serial Communications Circuitry			Inspection	Design
774	HAR 1 Harness shall be 17 lines minimum with a C12P Connector on one end and soldered with strain relief on the other.	6.4.8.2 Serial Communications Circuitry			Inspection	Design
775	In addition to the Controller interface, the EIA-485 Signal lines shall be routed to EX1 Connector.	6.4.8.2 Serial Communications Circuitry			Inspection	Design
776	All necessary driver/receiver and isolation circuitry shall be provided.	6.4.8.2 Serial Communications Circuitry			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
777	System Serial Port 5 (SP5) EIA 485 signal lines shall enter the I/O Module and be split into two-multi-drop isolated ports.	6.4.8.2 Serial Communications Circuitry		Are these the requirements that change given the exception? Not clear!	Analysis	Design
778	One [serial port line of SP5] shall be routed to the FCU and the other converted to EIA 485, then routed to Connector C12S.	6.4.8.2 Serial Communications Circuitry		Are these the requirements that change given the exception? Not clear!	Inspection	Design
779	System Serial Port 3 (SP3) EIA 485 signal lines shall enter the I/O module and be isolated, converted back to EIA 485 and then routed to connector C12S.	6.4.8.2 Serial Communications Circuitry		Are these the requirements that change given the exception? Not clear!	Inspection	Design
780	LINE SYNC and POWER DOWN lines shall be split and isolated, one routed to the FCU for shut down functions and the other changed to EIA-485; then routed to connector C12S for external module use.	6.4.8.2 Serial Communications Circuitry			Inspection	Design
781	CPU RESET and POWER UP (SYSRESET) lines shall be isolated and "OR'd" to form NRESET.	6.4.8.2 Serial Communications Circuitry			Inspection	Design
782	NRESET shall be used to reset FCU and other module devices.	6.4.8.2 Serial Communications Circuitry			Analysis	Design
783	NRESET shall also be converted to EIA-485 then routed to connector C12S.	6.4.8.2 Serial Communications Circuitry			Inspection	Design
784	If the Type 2070 module is a –2B, then routing to FCU doesn't apply.	6.4.8.2 Serial Communications Circuitry		Unclear as to why this is in the standard.	Analysis	Design
785	Isolation is between internal +5 VDC / Ground #1 and +12 VDC ISO / VDC Ground #2.	6.4.8.2 Serial Communications Circuitry			Analysis	Design
786	+12 VDC ISO is for board power and external logic.	6.4.8.2 Serial Communications Circuitry		Unclear as to why this is in the standard.	Analysis	Design
787	A Transition Buffer shall be provided capable of holding a minimum of 1024 recorded entries.	Buffers			Analysis	Design
789	There shall be two entry types (in the Transition Buffer): Transition and Rollover.	Buffers			Analysis	Design
790	The inputs (to the Transition Buffer) shall be monitored for state transition.	Buffers			Analysis	Design

#	Requirement (Standard Docume	nt Sectio	on)							Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
792	The MC shall be monitored for rol	lover.								Buffers			Analysis	Design
793	At each rollover transition (\$xxxx Transition Buffer.	FFFF - \$	XXXX	0000	0), a r	ollove	r entr	y shall b	e added to the	Buffers		In order to test this, one needs to know what causes a roll-over and be able to create on during testing.	Performance Test	Design
794	For rollover entries, all bits of byte	1 are se	t to in	dicat	te tha	this is	s a ro	llover er	ntry.	Buffers			Analysis	Design
797	The entry types are depicted as follows: Input Transition Entry									Buffers			Analysis	Design
	DescriptionmsblsbByte NumberTransition Entry IdentifierSInput Number1						lsb	Byte Number						
								1						
	MC Timestamp NLSB	X	X	X	X	X	X	X X	2					
	MC Timestamp LSB	X	X	X	X	X	X	x x	3					
	Millisecond Counter Rollover Entr Description Rollover Entry Identifier	<i>msl</i>	5 1	1	1	1	1	<i>lsb</i>	Byte Number					
	MC Timestamp MSB	X	X	X	X	X	X	x x	2					
	MC Timestamp NMSB	X	X	X	X			X X	3					
798	I/O Functions	•				•	•	•						Design
799	Input scanning shall begin at I0 (bi LSB to MSB.	t 0) and j	proce	ed to	the h	ighest	num	bered in	out, ascending from	I/O Functions			Analysis	Design
801	Once sampled, the logic state of an	input sh	all be	e held	d unti	the ne	ext in	put scan		I/O Functions			Performance Test	Design
802	Each input shall be sampled 1,000	times pe	r seco	ond.						I/O Functions			Analysis	Design
803	The time interval between samples	shall be	1 mil	llisec	ond (+/-100) mic	rosecono	ls).	I/O Functions			Analysis	Design
806	The Millisecond Counter shall be s scan.	sampled	within	n 10 i	micro	secono	ds of	the com	pletion of the input	I/O Functions			Analysis	Design
807	If configured, the inputs shall be fi	ltered by	the F	FCU 1	to ren	iove si	ignal	bounce.		I/O Functions		What does "if configured" mean in this context? Why would the inputs not be configured?	Analysis	Design
808	The filtered input signals shall ther	n be mon	itorec	d for	chang	es as 1	noted			I/O Functions			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
809	The filtering parameters for each input shall consist of Ignore Input Flag and the ON and OFF filter samples.	I/O Functions			Analysis	Design
810	If the Ignore Input flag is set, no input transitions shall be recorded.	I/O Functions			Analysis	Design
811	The ON and OFF filter samples shall determine the number of consecutive samples an input must be ON and OFF, respectively, before a change of state is recognized.	I/O Functions			Analysis	Design
812	If the change of state is shorter than the specified value, the change of state shall be ignored.	I/O Functions			Analysis	Design
					Performance Test	
813	The ON and OFF filter values shall be in the range of 0 to 255.	I/O Functions			Analysis	Design
814	A filter value of 0, for either or both values, shall result in no filtering for this input.	I/O Functions			Analysis	Design
815	The default values for input signals after reset shall be as follows:	I/O Functions			Inspection	Design
	<u>Input Signals</u> <u>Default Value</u>					
	Filtering Enabled					
	On and off filter values shall be set to 5					
	Transition monitoring Disabled (Timestamps are not logged)					
816	Simultaneous assertion of all outputs shall occur within 100 microseconds.	I/O Functions			Analysis	Design
					Performance Test	
817	Each output shall be capable of being individually configured in state to ON, OFF, or a state synchronized with either phase of LINESYNC.	I/O Functions			Analysis	Design
818	The condition of the outputs shall only be "ON" if the FI/O continues to receive active communications from the CPU Module.	I/O Functions			Analysis	Design
819	If there is no valid communications with the CPU Module for 2.0 seconds, all outputs shall revert	I/O Functions			Analysis	Design
	to the OFF condition, and the FI/O status byte shall be updated to reflect the loss of communication from the CPU Module.				Performance Test	

#	Requirem	ent (Standar	d Document S	Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
820	follows:	nd control bit Translation	s in the CPU M	Module-FI/O frame protocol shall control each output as	I/O Functions			Analysis	Design
	Case	Output Data Bit	Output Control Bit	Function					
	A	0	0	Output in the OFF state					
	В	1	1	Output is a square wave, synchronized to the LINESYNC signal. When LINESYNC is ON (1), the output is OFF, and when LINESYNC is OFF (0), the output is ON.					
	С	0	1	Output is a square wave, synchronized to the LINESYNC signal. When LINESYNC is ON (1), the output is ON, and when LINESYNC is OFF (0), the output is OFF					
	D	1	0	Output is in the ON state.					
824	All outputs	s shall never o	change state un	lless configured to do so.	I/O Functions		"Never" is very, very difficult to test.	Analysis	Design
825	All interru		apable of async	chronous operation with respect to all processing and all	I/O Functions			Analysis	Design
828	LINESYN LINESYN		This interrupt	shall be generated by both the 0-1 and 1-0 transitions of the	I/O Functions			Analysis Performance Test	Design
829		terrupt from t		or the MC interrupt and set the MC error flag if there has not source for 0.5 seconds (>/=60 consecutive LINESYNC	I/O Functions			Analysis	Design
830			pt shall synchr al once a secon	onize the 1 kilohertz time reference with the 0-1 transition d.	I/O Functions			Analysis Performance Test	Design
831				The LINESYNC interrupt has not successfully executed for tive millisecond interrupts).	I/O Functions			Analysis Performance Test	Design
832		el communica 85 communic		utine shall be provided to handle reception, transmission,	I/O Functions			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
833	The communication server shall automatically:	I/O Functions			Analysis	Design
	<u>For Transmission</u>				Performance Test	
	Generate the opening and closing flags					
	Generate the CRC value					
	Generate the abort sequence (minimum of 8 consecutive '1' bits) when commanded by the FCU					
	Provide zero bit insertion					
	For Receiving					
	Detect the opening and closing flags					
	Provide address comparison, generating an interrupt for messages addressed to the I/O Module, and ignoring messages not addressed to the I/O Module					
	Strip out inserted zeros					
	Calculate the CRC value, compare it to the received value, and generate an interrupt on					
	an error					
	Generate an interrupt if an abort sequence is received					
834	The task shall be to process the command messages received from the CPU Module, prepare, and start response transmission.	I/O Functions			Analysis	Design
835	The response message transmission shall begin within 4 milliseconds of the receipt of the received	I/O Functions			Analysis	Design
	message.				Performance Test	
836	The time from the receipt of message to the completion of the commanded task shall not exceed 70	I/O Functions			Analysis	Design
	milliseconds.				Performance Test	
837	This task shall process the raw input data scanned in by the 1 ms interrupt routine, perform all filtering, and maintain the transition queue entries.	I/O Functions			Analysis	Design
838	All communication with the CPU Module shall be SDLC-compatible command-response protocol, support 0 bit stuffing, and operate at a data rate of 614.4 kilobits per second.	Data Communications Protocols			Analysis	Design
839	The CPU Module shall always initiate the communication and should the command frame be	Data Communications			Analysis	Design
	incomplete or in error, no FI/O response shall be transmitted.	Protocols			Performance Test	
840	The amount of bytes of a command or response is dependent upon the I/O Module identification.	Data Communications Protocols			Analysis	Design
841	The frame type shall be determined by the value of the first byte of the message.	Data Communications Protocols			Analysis	Design

#	Requirement (Standard Document Section)	Document Section Pass Fail	Comments	Test Type	Requirement Type
842	The command frames type values 112-127 and associated response frame type values 240-255 are allocated to the manufacturer diagnostics.	Data Communications Protocols		Analysis	Design
843	All other frame types not called out are reserved.	Data Communications Protocols		Analysis	Design

#	Requirement	(Standard Do	cument Section)			Document Section	Pass Fail	Comments	Test Type	Requirement Type
844	The command follows: Frame Types	-response Fran	ne Type values and message ti	mes shall be as		Data Communications Protocols			Analysis	Design
	Module Command	I/0 Module Response	Description	Minimum Message Time	Maximum Message Time					
	0-43	128-171	Reserved for NEMA TS-2	•						
	49	177	Request Module Status	250 microseconds	275 microseconds					
	50	178	MILLISECOND CTR. Mgmt.	222.5 microseconds	237.5 microseconds					
	51	179	Configure Inputs	344.5 microseconds	6.8750 milliseconds					
	52	180	Poll Raw Input Data	317.5 microseconds	320 microseconds					
	53	181 Poll Filtered Input Data 317.5		317.5 microseconds	320 microseconds					
	54	182	Poll Input Transition Buffer	300 microseconds	10.25 microseconds					
	55	183	Command Outputs	405 microseconds	410 microseconds					
	56	184	Reserved	340 microseconds	10.25 milliseconds					
	57	185	Reserved	340 microseconds	6.875 milliseconds					
	58	186	Configure Watchdog	222.5 microseconds	222.5 microseconds					
	59	187	Controller Identification	222.5 microseconds	222.5 microseconds					
	60	188	I/O Module Identification	222.5 microseconds	222.5 microseconds					
	61-62	189-190	Reserved (note below)							
	63	191	Poll variable length raw input	317.5 microseconds	320 microseconds					
	64	192	Variable length command outputs	405 microseconds	410 microseconds					
	65	193	Reserved (note below)							
	67	195	Reserved (note below)							
15	Messages 61 /	189, 62 / 190,	65 / 193, and 67 / 195 are reso	erved for ITS Cabine	et Frame Types.	Data Communications Protocols		Software design specification.	Analysis	Design

#	Requirement (Standard Docume	nt Section)		Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
846	Message 63 / Message 191 shall be response shall denote the following	e the same as Message 52 / 180 except Byt g number of input data bytes.	te 2 of Message 180	Data Communications Protocols		Software design specification.	Analysis	Design
847		e as Message 55 / 183 except Byte 2 of the of output data bytes, plus the following o		Data Communications Protocols		Software design specification. Poorly worded.	Analysis	Design
848	The Command shall be used to req Command/response frames are as t Request Module Status Command	uest FI/O status information response. follows:		Data Communications Protocols		Poorly worded. "This" command?	Analysis	Design
	Description	msb lsb	Byte Number					
	(Type Number = 49)	0 0 1 1 0 0 0 1	Byte 1					
	Reset Status Bits	P E K R T M L W	Byte 2					
849	Request Module Status Response			Data Communications			Analysis	Design
	Description	msb lsb	Byte Number	Protocols				
	(Type Number = 177)	1 0 1 1 0 0 0 1	Byte 1					
	System Status	P E K R T M L W	Byte 2					
	SCC Receive Error Count	Receive Error Count	Byte 3					
	SCC Transmit Error Count	Transmit Error Count	Byte 4					
	MC Timestamp MSB	MC Timestamp MSB	Byte 5					
	MC Timestamp NMSB	MC Timestamp NMSB	Byte 6					
	MC Timestamp NLSB	MC Timestamp NLSB	Byte 7					
	MC Timestamp LSB	MC Timestamp LSB	Byte 8					
850	K - Indicates the Datak R - Indicates that the E T - Indicates that the E M - Indicates an error v L - Indicates an error in	Iware reset nications loss of greater than 2 seconds tey has failed or is not present IA-485 receive error count byte has rolled IA-485 transmit error count byte has rolled with the MC interrupt		Data Communications Protocols			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
851	The FI/O status byte shall be updated (set to '1') to reflect the faults noted in clause 4.3.9.2.1.	Data Communications Protocols			Analysis	Design
852	Each status bit shall only be reset (set to '0') when the corresponding bit of the Request Module Status Command is a '1'.	Data Communications Protocols			Analysis	Design
853	The Request Module Status Response shall report the current status (subsequent to reset and sampling).	Data Communications Protocols			Analysis	Design
854	The FI/O shall count the number of errored frames the FI/O Communications Processor reports.	Data Communications Protocols			Analysis	Design
855	Separate counts shall be maintained for transmit and received frames.	Data Communications Protocols			Analysis	Design
856	When an individual count rolls over (255-0), the corresponding roll-over flag shall be set.	Data Communications Protocols			Analysis Performance Test	Design
857	FI/O modules with Datakey: On NRESET transition to High or immediately prior to any interrogation of the Datakey, the FI/O shall test the presence of the Key.	Data Communications Protocols			Analysis	Design
861	The MC timestamp value shall be sampled just prior to the Request Module Status Response.	Data Communications Protocols			Analysis	Design
862	MC MANAGEMENT frame shall be used to set the value of the MC.	Data Communications Protocols			Analysis	Design
864	The 32-bit value shall be loaded into the MC at the next 0-1 transition of the LINESYNC signal.	Data Communications Protocols			Analysis	Design

#	Requirement (Standard Docume	ent Section)			Document Section	Pass Fail	Comments	Test Type	Requirement Type
865	The frames are as follows: Millisecond Counter Management	Command			Data Communications Protocols			Analysis	Design
	Description	msb	lsb	Byte Number					
	(Type Number = 50)	0 0 1 1 0 0 1	0	Byte 1					
	New MC Timestamp MSB	x x x x x x x x	X	Byte 2					
	New MC Timestamp NMSB	x x x x x x x x	X	Byte 3					
	New MC Timestamp NLSB	x x x x x x x x	X	Byte 4					
	New MC Timestamp LSB	X X X X X X X	X	Byte 5					
	Millisecond Counter Management	Response							
	Description	msb	lsb	Byte Number					
	(Type Number = 178)	1 0 1 1 0 0 1	0	Byte 1					
	Status	0 0 0 0 0 0 0	S	Byte 2					
866	The Configure Inputs command fr	ame shall be used to change input co	nfigu	rations.	Data Communications Protocols			Analysis	Design
867	The command-response frames are Configure Inputs Command	e as follows:			Data Communications Protocols			Analysis	Design
	Description	msb	lsb	Byte Number					
	(Type Number = 51)	0 0 1 1 0 0 1	1	Byte 1					
	Number of Items (n)	n n n n n n n	n	Byte 2					
	Item # - Byte 1	E Input Number		Byte 3(I-1)+3					
	Item # - Byte 2	Leading edge filter (e)		Byte 3(I-1)+4					
	Item # - Byte 3	Trailing edge filter (r)		Byte 3(I-1)+5					
	Configure Inputs Response								
	Description	msb	lsb	Byte Number					
	(Type Number = 179)	1 0 1 1 0 0 1	1	Byte 1					
	Status	0 0 0 0 0 0 0	S	Byte 2					

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
868	Block field definitions shall be as follows:	Data Communications Protocols			Analysis	Design
	E Ignore Input Flag. "1" = do not report transitions for this input, "0" = report transitions for this input					
	A one-byte leading edge filter specifying the number of consecutive input e - samples which must be "0" before the input is considered to have entered to "0" state from "1" state (range 1 to 255, 0 = disabled)					
	A one-byte trailing edge filter specifying the number of consecutive input r - samples which must be "1" before the input is considered to have entered to "1" state from "0" state (range 1 to 255, 0 = disabled)					
	S - return status $S = 0$ on completion or 11 on input error out of range					
869	The Poll Raw Input Data frame shall be used to poll the FI/O for the current unfiltered status of all inputs.	Data Communications Protocols			Analysis	Design
870	The response frame shall contain 8 bytes (2A) or 15 bytes (2B) of information indicating the current input status.	Data Communications Protocols			Analysis	Design

#	Requirement (Standard Document	ıt Section	1)								Document Section	Pass Fail	Comments	Test Type	Requirement Type
871	The frames are as follows:										Data Communications			Analysis	Design
	Poll Raw Input Data Command										Protocols				
	Description	msb	1						lsb	Byte Number					
	(TypeNumber = 52)	0	0	1	1	0	1	0	0	Byte 1					
	Poll Raw Input Data Response (207	70-2A)													
	Description	msb							lsb	Byte Number					
	(Type Number = 180)	1	0	1	1	0	1	0	0	Byte 1					
	Inputs I0 (lsb) to I7 (msb)	X	X	X	X	X	X	X	X	Byte 2					
	Inputs I8 to I63	Х	X	X	X	X	X	X	X	Bytes 3 to 9					
	MC Timestamp MSB	X	X	X	X	X	X	X	X	Byte 10					
	MC Timestamp NMSB	Х	X	X	X	X	X	X	X	Byte 11					
	MC Timestamp NLSB	Х	X	X	X	X	X	X	X	Byte 12					
	MC Timestamp LSB	X	X	X	X	x x x x x Byte 13									
	Poll Raw Input Data Response (207	70-8)													
	Description	msb							lsb	Byte Number					
	(Type Number = 180)	1	0	1	1	0	1	0	0	Byte 1					
	Inputs I0 (lsb) to I7 (msb)	X	X	X	X	X	X	X	X	Byte 2					
	Inputs I8 to I119	X	X	X	X	X	X	X	X	Bytes 3 to 16					
	MC Timestamp MSB	X	X	X	X	X	X	X	X	Byte 17					
	MC Timestamp NMSB	X	X	X	X	X	X	X	X	Byte 18					
	MC Timestamp NLSB	X	X	X	X	X	X	X	X	Byte 19					
	MC Timestamp LSB	X	X	X	X	X	X	x	X	Byte 20					
872	The Poll Filtered Input Data frame inputs.	shall be u	sed to	pol	l the	FI/C	for	the c	current	filtered status of all	Data Communications Protocols			Analysis	Design
873	The response frame shall contain 8 current filtered status of the inputs.	bytes (2A	(A) or 1	15 by	ytes (2B)	of in	form	ation	indicating the	Data Communications Protocols			Analysis	Design

#	Requirement (Standard Document Section)										Document Section	Pass Fail	Comments	Test Type	Requirement Type	
874	Raw input data shall be provided in	the respon	nse f	or in	puts	that	are r	not c	onfigu	red for filtering.	Data Communications Protocols			Analysis	Design	
875	The frames are as follows:										Data Communications			Analysis	Design	
	Poll Filter Input Data Command										Protocols					
	Description	msb							lsb	Byte Number						
	(TypeNumber = 53)	0	0	1	1	0	1	0	1	Byte 1						
	Poll Filter Input Data Response (20	070-2A)														
	Description	cription msb								Byte Number						
	(Type Number = 180)	1	0	1	1	0	1	0	0	Byte 1						
	Inputs I0 (lsb) to I7 (msb)	Х	Х	Х	X	Х	Х	X	X	Byte 2						
	Inputs I8 to I63	X	X	X	X	X	X	X	X	Bytes 3 to 9						
	MC Timestamp MSB		X	X	X	Byte 10										
	MC Timestamp NMSB		Byte 11													
	MC Timestamp NLSB	Х	X	X	X	X	X	X	X	Byte 12	-					
	MC Timestamp LSB	X	X	X	X	X	X	X	X	Byte 13						
	Poll Filter Input Data Response (20	070-8)														
	Description	msb							lsb	Byte Number						
	(Type Number = 181)	1	0	1	1	0	1	0	1	Byte 1						
	Inputs I0 (lsb) to I7 (msb)	X	X	Х	X	X	X	X	X	Byte 2						
	Inputs I8 to I119	X	X	Х	X	X	X	X	X	Bytes 3 to 16						
	MC Timestamp MSB	X	X	Х	X	X	X	X	X	Byte 17						
	MC Timestamp NMSB	X	X	X	X	X	X	X	X	Byte 18						
	MC Timestamp NLSB	X	X	Х	X	X	X	X	X	Byte 19						
	MC Timestamp LSB	X	X	Х	X	Х	X	X	X	Byte 20						
876	The Poll Input Transition Buffer frame shall poll the FI/O for the contents of the input transition buffer.										Data Communications Protocols			Analysis	Design	

#	Requirement (Standard Document Section)									Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
877	The response frame shall include a thr have occurred since the last interrogat		infor	mati	on f	ield	for ea	ch of tl	ne input changes that	Data Communications Protocols			Analysis	Design
878	The frames are as follows: Poll Input Transition Buffer Command	!								Data Communications Protocols			Analysis	Design
	Description	msb						lsb	Byte Number					
	(Type Number = 54)	0	0	1	1	0	1 1	0	Byte 1					
	Block Number	X	X	X	X	X	x x	X	Byte 2					
	Poll Input Transition Buffer Response													
	Description	msb						lsb	Byte Number					
	(Type Number = 182)	0	0	1	1	0	0 1	1	Byte 1					
	Block Number	X	X	X	X	X	x x	X	Byte 2					
	Number of Entries	X	X	X	X	X	x x	. X	Byte 3					
	Item#	S]	nput	t Nu	ımber		Byte 3(I-1)+4					
	Item # MC Timestamp NLSB	X	X	X	X	X	x x	X	Byte 3(I-1)+5					
	Item # MC Timestamp LSB	X	X	X		x	x x	. x	Byte 3(I-1)+6					
	Status	0	0	0	0	C	F E	G	Byte 3(I-1)+7					
	MC Timestamp MSB	X	X	X	X	X	X X	. X	Byte 3(I-1)+8					
	MC Timestamp NMSB	X	X	X	X	x	x x	. x	Byte 3(I-1)+9					
	MC Timestamp NLSB	X	X	X	X	X	X X	. x	Byte 3(I-1)+10					
	MC Timestamp LSB	X	X	X	X	X	X X	X	Byte 3(I-1)+11					
879	Each detected state transition for each as it occurs.	Each detected state transition for each active input (see configuration data) is placed in the queue as it occurs.						data) is	s placed in the queue	Data Communications Protocols			Analysis	Design
882	Bit definitions are as follows: S - Indicates the state of	ıt afte	er the	e trai	ısiti	on			Data Communications Protocols			Analysis	Design	
	C - Indicates the 255 tran						eeded							
	F - Indicates the transition													
	G - Indicates the requeste								ocrement seguence					
	E - Same block number i							wiiic II	icrement sequence					
	E - Same block number i	equeste	u, E	is se	. ın r	espo	onse							

#	Requirement (Standard Document Section)								Document Section	Pass Fail	Comments	Test Type	Requirement Type
883	The Block Number byte is a monotonica issued by the CPU Module.	lly incre	easing	num	ber in	creme	ented at	ter each command	Data Communications Protocols			Analysis	Design
889	The Block Number byte sent in the responsible command block.	onse blo	ck sha	ıll be	the sa	ame as	that re	eceived in the	Data Communications Protocols			Analysis	Design
890	Counter rollover shall be considered as a	incre	ment	•				Data Communications Protocols			Analysis	Design	
892	The Set Outputs frame shall be used to command the FI/O to set the Outputs according to the data in the frame.								Data Communications Protocols			Analysis	Design
893	If there is any error configuring the outputs, the 'E' flag in the response frame shall be set to '1'.							shall be set to '1'.	Data Communications Protocols			Analysis	Design
894	If the LINESYNC reference has been lost, the 'L' bit in the response frame shall be set.								Data Communications Protocols			Analysis	Design
895	Loss of LINESYNC reference shall also	be indic	cated i	n sys	stem s	tatus i	nforma	tion.	Data Communications Protocols			Analysis	Design
896	The output bytes depend upon field I/O module. These command and response frames are as follows: Set Outputs Command								Data Communications Protocols			Analysis	Design
	Description	ms	b				lsb	Byte Number					
	(Type Number = 55)	0	0	1	1 0	1	1 1	Byte 1					
	Outputs O0 (lsb) to O7 (msb) Data	X	х	X	x x	X	x x	Byte 2					
	Outputs O8 to O103 Data	X	X	X	x x	X	x x	Bytes 3 to 14					
	Outputs O0 (lsb) to O7 (msb) Control	X			X X	-	X X	Byte 15					
	Outputs O8 to O103 Control	X	X	X	X X	X	X X	Bytes 16 to 27					
	Set Outputs Response												
	Description n	ısb					lsb	Byte Number					
	(Type Number = 183)	1 0	1	1	0 1	. 1	1	Byte 1					
	Status	0 0	0	0	0 (L	Е	Byte 2					

#	Requirement (Standard Document	Section)		Document Section	Pass Fail	Comments	Test Type	Requirement Type
897	The Configure Watchdog frames shall The Command and response frames a Configure Watchdog Command	l be used to change the software watchdo re as follows:	g timeout value.	Data Communications Protocols			Analysis	Design
	Description	msb lsb	Byte Number					
	(Type Number = 58)	0 0 1 1 1 0 1 0	Byte 1					
	Timeout Value	x x x x x x x x x	Byte 2					
	Configure Watchdog Response							
	Description	msb lsb	Byte Number					
	(Type Number = 186)	1 0 1 1 1 0 1 0	Byte 1					
	Status	0 0 0 0 0 0 0 V	Byte 2					
898	The timeout value shall be in the rang	e between 10 to 100 milliseconds.		Data Communications Protocols			Analysis	Design
899	If the value is lower than 10, 10 shall assumed.	be assumed. If the value is greater than I	100, 100 shall be	Data Communications Protocols			Analysis	Design
900	On receipt of this frame, the watchdog and the "Y" bit set.	g timeout value shall be changed to the va	alue in the message	Data Communications Protocols			Analysis	Design
901	The response frame bit (Y) shall indic not.	rate a '1' if the watchdog has been previou	ısly set and a '0' if	Data Communications Protocols			Analysis	Design
902	This is a legacy message command / r	response for FI/O modules with Datakey	resident.	Data Communications Protocols			Analysis	Design
903	Upon command, a response frame cor on Request Module Status for FI/O St	ntaining the 128 bytes of the Datakey Secatus Bit 'K' definition.	e previous sections	Data Communications Protocols			Analysis	Design
904	If "K" bit set, only the first two bytes	shall be returned.		Data Communications Protocols			Analysis	Design

#	Requirement (Standard Docu	ment Section)			Document Section	Pass Fail	Comments	Test Type	Requirement Type
905	The Command and Response fr Controller Identification Comm				Data Communications Protocols			Analysis	Design
	Description	msb	lsb	Byte Number					
	(TypeNumber = 59)	0 0 1 1 1 0	1 1	Byte 1					
	Controller Identification Respo	ase							
	Description	msb	lsb	Byte Number					
	(Type Number = 187)	1 0 1 1 0	1 1	Byte 1					
	Status	0 0 0 0 0 0	0 K	Byte 2					
	Datakey	x x x x x x	x x	Bytes 3 to 130					
906	The I/O Module Identification (Identification value.	Command frame shall be used to re	equest the FI/0	0	Data Communications Protocols			Analysis	Design
907	A response of "1" shall be retur Type 1 FI/O and "32 to 40" are	ned by 2070-2A, "2" by 2070-8, "areserved for ITS Cabinets.	3" is reserved	for NEMA TS 2	Data Communications Protocols			Analysis	Design
908	The command and response fra Controller Identification Comm				Data Communications Protocols			Analysis	Design
	Description	msb	lsb	Byte Number					
	(TypeNumber = 60)	0 0 1 1 1 1	0 0	Byte 1					
	Controller Identification Respo	ase							
	Description	msb	lsb	Byte Number					
	(Type Number = 188)	1 0 1 1 1 1	0 0	Byte 1					
	FI/O I D byte	x x x x x x	X X	Byte 2					
909		provided with rate selection by ju asynchronous and shall be conne			6.4.9 EIA-232 Serial Port			Inspection	Design
910	A 22-line minimum HAR 2 Har Serial COMM Module in the T	ness shall be provided between Expe 2070 UNIT.	X2 Connector	and Model 2070-6	6.4.10 HAR 2 Harness			Inspection	Design
911	This provides two Modems or I	IA-232 Interfaces with the 2070 U	UNIT and the	outside world.	6.4.10 HAR 2 Harness			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
912	FAULT and VOLTAGE MONITOR circuitry – NEMA TS1 Controller FAULT and VOLTAGE MONITOR functions (outputs to cabinet monitor) shall be provided.	6.4.11 Fault and Voltage Monitor			Analysis	Design
913	Two 3-input OR gates shall be provided.	6.4.11 Fault and Voltage Monitor			Inspection	Design
914	The gate 1 output shall be connected to Connector A, Pin A (FAULT MONITOR) and gate 2 output shall be connected to Connector A, Pin C. Any FALSE state input shall cause a gate output FALSE (+24VDC) state.	6.4.11 Fault and Voltage Monitor			Analysis	Design
916	A MODULE Watchdog (WDT) circuit shall monitor the output.	6.4.11 Fault and Voltage Monitor			Analysis	Design
917	No state change for 2 +/- 0.1 seconds shall cause the circuit output to generate a FALSE (+24 VDC) output (input to gates 1 and 2).	6.4.11 Fault and Voltage Monitor			Analysis	Design
918	Should the FCU begin changing state, the WDT output shall return to TRUE (0 VDC) state.	6.4.11 Fault and Voltage Monitor			Analysis	Design
919	The module shall have a +5 VDC monitoring circuit which monitors the module's +5 VDC (+/-0.25).	6.4.11 Fault and Voltage Monitor			Analysis	Design
922	The FCU microprocessor output shall be assigned to FAULT Monitor (input to gate 1) and another output shall be assigned to VOLTAGE Monitor (input to gate 2).	6.4.11 Fault and Voltage Monitor			Analysis	Design
923	CPU Port 5 SET OUTPUT COMMAND Message OUTPUTs O78 and O79 shall be assigned to FAULT (O78) and VOLTAGE (O79).	6.4.11 Fault and Voltage Monitor			Analysis	Design
924	The bit logic state "1" shall be FCU output FALSE.	6.4.11 Fault and Voltage Monitor			Analysis	Design
925	CPU / FCU operation at POWER UP shall be as follows:	6.4.11 Fault and Voltage Monitor				Design
926	FCU Comm Loss Flag set. FAULT and VOLTAGE MONITOR outputs set to FALSE state.	6.4.11 Fault and Voltage Monitor			Analysis	Design
927	2. CPU REQUEST MODULE STATUS COMMAND Message with "E" bit set is sent to FCU to clear Comm Loss Flag and responds to CPU with "E" bit reset.	6.4.11 Fault and Voltage Monitor			Analysis	Design

#	Requirement (Star	ndard Document Section)		Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
928	In that data pins assign outputs de of other m	a, the 078 and 079 logicall ned for FM and VM outpu fined in the message will be	by set to "0" will ts to go to their The permitted at the	PUT COMMAND data must be sent. cause the FCU microprocessor port FRUE state. At this point, the signal ne output connectors. Any number E STATUS COMMAND and SET	6.4.11 Fault and Voltage Monitor			Analysis	Design
929		re message sequence is not FM shall retain the FALS		m Loss Flag shall be set (or remain)	6.4.11 Fault and Voltage Monitor			Analysis	Design
930	5. Performs i	tems 2 & 3 above User So	oftware.		6.4.11 Fault and Voltage Monitor			Analysis	Design
718	Voltage	Tolerances	I Minimum	I Maximum	6.4.4 Module Power			Analysis	Design
	+5 VDC	+4.875 to +5.125 VDC	1.0 ampere	10.0 ampere- MODULE 2070-4A 3.5 ampere- MODULE 2070-4B	Supply			Performance Test	
	+12 VDC Serial	+11. 4 to +12. 6 VDC	0.1 ampere	0.5 ampere					
	-12 VDC Serial	-11. 4 to -12. 6 VDC	0.1 ampere	0.5 ampere					
	+12 VDC	+11. 4 to +12. 6 VDC	0.1 AMP	1.0 AMP					
727	Power Supply Tran	sient response shall be suc	ch that peak trans	sient not to exceed 5%.	6.4.4 Module Power Supply			Performance Test	Design
728	The power supply s LOW.	hall supply 30 watts minii	mum for 550 mil	liseconds after ACFAIL going	6.4.4 Module Power Supply			Performance Test	Design
729			gup the Unit for t	two 500 milliseconds Power Loss	6.4.4 Module Power			Analysis	Design
	periods occurring in	n a 1.5-second period.			Supply			Performance Test	
741	3.5 VDC, and shall			s field connector input is less than trent is less than 100 microamperes	6.4.8.1 Parallel I/O Ports			Performance Test	Design
742		ve an internal pull-up to the a short circuit to ground.	ne Isolated +24 V	DC and shall not deliver greater than	6.4.8.1 Parallel I/O Ports			Performance Test	Design
746	Each output shall la active-low reset sig		emain stable unti	l either new data is written or the	6.4.8.1 Parallel I/O Ports			Performance Test	Design
747	Upon an active-low writing.	reset signal, each output	shall latch a logic	c "0" and retain that state until a new	6.4.8.1 Parallel I/O Ports			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
748	The state of all output circuits at the time of Power Up or in Power Down state shall be open (logic 0).	6.4.8.1 Parallel I/O Ports			Performance Test	Design
750	An output circuit state not changed during a new writing shall not glitch when other output circuits are updated.	6.4.8.1 Parallel I/O Ports		What exactly is the definition of "glitch"? Either this word should be changed or the specification should be dropped from the standard. (Depending upon how the user of the standard used this specification.)	Performance Test	Design
754	With the jumper in and NRESET transitions HIGH (FCU active), the FCU shall output a state change on Output Port 5, bit 8 (Connector C1, pin 103 – Monitor Watchdog Timer Input) every 100 milliseconds for 10 seconds or due to CPU Command.	Other Module Circuit Functions			Performance Test	Design
760	Once enabled, the watchdog timer shall not be disabled without resetting the FI/O.	Other Module Circuit Functions			Analysis Performance Test	Design
761	Failure of the FI/O to reset the watchdog timer within the prescribed timeout shall result in a hardware reset.	Other Module Circuit Functions			Performance Test	Design
766	At Power Up, the FCU loss of communications timer shall indicate loss of communications until the user program sends the Request Module Status message to reset the "E" Bit and a subsequent set output command is processed.	Other Module Circuit Functions			Analysis Performance Test	Design
771	If LED light ON, SP3 is active and available at C12S.	Other Module Circuit Functions		Further explanation needed.	Performance Test	Design
788	The Transition Buffer shall default to empty.	Buffers			Performance Test	Design
791	At each transition (if the input has been configured to report transition), a transition entry shall be added to the Transition Buffer.	Buffers			Performance Test	Design
795	Transition Buffer blocks are sent to the CPU module upon command.	Buffers			Performance Test	Design
796	Upon confirmation of their reception, the blocks shall be removed from the Transition Buffer.	Buffers			Analysis	Design
800	Each complete input scan shall finish within 100 microseconds.	I/O Functions			Analysis Performance Test	Design
804	If configured to report, each input that has transitioned since its last sampling shall be identified by input number, transition state, and timestamp (at the time the input scan began) and shall be added as an entry to the Transition Buffer.	I/O Functions			Analysis Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Test Type	Requirement Type
805	If multiple inputs change state during one input sample, these transitions shall be entered into the Input Transition Buffer by increasing input number.	I/O Functions			Analysis Performance Test	Design
821	In Case A above, the corresponding output shall be turned OFF if previously ON and if previously OFF remain OFF until otherwise configured.	I/O Functions			Performance Test	Design
822	For half-cycle switching (cases B and C), all outputs to be changed shall be changed within 50 microseconds after the corresponding LINESYNC transition and shall remain in the same state during the entire half cycle.	I/O Functions			Analysis Performance Test	Design
823	In Case D above, the corresponding output shall be turned ON if previously OFF and if previously ON remains ON until otherwise configured.	I/O Functions			Performance Test	Design
826	MILLISECOND Interrupt shall be activated by the 1 kilohertz reference once per millisecond.	I/O Functions			Analysis Performance Test	Design
827	An MC timestamp rollover flag set by MC rollover shall be cleared only on command.	I/O Functions			Analysis	Design
858	If absent, Status Bit "K" shall be set to '1' and no interrogation shall take place.	Data Communications Protocols			Performance Test	Design
859	If an error occurs during the interrogation, Status Bit "K" shall be set to '1'.	Data Communications Protocols			Performance Test	Design
860	FI/O modules without Datakey: Status Bit "K" shall always be set to '1'	Data Communications Protocols			Performance Test	Design
863	The 'S' bit shall return status '0' on completion.	Data Communications Protocols			Performance Test	Design
880	The FI/O shall set the 'F' bit to '1' when attempting to record a transition and the Transition Buffer is full.	Data Communications Protocols			Analysis	Design
881	While the Transition Buffer is full, all subsequent entries shall be discarded.	Data Communications Protocols			Analysis	Design
884	When the FI/O Module receives this command, it shall compare the associated Block Number with the Block Number of the previously received command.	Data Communications Protocols			Analysis	Design
885	If the new Block Number is the same as the previously-sent Block Number, the previous buffer shall be re-sent to the CPU Module and the 'E' flag set in the status response frame.	Data Communications Protocols			Analysis	Design
886	If the new Block Number is not equal to the previous Block Number, the old buffer shall be purged and the next block of data sent.	Data Communications Protocols			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Test Type	Requirement Type
887	If the block number is not incremented by one, the status G bit shall be set.	Data Communications Protocols			Analysis	Design
888	The block number received becomes the current number (even if out of sequence).	Data Communications Protocols			Analysis	Design
891	The Timestamp shall equal the MC value at the time the Poll Input Transition Buffer Response is generated.	Data Communications Protocols			Analysis	Design
915	The FCU Port 10, Bit 7 output shall normally change its state every 100 milliseconds.	6.4.11 Fault and Voltage Monitor			Performance Test	Design
920	If the voltage exceeds the limits, the circuit output shall generate a FALSE output (input to gates 1 and 2).	6.4.11 Fault and Voltage Monitor			Performance Test	Design
921	Normal operation shall return the output state to TRUE state.	6.4.11 Fault and Voltage Monitor			Performance Test	Design
699	The Module shall consist of the Module Chassis, Module Power Supply, FCU Controller, Parallel Input/Output Ports, Serial Communications Circuits and Module Connectors.	6.4.1 Type 2070-8 Field I/O Module			Inspection	Procurement
700	The Module CHASSIS shall be made of 0.06-inch minimum aluminum sheet and treated with clear chromate.	6.4.1 Type 2070-8 Field I/O Module		Manufacturing specification. Why is this in the standard?	Inspection	Procurement
701	All external screws, except where called out, shall be countersunk and shall be Phillips flat head stainless steel.	6.4.1 Type 2070-8 Field I/O Module		Manufacturing specification. Why is this in the standard?	Inspection	Procurement
702	The matching nuts shall be permanently captive on the mating surfaces.	6.4.1 Type 2070-8 Field I/O Module		Manufacturing specification. Why is this in the standard?	Inspection	Procurement

B.12 ITS Cabinet General Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
5	Sheet, Rod, Bar and Extruded shall be Type 1018/1020.	3.1.6 Metals		What performance requirement is addressed by this standard?	Inspection	Design
7	All cold roll steel shall be plated.	3.1.6 Metals			Inspection	Design
8	All plating shall be either cadmium plating meeting the requirements of Federal Specification QQ-P-416C, Type 2 Class l or zinc plating meeting the requirements of ASTM B633-85 Type II SC4.			Need to dig up this specification.	Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
9	All bolts, nuts, washers, screws, hinges and hinge pins shall be stainless steel unless otherwise specified.	3.1.6 Metals			Inspection	Design
10	Within the circuit of any device, module, or Printed Circuit Board (PCB), electrical isolation shall be provided between DC logic ground, equipment ground and the AC- conductor.	3.1.6 Metals			Inspection	Design
11	They [the DC logic ground and AC conductor] shall be electrically isolated from each other by 500 megohms, minimum, when tested at the input terminals with 500 VDC.	3.1.6 Metals			Performance Test	Design
12	Keyboards and LCD/LED Displays are considered daughter boards. Daughter boards shall be mechanically secured with a minimum of four spacers/metal screws.	3.1.6 Metals		It is sufficient to specify that the daughter boards are mechanically secured. Specifying the number of screws is not necessary and creates a useless requirement.	Inspection	Design
13	Connectors shall be either Flat Cable or PCB Headers.	3.1.6 Metals			Inspection	Design
14	Components are allowed to be mounted under the daughter board.	3.1.9 Daugher Boards		This requirement provides no value.	Drop from the standard.	Design
15	All components shall be second sourced and shall be of such design, fabrication, nomenclature or other identification as to be purchased from a wholesale distributor or from the component manufacturer, except as follows:	3.2.2 Components – General		Manufacturing and/or supply chain specification. What performance requirement is addressed by this standard?	Inspection	Design
16	When a component is of such special design that it precludes the purchase of identical components from any wholesale distributor or component manufacturer, one spare duplicate component shall be furnished with each 20, or fraction thereof, components used.	3.2.2 Components – General		This is a procurement requirement and has nothing to do with a design standard.	Drop from the standard.	Design
17	The electronic circuit design shall be such that all components of the same generic type, regardless of manufacturer, shall function equally in accordance with the specifications.	3.2.2 Components – General			Inspection	Design
18	No device shall be socket mounted unless specifically called out.	3.2.2 Components – Electronic			Inspection	Design
19	No component shall be operated above 80% of its maximum rated voltage, current or power ratings.	3.2.2 Components – Electronic		This is a procurement requirement and has nothing to do with the design of the cabinet.	Analysis	Design
20	Digital components shall not be operated above 3% over their nominal voltage, current or power ratings.	3.2.2 Components – Electronic			Analysis	Design
21	No component shall be provided where the manufactured date is three years older than the contract award date.	3.2.2 Components – Electronic			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
22	The design life of all components, operating for twenty-four hours a day and operating in their circuit application, shall be ten years or longer.	3.2.2 Components – Electronic			Analysis	Design
24	Where damage by shock or vibration exists, the component shall be supported mechanically by a clamp, fastener, retainer, or hold-down bracket.	3.2.2 Components – Electronic		How is the possibility for damage by shock or vibration quantified?	Inspection	Design
26	The Manufacturer shall certify that the component application meets the requirements of this standard.	3.2.2 Components – Electronic		Procurement requirement.	Analysis	Design
27	The DC and AC voltage ratings as well as the dissipation factor of a capacitor shall exceed the worst-case design parameters of the circuitry by 150%.	3.2.3 Capacitors			Analysis	Design
28	Capacitor encasements shall be resistant to cracking, peeling and discoloration.	3.2.3 Capacitors		What does this mean and how is it verified?	Inspection	Design
29	All capacitors shall be insulated and shall be marked with their capacitance values and working voltages.	3.2.3 Capacitors			Inspection	Design
30	Electrolytic capacitors shall not be used for capacitance values of less than 1.0 microfarad and shall be marked with polarity.	3.2.3 Capacitors			Inspection	Design
31	Potentiometers with ratings from 1 to 2 watts shall meet Military Type RV4 requirements.	3.2.4 Potentiometers		Need to dig up this specification.	Analysis	Design
36	Resistance values shall be indicated by the EIA color codes, or stamped value.	3.2.5 Resistors			Inspection	Design
38	Special ventilation or heat sinking shall be provided for all 2-watt or greater resistors.	3.2.5 Resistors			Inspection	Design
39	They [all resistors] shall be insulated from the PCB.	3.2.5 Resistors			Inspection	Design
40	All transistors, integrated circuits, and diodes shall be a standard type listed by EIA and clearly identifiable.	3.2.6 Semiconductor Devices		Need to dig up this specification.	Inspection	Design
41	All metal oxide semiconductor components shall contain circuitry to protect their inputs and outputs against damage due to high static voltages or electrical fields.	3.2.6 Semiconductor Devices			Inspection	Design
42	Device pin "1" locations shall be properly marked on the PCB adjacent to the pin.	3.2.6 Semiconductor Devices			Inspection	Design
44	All transformers and inductors shall have their windings insulated, shall be protected to exclude moisture, and their leads color coded with an approved EIA color code or identified in a manner to facilitate proper installation.	3.2.7 Transformers and Inductors		Need to dig up this specification.	Inspection	Design
45	Each triac with a designed circuit load of greater than 0.5 Amperes at 120 VAC shall be mounted to a heat sink with thermal conductive compound or material, in addition to being mechanically secured.	3.2.8 Triacs			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
47	The trip and frame sizes shall be plainly marked (marked on the breaker by the manufacturer), and the ampere rating shall be visible from the front of the breaker.	3.2.9 Circuit Breakers			Inspection	Design
49	Overload tripping shall not be influenced by an ambient air temperature range of from -18 degrees C to 50 degrees C.	3.2.9 Circuit Breakers			Performance Test	Design
50	The minimum Interrupting Capacity shall be 5,000 amperes, RMS when the breaker is secondary to a UL approved fuse or primary circuit breaker and both breakers in concert provide the rated capacity.	3.2.9 Circuit Breakers			Performance Test	Design
51	For circuit breakers 80 amperes and above, the minimum interrupting capacity shall be 10,000 amperes, RMS.	3.2.9 Circuit Breakers			Performance Test	Design
52	Circuit breakers shall be the trip-free type with medium trip delay characteristic (Carlingswitch Time Delay Curve #24 or equal).	3.2.9 Circuit Breakers		Need to dig up this specification.	Analysis	Design
53	The Load Circuit Breakers located on the PDA that are used to control Output Assembly Model 200 Switch Packs shall have auxiliary switches.	3.2.9 Circuit Breakers			Inspection	Design
54	The auxiliary switches shall "open" when the load breaker has tripped and the system will transfer the power from the Main Contactor to the Flash or Blank condition.	3.2.9 Circuit Breakers			Performance Test	Design
55	All Fuses that are resident in a bayonet style fuse holder shall have the fuse size rating labeled on the holder or on the panel adjacent to the holder.	3.2.10 Fuses			Inspection	Design
56	Fuses shall be easily accessible and removable without use of tools.	3.2.10 Fuses		Words such as, "easily accessible" are not of value in a standard, since they can neither be defined nor measured.	Inspection	Design
57	Dual-inline-package, quick snap switches shall be rated for a minimum of 30,000 operations per position at 50 milliamperes, 30 VDC.	3.2.11 Switches			Inspection	Design
59	The contacts shall be gold over brass.	3.2.11 Switches			Inspection	Design
60	The switch contacts shall be rated for a minimum of 1 ampere resistive load at 120 VAC and shall be silver over brass (or equal).	3.2.11 Switches			Inspection	Design
61	The switch shall be rated for a minimum of 40,000 operations.	3.2.11 Switches			Inspection	Design
63	The switch shall be rated for a minimum of 40,000 operations.	3.2.11 Switches			Inspection	Design
67	Screw size [for the terminal blocks] is called out under the associated file, panel or assembly.	3.2.12 Terminal Blocks			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
68	Provided the connectors mate, screw lug cam driven devices or crimp pin connectors shall be allowable if the interface is part of a harness.	3.2.13 Screw Lug and Cam Driven Connectors			Inspection	Design
69	For field termination, screw lug and cam driven assemblies are interchangeable for field wiring termination, provided they both accommodate 22-gauge wire on the inputs and 22-gauge wire on the outputs.	3.2.13 Screw Lug and Cam Driven Connectors		Is specifying an exact gauge of wire appropriate? Maybe 22-gauge wire is a minimum size. Can the 22-gauge specification be	Inspection	Design
				expressed in terms of performance?		
70	Harnesses shall be neat, firm and properly bundled with external protection.	3.2.14 Wiring, Cabling, and Harnesses		Words like "neat" have no value in a standard and are both untestable and undefined.	Inspection	Design
71	They shall be tie-wrapped and routed to minimize crosstalk and electrical interference.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design
72	Each harness shall be of adequate length to allow any conductor to be connected properly to its associated connector or termination point.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design
74	Printed circuit motherboards are to be used where possible to eliminate or reduce cabinet wiring.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design
75	Wiring containing AC shall be bundled separately or shielded separately from all DC logic voltage control circuits.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design
76	Wiring shall be routed to prevent conductors from being in contact with metal edges.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design
77	Wiring shall be arranged so that any removable assembly may be removed without disturbing conductors not associated with that assembly.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Design
82	Where insulation thickness is 15 mils or less, the conductor shall conform to MIL-W-16878/17.	3.2.14 Wiring, Cabling, and Harnesses		Why is insulation less than 15 mils allowed?	Inspection	Design
				Need to dig up this specification.		
84	All indicators and character displays shall be readily visible at a radius of up to 4 feet within the cone of visibility when the indicator is subjected to 97,000 lux (9,000 footcandles) of white light with the light source at 45 degrees (+/-2 degrees) to the front panel.	3.2.15 Indicators and Character Displays			Inspection	Design
85	All indicators and character displays shall have a minimum 90 degrees cone of visibility with its axis perpendicular to the panel on which the indicator is mounted.	3.2.15 Indicators and Character Displays			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
86	All indicators shall be self-luminous.	3.2.15 Indicators and Character Displays			Inspection	Design
87	All indicators shall have a rated life of 100,000 hours minimum.	3.2.15 Indicators and Character Displays			Inspection	Design
89	Indicators supplied on equipment requiring handles shall be mounted such that a horizontal clearance shall be provided.	3.2.15 Indicators and Character Displays			Inspection	Design
90	Liquid Crystal Displays (LCD) shall be readable at temperatures of -20 degrees C to +70 degrees C.	3.2.15 Indicators and Character Displays			Performance Test	Design
93	Type T connector shall be a single row, 10 position, feed through terminal block.	3.2.16 Connectors			Inspection	Design
94	The terminal block shall be a barrier type with 6-32, 0.25 inches or longer, nickel plated brass binder head screws.	3.2.16 Connectors			Inspection	Design
95	Each terminal shall be permanently identified as to its function.	3.2.16 Connectors			Inspection	Design
96	Pin and socket contacts for connectors shall be beryllium copper construction subplated with 1.27 microns nickel and plated with 0.76 microns gold.	3.2.16 Connectors			Inspection	Design
97	Pin diameter shall be 0.0618 inches.	3.2.16 Connectors			Inspection	Design
98	All pin and socket connectors shall use the AMP #601105-1 or #91002-1 contact insertion tool and the AMP #305183 contact extraction tool.	3.2.16 Connectors		Are they actually specifying a particular tool to be used for assembly? This is an assembly procedure not a design requirement. Why is a specific tool specified?	Inspection	Design
99	Edge connectors shall have bifurcated gold-plated contacts.	3.2.16 Connectors			Inspection	Design
100	The PCB receptacle connector shall meet or exceed the following:	3.2.16 Connectors			Performance Test	Design
	Operating Voltage: 600 VAC (RMS)					
	Current Rating: 5.0 Amperes					
	Insulation Material: Diallyl Phthalate or Thermoplastic					
	Insulation Resistance: 5,000 Megohms					
	Contact Material: Copper alloy plated with 0.00005 inches of nickel and 0.000010 inches of gold					
	Contact Resistance: 0.006 Ohm maximum					
101	The two-piece PCB connector shall meet or exceed the DIN 41612.	3.2.16 Connectors		Need to dig up this specification.	Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
102	The PCB 22/44 Connector shall have 22 independent contacts per side; dual sided with 0.156 inch contact centers.	3.2.16 Connectors			Inspection	Design
103	Each wire terminal shall be solder-less with PVC insulation and a heavy duty short-locking spade type connector.	3.2.16 Connectors		The type of crimping tool is an assembly procedure, not a design requirement.	Inspection	Design
104	All terminal connectors shall be crimped using a Controlled-Cycle type crimping tool.	3.2.16 Connectors		The crimping tool is specified due to the likelihood that improper crimps will result in poor connections. It could possibly be specified in a more direct manner.	Inspection	Design
105	Each flat cable connector shall be designed for use with 26 AWG cable; shall have dual cantilevered phosphor bronze contacts plated with 0.00015 inches of gold over 0.00005 inches of nickel; and shall have a current rating of 1 Ampere minimum and an insulation resistance of 5 Megohms minimum.	3.2.16 Connectors			Inspection Performance Test	Design
106	Each PCB header socket block shall be 0.025 inches square by 0.3425 inches high from the plane of the PCB to the end of the pin; shall be mounted on 0.10 inch centers; and shall be tempered hard brass plated with 0.00015 inches of gold over 0.00005 inches of nickel.	3.2.16 Connectors			Inspection	Design
107	Each PCB header socket contact shall be nylon or diallyl phthalate.	3.2.16 Connectors			Inspection	Design
108	Each PCB header socket contact shall be removable, but crimp-connected to its conductor.	3.2.16 Connectors			Inspection	Design
109	The Manufacturer shall list the part number of the extraction tool recommended by its manufacturer.	3.2.16 Connectors			Inspection	Design
110	Each PCB header socket contact shall be brass or phosphor bronze plated with 0.0010 inches of gold over 0.00005 inches of nickel.	3.2.16 Connectors			Inspection	Design
113	Assemblies shall be provided with two guides for each plug-in PCB or associated device (except relays).	3.3.1 Assemblies			Inspection	Design
114	The guides shall extend to within 0.75 inches from the face of either the socket or connector and front edge of the assembly.	3.3.1 Assemblies			Inspection	Design
115	If Nylon guides are used, the guides shall be securely attached to the file or assembly chassis.	3.3.1 Assemblies			Inspection	Design
116	All screw type fasteners shall utilize locking devices or locking compounds except for finger screws, which shall be captive.	3.3.2 Locking Devices			Inspection	Design
119	The manufacturer's model number and circuit issue or revision number shall appear on the rear panel of all equipment supplied (where such panel exists).	3.3.4 Model and Serial Numbers			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
120	In addition to any assignment of model numbers by the manufacturer, the TYPE number shall be displayed on the front panel in bold type, at least 0.25 inches high.	3.3.4 Model and Serial Numbers			Inspection	Design
121	A permanent label shall be affixed to the inside near and center floor of the Type 2070 unit chassis when viewed from the front. The label shall display the unit's serial number. The number shall be permanent and easy to read.	3.3.4 Model and Serial Numbers		Words like "easy to read" are undefined and as such, untestable.	Inspection	Design
122	Workmanship shall conform to the requirements of this specification and be in accordance with the highest industry standards.	3.3.5 Workmanship			Drop from the standard.	Design
123	The following tolerances shall apply, except as specifically shown on the plans or in these specifications: ### TYPE DIMENSIONAL TOLERANCE Sheet Metal +/-0.0525 inch PCB +0 inch, - 0.010 inch Edge Guides +/-0.015 inch *Note: These dimensional tolerances do not apply to material gauge or thickness.	3.3.5 Tolerances			Inspection	Design
126	PCBs shall slide smoothly in their guides while being inserted into or removed from the frame and shall fit snugly into the plug-in PCB connectors.	3.4.1 Human Engineering		As a standard requirement, this first phrase is worthless.	Inspection	Design
127	PCBs shall require a force no less than 5 pounds-force or greater than 50 pounds-force for insertion or removal.	3.4.1 Human Engineering			Inspection	Design
128	The design shall be inherently temperature compensated to prevent abnormal operation.	3.4.2 Design Engineering		What does "inherently temperature compensated" mean? I think their try to refer to using natural convection for cooling rather than using a fan since a fan is not fail-safe. The standard should say that more clearly.	Analysis	Design
129	The circuit design shall include such compensation as is necessary to overcome adverse effects due to temperature in the specified environmental range.	3.4.2 Design Engineering		What does this specification mean?	Drop from the standard.	Design
132	No item, component or subassembly shall emit a noise level sufficient to interfere with processing and communication functions of the controller circuits.	3.4.3 Generated Noise		At what noise level does processing and communications undergo interference?	Reword to include an actual specification.	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
23	Components shall be arranged so they are easily accessible, replaceable and identifiable for testing and maintenance.	3.2.2 Components – Electronic	P	Legacy requirements and performance needs have driven a system that is completely modular. The operational need for this requirement is clear. What is not clear is how a vendor would know they met the standard.	Inspection	Performance
88	Each LED indicator shall be white or clear when off. We did find on old EDI Switchpack that had red colored, and found that when under intense ambient light, it was not as easy to determine that the LED was flashing or off.	3.2.15 Indicators and Character Displays	P/F	The operational need is that the LED cannot look like it is "on" when lit by ambient light. As such, there must be no reflector behind it. A reflector would allow for a brighter LED with the same current, but it is important that only LEDs that are powered appear to be on.	Inspection	Performance
91	Connectors shall be keyed to prevent improper insertion of the wrong connector where equipment damage or operator injury may result. Note: We found SIU that were identical in function from two different vendors, and took pictures, showing that they were labeled with bogus numbers.	3.2.16 Connectors	P	The operational need is to make sure that different devices will not go into slots designed for other devices. The standard has drawings showing where the connectors should be placed.	Inspection	Performance
92	The mating connectors shall be designated as the connector number and male/female relationship, such as C1P (plug or PCB edge connector) and C1S (socket).	3.2.16 Connectors	P/F	DB25 is not keyed, but plugging in the wrong plug won't break anything.	Inspection	Performance
131	No item, component or subassembly shall emit an audible noise level exceeding the peak level of 55 dBa when measured at a distance of one meter away from its surface, except as otherwise noted.	3.4.3 Generated Noise	P	Dave Miller has a certification procedure showing the noise test and will provide those results. Furthermore, Dave Miller had his noise meter shipped to the HCTX site and we verified this requirement directly.	Performance Test	Performance
1	All sharp edges and corners shall be rounded and free of any burrs.	3.1.6 Metals			Inspection	Procurement

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
2	Aluminum sheets shall be Type 3003-H14 or Type 5052-H32 ASTM Designation B209 aluminum alloy.	3.1.6 Metals		This appears to be a manufacturing or manufacturer specification. What specific, measurable, performance standard is met by using a particular thickness or type of material?	Inspection	Procurement
3	Rod, Bar and Extruded shall be Type 6061-T6, or equal.	3.1.6 Metals		Same comment as above.	Inspection	Procurement
4	Sheet shall be annealed or one-quarter-hard complying with the ASTM Designation: A666 for Type 304, Grades A or B, stainless steel sheet.	3.1.6 Metals			Inspection	Procurement
6	Cold Rolled Steel sheet, rod, bar and extruded shall be Type 1018/1020.	3.1.6 Metals			Inspection	Procurement
25	The Manufacturer shall submit detailed engineering technical data on all components at the request of the AGENCY.	3.2.2 Components – Electronic		This specifies a documentation task for the manufacturer that has no affect on the cabinet design.	Analysis	Procurement
32	Potentiometers with ratings less than one-watt shall be used only for trimmer type functions.	3.2.4 Potentiometers			Inspection	Procurement
33	The potentiometer power rating shall be at least 100% greater than the maximum power requirements of the circuit.	3.2.4 Potentiometers			Analysis	Procurement
34	Fixed carbon film, deposited carbon, or composition insulated resistors shall conform to the performance requirements of Military Specifications MIL-R-11F or MIL-R-22684.	3.2.5 Resistors		Need to dig up this specification.	Inspection	Procurement
35	All resistors shall be insulated and shall be marked with their resistance values.	3.2.5 Resistors			Inspection	Procurement
37	The value of the resistors shall not vary by more than 5% between -37 degrees C and 74 degrees C.	3.2.5 Resistors			Analysis	Procurement
43	All power transformers and inductors shall have the manufacturer's name or logo and part number clearly and legibly printed on the case or lamination.	3.2.7 Transformers and Inductors			Inspection	Procurement
46	Circuit breakers shall be listed by UL or ETL.	3.2.9 Circuit Breakers			Inspection	Procurement
48	Contacts shall be silver alloy and enclosed in an arc quenching chamber.	3.2.9 Circuit Breakers			Inspection	Procurement
58	The switch contact resistance shall be 100 milliohms maximum at 2 milliamperes, 30 VDC.	3.2.11 Switches			Performance Test	Procurement
62	The switch contacts shall be rated for a minimum of 5 amperes resistive load at 120 VAC or 28 VDC and shall be silver over brass (or equal).	3.2.11 Switches			Inspection	Procurement
64	Ratings shall be the same as CONTROL, except the contact rating shall be a minimum of 10 amperes at 125 VAC.	3.2.11 Switches			Inspection	Procurement
65	The terminal blocks shall be barrier type, rated at 20 amperes and 600 VAC RMS minimum.	3.2.12 Terminal Blocks			Inspection	Procurement

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
66	The terminal screws shall be 0.3125 inches minimum length nickel plated brass binder head type with screw inserts of the same material.	3.2.12 Terminal Blocks			Inspection	Procurement
73	Conductors within an encased harness have no color requirements.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Procurement
78	All conductors, except those that can be readily traced, shall be labeled.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Procurement
79	Labels attached to each end of the conductor shall identify the destination of the other end of the conductor.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Procurement
80	All conductors shall conform to MIL-W-16878E/1 or better and shall have a minimum of 19 strands of copper.	3.2.14 Wiring, Cabling, and Harnesses		Need to dig up this specification.	Inspection	Procurement
81	The insulation shall be polyvinyl chloride with a minimum thickness of 10 mils or greater.	3.2.14 Wiring, Cabling, and Harnesses			Inspection	Procurement
83	Conductor color identification shall be as follows: AC- circuits – white Equip. Ground – solid green or continuous green color with 1 or more yellow stripes. DC logic ground – continuous white with a red stripe. AC+ circuits – continuous black or black with colored stripe. DC logic ungrounded or signal – any color not specified.	3.2.14 Wiring, Cabling, and Harnesses		Is this an industry recognized color codes scheme or just something someone made up? Need to find the source of these color codes.	Inspection	Procurement
111	The surge suppression device shall comply with ANSI/IEEE C62.41 (100 Kilohertz Ring Wave, the 1.2/50 microseconds – 8/20 Combination Wave and the EFT Burst) at voltages and currents specified at "Location Category B2" and at "Test Severity" level III (i.e. up to 4.0 Kilovolts, open-circuit).	3.2.17 Surge Protection Device		Need to dig up this specification.	Inspection	Procurement
112	All assemblies shall be modular, easily replaceable and incorporate plug-in capability for their associated devices or PCBs.	3.3.1 Assemblies		Words like, "easily replaceable" are undefined and as such, un-testable.	Inspection	Procurement
117	No components, traces, brackets or obstructions shall be within 0.125 inches of the board edge (guide edges).	3.3.3 PCB Design and Connectors			Inspection	Procurement
118	The manufacturer's name or logo, model number, serial number, and circuit issue or revision number shall appear and be readily visible on all PCBs.	3.3.3 PCB Design and Connectors			Inspection	Procurement
124	The equipment shall be engineered for simplicity, ease of operation and maintenance.	3.4.1 Human Engineering			Drop from the standard.	Procurement

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
125	Knobs shall be a minimum of 0.5 inches in diameter and a minimum separation of 0.5 inches edge to edge.	3.4.1 Human Engineering			Inspection	Procurement
130	The design shall take into consideration the protection of personnel from all dangerous voltages.	3.4.2 Design Engineering		What does "take into consideration" actually mean and how is it assessed?	Drop from the standard.	Procurement

B.13 ITS Cabinet PCBoard Requirements

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Type	Requirement Type
133	All contacts on PCBs shall be plated with a minimum thickness of 0.00003 inches gold over a minimum thickness of 0.000075 inches nickel.	3.5.1 PCB – Design, Fabrication, and Mounting			Inspection	Design
134	PCB design shall be such that when a component is removed and replaced, no damage is done to the board, other components, conductive traces or tracks.	3.5.1 PCB – Design, Fabrication, and Mounting			Performance Test	Design
136	NEMA FR-4 glass cloth base epoxy resin copper clad laminates 0.0625 inches minimum thickness shall be used.	3.5.1 PCB – Design, Fabrication, and Mounting			Inspection	Design
137	Inter-component wiring shall be by laminated copper clad track having a minimum weight of 0.2 ounces per square foot with adequate cross section for current to be carried.	3.5.1 PCB – Design, Fabrication, and Mounting			Inspection	Design
138	All copper tracks shall be plated or soldered to provide complete coverage of all exposed copper tracks.	3.5.1 PCB – Design, Fabrication, and Mounting			Inspection	Design
139	Jumper wires to external PCB components shall be from plated-through padded holes and as short as possible.	3.5.1 PCB – Design, Fabrication, and Mounting			Inspection	Design
140	All PCBs shall conform to Section 3.3 of Military Specification MIL-P-13949G. Grade of Pits and Dents shall be of Grade B quality (3.5.1.3) or better.	3.5.1 PCB – Design, Fabrication, and Mounting		Need to dig up this specification.	Inspection	Design
141	The class of permissible bow or twist shall be Class C (Table V) or better.	3.5.1 PCB – Design, Fabrication, and Mounting			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
142	The class of permissible warp or twist shall be Class A (Table II) or better.	3.5.1 PCB – Design, Fabrication, and Mounting			Inspection	Design
143	Sections 4.2 through 6.6 of Military Specification MIL-P-13949G (inclusive) shall be omitted except as referenced in previous sections of this specification.	3.5.1 PCB – Design, Fabrication, and Mounting		Need to dig up this specification.	Inspection	Design
144	The mounting of parts and assemblies on the PCB shall conform to Military Specification MIL-STD-275E, except as follows:	3.5.1 PCB – Design, Fabrication, and Mounting		Need to dig up this specification.	Inspection	Design
145	Semiconductor devices that dissipate more than 250 milliwatts or cause a temperature rise of 10 degrees C or more shall be mounted with spacers, transipads or heat sinks to prevent contact with the PCB.	3.5.1 PCB – Design, Fabrication, and Mounting			Analysis	Design
146	When completed, all residual flux shall be removed from the PCB.	3.5.1 PCB – Design, Fabrication, and Mounting		This is okay, but should be worded differently. This reads like a manufacturing step. Maybe it should just say that the PCB shall be free of all residual flux.	Inspection	Design
147	The resistance between any two isolated, independent conductor paths shall be at least 100 Megohms when a 500 VDC potential is applied.	3.5.1 PCB – Design, Fabrication, and Mounting			Performance Test	Design
148	All PCBs shall be coated with a moisture resistant coating.	3.5.1 PCB – Design, Fabrication, and Mounting			Inspection	Design
149	Where less than 0.25 inches lateral separation is provided between the PCB (or the components of a PCB) and any metal surface, a 0.0625 inches (+/-0.0005 inches) Thick Mylar (polyester) plastic cover shall be provided on the metal to protect the PCB.	3.5.1 PCB – Design, Fabrication, and Mounting			Inspection	Design
150	Each PCB connector edge shall be chamfered at 30 degrees from board side planes.	3.5.1 PCB – Design, Fabrication, and Mounting			Inspection	Design
151	The key slots shall also be chamfered so that the connector keys are not extracted upon removal of board or jammed upon insertion.	3.5.1 PCB – Design, Fabrication, and Mounting			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
152	The key slots shall be 0.045 inches (+/- 0.005 inches) for 0.1 inches spacing and 0.055 inches (+/- 0.005 inches) for 0.156 inches spacing.	3.5.1 PCB – Design, Fabrication, and Mounting			Inspection	Design
153	Hand soldering shall comply with Military Specification MIL-STD-2000.	3.5.2 PCB – Soldering		Need to dig up this specification.	Inspection	Design
154	Automatic flow soldering shall be a constant speed conveyor system with the conveyor speed set at optimum to minimize solder peaks or points.	3.5.2 PCB – Soldering		This is a manufacturing process requirement rather than a design requirement. The soldering process is specified due to the likelihood that poor solder points will result in poor connections. It could possibly be specified in a more direct manner. The quality of the solder points is not directly testable. As such, determining if this standard has been met becomes an exercise in verifying the performance of the board supplier. Is the quality of the vendor an item for a standard?	Inspection	Design
155	Temperature shall be controlled to within +/- 8 degrees C of the optimum temperature.	3.5.2 PCB – Soldering			Inspection	Design
156	The soldering process shall result in the complete coverage of all copper runs, joints and terminals with solder except that which is covered by an electroplating process.	3.5.2 PCB – Soldering			Inspection	Design
157	Wherever clinching is not used, a method of holding the components in the proper position for the flow process shall be provided.	3.5.2 PCB – Soldering			Inspection	Design
158	If exposure to the temperature bath is of such a time-temperature duration, as to come within 80% of any component's maximum specified time-temperature exposure, that component shall be hand soldered to the PCB after the flow process has been completed.	3.5.2 PCB – Soldering		This is a manufacturing process requirement rather than a design requirement.	Inspection	Design
159	Definitions for the purpose of this section on PCBs shall be taken from MIL-P-55110D Section 3.3 and any current addendum.	3.5.3 PCB – Definitions		Need to dig up this specification.	Inspection	Design
160	Jumpers are not allowed unless called out in the specifications or approved by the AGENCY.	3.5.4 PCB – Jumpers			Drop from the standard.	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
135	Fabrication of PCBs shall be in compliance with Military Specification MIL-P-13949, except as follows:	3.5.1 PCB – Design, Fabrication, and Mounting		Need to dig up this specification.	Inspection	Procurement

B.14 ITS Cabinet Models 200 and 204 Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
161	The unit chassis shall be made of metal suitable to meet rigid support and environmental requirements.	4.1.1 Models 200 and 204 General		This requirement could refer to road-side constraints, but it still seems odd.	Inspection	Design
162	Where electrical isolation is the only requirement, plastic insulation material may be used in lieu of metal.	4.1.1 Models 200 and 204 General			Analysis Inspection	Design
163	The unit control circuitry and switches shall be readily accessible by the use of a screwdriver or wrench.	4.1.1 Models 200 and 204 General			Inspection	Design
165	The unit shall be constructed so that no live voltage is exposed.	4.1.1 Models 200 and 204 General			Inspection	Design
166	A handle shall be attached to the front panel for insertion or removal from the unit mating connector.	4.1.1 Models 200 and 204 General			Inspection	Design
167	The unit shall be so constructed that its lower surface shall be no more than 2.06 inches below the centerline of the connector and no part shall extend more than 0.9 inches to the left or 1.1 inches to the right of the connector centerline.	4.1.1 Models 200 and 204 General			Inspection	Design
168	Continuous edge guides shall be provided on the unit.	4.1.1 Models 200 and 204 General			Inspection	Design
169	Each switch shall be capable of switching any current from 0.050 Amperes to 10.0 Amperes (AC) load with power factor of 0.85 or higher.	4.1.1 Models 200 and 204 General			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
164	Only one type of screw head end (Slotted or Phillips) shall be used.	4.1.1 Models 200 and 204 General	F	The operational need is to avoid a maintenance person having to go back to his vehicle, but communications ports <i>only</i> come with slotted screws. As a result, the cabinet already has a mix of screw types and must.	Inspection	Performance
170	Unit indicators shall be vertically centered on the front panel with indicators positioned no more than one inch from said center. Note: The front panels are not shown in the standard and, as a result, the different vendors do not follow a consistent labeling criterion, that is, some switchpacks show "flasher" versus "signal" and do not have consistent numbering schemes.	4.1.1 Models 200 and 204 General	P	The operational need is to maintain a similar look and feel. There is no drawing of the front, yet three different vendors accomplished the task in a very similar way, meeting the standard.	Inspection	Performance
171	Model plug connectors shall be: Model 200 BEAU P 5412 – LAB or approved equal	4.1.2 Model Plug Connectors			Inspection	Procurement

B.15 ITS Cabinet Model 200 Switch Pack Unit Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
172	The Model 200 Switch Pack Unit shall be a modular plug-in device containing three solid-state switches.	4.2.1 General			Inspection	Design
173	Each switch shall open or close a connection between applied power and external load.	4.2.1 General			Inspection	Design
174	A Ground True Controller Unit Input (0 VDC to 6 VDC) shall cause the switch to conduct (ON) and a Ground False (16 VDC or more) shall cause it to not conduct (OFF), State transition shall occur between 6 VDC and 16 VDC.	4.2.1 General			Inspection	Design
175	The input shall not sink more than 20 milliamperes or be subjected to more than 30 VDC. The input shall have reverse polarity protection.	4.2.1 General			Inspection	Design
177	Each switch shall have an OFF state dv/dt rating of 100 Volts per microsecond or better.	4.2.1 General			Inspection	Design
178	Each switch shall provide isolation between inputs and outputs of at least 2000 Vdc and at least 100 megaohms resistive.	4.2.1 General			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
182	The resistance between the AC+ input terminal and the AC+ output terminal of each switch shall be a minimum of 15K Ohms when the switch is in open (OFF) state.	4.2.1 General			Performance Test	Design
183	When the switch is in the OFF state, the output current through the load shall not exceed 10 milliamperes peak.	4.2.1 General			Performance Test	Design
176	With all switches ON, the unit shall not draw more than 60 milliamperes at +16 VDC or more from the +24 VDC cabinet power supply.	4.2.1 General		The operational need is that the switchpack does not draw too much current.	Performance Test	Performance
179	The unit front panel shall have an indicator on the input to each switch.	4.2.1 General	P		Inspection	Performance
180	The indicator shall be labeled or color-coded "Red"-top switch, "Yellow"-middle switch, and "Green"-bottom switch.	4.2.1 General	P		Inspection	Performance
181	The middle switch indicator shall be vertically centered on the unit front panel with the other indicators positioned one inch above and below.	4.2.1 General	F	None of the devices found had LEDs one inch apart. The Caltrans approved device had LEDs ³ / ₄ inch apart.	Inspection	Performance

B.16 ITS Cabinet Model 204 Flasher Unit and Model 205 Flash Transfer Unit Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
184	The FLASHER UNIT shall be a modular plug-in device containing a flasher control circuit and two solid-state switches.	4.3.1 Model 204 Flasher Unit			Inspection	Design
185	The unit's function is to alternatively open and close connections between applied power and external load.	4.3.1 Model 204 Flasher Unit			Inspection	Design
186	The unit shall generate its own internal DC power from the AC Line.	4.3.1 Model 204 Flasher Unit			Inspection	Design
188	Each switch shall have an OFF state dv/dt rating of 200 V/microsecond or better.	4.3.1 Model 204 Flasher Unit			Inspection	Design
192	The two indicators shall be centered with one inch minimum spacing.	4.3.1 Model 204 Flasher Unit			Inspection	Design
193	Each circuit shall be designed to operate in an open-circuit condition without load for 10 years minimum.	4.3.1 Model 204 Flasher Unit			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
194	A surge arrestor shall be provided between AC (pin 11) and Flasher Output (pins 7 & 8).	4.3.1 Model 204 Flasher Unit			Inspection	Design
195	The [surge] arrestor shall meet the following requirements: Recurrent Peak Voltage: 212 Volts Maximum Energy Rating: 50 Joules Average Power Dissipation: 0.85 Watts Peak Current for pulses less than 6 microseconds: 2000 Amperes Standby Current: less than one mA	4.3.1 Model 204 Flasher Unit			Performance Test	Design
196	Each switch shall be designed for a minimum of 100,000 (reference is a 10-year lifespan) operations while switching a tungsten load of 1000 Watts at 70 degrees C. Switch isolation between DC input and AC output circuit shall be at least 10,000 Megohms at 2000 VDC.	4.3.2 Model 205 Flash Transfer Unit			Analysis	Design
197	The Flash Transfer Relay Unit shall be of electromechanical type, designed for continuous duty.	4.3.2 Model 205 Flash Transfer Unit			Inspection	Design
198	Each unit shall be enclosed in a removable, clear plastic cover.	4.3.2 Model 205 Flash Transfer Unit			Inspection	Design
199	The manufacturer's name, electrical rating, and part number shall be placed on the cover.	4.3.2 Model 205 Flash Transfer Unit			Inspection	Design
200	They shall be durable, permanent and readily visible.	4.3.2 Model 205 Flash Transfer Unit		Specifications such as "readily visible" need to be quantified or omitted.	Inspection	Design
201	Each unit shall be provided with DPDT contacts.	4.3.2 Model 205 Flash Transfer Unit			Inspection	Design
202	The contact points shall be of fine silver, silver alloy or a superior alternate material.	4.3.2 Model 205 Flash Transfer Unit			Inspection	Design
203	Contact points and arms shall be capable of switching 20 Amperes or one Kilowatt Tungsten Load at 120 VAC per contact at least 100,000 operations without contact welding or excessive burning, pitting or cavitation.	4.3.2 Model 205 Flash Transfer Unit			Analysis	Design
204	The points and arms shall be able to withstand 10 Gs, 10 –55 Hertz without contact chatter.	4.3.2 Model 205 Flash Transfer Unit			Performance Test	Design
205	The relay coil shall have a power consumption of 10 Volt - Ampere maximum	4.3.2 Model 205 Flash Transfer Unit			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
206	Each relay shall withstand a potential of 1500 VAC at 60 Hertz between insulated parts and between current carrying or non-carrying parts.	4.3.2 Model 205 Flash Transfer Unit			Analysis	Design
207	Each relay shall have a one cycle surge rating of 175 Amperes RMS and pickup and drop out within 20 milliseconds.	4.3.2 Model 205 Flash Transfer Unit			Performance Test	Design
187	The unit shall commence flashing operation when AC power is applied providing 50 to 60 flashes per minute per switch with a 50 % duty cycle.	4.3.1 Model 204 Flasher Unit	P	How long after application should flashing begin? What is the tolerance around 50% duty cycle? Tolerances are located in the glossary of the standard!	Performance Test	Performance
189	The resistance between the AC+ input terminal and the AC+ output terminal of each switch shall be a minimum of 15K Ohms when the switch is in open (OFF) state.	4.3.1 Model 204 Flasher Unit			Inspection	Performance
190	When the switch is in OFF state the output current shall not exceed 10 milliamperes peak.	4.3.1 Model 204 Flasher Unit			Inspection	Performance
191	An indicator showing each switch output state shall be provided.	4.3.1 Model 204 Flasher Unit	P		Inspection	Performance

B.17 ITS Cabinet Model 212 Monitor Unit (CMU) Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
	The following indicators shall be provided (Top to Bottom):					
230	This input shall be considered active when the input voltage exceeds 89 Volts RMS.	4.4.9 Input Signals			Performance Test	
231	This input shall not be considered active when the input voltage is less than 70 Volts RMS.	4.4.9 Input Signals			Performance Test	
277	Clear LEDs shall not depend on a reflector or diffusion as part of its design.	4.4.11 Front Panel Devices		This verbiage actually defines "clear" LEDs.	Inspection	
208	4.4.1 General – 4.4.6 Exit From Failed State Action	4.4.1 General – 4.4.6 Exit From Failed State Action		I haven't a clue how to set these requirements up for "testing" via the standard!		Design
209	The CMU shall compare the active states of the field signals with the states reported by the ATC Controller Unit in the Type 61 frame.	4.4.7 Field Output Check			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
210	When a mismatch is detected for less than 700 milliseconds the CMU shall not cause a LFSA.	4.4.7 Field Output Check			Performance Test	Design
212	When a mismatch is detected for more than 700 milliseconds but less than 1000 milliseconds, the CMU may or may not cause a LFSA.	4.4.7 Field Output Check		This is almost "over specified" and could be left out.	Performance Test	Design
214	There shall be a programming in the serial memory key to disable Field Output Check monitoring on a field input basis.	4.4.7 Field Output Check			Analysis	Design
215	The CMU shall compare the active states of the field signals with the states reported by the ATC Controller Unit in the Type 61 frame.	4.4.7 Field Output Check			Analysis	Design
216	When a mismatch is detected while a Conflict, Lack of Signal, or Multiple fault is timing, Field Check Status shall be reported with the fault to indicate the faulty channel(s) and color(s).	4.4.7 Field Output Check			Analysis	Design
217	Field Output Check monitoring shall be disabled when the MAIN CONTACTOR COIL STATUS input is not active.	4.4.7 Field Output Check			Analysis	Design
218	There shall be a programming in the serial memory key to disable Field Output Check monitoring on a field input basis.	4.4.7 Field Output Check			Analysis	Design
219	The CMU shall measure the temperature at the CMU and report this value in the Type 182 frame.	4.4.8 CMU Temperature			Analysis	Design
220	Temperature accuracy shall be +/-6 degrees C over the operating temperature range of the CMU.	4.4.8 CMU Temperature			Analysis	Design
221	A Green or Yellow signal input shall be sensed active when it exceeds 25 Volts RMS and shall not be sensed active when it is less than 15 Volts RMS.	4.4.9 Input Signals			Analysis	Design
222	A Green or Yellow signal between 15 Volts RMS and 25 Volts RMS may or may not be sensed active.	4.4.9 Input Signals		What does specifying that a signal may or may not be sensed active accomplish?	Analysis	Design
223	There shall be a programming in the serial memory key to disable the Yellow input for each physical channel.	4.4.9 Input Signals			Analysis	Design
226	A channel shall be sensed active when the load current exceeds 105% of the Channel Current Sense Threshold programmed for that channel in the serial memory key.	4.4.9 Input Signals			Analysis	Design
227	A channel shall not be sensed active when the load current is less than 95% of the Channel Current Sense Threshold programmed for that channel in the serial memory key.	4.4.9 Input Signals			Analysis	Design
228	A load current value between 95% and 105% of the Channel Current Sense Threshold may or may not be sensed active.	4.4.9 Input Signals			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
229	This input shall be internally connected to the CMU Output Relay COM pin.	4.4.9 Input Signals			Inspection	Design
232	Signals between 89 Volts RMS and 70 Volts RMS may or may not be considered active.	4.4.9 Input Signals		This requirement defines "active" but the specification is not used further. If the signal can be considered either, what value is the specification?	Performance Test	Design
233	Operation of the cabinet in AUTO mode shall place AC+ on this input.	4.4.9 Input Signals			Analysis	Design
234	Operation of the cabinet in FLASH mode shall be open circuit on this input.	4.4.9 Input Signals			Analysis	Design
235	The CMU shall report the state of this input in the Type 189 frame.	4.4.9 Input Signals			Analysis	Design
236	The MAIN CONTACTOR COIL STATUS input shall be connected to the AC+ Raw side of the main contactor signal bus relay coil.	4.4.9 Input Signals			Inspection	Design
237	An active signal on this input indicates the Signal Bus should be powering the Switch Packs.	4.4.9 Input Signals			Analysis	Design
238	This input shall be considered active when the input voltage exceeds 89 Volts RMS.	4.4.9 Input Signals			Performance Test	Design
239	This input shall not be considered active when the input voltage is less than 70 Volts RMS.	4.4.9 Input Signals			Performance Test	Design
240	Signals between 89 Volts RMS and 70 Volts RMS may or may not be considered active.	4.4.9 Input Signals		This requirement defines "active" but the specification is not used further. If the signal can be considered either, what value is the specification?	Performance Test	Design
241	The CMU shall report the state of this input in the Type 189 frame.	4.4.9 Input Signals			Performance Test	Design
242	The MAIN CONTACTOR SECONDARY STATUS input shall be connected to the output side of the main contactor signal bus relay.	4.4.9 Input Signals			Inspection	Design
243	This input shall be considered active when the input voltage exceeds 89 Volts RMS.	4.4.9 Input Signals			Performance Test	Design
244	This input shall not be considered active when the input voltage is less than 70 Volts RMS.	4.4.9 Input Signals			Performance Test	Design
245	Signals between 89 Volts RMS and 70 Volts RMS may or may not be considered active.	4.4.9 Input Signals		This requirement defines "active" but the specification is not used further. If the signal can be considered either, what value is the specification?	Performance Test	Design
246	The CMU shall report the state of this input in the Type 189 frame.	4.4.9 Input Signals			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
247	The FTR COIL DRIVE STATUS input shall be connected to the FTR COIL DRIVE signal in the AC SIGNAL POWER BUS.	4.4.9 Input Signals			Inspection	Design
248	This input shall be considered active when the input voltage exceeds 89 Volts RMS.	4.4.9 Input Signals			Performance Test	Design
249	This input shall not be considered active when the input voltage is less than 70 Volts RMS.	4.4.9 Input Signals			Performance Test	Design
250	Signals between 89 Volts RMS and 70 Volts RMS may or may not be considered active.	4.4.9 Input Signals			Performance Test	Design
251	The CMU shall report the state of this input in the Type 189 frame.	4.4.9 Input Signals			Analysis	Design
252	The CB TRIP STATUS input shall be connected to the Auxiliary Switch output of the circuit breaker unit.	4.4.9 Input Signals			Inspection	Design
253	This input shall be considered active when the input voltage exceeds 89 Volts RMS.	4.4.9 Input Signals			Performance Test	Design
254	This input shall not be considered active when the input voltage is less than 70 Volts RMS.	4.4.9 Input Signals			Performance Test	Design
255	Signals between 89 Volts RMS and 70 Volts RMS may or may not be considered active.	4.4.9 Input Signals			Performance Test	Design
256	The CMU shall report the state of this input in the Type 189 frame.	4.4.9 Input Signals			Analysis	Design
258	These inputs shall be considered active (door open) when the input voltage exceeds 89 Volts RMS.	4.4.9 Input Signals			Performance Test	Design
259	These inputs shall not be considered active (door closed) when the input voltage is less than 70 Volts RMS.	4.4.9 Input Signals			Performance Test	Design
260	Signals between 89 Volts RMS and 70 Volts RMS may or may not be considered active.	4.4.9 Input Signals		How does this specification aid the implementer of the standard?	Performance Test	Design
261	The CMU shall report the state of these inputs in the Type 189 frame.	4.4.9 Input Signals			Analysis	Design
262	The MONITOR INTERLOCK input shall be connected to VDC GROUND within the CMU.	4.4.9 Input Signals			Inspection	Design
263	The Address Select input pins ADDRESS 0 and ADDRESS 1 define the Serial Bus #1 address of the CMU.	4.4.9 Input Signals			Inspection	Design
264	The pins are left open for a logical False, and are connected to VDC GROUND for a logical True.	4.4.9 Input Signals			Inspection	Design
265	ADDRESS 1 ADDRESS 0 SB #1 Address	4.4.9 Input Signals			Analysis	Design
	False False 0x0F					
	False True 0x10					
	True False 0x11					
	True True 0x12					

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
266	The CMU shall be operational over the voltage range of 80 Volts RMS to 135 Volts RMS.	4.4.10 Power and Circuit Requirements			Analysis	Design
267	It [the CMU] shall be capable of insertion and removal while AC power is applied to the cabinet.	4.4.10 Power and Circuit Requirements			Performance Test	Design
268	Surge current on AC+ Raw shall be less than 2 Amperes peak.	4.4.10 Power and Circuit Requirements			Performance Test	Design
269	The CMU shall not use the Cabinet +24VDC Power Supply to run any of its internal circuitry.	4.4.10 Power and Circuit Requirements			Analysis	Design
270	The +24 VDC MONITOR and +12 VDC MONITOR input circuits shall be optically isolated from the AC+ Raw circuitry.	4.4.10 Power and Circuit Requirements			Inspection	Design
271	The maximum current into the +24 VDC or +12 VDC Monitor inputs over the voltage range of 0 VDC to 30 VDC shall be less than 20 milliamperes.	4.4.10 Power and Circuit Requirements			Performance Test	Design
272	The Output relay of the CMU shall have one set of isolated Form C contacts.	4.4.10 Power and Circuit Requirements			Inspection	Design
273	These relay contacts shall be rated for a minimum of three Amperes at 120 Volts RMS and 100,000 operations.	4.4.10 Power and Circuit Requirements			Inspection	Design
274	Contact opening/closing time shall be 30 milliseconds or less.	4.4.10 Power and Circuit Requirements			Performance Test	Design
275	The relay coil shall be energized in the No Fault state and de-energized in the FSA state.	4.4.10 Power and Circuit Requirements			Performance Test	Design
276	All indicators shall be clear LEDs.	4.4.11 Front Panel Devices			Inspection	Design
294	A yellow indicator shall illuminate for 40 milliseconds (+/-5 milliseconds) each time the CMU correctly receives a frame on Serial Bus #1.	4.4.11 Front Panel Devices			Performance Test	Design
295	A yellow indicator shall illuminate for 40 milliseconds (+/-5 milliseconds) each time the CMU correctly receives a frame on Serial Bus #3.	4.4.11 Front Panel Devices			Performance Test	Design
296	The Serial Bus #3 RxD+ input shall be terminated on the CMU to the Serial Bus #3 EIA-485 supply voltage through a 560 Ohm resistor.	4.4.11 Front Panel Devices			Inspection	Design
297	The Serial Bus #3 RxD- input shall be terminated on the CMU to AC Raw- through a 560 Ohm resistor.	4.4.11 Front Panel Devices			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
298	A 120 Ohm resistor shall be connected on the CMU between RxD+ and RxD	4.4.11 Front Panel Devices			Inspection	Design
299	The CMU Serial Bus #3 TxD drivers shall remain in the mark state with drivers enabled when the CMU is not transmitting a command frame.	4.4.11 Front Panel Devices			Performance Test	Design
300	Note: A 120 Ohm resistor shall be connected between TxD+ and TxD- on the Serial Bus #3 cable assembly in the last Output Assembly installed in the Serial Bus #3 daisy chain.	4.4.11 Front Panel Devices			Inspection	Design
301	An EIA-232-E Data Terminal Equipment (DTE) interface and connector shall be provided for interconnecting to a personal computer.	4.4.11 Front Panel Devices			Inspection	Design
302	Where differences occur between the EIA-232 standard and this document, this document shall govern.	4.4.11 Front Panel Devices		Need to dig up this specification.	Inspection	Design
303	The connector shall be mounted on the front panel and shall be a 9-position subminiature D-type connector with metal shell.	4.4.11 Front Panel Devices			Inspection	Design
304	The connector shall utilize female contacts with 15 millionths of an inch gold plating in the mating areas.	4.4.11 Front Panel Devices			Inspection	Design
305	Pin # Function I/O 1 Reserved - 2 RxD I 3 TxD O 4 Reserved - 5 Signal Ground - 6 Reserved - 7 Reserved - 8 Reserved - 9 Reserved -	4.4.11 Front Panel Devices			Analysis	Design
306	The RxD input shall contain the serial data input to the CMU.	4.4.11 Front Panel Devices			Analysis	Design
307	The TxD output shall contain the serial data output from the CMU.	4.4.11 Front Panel Devices			Analysis	Design
308	All signals shall be referenced to Signal Ground and shall be optically isolated from the CMU.	4.4.11 Front Panel Devices			Inspection	Design
309	Transmission shall be in asynchronous start/stop mode.	4.4.11 Front Panel Devices			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
310	The format shall be 8 bit data, 1 stop bit, even parity, and 9600 bits per second (+/-2%) at a minimum.	4.4.11 Front Panel Devices			Analysis	Design
311	The CMU shall be capable of full duplex operation.	4.4.11 Front Panel Devices			Inspection	Design
312	Flow control shall use XON/XOFF procedures.	4.4.11 Front Panel Devices			Inspection	Design
211	When a mismatch is detected for 1000 milliseconds or more, the CMU shall cause a LFSA.	4.4.7 Field Output Check	P	Verified because Mr. Johnson pulled out a relay "hot" and we saw the unit go into flash.	Performance Test	Performance
213	Field Output Check monitoring shall be disabled when the MAIN CONTACTOR COIL STATUS input is not active.	4.4.7 Field Output Check	P		Analysis	Performance
224	A Red signal input shall be sensed active when it exceeds 70 Volts RMS and shall not be sensed active when it is less than 50 Volts RMS.	4.4.9 Input Signals	P	Verified by changing the input voltage via a variac, monitored in RMS with a Tektronix Scope. The operational need for using 70 Vols revolves around the fact that at that voltage, the light is seen as "on."	Performance Test	Performance
225	A Red signal between 50 Volts RMS and 70 Volts RMS may or may not be sensed active.	4.4.9 Input Signals	P		Performance Test	Performance
257	The CMU shall monitor the DOOR SWITCH FRONT and DOOR SWITCH REAR inputs.	4.4.9 Input Signals	P	If either door is open the door is open, but only when both doors are closed does it report closed.	Inspection	Performance
278	Clear LEDs shall only show the die and not appear to be ON when exposed to ambient light.	4.4.11 Front Panel Devices	P	This verbiage actually defines "clear" LEDS. Verified by shing a high intensity light into the flashing LEDs in the Cabinet.	Inspection	Performance
279	A green POWER indicator shall illuminate to indicate AC+ Raw voltage is proper.	4.4.11 Front Panel Devices	P		Performance Test	Performance
280	It [the green POWER indicator] shall flash at a 2 Hertz rate when the NRESET or POWERDOWN input is True.	4.4.11 Front Panel Devices	P		Performance Test	Performance
281	It [the green POWER indicator] shall remain off when the voltage is less than 80 Volts RMS (+/-2 Volts RMS).	4.4.11 Front Panel Devices	P	This occurred at around 69V RMS.	Performance Test	Performance

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
282	A red 24VDC FAIL indicator shall illuminate when the CMU is in FSA as a result of a 24VDC cabinet power supply fault.	4.4.11 Front Panel Devices	P	Verified by removing the fuse.	Performance Test	Performance
283	A red 12VDC FAIL indicator shall illuminate when the CMU is in FSA as a result of a 12VDC cabinet power supply fault.	4.4.11 Front Panel Devices	n/a	The Seimens cabinet we used was not programmed for this functionality.	Performance Test	Performance
284	The 12VDC FAIL indicator shall flash at a 2 Hertz rate when the 12 VDC monitor function is disabled.	4.4.11 Front Panel Devices	P	Because our unit was programmed as above, we could verify this could be tested.	Performance Test	Performance
285	A red CONFLICT indicator shall illuminate when the CMU is in FSA as a result of a Conflicting Channels fault.	4.4.11 Front Panel Devices	P		Performance Test	Performance
286	A red LACK OF SIGNAL indicator shall illuminate when the CMU is in FSA as a result of a Lack of Signal Inputs fault.	4.4.11 Front Panel Devices	P		Performance Test	Performance
287	A red MULTIPLE indicator shall illuminate when the CMU is in FSA as a result of a Multiple Inputs fault.	4.4.11 Front Panel Devices	P	In our case, we had a conflict running concurrently, so we could not see this on the CMU we were looking at. We re-ran with the conflict cleared to	Performance Test	Performance
288	A red ATC/LOCAL FLASH indicator shall illuminate when the CMU is in FSA as a result of a Type 62 – Send to Local Flash Command from the ATC Controller Unit, the LOCAL FLASH STATUS input sensed inactive, or CB TRIP STATUS active.	4.4.11 Front Panel Devices	P	Verified via CB TRIP.	Performance Test	Performance
289	A red CLEARANCE indicator shall illuminate when the CMU is in FSA as a result of a Yellow Clearance or Yellow Plus Red Clearance fault.	4.4.11 Front Panel Devices	P		Performance Test	Performance
290	A red SB #1 ERROR indicator shall illuminate when the CMU is in FSA as a result of a Serial Bus #1 fault.	4.4.11 Front Panel Devices	P		Performance Test	Performance
291	A red SB #3 ERROR indicator shall illuminate when the CMU is in FSA as a result of a Serial Bus #3 fault.	4.4.11 Front Panel Devices	P		Performance Test	Performance
292	A red DIAGNOSTIC indicator shall illuminate when the CMU is in FSA as a result of a Diagnostic fault.	4.4.11 Front Panel Devices	P	Verified by removing the Key.	Performance Test	Performance

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
293	The DIAGNOSTIC indicator shall flash at a 4 Hertz rate if the serial memory key is not present and a FSA state does not exist.	4.4.11 Front Panel Devices	P	Verified by removing the Key.	Performance Test	Performance

B.18 ITS Cabinet Model 214 Auxiliary Monitor Unit (AMU) Requirements

#	Requirement (Standa	rd Document Sec	tion)			Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
	The following indicator	rs shall be provide	d (Top to Bottom)	:						Design
313	The AMU shall reside	in each of the Outp	out Assemblies.			4.5.1 General			Inspection	Design
314	The AMU shall interface	ce to the CMU via	Serial Bus #3.			4.5.1 General			Inspection	Design
315	An AMU shall operate depending on the Addr		nel mode (14 Pac	k) or a six-channe	l mode (6 Pack)	4.5.1 General			Inspection	Design
316	The Address Select inp Serial Bus #3 address of				shall define the	4.5.1 General			Inspection	Design
317	The [Address Select in ADDRESS COMMON			cal False, and are	connected to	4.5.1 General			Inspection	Design
318	Mode / Position	ADDRESS 2	ADDRESS 1	ADDRESS 0	SB #3 ADDRESS	4.5.1 General			Analysis	Design
	14 Ch/1 and 2	False	False	True	0x01					
	14 Ch/3 and 4	False	True	True	0x03					
	6 Ch/1	True	False	True	0x05					
	6 Ch/2	True	True	False	0x06					
	6 Ch/3	True	True	True	0x07					
	6 Ch/4	True	False	False	0x04					
319	A 14 Pack Output Asse #2 reserved.	embly configured i	n position 1 and 2	shall respond as	AMU #1 with AMU	4.5.1 General			Inspection	Design
320	A 14 Pack Output Asse #4 reserved.	embly configured i	n position 3 and 4	shall respond as	AMU #3 with AMU	4.5.1 General			Inspection	Design
321	The 6 Pack Output Ass COMMON on the asse		ADDRESS 2 perm	anently connected	d to ADDRESS	4.5.1 General			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
322	All AC RMS voltage measurements shall be made over an RMS period of 33.3 milliseconds (two AC Line cycles).	4.5.2 AC Voltage Sensing			Performance Test	Design
323	All AC signals shall be sampled at a minimum of 1920 samples per second.	4.5.2 AC Voltage Sensing			Analysis	Design
324	A True RMS voltage measurement shall be made regardless of phase or wave-shape, including both positive and negative half wave sinusoids, over the voltage range of 0 Volts RMS to 135 Volts RMS.	4.5.2 AC Voltage Sensing			Analysis	Design
325	AC voltage measurements shall be accurate to +/-2 Volts RMS.	4.5.2 AC Voltage Sensing			Analysis	Design
326	Three inputs shall be provided for each of fourteen channels (36 total) to permit the monitoring of voltages at the Green, Yellow, and Red signal field terminals.	4.5.3 Field Signal Sensing			Inspection	Design
327	The AMU shall be designed so that unused Green, Yellow, or Red signal inputs are not sensed as active signals.	4.5.3 Field Signal Sensing			Analysis	Design
329	Each field input voltage shall be reported in the Type 129 or 130 frame.	4.5.3 Field Signal Sensing			Performance Test	Design
331	The AC Line voltage shall be reported in the Type 129 or 130 frame.	4.5.4 AC Line Sensing			Performance Test	Design
333	Each FLASHER input voltage shall be reported in the Type 129 or 130 frame.	4.5.5 Flasher Line Sensing			Performance Test	Design
335	Voltages at, or greater than, +22 VDC shall be considered proper for Assembly operation.	4.5.6 +24 VDC Sensing			Analysis	Design
336	Voltages at, or less than, +18 VDC shall be considered not proper for Assembly operation.	4.5.6 +24 VDC Sensing			Analysis	Design
337	The +24 VDC MONITOR state shall be reported in the Type 129 or 130 frames.	4.5.6 +24 VDC Sensing			Performance Test	Design
338	The +24 VDC MONITOR voltage section shall be electrically isolated from the AC- Raw referenced circuitry.	4.5.6 +24 VDC Sensing			Performance Test	Design
339	All AC RMS current measurements shall be made over a period of two AC Line cycles (33.3 milliseconds).	4.5.7 Current Sensing		Current Sensing is currently not implemented in this design.	Analysis	Design
340	A True RMS current measurement shall be made regardless of phase or wave-shape, including both positive and negative half wave sinusoids.	4.5.7 Current Sensing			Analysis	Design
341	AC current measurements shall be accurate to +/-35%.	4.5.7 Current Sensing			Performance Test	Design
342	The AMU shall sense the total output current of each Switch Pack.	4.5.7 Current Sensing			Analysis	Design
343	Each Switch Pack output current shall be reported in the Type 129 or 130 frames.	4.5.7 Current Sensing			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
344	The input impedance of the COIL+ input with respect to the COIL-input shall be 1000 Ohms.	4.5.7 Current Sensing			Analysis	Design
345	Full-scale current is set by the number of primary turns through the transformer and shall be a maximum of four turns.	4.5.7 Current Sensing			Inspection	Design
346	Unless specified otherwise, one turn shall be provided.	4.5.7 Current Sensing			Inspection	Design
347	The Switch Pack current sensing transformers shall meet the following requirements: Linearity 25% from 10 milliamperes to 1Ampere (single primary turn) Accuracy +/-25% (Rin = 1000 Ohms) Primary Current 10 Amperes maximum Minimum hole size 0.25 inch diameter Insulation Resistance 100 Megohms at 500 VDC	4.5.7 Current Sensing			Performance Test	Design
348	The transformer shall output a voltage of 1.0 Volts RMS (+/-5%) across 1K Ohms when driven by 1.0 Arms sinusoidal current through one primary turn.	4.5.7 Current Sensing			Performance Test	Design
349	Sufficient secondary turns shall be provided to compensate for differences in core material and losses to produce the 1.0 Volts RMS output.	4.5.7 Current Sensing			Inspection	Design
350	The AMU shall be provided with a resident series of self-check diagnostic capabilities.	4.5.8 Diagnostic Error			Analysis	Design
351	At a minimum, the AMU shall contain provisions to verify all memory elements on power-up and Reset.	4.5.8 Diagnostic Error			Analysis	Design
353	This test [the RAM diagnostic] shall verify that all RAM elements are operating correctly at power-up.	4.5.8 Diagnostic Error			Analysis	Design
354	Patterns shall be written to RAM.	4.5.8 Diagnostic Error			Performance Test	Design
355	Each Write shall be followed by a Read to verify that it contains the written pattern.	4.5.8 Diagnostic Error			Performance Test	Design
356	This test [the non-volatile memory diagnostic] shall verify that the nonvolatile ROM(s) contain the proper program.	4.5.8 Diagnostic Error			Analysis	Design
357	The routine shall perform a check on each ROM and make a comparison with a preprogrammed check value.	4.5.8 Diagnostic Error			Analysis	Design
358	This test shall be performed at power-up and at a minimum rate of 1024 bits per second during operation.	4.5.8 Diagnostic Error			Performance Test	Design
359	The AMU shall monitor the operation of its microprocessor.	4.5.8 Diagnostic Error			Analysis	Design
360	At a minimum, the monitoring circuit shall be triggered at least every 100 milliseconds.	4.5.8 Diagnostic Error			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
361	The microprocessor shall be reset and the DIAGNOSTIC indicator illuminated if the monitoring circuit has not been triggered for a maximum of 1000 milliseconds.	4.5.8 Diagnostic Error			Performance Test	Design
362	The AMU shall generate its own power supply voltage from the AC+ Raw input using no more than 5 Watts.	4.5.9 Power Requirements			Performance Test	Design
363	It [the AMU] shall be capable of insertion and removal while AC power is applied to the cabinet.	4.5.9 Power Requirements			Performance Test	Design
364	Surge current on AC+ Raw input shall be less than 2 Amperes peak.	4.5.9 Power Requirements			Performance Test	Design
365	The AMU shall be operational over the voltage range of 80 Volts RMS to 135 Volts RMS.	4.5.9 Power Requirements			Analysis	Design
366	The AMU shall be fully functional within 500 milliseconds following AC+ Raw voltage exceeding 80 Volts RMS or Reset.	4.5.9 Power Requirements			Performance Test	Design
367	During the loss of AC+ Raw voltage for 700 milliseconds or less the AMU shall continue to operate.	4.5.9 Power Requirements			Performance Test	Design
368	All indicators shall be clear LEDS.	4.5.10 AMU User Interface			Inspection	Design
369	Clear LEDs shall not depend on a reflector or diffusion as part of its design.	4.5.10 AMU User Interface			Inspection	Design
370	Clear LEDs shall only show the die and not appear to be ON when exposed to ambient light.	4.5.10 AMU User Interface			Inspection	Design
376	The [yellow] indicator shall pulse ON for 40 milliseconds each time the AMU correctly receives a frame with its address on the Bus #3 input.	4.5.10 AMU User Interface			Performance Test	Design
377	This [yellow] indicator shall be labeled SB #3 RX.	4.5.10 AMU User Interface			Inspection	Design
381	A recessed RESET switch shall be provided which applies a direct reset to the microprocessor device on the AMU.	4.5.10 AMU User Interface			Analysis	Design
382	All voltage and current data shall be initialized to zero following Reset.	4.5.10 AMU User Interface			Performance Test	Design
383	The access hole shall be 0.25 inches in diameter.	4.5.10 AMU User Interface			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
384	The AMU connector shall be a DIN 4161296 Header Type.	4.5.10 AMU User Interface			Inspection	Design
385	Pins A31 (Equipment Ground), B32 (AC-Raw), and C32 (AC-Raw) shall pre-mate before all other pins.	4.5.10 AMU User Interface			Inspection	Design
386	The AMU pin assignments shall be as shown on drawing 4-11-6.	4.5.10 AMU User Interface		Need to have the full standard available to reference these drawings.	Inspection	Design
387	TxD+, TxD- and RxD+, RxD- shall consist of two interface links conforming to the requirements of the Electronic Industries Association EIA-485, Standard for Electrical Characteristics of Generators and Receivers for use in Balanced Digital Multipoint Systems, dated April 1983.	4.5.11 Bus #3 Profile			Analysis	Design
388	Where differences occur between the EIA-485 standard and this document, this document shall govern.	4.5.11 Bus #3 Profile		Need to dig up this specification.	Inspection	Design
389	All voltage potentials on the Bus #3 TxD+, TxD-, RxD+, and RxD- interface links shall be referenced to AC- Raw.	4.5.11 Bus #3 Profile			Analysis	Design
390	The data link layer protocol is based on a subset of HDLC as defined by ISO/IEC 3309. Each frame shall consist of the following fields: 1. Flag byte = 0x7E 2. Address byte = 0x01 through 0x07 3. Control byte = 0x13 (U Format) 4. Information field = defined below in section 4.5.12, Frame Types 5. Frame Check Sequence = 16 bit FCS procedure defined in clause 4.6.2 of ISO/IEC 3309. 6. Flag byte = 0x7E	4.5.11 Bus #3 Profile			Analysis	Design
391	Transmission shall be in start/stop mode with basic transparency defined by clause 4.5.2.2 of ISO/IEC 3309 applied.	4.5.11 Bus #3 Profile		Need to dig up this specification.	Analysis	Design
392	The format shall be 8 bit data, 1 stop bit, no parity, and 153,600 bits per second (+/-2%).	4.5.11 Bus #3 Profile			Analysis	Design
393	Only asynchronous half duplex operation shall be permitted.	4.5.11 Bus #3 Profile			Analysis	Design
394	Frames transmitted by the CMU shall be referred to as command frames and frames transmitted by the AMU shall be referred to as response frames.	4.5.11 Bus #3 Profile			Analysis	Design
395	Command frames shall be transmitted only to those AMUs that are present, as determined by the programming entries made in the CMU.	4.5.11 Bus #3 Profile			Analysis	Design
396	Response frames shall only be transmitted as a result of correctly receiving a command frame.	4.5.11 Bus #3 Profile			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
397	The first eight bits in each information field shall contain the frame Type number.	4.5.11 Bus #3 Profile			Analysis	Design
398	There shall be a maximum of 64 different command frame types and 64 different response frame types.	4.5.11 Bus #3 Profile			Analysis	Design
399	Additionally, there shall be 64 different command frame types reserved for special application use and 64 different response frame types reserved for special application use, as outlined below.	4.5.11 Bus #3 Profile			Analysis	Design
	FRAME TYPES FUNCTION					
	1-63 Command frame defined by this standard					
	0, 64-127 Command frame reserved					
	128-191 Response frame defined by this standard					
	192-255 Response frame reserved					
400	Reserved bits shall always be set to zero by the transmitting station.	4.5.11 Bus #3 Profile			Analysis	Design
401	The AMU shall begin its response to command frames from the CMU within a designated period of time following the correct reception of a complete command frame including the closing flag.	4.5.11 Bus #3 Profile			Analysis	Design
402	This [designated period for the AMU to begin its response] period shall be known as the Service Time and shall have a maximum value of 500 microseconds.	4.5.11 Bus #3 Profile			Analysis	Design
403	The AMU TxD link output shall be in its high impedance state outside of the interval defined by the Service Time plus Response Time.	4.5.11 Bus #3 Profile			Analysis	Design
404	The AMU shall complete its transmission of the response frame including the closing flag within a designated time known as the Response Time, depending on the number of bytes transmitted in the response frame.	4.5.11 Bus #3 Profile			Analysis	Design
405	The AMU TxD link output shall be in its high impedance state a maximum of 200 microseconds following the transmission of the closing flag.	4.5.11 Bus #3 Profile			Analysis	Design
406	The Response Time period shall have a maximum value of (1.2) *(# of bytes in information field +6)*(10/153600).	4.5.11 Bus #3 Profile			Analysis	Design
407	Note that due to the transparency mechanism, any occurrence of the flag byte $(0x7E)$ or control escape byte $(0x7D)$ in the information field adds a second byte to the count. Thus, the number of bytes in the information field could be doubled if all characters are $0x7E$ or $0x7D$.	4.5.11 Bus #3 Profile			Analysis	Design
408	Following the transmission of each command frame, there shall be a Dead Time during which the CMU does not transmit.	4.5.11 Bus #3 Profile			Analysis	Design
409	This Dead Time shall be a minimum of the Service Time plus the Response Time.	4.5.11 Bus #3 Profile			Analysis	Design

#	Requireme	ent (Standard Document Section	on)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
410		RMS period (33.3 milliseconds,	be transmitted from the CMU to each AMU-6 at least two AC Line cycles, averaging time for RMS	4.5.12 Frame Types			Analysis	Design
411	Its [the Typ	oe I Command Frame] purpose is	s to request the status from an AMU-6.	4.5.12 Frame Types			Analysis	Design
412	Polling the AMU-6 more often than the RMS period may result in the same response frame being repeated.			4.5.12 Frame Types			Analysis	Design
	Byte #	Contents	Description					
	1	01	Frame Type					
413		-6 Status frame shall be transmit om the CMU.	ted only if a Type 1 command frame has been correctly	4.5.12 Frame Types			Analysis	Design
414	The AMU-command i	6 shall report the data for the most received.	ost recent RMS period calculated when the Type 1	4.5.12 Frame Types			Performance Test	Design
415	The Type 1	command frame polling rate sh	all not affect the accuracy or RMS period of the data.	4.5.12 Frame Types			Analysis	Design
416	Byte # 1 2	Contents 129 AMU Status	Prame Type 6 Pack AMU Status b0 = set to 1 if +24 VDC MONITOR input is Low b1:4 = reserved b5 = set if AMU has reset since last poll b6 = set if last RMS period data was not transmitted b7 = diagnostic failure	4.5.12 Frame Types			Analysis	Design
	3	0-135	AC+ Raw voltage					
	4	Channel 1 Red	Channel RMS Voltages					
	5	Channel 2 Red						
	<u>6</u> 7	Channel 3 Red Channel 4 Red	-					
	8	Channel 5 Red						
	9	Channel 6 Red						
	10	Channel 1 Yellow						
	11	Channel 2 Yellow						
	12	Channel 3 Yellow						
	13	Channel 4 Yellow						

#	Requireme	nt (Standard Document Section	on)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
	14 15 16 17 18 19 20 21 22 23 24 25 26 27 28 29 30 31	Channel 5 Yellow Channel 6 Yellow Channel 1 Green Channel 2 Green Channel 3 Green Channel 5 Green Channel 6 Green Flasher #1-1 Flasher #1-2 Flasher #2-1 Flasher #2-2 Channel 1 Channel 2 Channel 3 Channel 4 Channel 5 Channel 6	Flasher RMS Voltages Channel Load Current The current value reported shall be the measured current in Amperes times 255 divided by the Full Scale (FS) parameter. For 1 primary turn, FS =1.0 (range is 0 to 1.0 Arms) For 2 primary turns, FS =0.5 (range is 0 to 0.5 Arms) For 3 primary turns, FS = 0.33 (range is 0 to 0.33 Arms) For 4 primary turns, FS =0.25 (range is 0 to					
	32	0	0.25 Arms) Reserved Reserved					
417	This frame [_	be transmitted from the CMU to each AMU-14 at	4.5.12 Frame Types			Analysis	Design
418	Its [Type 2 0	Command Frame] purpose is to	request the status from an AMU-14.	4.5.12 Frame Types			Analysis	Design
419	Polling the being repeat		MS period may result in the same response frame	4.5.12 Frame Types		It is not clear what part this type of information plays in a standard.	Analysis	Design
420	<i>Byte</i> # 1	Contents 02	Description Frame Type	4.5.12 Frame Types			Analysis	Design

#	Requirem	ent (Standard Document Secti	ion)	Document Section	Pass Fail	Comments	Туре	Requirement Type
421		-14 Status frame shall be transmeceived from the CMU.	nitted only if a Type 2 command frame has been	4.5.12 Frame Types			Analysis	Design
422	The AMU-		most recent RMS period calculated when the Type 2	4.5.12 Frame Types			Analysis	Design
423	The Type 2	2 command frame polling rate sl	nall not affect the accuracy or RMS period of the data.	4.5.12 Frame Types			Performance Test	Design
424	Byte #	Contents	Description	4.5.12 Frame Types			Analysis	Design
	1	130	Frame Type					
	2	AMU Status	14 Pack AMU Status b0 = set to 1 if +24 VDC MONITOR input is Low b1:4 = reserved b5 = set if AMU has reset since last poll b6 = set if last RMS period data was not transmitted b7 = diagnostic failure					
	3	0-135	AC+ Raw voltage					
	4	Channel 1 Red	Channel RMS Voltages					
	5	Channel 2 Red						
	6	Channel 3 Red						
	7	Channel 4 Red						
	8	Channel 5 Red						
	9	Channel 6 Red	_					
	10	Channel 7 Red Channel 8 Red	_					
	11	Channel 9 Red	_					
	12	Channel 9 Red Channel 10 Red	-					
	14	Channel 11 Red	-					
	15	Channel 12 Red	-					
	16	Channel 13 Red	-					
	17	Channel 14 Red						
	18	Channel 1 Yellow						

#	Requirem	ent (Standard Document Section	on)	Document Section	Pass Fail	Comments	Туре	Requirement Type
	19	Channel 2 Yellow						
	20	Channel 3 Yellow						
	21	Channel 4 Yellow						
	22	Channel 5 Yellow						
	23	Channel 6 Yellow						
	24	Channel 7Yellow						
	25	Channel 8 Yellow						
	26	Channel 9 Yellow						
	27	Channel 10 Yellow						
	28	Channel 11 Yellow						
	29	Channel 12 Yellow						
	30	Channel 13 Yellow						
	31	Channel 14 Yellow						
	32	Channel 1 Green						
	33	Channel 2 Green						
	34	Channel 3 Green						
	35	Channel 4 Green						
	36	Channel 5 Green						
	37	Channel 6 Green						
	38	Channel 7 Green						
	39	Channel 8 Green						
	40	Channel 9 Green						
	41	Channel 10 Green						
	42	Channel 11 Green						
	43	Channel 12 Green						
	44	Channel 13 Green						
	45	Channel 14 Green						
	46	Flasher #1-1	Flasher RMS Voltages					
	47	Flasher #1-2						
	48	Flasher #2-1						
	49	Flasher #2-2						

#	Requirem	ent (Standard Document Sec	ction)	Document Section	Pass Fail	Comments	Туре	Requirement Type
	50 51 52 53 54 55 56 57 58 59 60 61 62 63	Channel 1 Channel 2 Channel 3 Channel 4 Channel 5 Channel 6 Channel 7 Channel 8 Channel 9 Channel 10 Channel 11 Channel 12 Channel 13 Channel 13	Channel Load Current The current value reported shall be the measured current in Amperes times 255 divided by the Full Scale (FS) parameter. For 1 primary turn, FS =1.0 (range is 0 to 1.0 Arms) For 2 primary turns, FS =0.5 (range is 0 to 0.5 Arms) For 3 primary turns, FS = 0.33 (range is 0 to 0.33 Arms) For 4 primary turns, FS =0.25 (range is 0 to 0.25 Arms)					
	64 65	0	Reserved Reserved					
425			AMU to the CMU as a Negative Acknowledge response ommand frame with an invalid parameter.	4.5.12 Frame Types			Analysis	Design
426	Byte # 1 2	Contents 128 Status	Description Frame Type (Negative Acknowledge) AMU SB #3 Error Type b0 = set to 1 if invalid frame type received b1:7 = reserved	4.5.12 Frame Types			Analysis	Design
328	The AMU 1500 picof		nn 15 Volts RMS when connected to AC Line through	4.5.3 Field Signal Sensing	Р		Performance Test	Performance
330	The AMU input.	shall include the capability of	monitoring the AC Line voltage applied to its AC+ Raw	4.5.4 AC Line Sensing	P		Inspection	Performance
332	Four inputs		g of voltages at the FLASHER #1-1, FLASHER #1-2, gnal input terminals of the Output Assembly.	4.5.5 Flasher Line Sensing	P		Inspection	Performance
334	The AMU	shall sense the state of the +24	4 VDC MONITOR input.	4.5.6 +24 VDC Sensing	P		Analysis	Performance

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
352	When an error is detected, the AMU shall illuminate the DIAGNOSTIC indicator and disable the Serial Bus #3 port.	4.5.8 Diagnostic Error	P		Performance Test	Performance
372	A green POWER indicator shall be provided.	4.5.10 AMU User Interface	p		Inspection	Performance
373	The [green POWER] indicator shall be illuminated when the AC+ Raw input is 80 Volts RMS (+/-2 Volts RMS) or greater.	4.5.10 AMU User Interface	p		Inspection	Performance
374	This [green] indicator shall be labeled POWER.	4.5.10 AMU User Interface	р		Inspection	Performance
375	A yellow Serial Bus #3 indicator shall be provided.	4.5.10 AMU User Interface	р		Inspection	Performance
378	A red DIAGNOSTIC indicator shall be provided.	4.5.10 AMU User Interface	P		Inspection	Performance
379	The [red DIAGNOSTIC] indicator shall be ON when an internal diagnostic error is detected.	4.5.10 AMU User Interface		Cannot be performed.	Performance Test	Performance
380	This [red] indicator shall be labeled DIAGNOSTIC.	4.5.10 AMU User Interface	р		Inspection	Performance

B.19 ITS Cabinet Model 216-12 & 216-24 Power Supply Unit Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
429	When resident in the PDA ITS, the units shall be held firmly in place by its stud screws and wing nut.	4.6.1 General Requirements			Inspection	Design
430	Two units, 216-12 and 216-24 shall provide +12 and +24 VDC, respectively, to the cabinet assemblies.	4.6.1 General Requirements			Inspection	Design
431	They shall be of ferro-resonant design.	4.6.1 General Requirements		What does "ferro-resonant" mean?	Inspection	Design
432	They [unit chassis] shall have no active components and conform to the requirements of this section.	4.6.1 General Requirements			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
434	This [line and load regulation] includes ripple noise; from 90 VAC to 135 VAC at 60 Hertz, plus an additional 1.6% for each additional 1.0% frequency change; and current range from 1 Ampere to 5 Amperes with a maximum temperature rise of 30 degrees C above ambient.	4.6.1 General Requirements			Analysis	Design
435	Design Center Voltage shall be +24 VDC (+/-0.5 VDC) and +12 VDC (+/-0.5 VDC) at full load, at 30 degrees C, and with 115 VAC incoming after a 30-minute warm-up period.	4.6.1 General Requirements			Analysis	Design
436	Full Load Current shall be 5 AMPERES each for +24 VDC and +12 VDC, minimum.	4.6.1 General Requirements			Analysis	Design
437	Ripple Noise shall be 2 Volts peak-to-peak and 500 millivolts RMS at full load.	4.6.1 General Requirements			Analysis	Design
438	Line Voltage shall be 90 VAC to 135 VAC.	4.6.1 General Requirements			Analysis	Design
439	Efficiency shall be 70% minimum.	4.6.1 General Requirements			Analysis	Design
440	Circuit capacitors shall be rated for 40 Volts minimum.	4.6.1 General Requirements			Analysis	Design
441	The front panel shall include AC and DC fuses, power ON light and banana clip test points for monitoring the output voltages.	4.6.1 General Requirements			Inspection	Design
442	The unit, including terminals, shall be protected with a 1K Ohm, 0.5 watt resistor to prevent accidental contact with energized parts.	4.6.1 General Requirements			Inspection	Design
427	The unit chassis shall be vented.	4.6.1 General Requirements	P	Units are usually open.	Inspection	Performance
428	The power supply cage and transformers shall be securely braced to prevent damage in transit.	4.6.1 General Requirements	P		Inspection	Performance
433	Line and load regulation shall meet the two power supply ranges for +24 VDC (23.0 VDC to 26 VDC) and +12 VDC (11.65 VDC to 13.35 VDC).	4.6.1 General Requirements	P	Saw a slight overage on the +12 VDC line at either end of the input voltage – 77 – 125V. By plugging in some load detectors that actually used the DC line, we saw expected performance out of the power supply.	Analysis	Performance

B.20 ITS Cabinet Type 218 – Serial Interface Unit (SIU) Requirements

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
	The SIU includes three interrupt sources as follows:	4.7.11 Interrupts				Design
445	In advanced detectors, the status outputs may be converted to per channel resets.	4.7.1 General			Inspection	Design
446	When installed in an ITS 14 Pack Output Assembly, the SIU controls fourteen Switch Pack Units (forty-two Outputs) and four Optical Inputs through the CDC socket.	4.7.1 General			Inspection	Design
447	The SIU requires a nominal supply voltage of 24 VDC (+/-2 VDC).	4.7.2 Power Requirements			Inspection	Design
448	A voltage of 16 VDC or less shall be considered loss of power and a voltage of 18 VDC or greater shall be considered adequate for operation.	4.7.2 Power Requirements			Analysis	Design
449	The SIU shall not require more than 300 milliamperes over the voltage range of 16 VDC to 30 VDC and the power surge shall be limited to a maximum of 1.25 Amperes from initial application of DC power.	4.7.2 Power Requirements			Analysis	Design
450	The SIU shall not be damaged by insertion to, or removal from, powered input or output assemblies.	4.7.2 Power Requirements			Performance Test	Design
451	The SIU operates normally for 700 milliseconds after power loss.	4.7.2 Power Requirements			Performance Test	Design
452	The SIU Controller Unit shall include a microprocessor/controller unit together with all required clocking and support circuitry.	4.7.3 Microprocessor			Inspection	Design
453	Operational software necessary to meet housekeeping and functional requirements shall be provided resident in socketed firmware or internal Flash memory.	4.7.4 Memory			Inspection	Design
454	The SIU uses NRESET lines for SIU shut down/turn on operations matching the ATC Controller Unit CPU.	4.7.5 Control Signals			Analysis	Design
455	The SIU shall be fully initialized and providing specified operation upon NRESET Line going HIGH (Power Up).	4.7.5 Control Signals			Performance Test	Design
456	In the ATC Controller, the NRESET operation shall cause the SIU program restart.	4.7.5 Control Signals			Performance Test	Design
457	No prior message operation data retention is required [after an SIU program restart].	4.7.5 Control Signals			Analysis	Design
458	The Request Module Status Response may report this restart as either a Power On or Watchdog.	4.7.5 Control Signals			Performance Test	Design
459	ATC Controller Unit LINESYNC is used as a system time reference.	4.7.5 Control Signals			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
460	The microprocessor/controller unit is reset by any of the following:	4.7.5 Control Signals			Performance Test	Design
	Pushbutton Reset					
	NRESET Signal					
	+5 VDC out of regulation					
	Microprocessor/controller unit watchdog					
461	The SIU includes a 1 Kilohertz Time Reference to provide system response time stamps.	4.7.6 Time References			Inspection	Design
462	The 1 Kilohertz Time Reference shall maintain a frequency accuracy of +/-0.01% (+/-0.1 counts per second).	4.7.6 Time References			Performance Test	Design
463	A watchdog circuit shall be provided.	4.7.7 Watchdog			Analysis	Design
464	The SIU shall power up with the watchdog enabled.	4.7.7 Watchdog			Performance Test	Design
465	Within the first watchdog time period, the watchdog value shall be set to 200 milliseconds +/-100 milliseconds.	4.7.7 Watchdog			Performance Test	Design
466	The watchdog state shall be reported in the SIU status byte as an indication that a watchdog has occurred, which will remain until cleared in the Request Module Status command.	4.7.7 Watchdog			Performance Test	Design
467	Failure of the SIU to reset the watchdog timer shall result in hardware reset.	4.7.7 Watchdog			Performance Test	Design
468	A 32-bit Millisecond Counter shall be provided for "time stamping."	4.7.8 Millisecond Counter			Inspection	Design
469	Each 1 Kilohertz reference shall increment the Millisecond Counter.	4.7.8 Millisecond Counter			Performance Test	Design
470	A Transition Buffer shall be provided capable of holding a minimum of 1024 recorded entries.	4.7.9 Buffers			Analysis	Design
471	The Transition Buffer shall default to empty.	4.7.9 Buffers			Performance Test	Design
472	There shall be two entry types [in the Transition Buffer]: Transition and Rollover.	4.7.9 Buffers			Analysis	Design
473	The inputs shall be monitored for state transition.	4.7.9 Buffers			Analysis	Design
474	At each transition (if the input has been configured to report transition, 4.7.15.4), a transition entry shall be added to the Transition Buffer.	4.7.9 Buffers			Performance Test	Design
475	If multiple inputs change state during one input sample, these transitions shall be entered into the Input Transition Buffer by increasing input number.	4.7.9 Buffers			Performance Test	Design
476	The Millisecond Counter shall be monitored for rollover.	4.7.9 Buffers			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
477	At each rollover transition (\$xxxx FFFF - \$xxxx 0000), a rollover entry shall be added to the Transition Buffer.	4.7.9 Buffers			Analysis	Design
478	For rollover entries, all bits of byte 1 are set to indicate that this is a rollover entry.	4.7.9 Buffers			Inspection	Design
479	A new entry shall be discarded when storage is not available for the new entry.	4.7.9 Buffers			Analysis	Design
480	Transition Buffer blocks are sent to the ATC Controller Unit upon command.	4.7.9 Buffers			Performance Test	Design
481	Upon confirmation of their reception, the [Transition Buffer] blocks shall be removed from the Transition Buffer. See Section 4.7.15.7.	4.7.9 Buffers			Performance Test	Design
482	The entry types are as follows:	4.7.9 Buffers			Analysis	Design
	Input Transition Entry					
	Description msb lsb Byte Number					
	Transition Entry Identifier S Input Number (I0 – I59) 1					
	Timestamp NLSB					
	Timestamp LSB x x x x x x x x 3					
	Millisecond Counter Rollover Entry					
	Description msb lsb Byte Number					
	Rollover Entry Identifier 1 <td></td> <td></td> <td></td> <td></td> <td></td>					
	Timestamp MSB	<u> </u>				
	Timestamp NMSB x x x x x x x x 3	_				
483	At Power Up, the SIU loss of communications timer shall indicate loss of communications until the user program sends the Request Module Status message to reset the "E" Bit and a subsequent set output command is processed.	4.7.10 Power Up Initialization			Analysis	Design
484	All interrupts shall be capable of asynchronous operation with respect to all processing and all other interrupts.	4.7.11 Interrupts			Analysis	Design
485	MILLISECOND Interrupt shall be activated by the Time Reference.	4.7.11 Interrupts			Analysis	Design
486	A timestamp rollover flag set by Millisecond Counter (MC) rollover shall be cleared only on command.	4.7.11 Interrupts			Analysis	Design
487	The LINESYNC signal shall be generated by the controller power supply.	4.7.11 Interrupts			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
488	LINESYNC Interrupt shall be generated by both the 0-1 and 1-0 transitions of the LINESYNC signal.	4.7.11 Interrupts			Performance Test	Design
489	The LINESYNC interrupt shall monitor the Millisecond Counter interrupt and set the Millisecond Counter error flag if there has not been an interrupt from the 1 Kilohertz source for 0.5 seconds (≥60 consecutive LINESYNC interrupts).	4.7.11 Interrupts			Analysis	Design
490	The LINESYNC interrupt shall synchronize the 1 KHz time reference with the 0-1 transition of the LINESYNC signal once a second.	4.7.11 Interrupts			Performance Test	Design
491	A LINESYNC error flag shall be set if the LINESYNC interrupt has not successfully executed for 0.5 seconds or longer (≥500 consecutive millisecond interrupts).	4.7.11 Interrupts			Performance Test	Design
492	The Line Frequency Reference input pin shall receive a square wave signal from the cabinet power supply for the purposes of synchronizing SIU outputs with the AC line.	4.7.11 Interrupts			Analysis	Design
493	Line Frequency Reference Interrupt shall be generated by both the 0-1 and 1-0 transitions of the Line Frequency Reference signal.	4.7.11 Interrupts			Performance Test	Design
494	The Line Frequency Reference interrupt shall monitor the Millisecond Counter interrupt and set the Millisecond Counter error flag if there has not been an interrupt from the 1 Kilohertz source for 0.5 seconds (≥60 consecutive Line Frequency Reference interrupts).	4.7.11 Interrupts			Performance Test	Design
495	The Line Frequency Reference interrupt shall synchronize the Time Reference with the 0-1 transition of the Line Frequency Reference signal once a second.	4.7.11 Interrupts			Analysis	Design
496	A Line Frequency Reference error flag shall be set if the Line Frequency Reference interrupt has not successfully executed for 0.5 seconds or longer (≥500 consecutive millisecond interrupts).	4.7.11 Interrupts			Performance Test	Design
497	 The electrical characteristics of the Line Frequency input are as follows: A voltage between 0 and 8 volts shall be considered the LOW state, and shall occur when the AC line is in the positive half cycle. A voltage between 16 and 26 volts shall be considered the High state, and shall occur when the AC line is in the negative half-cycle. 	4.7.11 Interrupts			Analysis	Design
	3. The Line Frequency Reference input shall exhibit a nominal impedance of 10K (+/-10%) to the +24 VDC input and shall not have more than 1000 picofarads of load capacitance.					
	4. The rise and fall time of the signal connected to this input shall not exceed 50 microseconds.					
498	The SIU/BIU input shall be used by the SIU to determine the AC timing source.	4.7.11 Interrupts			Analysis	Design
499	If the SIU/BIU input is grounded, LINESYNC shall be used as the interrupt source.	4.7.11 Interrupts			Analysis	Design
500	If the SIU/BIU input is pulled up, Line Frequency Reference shall be used as the interrupt source.	4.7.11 Interrupts			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
501	A low-level communication service routine shall be provided to handle reception, transmission, and EIA-485 communication faults.	4.7.11 Interrupts			Analysis	Design
502	The communication server shall automatically:	4.7.11 Interrupts			Analysis	Design
	For Transmission: Generate the opening and closing flags Generate the CRC value Generate the abort sequence (minimum of eight consecutive '1' bits) when commanded by the Microprocessor Unit Provide zero bit insertion For Reception: Detect the opening and closing flags Provide address comparison, generating an interrupt for messages addressed to the SIU, and ignoring messages not addressed to the SIU Strip out inserted zeros Calculate the CRC value, compare it to the received value, and generate an interrupt on an error Generate an interrupt if an abort sequence is received					
503	The task shall be to process the command messages received from the ATC Controller Unit, prepare, and start response transmission.	4.7.12 Communication Processing			Analysis	Design
504	The response message transmission shall begin within four milliseconds of the receipt of the received message.	4.7.12 Communication Processing			Performance Test	Design
505	The SIU shall complete the execution of each command within 70 milliseconds of the end of each response message transmission.	4.7.12 Communication Processing			Performance Test	Design
506	This task shall process the raw input data scanned in by the 1 milliseconds interrupt routine, perform all filtering, and maintain the transition queue entries.	4.7.13 Imput Processing			Analysis	Design
507	The SIU shall have four Optically Coupled Inputs, fifty-four Parallel Input/Outputs and four Serial Ports.	4.7.14 Inputs and Outputs			Inspection	Design
508	The Opto Common input shall be the common reference pin for four Opto Inputs.	4.7.14 Inputs and Outputs			Inspection	Design
509	The Opto Inputs are intended to provide optical isolation for Pedestrian Detection, internal cabinet functions, Remote Interconnect or other auxiliary inputs.	4.7.14 Inputs and Outputs			Analysis	Design

#	Requirement (Standard	l Document Section)		Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
510			27K Ohm, 1-Watt resistors for 120 o 12 VAC for Pedestrian Detector	4.7.14 Inputs and Outputs			Inspection	Design
511	These [Opto] inputs may connected to -24 VDC.	also be used for low-true DC ap	plications when the Opto Common pin is	4.7.14 Inputs and Outputs		This specification appears to be informational only.	Inspection	Design
512	These inputs may function	on in the place of 242/252 isolato	r modules.	4.7.14 Inputs and			Analysis	Design
	1000 VAC RMS mi		f 10 Megohms minimum resistance and tor pins except the Opto Common pin, at peres RMS.	Outputs				
	2. These inputs shall exto the Opto Common		Opto Common pin of 5000 Ohms, +10%					
	3. The Opto Inputs sha Opto Common input	AC sinusoid or DC) or less relative to the						
	4. The Opto Inputs shared Opto Common input	sinusoid or DC) or more relative to the						
	5. Any steady state vo		Input and the Opto Common shall not					
		ot be acknowledged when active active for 50 milliseconds or mo	for 25 milliseconds or less, and shall be ore.					
	7. The Opto Inputs sha	ll conform to transient immunity	specifications of section 3.7.5.4.					
513	The first Output Assemb	ly assignments shall be dedicated	d as follows:	4.7.14 Inputs and			Analysis	Design
	PIN	I st OUTPUT ASSEMBLY	APPLICABLE HOUSING TYPE	Outputs				
	Opto Input 1	Manual Control Enable	All					
	Opto Input 2	Interval Advance	All					
	Opto Input 3	Stop Time	All					
	Opto Input 4	Manual Flash	All					
	Opto Input Common	AC-	All					
514	SIU shall control fifty-fo	ur input/output lines using groun	d-true logic.	4.7.14 Inputs and Outputs			Inspection	Design
515		logic "1" (ON) when the input vo e read logic "0" (OFF) when the i	oltage at its field connector input is less nput voltage exceeds 16 VDC.	4.7.14 Inputs and Outputs			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
516	Each input shall have an internal pull-up to +24 VDC of 11K Ohms maximum, and shall not deliver greater than 10 milliamperes to a short circuit to ground.	4.7.14 Inputs and Outputs			Performance Test	Design
517	Each output written as a logic "1" (ON) shall have a voltage at its field connector output of less than 4.0 VDC.	4.7.14 Inputs and Outputs			Analysis	Design
518	Each output written as logic "0" (OFF) shall provide an open circuit (1 Megohm or more) at its field connector output.	4.7.14 Inputs and Outputs			Performance Test	Design
519	Each output shall consist of an open-collector capable of driving 40 VDC minimum and sinking 100 milliamperes minimum.	4.7.14 Inputs and Outputs			Inspection	Design
520	Each output circuit shall be capable of switching from logic "1" to logic "0" within 100 microseconds when connected to a load of 100K Ohms minimum.	4.7.14 Inputs and Outputs			Performance Test	Design
521	Each output circuit shall be protected from transients of 10 microseconds (+/-2 microseconds) duration, +/-300 VDC from a 1K Ohm source, with a maximum rate of 1 pulse per second.	4.7.14 Inputs and Outputs			Performance Test	Design
522	Each output shall latch the data written and remain stable until either new data is written or the active-low reset signal.	4.7.14 Inputs and Outputs			Analysis	Design
523	Upon an active-low reset signal, each output shall latch a logic "0" and retain that state until a new writing.	4.7.14 Inputs and Outputs			Performance Test	Design
524	The state of all output circuits at the time of Power Up or in Power Down state shall be OFF.	4.7.14 Inputs and Outputs			Inspection	Design
525	It shall be possible to simultaneously assert all outputs within 100 microseconds of each other.	4.7.14 Inputs and Outputs			Performance Test	Design
526	An output circuit state not changed during a new writing shall not glitch when other output circuits are updated.	4.7.14 Inputs and Outputs		What is the exact meaning of "glitch" in this specification?	Analysis	Design
527	Each parallel Input/Output function contains all of the functions listed below of both the Input Function and Output Function.	4.7.14 Inputs and Outputs			Analysis	Design
528	Input scanning shall begin at I0 (bit 0) and proceed to the highest numbered input, ascending from LSB to MSB.	4.7.14 Inputs and Outputs			Analysis	Design
529	Each complete input scan shall finish within 100 microseconds.	4.7.14 Inputs and Outputs			Performance Test	Design
530	Once sampled, the logic state of an input shall be held until the next input scan.	4.7.14 Inputs and Outputs			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
531	Each input shall be sampled 1,000 times per second.	4.7.14 Inputs and Outputs			Performance Test	Design
532	The time interval between samples shall be 1 milliseconds (+/-100 microseconds).	4.7.14 Inputs and Outputs			Performance Test	Design
533	The Millisecond Counter shall be sampled within 10 microseconds of the completion of the input scan.	4.7.14 Inputs and Outputs			Performance Test	Design
534	If configured, the inputs shall be filtered by the SIU to remove signal bounce.	4.7.14 Inputs and Outputs			Analysis	Design
535	The filtered input signals shall then be monitored for changes as noted.	4.7.14 Inputs and Outputs			Analysis	Design
536	The filtering parameters for each input shall consist of Ignore Input Flag and the ON and OFF filter samples.	4.7.14 Inputs and Outputs			Inspection	Design
537	If the Ignore Input flag is set, no input transition entries shall be placed into the Input Transition buffer.	4.7.14 Inputs and Outputs			Performance Test	Design
538	The ON and OFF filter samples shall determine the number of consecutive samples an input must be ON and OFF, respectively, before a change of state is recognized.	4.7.14 Inputs and Outputs			Performance Test	Design
539	If the change of state is shorter than the specified value, the change of state shall be ignored.	4.7.14 Inputs and Outputs			Performance Test	Design
540	The ON and OFF filter values shall be in the range of 0 to 255.	4.7.14 Inputs and Outputs			Analysis	Design
541	A filter value of 0, for either or both values, shall result in no filtering for this input.	4.7.14 Inputs and Outputs			Performance Test	Design
542	The default values for input signals after reset shall be as follows: Filtering: Enabled: On and off filter values shall be set to: 5 Transition monitoring: Disabled (Timestamps are not logged)	4.7.14 Inputs and Outputs			Analysis	Design
543	Simultaneous assertion of all outputs shall occur within 100 microseconds.	4.7.14 Inputs and Outputs			Performance Test	Design
544	Each output shall be capable of being individually configured in state to ON, OFF, or a state synchronized with either phase of LINESYNC.	4.7.14 Inputs and Outputs			Analysis	Design

#	Require	ement (Sta	ındard Docu	iment Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
545				all only be "ON" if the SIU continues to receive active Controller Unit.	4.7.14 Inputs and Outputs			Analysis	Design
546	revert to	the OFF	ondition, an	tions with the ATC Controller Unit for 2.0 seconds, all outputs shall d the SIU status byte shall be updated to reflect the loss of Controller Unit.	4.7.14 Inputs and Outputs			Performance Test	Design
547	as follow			ATC Controller Unit-SIU frame protocol shall control each output	4.7.14 Inputs and Outputs			Analysis	Design
	Case	Output Data Bit	Output Control Bit	Function					
	A	0	0	Output in the OFF state					
	В	1	1	Output is a square wave, synchronized to the LINESYNC signal. When LINESYNC is ON (1), the output is OFF, and when LINESYNC is OFF (0), the output is ON.					
	С	0	1	Output is a square wave, synchronized to the LINESYNC signal. When LINESYNC is ON (1), the output is ON, and when LINESYNC is OFF (0), the output is OFF					
	D	1	0	Output is in the ON state.					
548				ding output shall be turned OFF if previously ON and if previously se configured.	4.7.14 Inputs and Outputs			Analysis	Design
549	microse	f-cycle swire econds after the entire h	the correspo	B and C), all outputs to be changed shall be changed within 50 onding LINESYNC transition and shall remain in the same state	4.7.14 Inputs and Outputs			Performance Test	Design
550			he correspon til otherwise	ding output shall be turned ON if previously OFF and if previously configured.	4.7.14 Inputs and Outputs			Performance Test	Design
551	All outp	outs shall n	ever change	state unless configured to do so.	4.7.14 Inputs and Outputs			Analysis	Design
554	Commu	inications c	ircuitry shall	l be capable of 614.4 Kilobits per second of data pass through.	4.7.14 Inputs and Outputs			Performance Test	Design
555	Port 1 sl	hall interfa	ce the SIU to	Serial Bus 1 of the ITS cabinet Modular Bus Assemblies.	4.7.14 Inputs and Outputs			Analysis	Design

#	Requiremen	nt (Standard Document	Sectio	on)							Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
56	All commun	ications circuitry and pro	otocol s	shall ma	tch Seria	ıl Bus 1	require	ments.			4.7.14 Inputs and Outputs			Analysis	Design
57	The SIU sha appropriate a	Il function as the "LOCA action.	AL" coi	mmand 1	node for	this net	work re	spondin	g with		4.7.14 Inputs and Outputs			Analysis	Design
58	See ATC Co	ontroller Unit specification	n, CPU	J Field I	/O, for p	orotocol	and rec	uiremer	nts.		4.7.14 Inputs and Outputs			Analysis	Design
59	The SP5 SD	LC frame address assign	ments ((Comma	and/Resp	onses)	are as fo	ollows:			4.7.14 Inputs and			Analysis	Design
	Address SYSTEM SIU ADDRESS			Outputs											
	Adaress	ASSEMBLY / UNIT	A7	A6	A5	A4	A3	A2	Al	A0					
	0 Reserved														
	1	14 Pack in position 1	0	0	0	0	0	0	0	1					
	2 Reserved														
	3	14 Pack in position 3	0	0	0	0	0	0	1	1					
	4	r · · · · · · · · · · · · · · · · · · ·	0												
		0	1												
	6	6 Pack in position 2	0	0	0	0	0	1	1	0					
	7	6 Pack in position 3	0	0	0	0	0	1	1	1					
	8	7			Reserve				1 0						
	9	Input #1	0	0	0	0	l	0	0	1					
	10	Input #2	0	0	0	0	1	0	1	0					
	11	Input #3	0	0	0	0	1	0	1	1					
	12	Input #4	0	0	0	0	1	1	0	0					
	13	Input #5	U		0 Reserve	0	1	1	1 0	1					
	15	CMU #1	0	0	0	0	1	1	1	1					
	16	CMU #2	0	0	0	1	0	0	0	0					
	17	CMU #3	0	0	0	1	0	0	0	1					
	18	CMU #4	0	0	0	1	0	0	1	0					
	19	CPU	0	0	0	1	0	0	1	1					
	20	FI/O 2A or 8	0	0	0	1	0	1	0	0					
	21 to 254				Reserve	d		1	<u> </u>						
	255	Broadcast All	1	1	1	1	1	1	1	1					
		to A3 are Input to SIU wopen or ground false. 1=		-			d)								

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
560	SIU Port 2 shall interface to Serial Bus 2 of the ITS cabinet Modular Bus Assemblies providing a communications path to the ATC Controller Unit for block data retrieval.	4.7.14 Inputs and Outputs			Analysis	Design
561	No connection exists between SIU Port 1 and SIU Port 2.	4.7.14 Inputs and Outputs			Inspection	Design
562	Similarly, no connection exists between SIU Port 2 and the microprocessor/controller unit.	4.7.14 Inputs and Outputs			Inspection	Design
563	All data transfers between SIU Ports 1 and 2 shall be accomplished by the ATC Controller Unit. For example, data sent back may include monitor diagnostic status and communication status; input diagnostics status (detector sensor or isolator); and processed channel inputs data such as rate counts, occupancies, average speeds, speed classification and incident/presence.	4.7.14 Inputs and Outputs			Analysis	Design
564	If the ATC Controller Unit is communicating via Logical Port SP3S, SIU Port 2 shall communicate in SDLC format and protocol, and the hardware requirements shall match Serial Bus 2 (synchronous TX/RX using TxC from the ATC Controller Unit CPU for common clocking).	4.7.14 Inputs and Outputs			Analysis	Design
565	If the ATC Controller Unit is communicating via Logical Port SP3, SIU Port 2 shall communicate in an asynchronous START BIT/STOP BIT format and protocol.	4.7.14 Inputs and Outputs			Analysis	Design
566	The SIU Port 3 shall be provided for communication to a personal computer via a front panel 9-position subminiature D-type connector and EIA-232 logic.	4.7.14 Inputs and Outputs			Analysis	Design
567	Its [SIU Port 3] purpose is to upload diagnostic information, and to download the SIU program.	4.7.14 Inputs and Outputs			Analysis	Design
568	The SIU Port 3 protocol shall be defined by the vendor, and operate with vendor-supplied software.	4.7.14 Inputs and Outputs			Inspection	Design
569	The pin assignments of SIU Port 3 shall match that of ATC Controller Unit C60 port.	4.7.14 Inputs and Outputs			Inspection	Design
570	SIU Port 4 consists of Detector Rack signal INBUS TxD, INBUS RxD, INBUS TxC, and INBUS RxC, and shall conform to the electrical standards of EIA-485, single-ended.	4.7.14 Inputs and Outputs			Analysis	Design
571	In this scheme, the RxD- and RxC- inputs of the EIA-485 receivers are connected to 2.5 Volts, while the TxD- and TxC- outputs of the EIA-485 drivers are not used.	4.7.14 Inputs and Outputs			Inspection	Design
572	SIU Port 4 receivers shall withstand +/-25 Volts, suitable for reception of EIA-232 bipolar signals.	4.7.14 Inputs and Outputs			Performance Test	Design
573	All four INBUS signals shall be terminated at each receiver with impedance of 6,800 Ohms (+/-5%), connected from signal to +5V Ground on the SIU.	4.7.14 Inputs and Outputs			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
574	The detector vendor shall define the SIU Port 4 messages.	4.7.14 Inputs and Outputs			Analysis	Design
575	The detector vendor shall define the SIU Port 4 protocol.	4.7.14 Inputs and Outputs			Analysis	Design
576	The SIU provides one inversion to ensure a controller MARK equates to a detector MARK.	4.7.14 Inputs and Outputs			Analysis	Design
577	The SIU shall provide an LED indicator for TxD and RxD, such that is illuminated during a MARK (START Bit, for example) and extinguished during a SPACE (STOP Bit, for example).	4.7.14 Inputs and Outputs			Analysis	Design
578	SIU Port 4 provides the buffering to SIU Port 2, allowing the ATC Controller Unit to communicate directly to the detectors, as follows:	4.7.14 Inputs and Outputs				Design
579	If the ATC Controller Unit is communicating to detectors via Logical Port SP3S, the SIU Port 4 buffers shall convert SIU Port 2 TxD+ and TxD- to EIA-485 which shall then be transmitted to the detectors via INBUS TxD.	4.7.14 Inputs and Outputs			Analysis	Design
580	Likewise, the SIU Port 4 buffers shall convert SIU Port 2 TxC+ and TxC- to EIA-485, which shall then be transmitted to the detectors via INBUS TxC.	4.7.14 Inputs and Outputs			Analysis	Design
581	If the ATC Controller Unit is communicating to detectors via Logical Port SP3S, the SIU Port 4 buffers shall convert INBUS RxD from EIA-485, which shall then be transmitted to the ATC Controller Unit via SIU Port 2 RxD+ and RxD	4.7.14 Inputs and Outputs			Analysis	Design
582	Likewise, the SIU Port 4 buffers shall convert INBUS RxC from EIA-485, which shall then be transmitted to the ATC Controller Unit via SIU Port 2 RxC+ and RxC	4.7.14 Inputs and Outputs			Analysis	Design
583	If the ATC Controller Unit is communicating to detectors via Logical Port SP3, the SIU Port 4 buffers shall convert SIU Port 2 TxD+ and TxD- to EIA-485 which shall be transmitted to the detectors via INBUS TxD.	4.7.14 Inputs and Outputs			Analysis	Design
584	If the ATC Controller Unit is communicating to detectors via Logical Port SP3, the SIU Port 4 buffers shall convert INBUS RxD is from EIA-485, which shall be transmitted to the ATC Controller Unit via SIU Port 2 RxD+ and RxD	4.7.14 Inputs and Outputs			Analysis	Design
585	Asynchronous operation shall not use Port 2 TxC+, TxC-, RxC+, RxC-, nor Port 4 INBUS TxC, or INBUS RxC.	4.7.14 Inputs and Outputs			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
586	The SIU shall sense the rack address block and generate a square wave on the ASSEMBLY ADDRESS signal as follows: ASSEMBLY ADDRESS ASSEMBLY ADDRESS FREQUENCY (Hertz)(+/-15%) 1 60 2 30 3 15 4 7.5 5 3.75	4.7.14 Inputs and Outputs			Analysis	Design
587	The INBUS RTS line shall be pulled to +24 Volts via a 10K Ohm resistor on the SIU.	4.7.14 Inputs and Outputs			Analysis	Design
588	In systems using legacy detectors that do not use INBUS RTS, this line [INBUS RTS] shall not be used (no connection).	4.7.14 Inputs and Outputs			Analysis	Design
589	Detectors equipped with INBUS RTS shall drive this line low when transmitting data from that detector to the SIU via INBUS.	4.7.14 Inputs and Outputs			Performance Test	Design
590	When not transmitting data, this line shall not be driven low and is pulled to +24V via the 10K Ohm resistor.	4.7.14 Inputs and Outputs			Performance Test	Design
591	The controller transmits a message on Serial Bus 2 which shall be received by each detector via the SIU INBUS TxD and INBUS TxC.	4.7.14 Inputs and Outputs			Analysis	Design
592	If the detector is asynchronous, INBUS TxC shall be ignored.	4.7.14 Inputs and Outputs			Analysis	Design
593	Each detector shall compare the address field of the message with its own slot address and assembly address.	4.7.14 Inputs and Outputs			Analysis	Design
594	If the address matches, that detector shall respond with data on INBUS RxD and INBUS RxC.	4.7.14 Inputs and Outputs			Performance Test	Design
595	If the detector is asynchronous, INBUS RxC shall not be used.	4.7.14 Inputs and Outputs			Inspection	Design
596	The SIU of the responding detector shall enable its EIA-485 line drivers to transmit the response from INBUS to SB2.	4.7.14 Inputs and Outputs			Performance Test	Design
597	This driver [Serial Bus 2 Control] shall be enabled by any of the three following conditions: Activity on INBUS RxD Activity on INBUS RxC INBUS RTS at low (true)	4.7.14 Inputs and Outputs			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
598	This driver [Serial Bus 2 Control] shall be disabled by either of the following two conditions: Lack of activity on both INBUS RxD and RxC for 1.5 milliseconds Inbus RTS transitions from low (true) to high (false)	4.7.14 Inputs and Outputs			Analysis	Design
599	All communication with the ATC Controller Unit shall be SDLC-compatible command-response protocol, support 0-bit stuffing, and operate at a data rate of 614.4 Kilobits per second.	4.7.15 Data Communications Protocol			Analysis	Design
600	The ATC Controller Unit shall always initiate the communication and should the command frame be incomplete or in error, no SIU response shall be transmitted.	4.7.15 Data Communications Protocol			Analysis	Design
601	There is no requirement for a Command message Queue that results in a response stream of messages.	4.7.15 Data Communications Protocol			Analysis	Design
602	An incoming Command Message may abort a planned response or truncate a response already in progress.	4.7.15 Data Communications Protocol			Analysis	Design
603	Command Frame Errors shall include Microprocessor identified abnormalities, such as CRC errors, bit alignment or bit stuffing problems.	4.7.15 Data Communications Protocol			Analysis	Design
604	Message irregularities shall include unknown Message numbers or improper command lengths.	4.7.15 Data Communications Protocol			Analysis	Design
605	The frame type shall be determined by the value of the first byte of the message.	4.7.15 Data Communications Protocol			Analysis	Design
606	The command frames type values \$70 - \$7F and associated response frame type values \$F0 - \$FF are allocated to the Manufacturer diagnostics.	4.7.15 Data Communications Protocol			Analysis	Design
607	All other frame types not called out are reserved.	4.7.15 Data Communications Protocol			Analysis	Design

#	Requiremen	t (Standard	l Document Section)			Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
608	The comman Frame Types	•	Frame Type values and messa	age times shall be as fo	llows:	4.7.15 Data Communications Protocol			Analysis	Design
	Module Command	I/0 Module Response	Description	Minimum Message Time	Maximum Message Time	Protocol				
	49	177	Request Module Status	250 microseconds	275 microseconds					
	50	178	MILLISECOND CTR. Mgmt.	222.5 microseconds	237.5 microseconds					
	51	179	Configure Inputs	344.5 microseconds	6.8750 milliseconds					
	52	180	Poll Raw Input Data	317.5 microseconds						
	53	181	Poll Filtered Input Data	317.5 microseconds						
	54	182	Poll Input Transition Buffer	300 microseconds	10.25 milliseconds					
	55	183	Command Outputs	405 microseconds	410 microseconds					
	56	184	Config. Input Tracking Functions	340 microseconds	10.25 milliseconds					
	57	185	Config. Complex Output Functions	340 microseconds	6.875 milliseconds					
	58	186	Reserved							
	59	187	Reserved							
	60	188	SIU Identification	222.5 microseconds	222.5 microseconds					
	61-62	189-190	Reserved (note below)							
	63	191	Reserved							
	64	192	Reserved							
	65	193	Reserved (note below)							
	66		Reserved (note below)							
	67	195	Reserved (note below)							
609	Cabinet Mon Message 66/1	itor System No Respons	O, 65/193, and 67/195 shall be Serial Bus #1 (section 25) for e is a Broadcast Message to A and process this message if it	r Command and Respo Address 255 containing	nse Frames. the current time.	4.7.15 Data Communications Protocol			Analysis	Design
610	The Commar	nd [Request	Mode Status] shall be used to	request SIU status inf	ormation response.	4.7.15 Data Communications Protocol			Analysis	Design

#	Requirement (Standard Document Section)		Document Section	Pass Fail	Comments	Туре	Requirement Type
611	Command/Response frames shall be as follows: Request Module Status Command		4.7.15 Data Communications Protocol			Analysis Analysis Analysis	Design
	Description msb lsb	Byte Number	Trotocor				
	(Type Number = 49) 0 0 1 1 0 0 0 1	Byte 1					
	Reset Status Bits P E K R T M L W	Byte 2					
612	Request Module Status Response		4.7.15 Data			Analysis	Design
	Description msb lsb	Byte Number	Communications Protocol				
	(Type Number = 177) 1 0 1 1 0 0 1 1	Byte 1	1100001				
	System Status P E K R T M L W	Byte 2					
	SCC Receive Error Count Receive Error Count	Byte 3					
	SCC Transmit Error Count Transmit Error Count	Byte 4					
	MC Timestamp MSB MC Timestamp MSB	Byte 5					
	MC Timestamp NMSB MC Timestamp NMSB	Byte 6					
	MC Timestamp NLSB MC Timestamp NLSB	Byte 7					
	MC Timestamp LSB MC Timestamp LSB	Byte 8					
613	The response status bits are defined as follows: P - Indicates SIU hardware reset E - Indicates a communications loss of greater than two secon M - Indicates an error with the Millisecond Counter interrupt L - Indicates an error in the LINESYNC W - Indicates that the SIU has been reset by the Watchdog R - Indicates that the EIA-485 receive error count byte has rol T - Indicates that the EIA-485 transmit error count byte has rol K - Not Used	lled over	4.7.15 Data Communications Protocol			Analysis	Design
614	Each of these bits shall be individually reset by a '1' in the corresponding bit Request Module Status frame, and the response frame shall report the current		4.7.15 Data Communications Protocol			Analysis	Design
615	The SCC error count bytes shall not be reset. When a count rolls over (255 roll-over flag shall be set.	- 0), its corresponding	4.7.15 Data Communications Protocol			Analysis	Design

#	Requirement (Standard Docume	ent Section)		Document Section	Pass Fail	Comments	Type	Requirement Type
616	The Millisecond Counter Manager Counter.	ment Frame shall be used to set the	value of the Millisecond	4.7.15 Data Communications Protocol			Analysis	Design
617	The 'S' bit shall return status '0' on	completion or '1' on error.		4.7.15 Data Communications Protocol			Performance Test	Design
618	The 32-bit value shall be loaded in LINESYNC signal.	4.7.15 Data Communications Protocol			Performance Test	Design		
619	The frames shall be as follows: Millisecond Counter Management	^t Command		4.7.15 Data Communications Protocol			Analysis	Design
	Description	msb	lsb Byte Number					
	(Type Number = 50)	0 0 1 1 0 0 1	0 Byte 1					
	New MC Timestamp MSB	x x x x x x x x	x Byte 2					
	New MC Timestamp NMSB	x x x x x x x x	x Byte 3					
	New MC Timestamp NLSB	x x x x x x x x	x Byte 4					
	New MC Timestamp LSB	x x x x x x x x	x Byte 5					
	Millisecond Counter Management	Response						
	Description	msb	lsb Byte Number					
	(Type Number = 178)	1 0 1 1 0 0 1	0 Byte 1					
	Status	0 0 0 0 0 0 0	S Byte 2					
620	The Configure Inputs command fr	4.7.15 Data Communications Protocol			Analysis	Design		

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
621	The command-response frames shall be as follows: Configure Inputs Command	4.7.15 Data Communications Protocol			Analysis	Design
	Description msb lsb Byte Nu				Analysis	
	(Type Number = 51) 0 0 1 1 0 0 1 1 Byte	1				
	Number of Items (n) n n n n n n n Byte	2				
	Item # - Byte 1 E Input Number (I0 – I59) Byte 3(I	1)+3				
	Item # - Byte 2 Leading edge filter (e) Byte 3(1)	1)+4				
	Item # - Byte 3 Trailing edge filter (r) Byte 3(1)	1)+5				
	NOTE: In the case of an invalid parameter error, the entire message shall be rejected.					
622	Configure Inputs Response	4.7.15 Data			Analysis	Design
	Description msb lsb Byte Nu	Communications Protocol				
	(Type Number = 179) 1 0 1 1 0 0 1 1 Byte					
	Status 0 0 0 0 0 0 S Byte	2				
623	Block field definitions shall be as follows:	4.7.15 Data			Analysis	Design
	E - Ignore Input Flag. "1" = do not record transition entries for this in record transition entries for this input	ut, "0" = Communications Protocol				
	e - A one-byte leading edge filter specifying the number of consecutive input sam must be "0" before the input is considered to have entered to "0" state from					
	(range 1 to 255, 0 = filtering disabled)					
	r - A one-byte trailing edge filter specifying the number of consecutive input sam must be "1" before the input is considered to have entered to "1" state fror (range 1 to 255, 0 = filtering disabled)					
	S - return status $S = 0$ on completion or 1 on error					
624	The Poll Raw Input Data frame shall be used to poll the SIU for the current unfiltered st inputs.	tus of all 4.7.15 Data Communications Protocol			Analysis	Design
625	The response frame shall contain 8 bytes (Inputs 0-63) of information indicating the cur status.	ent input 4.7.15 Data Communications Protocol			Analysis	Design

#	Requirement (Standard Docume	ent Section)	Document Section	<u>Pass</u> Fail	Comments	Type	Requirement Type
626	The frames shall be as follows: Poll Raw Input Data Command		4.7.15 Data Communications Protocol			Analysis	Design
	Description	msb lsb By	rte Number				
	(Type Number = 52)	0 0 1 1 0 1 0 0	Byte 1				
	Poll Raw Input Data Response						
	Description	msb lsb By	rte Number				
	(Type Number = 180)	1 0 1 1 0 1 0 0	Byte 1				
	Inputs I0 (lsb) to I7 (msb)	x x x x x x x x x x	Byte 2				
	Inputs I8 to I53, I56 to I59	x x x x x x x x x B	ytes 3 to 9				
	MC Timestamp MSB	x x x x x x x x x x	Byte 10				
	MC Timestamp NMSB	x x x x x x x x x x	Byte 11				
	MC Timestamp NLSB	x x x x x x x x x x	Byte 12				
	MC Timestamp LSB	x x x x x x x x x x	Byte 13				
627	The Poll Filtered Input Data frame inputs.	e shall be used to poll the SIU for the current filte	ered status of all 4.7.15 Data Communications Protocol			Analysis	Design
628	The response frame shall contain 8 filtered status of the inputs.	8 bytes (Inputs 0-63) of information indicating the	4.7.15 Data Communications Protocol			Analysis	Design
629	Raw input data shall be provided i	in the response for inputs that are not configured	for filtering. 4.7.15 Data Communications Protocol			Analysis	Design

#	Requirement (Standard Documen			Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type	
630	The frames shall be as follows: Poll Filter Input Data Command				4.7.15 Data Communications Protocol			Analysis	Design
	Description	msb	lsb	Byte Number	1100001				
	(Type Number = 53)	0 0 1 1 0 1) 1	Byte 1					
	Poll Filter Input Data Response								
	Description	msb	lsb	Byte Number	=				
	(Type Number = 181)	1 0 1 1 0 1	0 1	Byte 1					
	Inputs I0 (lsb) to I7 (msb)	x x x x x x x	x x	Byte 2					
	Inputs I8 to I53, I56 to I59	x x x x x x x	x x	Bytes 3 to 9					
	MC Timestamp MSB	x x x x x x x	x x	Byte 10					
	MC Timestamp NMSB	x x x x x x x	x x	Byte 11					
	MC Timestamp NLSB	x x x x x x x	x x	Byte 12					
	MC Timestamp LSB	x x x x x x x	x x	Byte 13					
631	The Poll Input Transition Buffer frame shall poll the SIU for the contents of the input transition buffer.				4.7.15 Data Communications Protocol			Analysis	Design
632	The response frame shall include a three-byte information field for each of the input changes that have occurred since the last interrogation.			the input changes that	4.7.15 Data Communications Protocol			Analysis	Design

#	Requirement (Standard Document	nt Section)		Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
633	The frames are as follows: Poll Input Transition Buffer Commo	and		4.7.15 Data Communications			Analysis	Design
	Description	msb lsb	Byte Number	Protocol				
	(Type Number = 54)	0 0 1 1 0 1 1 0	Byte 1					
	Block Number	x x x x x x x x x	Byte 2					
	Poll Input Transition Buffer Respon	nse						
	Description	msb lsb	Byte Number					
	(Type Number = 182)	1 0 1 1 0 1 1 0	Byte 1					
	Block Number	x x x x x x x x x x	Byte 2					
	Number of Entries = N	x x x x x x x x x x	Byte 3					
	Item#	S Input Number (I0 – I59)	Byte 3(I-1)+4					
	Item # MC Timestamp NLSB	x x x x x x x x x x	Byte 3(I-1)+5					
	Item # MC Timestamp LSB	x x x x x x x x x	Byte 3(I-1)+6					
	Status	0 0 0 0 C F E G	Byte 3(I-1)+7					
	MC Timestamp MSB	x x x x x x x x x x	Byte 3(N-1)+8					
	MC Timestamp NMSB	x x x x x x x x x x	Byte 3(N-1)+9					
	MC Timestamp NLSB	x x x x x x x x x	Byte 3(N-1)+10					
	MC Timestamp LSB	x x x x x x x x x	Byte 3(N-1)+11					
634	Each detected state transition for ea as it occurs.	ach active input (see 4.7.9 and 4.7.15.4) i	is placed in the queue	4.7.15 Data Communications Protocol			Analysis	Design
635	transition, bit is 0 if th	the input after the transition, bit is 1 if the Input is OFF after the transition y buffer limit has been exceeded	he Input is ON after the	4.7.15 Data Communications Protocol			Analysis	Design
		F - Indicates the 1024 buffer limit has been exceeded						
	G - Indicates the requested							
	E - Same block number re	equested, E is set in response						

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
636	The entries provided within the Transition Buffer Poll response shall be ordered from the start of the reply as the oldest to newest.	4.7.15 Data Communications Protocol			Analysis	Design
637	The very first access provides the oldest entry.	4.7.15 Data Communications Protocol			Analysis	Design
638	The SIU device shall initialize, upon Power Up or Reset, its last Block Number received value to 0xFF in order to facilitate suppression of the G Bit response when the ATC Controller Unit program starts and uses 0x00 as the first Block Number.	4.7.15 Data Communications Protocol			Performance Test	Design
639	Subsequent responses are subject to the old-buffer purge mechanism stated below.	4.7.15 Data Communications Protocol			Analysis	Design
640	The ATC Controller Unit program monotonically increases the Block Number after each command issued to purge the old buffer.	4.7.15 Data Communications Protocol			Analysis	Design
641	When the SIU Module receives this command, it shall compare the associated Block Number with the Block Number of the previously received command.	4.7.15 Data Communications Protocol			Analysis	Design
642	If it [the latest command received by the SIU Module] is the same [as the previous command received by the SIU Module], the previous buffer shall be re-sent to the ATC Controller Unit and the 'E' flag set in the status response frame.	4.7.15 Data Communications Protocol			Performance Test	Design
643	If it [the latest command received by the SIU Module] is not equal to the previous Block Number, the old buffer shall be purged and the next block of data sent.	4.7.15 Data Communications Protocol			Analysis	Design
644	If the block number is not incremented by one, the status G bit shall be set.	4.7.15 Data Communications Protocol			Performance Test	Design
645	The block number received becomes the current number (even if out of sequence).	4.7.15 Data Communications Protocol			Performance Test	Design
646	The Block Number byte sent in the response block shall be the same as that received in the command block.	4.7.15 Data Communications Protocol			Performance Test	Design

#	Requirement (Standard Document Sec	ction)									Document Section	Pass Fail	Comments	Туре	Requirement Type
647	The Set Outputs frame shall be used to coin the frame.	omma	nd th	ne SIU	J to s	et the	Out	puts a	accord	ling to the data	4.7.15 Data Communications Protocol			Analysis	Design
648	If there is any error configuring the output	its, the	e 'E' 1	flag ii	n the	respo	nse i	frame	shall	be set to '1'.	4.7.15 Data Communications Protocol			Performance Test	Design
649	If the LINESYNC reference has been los	INESYNC reference has been lost, the 'L' bit in the response frame shall be set. LINESYNC reference shall also be indicated in system status information						me sł	nall be	e set.	4.7.15 Data Communications Protocol			Performance Test	Design
650	Loss of LINESYNC reference shall also	ss of LINESYNC reference shall also be indicated in system status information.					4.7.15 Data Communications Protocol			Performance Test	Design				
651	These command and response frames are as follows: Set Outputs Command										4.7.15 Data Communications Protocol			Analysis	Design
	Description	msb)					lsb Byte Number			Frotocoi				
	(Type Number = 55)	0	0	1	1	0	1	1	1	Byte 1					
	Outputs O0 (lsb) to O7 (msb) Data	X	X	Х	X	х	X	X	X	Byte 2					
	Outputs O8 to O54 Data	X	X		X	X	X	X	X	Bytes 3 to 8					
	Outputs O56 to O63 Data (reserved)	0	0	0	0	0	0	0	0	Byte 9					
	Outputs O0 (lsb) to O7 (msb) Control	X	X	X	X	X	X	X	X	Byte 10					
	Outputs O8 to O54 Control	х	X	x	x	х	X	X	X	Bytes 11 to 16					
	Outputs O56 to O63 Control (reserved)	0	0	0	0	0	0	0	0	Byte 17					
	Set Outputs Response														
	Description msb lsb Byte Number						By	te Number							
	(Type Number = 183) 1 0 1 1 0 1 1 1 Byte 1				Byte 1										
	Status 0	0	0	0	0 (L	Е			Byte 2					

#	Requirement (Standard Docume	ent Section)		Document Section	Pass Fail	Comments	Туре	Requirement Type
652	output that responds to transitions	nctions frame shall be used to configure the on a particular input. The maximum nung Functions Overview' for additional deta	nber of active	4.7.15 Data Communications Protocol			Analysis	Design
653	Please note that Configure Input T Control Applications. (Authorized	Fracking Functions is not intended for use d Engineering Information)	with Traffic Signal	4.7.15 Data Communications Protocol		What value does this specification add to the standard?	Analysis	Design
654	The command and response frame Configure Input Tracking Function	es for Input Tracking Functions shall be as ans Command	s follows:	4.7.15 Data Communications Protocol			Analysis	Design
	Description	msb lsb	Byte Number					
	(Type Number = 56)	0 0 1 1 1 0 0 0	Byte 1					
	Number of Items							
	Item # - Byte 1	E Output Number (O0 – O54)	Byte 2(I-1)+3					
	Item # - Byte 2	I Input Number (I0 – I59)	Byte 2(I-1)+4					
655	Number of Items: 0-16 Tracking I	Definitions are contained in this message.		4.7.15 Data Communications Protocol			Analysis	Design
656			4.7.15 Data Communications Protocol			Analysis	Design	
657	Output Number: 0 - Maximum O	Output Number for the SIU device type. nput Number for the SIU device type.		4.7.15 Data Communications Protocol			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
658	Configure Input Tracking Functions Response	4.7.15 Data			Analysis	Design
	Description msb lsb Byte Number	Communications Protocol				
	(Type Number = 184) 1 0 1 1 1 0 0 Byte 1	11010001				
	Status 0 0 0 0 0 0 V Byte 2					
	MC Timestamp MSB					
	MC Timestamp NMSB					
	MC Timestamp NLSB					
	MC Timestamp LSB					
	Field Definitions:					
	V '1' - Maximum number of configurable outputs will be exceeded.					
	'0' - No error					
659	The timestamp value shall be sampled prior to the response frame.	4.7.15 Data Communications Protocol			Analysis	Design
660	Outputs, which track inputs, shall be updated no less than once per millisecond. Input to output signal propagation delay shall not exceed 2 milliseconds.	4.7.15 Data Communications Protocol			Performance Test	Design
661	A maximum of eight different [Tracking Functions] Output numbers may be activated by specifying eight definitions.	4.7.15 Data Communications Protocol			Analysis	Design
662	One complete definition for an Output that tracks an Input consists of two bytes containing four parameters: 1) the instruction to install or to remove the definition, 2) the Output Number, 3) the relationship of the state of the Output to the Input and 4) the Input Number.	4.7.15 Data Communications Protocol			Analysis	Design
663	Each definition specifies the controlling Input number for that unique output number.	4.7.15 Data Communications Protocol			Analysis	Design
664	More than one output definition may specify the same Input controlling source. [That is, the same input may be used as the control source for more than one Tracking Output.]	4.7.15 Data Communications Protocol			Analysis	Design
665	A complete definition [of an Output that tracks an Input] is called an Item in the Command Message frame.	4.7.15 Data Communications Protocol			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
666	The 'Number of Items' byte specifies the quantity of complete definitions contained in the Command Frame.	4.7.15 Data Communications Protocol			Analysis	Design
667	If the value is 0, all existing active Input Tracking definitions shall be removed.	4.7.15 Data Communications Protocol			Performance Test	Design
668	 The transmission of a definition may: a) Install a new active Tracking definition. b) Remove an existing active Tracking definition. When an Input Tracking definition is removed, the output is set according to the most recently received Set Outputs Command. c) Convert an active output definition from Complex or Square Wave definition to Tracking. Conversion removes the existing definition and assigns the Tracking definition without a transition through the 'output is set according to the most recently received Set Outputs Command' state. The most recent state of the output remains until the new function changes it. d) Redefine an existing Tracking definition. 	4.7.15 Data Communications Protocol			Analysis	Design
669	If a command frame to be processed by the SIU would result in having more than the maximum number (8) of definitions activated, the entire command frame shall be rejected.	4.7.15 Data Communications Protocol			Analysis	Design
670	[After an entire command frame is rejected due to having more than the maximum number of definitions activated,] The response V bit shall be set to 1.	4.7.15 Data Communications Protocol			Performance Test	Design
671	The V bit response is based on counting the current active quantity plus the projected Enable definitions after accounting for Remove definitions and invalid Output numbers.	4.7.15 Data Communications Protocol			Analysis	Design
672	The V bit response evaluation takes the currently active definition quantity, adds the projected Enable definitions, subtracts the Remove definitions, ignores invalid Input and Output numbers and compares the result to the Maximum Number of active Tracking definitions allowed.	4.7.15 Data Communications Protocol			Analysis	Design
673	If the quantity of Active definitions would become greater than the Maximum Number of active Tracking definitions, or if there are more Remove definitions than existing active definitions, the V Bit shall be set in the response.	4.7.15 Data Communications Protocol			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
674	While processing an Enable request, an Out of Range Input number shall preclude processing for that definition.	4.7.15 Data Communications Protocol			Analysis	Design
675	The Out of Range Output and Input numbers shall not affect the active definition count.	4.7.15 Data Communications Protocol			Analysis	Design
676	No error response is returned.	4.7.15 Data Communications Protocol			Performance Test	Design
677	The rest of the message shall be processed.	4.7.15 Data Communications Protocol			Analysis	Design
678	The "Number of Items" field is valid from 0 to 16 because the longest message may contain 8 Enable and 8 Remove definitions.	4.7.15 Data Communications Protocol			Analysis	Design
679	The Input state always comes from the Filtered Input Data source.	4.7.15 Data Communications Protocol			Analysis	Design
680	Valid Input and Output Number Ranges: ITS SIU device types: Inputs 0 - 53 & 56 - 59, Outputs 0 - 54	4.7.15 Data Communications Protocol			Analysis	Design
681	The Configure Complex Output Functions frame shall be used to configure the definition for an output that provides a complex operation.	4.7.15 Data Communications Protocol			Analysis	Design
682	The maximum number of active definitions is 8. Refer to 'Complex Output Functions Overview' for additional details.	4.7.15 Data Communications Protocol		It is unclear what the implementer should gather by referring to 'Complex Output Functions Overview'.	Analysis	Design
683	Please note that Configure Complex Output Functions is not intended for use with Traffic Signal Control Applications. (Authorized Engineering Information)	4.7.15 Data Communications Protocol		It is unclear what this requirement means.	Analysis	Design

#	Requirement (Standard Docume	ent Section)		Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type	
684	The command and response frame Configure Complex Output Function			4.7.15 Data Communications Protocol			Analysis	Design	
	Description	msb lsb	Byte Number	Protocoi					
	(Type Number = 57)	0 0 1 1 1 0 0 1	Byte 1						
	Number of Items	Number of Items	Byte 2						
	Item # - Byte 1	0 Output Number (O0 – O54)	Byte 7(I-1)+3						
	Item # - Byte 2	Primary Duration (MSB)							
	Item # - Byte 3	Primary Duration (LSB)	Byte 7(I-1)+5						
	Item # - Byte 4	Secondary Duration (MSB)	Byte 7(I-1)+6						
	Item # - Byte 5	Secondary Duration (LSB)	Byte 7(I-1)+7	1					
	Item # - Byte 6	0 Input Number (I0 – I59)	Byte 7(I-1)+8						
	Item # - Byte 7	P W G E J F R L	Byte 7(I-1)+9						
685	Number of Items: 0-16 Complex (Output Definitions are contained in this m	nessage.	4.7.15 Data			Analysis	Design	
	Output Number: 0 - Maximum C	Output Number for the SIU device type.		Communications				_	
	Primary Duration: MSB & LSB fo	orm a 16 bit Hex numerical value 0x0000	- 0xffff.	Protocol					
	•	Secondary Duration: MSB & LSB form a 16 bit Hex numerical value 0x0000 - 0xffff.							
		•							

#	Requirement (Standard Document Section)			Document Section	Pass Fail	Comments	Туре	Requirement Type
686	Field De	finitions	S:	4.7.15 Data			Analysis	Design
	Р	'1' - '0' -	The output is configured for single-pulse operation. Once complete, the complex output function shall be disabled. The output is configured for continuous oscillation.	Communications Protocol			-	
	W	'1' - '0' -	It is triggered by the specified input. Triggered complex output shall commence within 2 milliseconds of the associated trigger recognition. Operation shall begin within two milliseconds of the command receipt.					
	G	'1' - '0' -	Operation shall be gated active by the specified input. Gating is inactive.					
	Е	'1' '0'	Enable complex output function for this output Remove complex output function for this output					
	J	'1' '0'	During primary duration, the output shall be written as a logic '1'. During secondary duration, the output shall be written as a logic '0'. During primary duration, the output shall be written as a logic '0'. During secondary duration, the output shall be written as a logic '1'					
	F	'1' -	The trigger or gate shall be acquired subsequent to filtering the specified input. The raw input signal shall be used if filtering is not enabled for the specified input. The trigger or gate shall be derived from the raw input.					
	R	'1' -	For triggered output, the output shall be triggered by an ON-to-OFF transition of the specified input and shall be triggered immediately upon command receipt if the input is OFF. For gated output, the output shall be active while the input is OFF.					
		'0' -	For triggered output, the output shall be triggered by an OFF-to-ON transition of the specified input and shall be triggered immediately upon command receipt if the input is ON. For gated output, the output shall be active while the input is ON.					
	L	'1' - '0' -	The LINESYNC based clock shall be used for the time ticks. The Millisecond Counter shall be used for the time ticks.					

#	Requirement (Standard Documen	t Secti	on)							Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
687	Configure Complex Output Function	ıs Resp	onse							4.7.15 Data			Analysis	Design
	Description	msb						lsb	Byte Number	Communications				
	(Type Number = 185)	1	0	1	1 1	0	0	1	Byte 1	Protocol				
	Status	0	0	0	0 0	0	0	V	Byte 2					
	MC Timestamp (MSB)	Х	х	х	x x	X	X	X	Byte 3					
	MC Timestamp (NMSB)	х	X	х	x x	X	X	X	Byte 4					
	MC Timestamp (NLSB)	Х	X	х	x x	X	X	X	Byte 5					
	MC Timestamp (LSB)	Х	X	х	x x	X	X	X	Byte 6					
	Field Definitions:													
	V '1' - Maximum number	of cor	ıfigur	able	outpu	ts wil	ll be	excee	ded.					
	'0' - No error		Ü		•									
688	Controlling input signals shall be sa	mpled a	at lea	st onc	e per	milli	seco	nd.		4.7.15 Data Communications Protocol			Analysis	Design
689	A maximum of eight different Outpo	ıt numl	bers i	nay b	e acti	vated	l by s	pecify	ring eight definitions.	4.7.15 Data Communications Protocol			Analysis	Design
690	One complete definition for a Coparameters: 1) the Output Number, 2, 3) Primary Duration: MSB & LS 4, 5) Secondary Duration: MSB & LS 6) the Input Number, 7) Bit P: One Pulse or Continuo 8) Bit W: Output Operation is E 9) Bit G: Output Operation is G 10) Bit E: Enable Definition or R 11) Bit J: Defines Primary/Secon 12) Bit F: Input from Filtered or I 13) Bit R: Selects Edge for Trigg for Gated to be active by Input 14) Linesync edges or Millisecon	SB form LSB form us Osci dge Tri ated by emove dary Do Raw Da ered by it OFF	n a 16 orm a illatio iggero Inpu Defin uratio ata, y Inpo or by	6 bit I 16 bi on, ed by it or is nition on rela ut ON	Hex mit Hex Input Cont Cont Cont Cont Cont Cont Cont Con	umer or N tinuo	ical venerical for Trus Os	value, al valu rigger scillat DFF o	ed by Input, ion, r OFF/ON,	4.7.15 Data Communications Protocol			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Type	Requirement Type
691	Each definition [of a Complex Output] specifies the controlling Input number for that unique output number.	4.7.15 Data Communications Protocol			Analysis	Design
692	The Input is a functional control only when the operation is specified as Triggered (W=1) or Gated (G=1).	4.7.15 Data Communications Protocol			Analysis	Design
693	Otherwise [when the Input is not functional], the Input number is ignored.	4.7.15 Data Communications Protocol			Performance Test	Design
694	More than one output definition may specify the same Input controlling source. [That is, the same input may be used as the control source for more than one Complex Output.]	4.7.15 Data Communications Protocol			Analysis	Design
695	If both W=1 and G=1 are set in the definition, the G=1 shall be used as if W=0.	4.7.15 Data Communications Protocol			Analysis	Design
696	The primary duration is the first timed interval of a pulse or the first portion of a continuous oscillation.	4.7.15 Data Communications Protocol			Analysis	Design
697	The first portion [of a continuous oscillation] follows acquisition of a Trigger or Gated Input. If not Triggered or Gated, the first portion follows the activation of the definition.	4.7.15 Data Communications Protocol			Analysis	Design
698	The 'Number of Items' byte specifies the quantity of complete definitions contained in the Command Frame.	4.7.15 Data Communications Protocol			Analysis	Design
699	If the value is 0, all existing active Complex Output definitions shall be removed.	4.7.15 Data Communications Protocol			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
700	The transmission of a definition may: a) Install a new active Complex Output definition. b) Remove an existing active Complex Output definition. When a Complex Output definition is removed, the output is set according to the most recently received Set Outputs Command. c) Convert an active output definition from Tracking or Square Wave definition to Complex Output. Conversion removes the existing definition and assigns the Complex Output definition without a transition through the 'output is set according to the most recently received Set Outputs Command' state. The most recent state of the output remains until the new function changes it. d) Redefine an existing Complex Output definition.	4.7.15 Data Communications Protocol			Analysis	Design
701	If a command frame to be processed by the SIU would result in having more than the maximum number (8) definitions activated, the entire command frame shall be rejected.	4.7.15 Data Communications Protocol			Performance Test	Design
702	[After a command frame has been rejected,] The response V bit shall be set to 1.	4.7.15 Data Communications Protocol			Performance Test	Design
703	The V bit response evaluation takes the currently active definition quantity, adds the projected Enable definitions, subtracts the Remove definitions, ignores invalid Input and Output numbers and compares the result to the maximum number of active Complex definitions allowed.	4.7.15 Data Communications Protocol			Analysis	Design
704	If the quantity of active definitions would become greater than the maximum number of active Complex Output definitions, or if there are more Remove definitions than existing active Complex Output definitions, the V Bit shall be set in the response.	4.7.15 Data Communications Protocol			Performance Test	Design
705	While processing an Enable request that requires Triggered or Gated operation, an Out of Range Input number shall preclude processing for that definition.	4.7.15 Data Communications Protocol			Analysis	Design
706	The Out of Range Output and Input numbers shall not affect the active definition count. No error response is returned.	4.7.15 Data Communications Protocol			Analysis	Design
707	The rest of the message shall be processed.	4.7.15 Data Communications Protocol			Analysis	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
708	The "Number of Items" field is valid from 0 to 16 because the longest message may contain 8 Enable and 8 Remove definitions.	4.7.15 Data Communications Protocol			Analysis	Design
709	The Input state comes from the Filtered or Raw Input Data source as specified by the Bit F value.	4.7.15 Data Communications Protocol			Analysis	Design
710	Valid Input and Output Number Ranges: ITS SIU device types: Inputs 0 - 53 & 56 - 59, Outputs 0 - 54	4.7.15 Data Communications Protocol			Analysis	Design
711	The LINESYNC based clock shall used both the rising and falling edges providing a nominal 8.33 millisecond time tick.	4.7.15 Data Communications Protocol			Analysis	Design
712	The SIU Identification command frame shall be used to request the SIU Identification value for ITS Cabinet SIUs and CMUs.	4.7.15 Data Communications Protocol			Analysis	Design
713	Reply message shall use the following addresses: ATC Controller Unit Field I/Os shall respond with address 20.	4.7.15 Data Communications Protocol			Analysis	Design
714	SIUs respond with their own address ranging from 0-14.	4.7.15 Data Communications Protocol			Analysis	Design
715	CMUs respond with their own addresses, ranging from 15-18.	4.7.15 Data Communications Protocol			Analysis	Design

#	Requirement (Standard Document Section)		Document Section	Pass Fail	Comments	Туре	Requirement Type
716	The command and response frames shall be shown as follows: I/O Module Identification Command		4.7.15 Data Communications Protocol			Analysis	Design
	Description msb lsb Byte	Number	Trotocor				
	(Type Number= 60) 0 0 1 1 1 1 0 0 B	Byte 1					
	I/O Module Identification Response						
	Description msb lsb Byte	Number					
	(Type Number= 188) 1 0 1 1 1 0 0 B	Byte 1					
	SIU I D byte x x x x x x x x B	Byte 2					
717	The Address Select input bits shall define the logical position of each SIU.		4.7.16 Address Select Inputs			Analysis	Design
718	No connection shall be logical False, while a connection to Logic Ground shall be a l	logical True.	4.7.16 Address Select Inputs			Analysis	Design
719	There shall be sixteen unique address positions selected with a binary code, using bit significant and bit 3 as most significant.	0 as least	4.7.16 Address Select Inputs			Inspection	Design
720	The SIU shall contain one input that shall be read directly by microprocessor.		4.7.17 SIU/BIU Input			Analysis	Design
721	When not connected, this input shall be logical False, while a connection to Ground s logical True.	shall be a	4.7.17 SIU/BIU Input			Performance Test	Design
725	The Serial Bus 1 indicators shall be sensed on the microprocessor/controller pins.		4.7.18 Hardware Requirements			Analysis	Design
726	Serial Bus 2 indicators shall be sensed on the Port 4 (EIA-485) signal lines.		4.7.18 Hardware Requirements			Analysis	Design
727	The SIU Power LED shall indicate that the +24 VDC power supply is within regulation	ion.	4.7.18 Hardware Requirements			Performance Test	Design
728	The SIU Active LED shall be controlled via SIU I/O 55.		4.7.18 Hardware Requirements			Analysis	Design
730	A 9-position subminiature D-type connector shall be mounted on the front panel for F	Port 3 entry.	4.7.18 Hardware Requirements			Inspection	Design
731	The connector pin assignment is Pin 2- RxD, Pin 3- TxD and Pin 5- Signal Ground.		4.7.18 Hardware Requirements			Inspection	Design

#	Requirement (Standar	rd Document Section)				Document Section	Pass Fail	Comments	Туре	Requirement Type
732	The SIU Input Connecti	ion pin assignments shall b	e as show	vn in drawing 4-11-8.		4.7.18 Hardware Requirements			Analysis	Design
733	SIU	Set Output Command T	Type 55	Raw Input Data Res	ponse Type 180	4.7.19 SIU Input and			Analysis	Design
	I/O 0	BYTE 2 BI	IT 0	BYTE 2	BIT 0	Output Assignments				_
	I/O 1	BYTE 2 BI	IT 1	BYTE 2	BIT 1					
	I/O 2		IT 2	BYTE 2	BIT 2					
	I/O 3		IT 3	BYTE 2	BIT 3					
	I/O 4		IT 3	BYTE 2	BIT 4					
	I/O 5		IT 5	BYTE 2	BIT 5					
	I/O 6		IT 6	BYTE 2	BIT 6					
	I/O 7		IT 7	BYTE 2	BIT 7					
	I/O 8		IT 0	BYTE 3	BIT 0					
	I/O 9		IT 1	BYTE 3	BIT 1					
	I/O 10		IT 2	BYTE 3	BIT 2					
	I/O 11		IT 3	BYTE 3	BIT 3					
	I/O 12		IT 4	BYTE 3	BIT 4					
	I/O 13		IT 5	BYTE 3	BIT 5					
	I/O 14		IT 6	BYTE 3	BIT 6	1				
	I/O 15		IT 7	BYTE 3	BIT 7					
	I/O 16		IT 0	BYTE 4	BIT0					
	I/O 17		IT 1	BYTE 4	BIT1					
	I/O 18		IT 2	BYTE 4	BIT2					
	I/O 19		IT 3	BYTE 4	BIT3					
	I/O 20		IT 4	BYTE 4	BIT4					
	I/O 21		IT 5	BYTE 4	BIT5					
	I/O 22		IT 6	BYTE 4	BIT6					
	I/O 23		IT 7	BYTE 4	BIT7					
	I/O 24		IT0	BYTE 5	BIT 0					
	I/O 25		IT1	BYTE 5	BIT 1					
	I/O 26		IT2	BYTE 5	BIT 2		1			
	I/O 27		IT3	BYTE 5	BIT 3					
	I/O 28		IT4	BYTE 5	BIT 4		1			
	I/O 29		IT5	BYTE 5	BIT 5					
	I/O 30		IT6	BYTE 5	BIT 6		1			
	I/O 31	BYTE 5 BI	IT7	BYTE 5	BIT 7					

#	Requirement (Standard	l Document Section	on)			Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
	I/O 32	BYTE 6	BIT0	BYTE 6	BIT 0					
	I/O 33	BYTE 6	BIT1	BYTE 6	BIT 1					
	I/O 34	BYTE 6	BIT2	BYTE 6	BIT 2					
	I/O 35	BYTE 6	BIT3	BYTE 6	BIT 3					
	I/O 36	BYTE 6	BIT4	BYTE 6	BIT 4					
	I/O 37	BYTE 6	BIT5	BYTE 6	BIT 5					
	I/O 38	BYTE 6	BIT6	BYTE 6	BIT 6					
	I/O 39	BYTE 6	BIT7	BYTE 6	BIT 7					
	I/O 40	BYTE 6	BIT0	BYTE 6	BIT 0					
	I/O 41	BYTE 7	BIT1	BYTE 7	BIT 1					
	I/O 42	BYTE 7	BIT2	BYTE 7	BIT 2					
	I/O 43	BYTE 7	BIT3	BYTE 7	BIT 3					
	I/O 44	BYTE 7	BIT4	BYTE 7	BIT 4					
	I/O 45	BYTE 7	BIT5	BYTE 7	BIT 5					
	I/O 46	BYTE 7	BIT6	BYTE 7	BIT 6					
	I/O 47	BYTE 7	BIT7	BYTE 7	BIT 7					
	I/O 48	BYTE 8	BIT0	BYTE 8	BIT 0					
	I/O 49	BYTE 8	BIT1	BYTE 8	BIT 1					
	I/O 50	BYTE 8	BIT2	BYTE 8	BIT 2					
	I/O 51	BYTE 8	BIT3	BYTE 8	BIT 3					
	I/O 52	BYTE 8	BIT4	BYTE 8	BIT 4					
	I/O 53	BYTE 8	BIT5	BYTE 8	BIT 5					
	Active LED (O54)	BYTE 8	BIT6							
	Opto Input 1 (I56)			BYTE 9	BIT 0					
	Opto Input 2 (I57)			BYTE 9	BIT 1					
	Opto Input 3 (I58)			BYTE 9	BIT 2					
	Opto Input 4 (I59)			BYTE 9	BIT 3					
	A000			BYTE 9	BIT 4					
	A001			BYTE 9	BIT 5					
	A002			BYTE 9	BIT 6					
	A003			BYTE 9	BIT 7					

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
734	Each SIU shall contain 54 Input/Outputs and each shall be connected as follows: TxD	4.7.20 Block Diagrams			Analysis	Design
	Exhibit 4-1. SIU Input/Output Connections					
735	When the SIU is powered, all outputs shall be initialized OFF and fifty-four inputs shall be available.	4.7.20 Block Diagrams			Analysis	Design
737	Each output must be able to be read back as an input in order to check integrity.	4.7.20 Block Diagrams			Performance Test	Design
443	The SIU shall be capable of processing fifty-four Input/Output pins and four Optical Input pins.	4.7.1 General	P	Verified via the SIU Input monitoring program running on a laptop.	Inspection	Performance
444	When installed in an ITS Input Assembly, it [the SIU] processes twenty-four detector outputs (pins F and W), twenty-four detector status outputs, and provides six detector reset signals (per two slots).	4.7.1 General	P	Verified by analysis of the drawing.	Inspection	Performance
552	The SIU shall have a minimum of four serial ports, identified as SIU Ports 1-4.	4.7.14 Inputs and Outputs	F	The specification is discrepant, since the "ports" are neither properly identified nor labeled on the drawings as shown in the standard.	Inspection	Performance

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
553	Serial Ports 1 and 3 are connected to the SIU microprocessor/controller unit, while Serial Ports 2 and 4 provide a buffered communications path from the ATC Controller Unit to the detectors, and are not connected to the microprocessor/controller unit.	4.7.14 Inputs and Outputs	F	The words "port" is discrepant as well, as per above.	Inspection	Performance
722	The SIU Module shall be physically composed of a printed circuit board, 4.5 inches high by 6.5 inches long, a front panel 2.25 inches wide by 4.5 inches high with a DIN 96-pin connector on the connector end (opposite the front panel).	4.7.18 Hardware Requirements	P		Inspection	Performance
723	A "U" handle shall be mounted on the front panel for insertion/extraction.	4.7.18 Hardware Requirements	P		Inspection	Performance
724	Six LED indicators shall be provided on the front panel, as follows: SIU Active SIU Power Serial Bus 1 TxD Serial Bus 2 TxD Serial Bus 1 RxD Serial Bus 2 RxD	4.7.18 Hardware Requirements	P	We saw two different implementations of this, because the standard shows two different implementations, one on the drawing and one in this clause of the standard.	Inspection	Performance
729	The SIU front panel shall provide a RESET pushbutton that shall provide a hardware RESET to the microprocessor/controller unit.	4.7.18 Hardware Requirements	P	Verified during previous tests.	Inspection	Performance
736	Without jumpers or firmware changes, the Controller software shall be able to turn ON any of the fifty-four outputs.	4.7.20 Block Diagrams	P	Verified via an emulation program running on a remote control. Stepped through all channels available in the Cabinet we had, which only had 14 channels.	Performance Test	Performance

B.21 ITS Cabinet Loop Detector General Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
738	The sensor and isolator channels shall be operationally independent from each other.	5.1 General Requirements			Analysis	Design
739	Each sensor unit or AC isolator channel shall draw no more than 100 milliamperes from the +24 VDC cabinet power supply and shall be insensitive to 700 millivolts RMS ripple on the incoming +24 VDC line.	5.1 General Requirements			Performance Test	Design
740	The sensor unit or isolator front panel shall be provided with a hand pull to facilitate insertion and removal from the Input Assembly.	5.1 General Requirements			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
741	All control switches, gain dials and channel indicators shall be mounted on the front panel.	5.1 General Requirements			Inspection	Design
742	Each sensor unit or isolator channel shall have an indicator to provide visual indication of detector or incoming signal.	5.1 General Requirements			Inspection	Design
743	Each sensor unit or isolator channel output shall be an opto-isolated NPN Open Collector capable of sinking 50 milliamperes at 30 VDC.	5.1 General Requirements			Analysis	Design
744	The output [of each sensor unit or isolator] shall be compatible with the controller unit inputs.	5.1 General Requirements			Inspection	Design
745	A valid channel input shall cause a channel Ground True Output to the controller unit of a minimum 100 milliseconds in duration.	5.1 General Requirements			Performance Test	Design
746	An onboard physical switching mechanism shall be provided to disable this feature when the mechanism is in an OPEN position.	5.1 General Requirements			Inspection	Design
747	Said [onboard physical] switching mechanism shall eliminate the minimum timing requirement.	5.1 General Requirements			Analysis	Design
748	The output transistor shall switch from OFF to ON state or ON to OFF state in 20 microseconds or less.	5.1 General Requirements			Performance Test	Design
749	Onboard protection shall be provided to enable the sensor unit or isolator to comply with ANSI/IEEE C62.41 (100 Kilohertz Ring Wave and the EFT Burst) at voltages and currents specified at "Location Category A1" (i.e. up to 2.0 Kilovolts, 0.07 Kiloampheres for the 100 Kilohertz Ring Wave) and at "Test Severity" level I (i.e. up to 1.0 Kilovolts, open-circuit) for the EFT Burst.	5.1 General Requirements			Analysis	Design
750	Detector Sensor Units and Isolators shall have a front panel mounted test switch for each channel to simulate valid input.	5.1 General Requirements			Inspection	Design
751	The test switch shall be a single-pole double-throw, three position CONTROL test switch: The position assignment shall be UP = Constant ON; MIDDLE = Normal Operation; and DOWN = Momentary ON.	5.1 General Requirements	P	The text does not reflect the actual look and feel of the standard.	Inspection	Performance

B.22 ITS Cabinet Model 222 & 224 Loop Detector Sensor Unit Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
752	The sensor unit channel shall produce an output signal when a vehicle passes over or remains over loop wires embedded in the roadway.	5.2.1 General Requirements			Performance Test	Design
753	The method of detection shall be based upon a design that renders the output signal when a metallic mass (vehicle) enters the detection zone causing a change of 0.02% minimum decrease in inductance of the circuit measured at the input terminals of the sensor unit.	5.2.1 General Requirements		This appears to be a design "suggestion" versus a requirement. Should be re-worded for clarity.	Analysis	Design
754	The detector zone shall include, but not be limited to, all configurations listed in section 5.2.3.1.	5.2.1 General Requirements			Analysis	Design
755	An open loop shall cause the sensor unit channel to output a signal indicating a non-detect situation.	5.2.1 General Requirements			Performance Test	Design
756	Each sensor unit channel must be capable of detecting all types of AGENCY licensed motor vehicles when connected to the loop configuration/lead-in requirements of section 5.2.3.1	5.2.1 General Requirements			Analysis	Design
757	The sensor unit shall comply with all performance requirements when connected to an inductance (loop plus lead-in) from 50 to 700 micro Henries with a Q-parameter as low as 5 at the sensor unit operating frequency.	5.2.1 General Requirements			Performance Test	Design
758	Loop inputs to each channel shall be transformer-isolated.	5.2.1 General Requirements			Inspection	Design
759	Each individual channel shall have a minimum of four switch-selectable operating frequencies.	5.2.1 General Requirements			Inspection	Design
760	The sensor unit channel tuning circuits shall be automatic and shall be so designed that drift caused by environmental changes or changes in applied power shall not cause an actuation.	5.2.1 General Requirements			Performance Test	Design
761	A switch or switch position shall be provided on the front panel to disable each channel output.	5.2.1 General Requirements			Inspection	Design
762	Each sensor unit channel shall have PULSE and PRESENCE selectable modes.	5.2.2 Mode Selection Requirements			Inspection	Design
763	In the PULSE MODE, each new vehicle presence within the detection zone shall initiate a sensor unit channel output pulse of 125 milliseconds (+/-25 milliseconds) in duration.	5.2.2 Mode Selection Requirements			Performance Test	Design
764	Should a vehicle remain in a portion of the detection zone for a period in excess of two seconds, the sensor unit channel shall automatically "tune out" the presence of said vehicle.	5.2.2 Mode Selection Requirements			Performance Test	Design
765	The sensor unit channel shall then [after "tuning out" the presence of a vehicle] be capable of detecting another vehicle entering the same detection zone.	5.2.2 Mode Selection Requirements			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
766	The recovery time to full sensitivity between the first vehicle pulse and channel capability to detect another vehicle shall be a maximum of three seconds.	5.2.2 Mode Selection Requirements			Performance Test	Design
767	In the PRESENCE MODE, the sensor unit channel shall recover to normal sensitivity within one second after termination of vehicle presence in the detection zone regardless of the duration of the presence.	5.2.2 Mode Selection Requirements			Performance Test	Design
768	The channel sensitivity settings shall provide presence detection of a vehicle in the detection zone for a specified time period and inductance change(s).	5.2.2 Mode Selection Requirements			Analysis	Design
769	The conditions are as follows: MINIMUM TIME DETECTOR INPUT DURATION IN INDUCTANCE CHANGE MINUTES SETTING 6 3 0.02% or more 10 0.06% or more	5.2.2 Mode Selection Requirements			Analysis	Design
770	SETTING 2 4 1.00% or more [The Loop Detector Sensor Units must properly function with] Single Type A, B, Q or Round	5.2.3 Sensitivity			Performance Test	Design
	Loop with a 250 foot lead-in cable.	-				_
771	[The Loop Detector Sensor Units must properly function with] Single Type A, B, Q or Round Loop with a 1000 foot lead-in cable.	5.2.3 Sensitivity			Performance Test	Design
772	[The Loop Detector Sensor Units must properly function with] 4 Type A, B, or Q Loops connected in series/parallel with a 250 foot lead-in cable.	5.2.3 Sensitivity			Performance Test	Design
773	[The Loop Detector Sensor Units must properly function with] 4 Type A, B, Q or Round Loops connected in series with a 1000 foot lead-in cable.	5.2.3 Sensitivity			Performance Test	Design
774	[The Loop Detector Sensor Units must properly function with] One 50 foot Type C Loop with a 250 foot lead-in cable.	5.2.3 Sensitivity			Performance Test	Design
775	Each sensor unit channel shall be equipped with seven selectable sensitivity setting(s) in presence and pulse modes to accomplish the following under operational and environmental requirements of this specification:	5.2.3 Sensitivity			Inspection	Design
776	Each sensor unit channel shall respond while in Setting 2 to a nominal change in inductance between 0.15% to 0.4% (median sensitivity of 0.32%) while connected to the loop configurations described in section 5.2.3.1.	5.2.3 Sensitivity			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
777	Each sensor unit channel shall respond while in Setting 6 to an inductance of 0.02% while connected to the loop configurations described in section 5.2.3.1.	5.2.3 Sensitivity			Performance Test	Design
778	All sensitivity settings shall not differ +/-40% from the nominal value chosen.	5.2.3 Sensitivity			Performance Test	Design
779	Each sensor unit channel shall not detect vehicles, moving or stopped, at distances of three feet or more from any loop perimeter, in all configurations listed in section 5.2.3.1.	5.2.3 Sensitivity			Performance Test	Design
780	Response time of the sensor unit channel for Sensitivity Setting 2 shall be less than five +/- one milliseconds at an approximate loop frequency of 40 Kilohertz.	5.2.4 Response Time			Performance Test	Design
781	That is, for any decreased inductive change that exceeds its sensitivity threshold, the channel shall output a ground true logic level within five milliseconds (+/- one millisecond).	5.2.4 Response Time			Performance Test	Design
782	When such change [any decreased inductive change that exceeds the sensitivity threshold of the loop] is removed, the output shall become an open circuit within five milliseconds (+/- one millisecond).	5.2.4 Response Time			Performance Test	Design
783	The sensor unit channels shall begin normal operation within two seconds after the application of power or after a reset signal of 30 microseconds.	5.2.5 Beginning of Normal Operation			Performance Test	Design
784	The sensor unit shall be capable of compensating or tracking for an environmental change up to 0.001% change in inductance per second.	5.2.6 Tracking Rate			Performance Test	Design
785	The sensor unit shall be capable of normal operation as the input inductance is changed from +/- 5.0% from the quiescent tuning point regardless of internal circuit drift.	5.2.7 Tracking Range			Performance Test	Design
786	The sensor unit shall be capable of normal operation as the input resistance is changed from +/- 0.5% from the quiescent tuning point regardless of internal circuit drift.	5.2.7 Tracking Range			Performance Test	Design
787	The operation of the sensor unit shall not be affected by changes in the inductance and/or capacitance of the loop caused by environmental changes, with the rate of temperature change not exceeding 1 degree C per 3 minutes.	5.2.8 Temperature Change			Performance Test	Design
788	The opening or closing of the controller cabinet door with a temperature differential of up to 18 degrees C between the inside and outside air shall not affect the proper operation of the sensor unit.	5.2.8 Temperature Change			Performance Test	Design

B.23 ITS Cabinet Model 231 Magnetic Detector Sensing Element Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
789	Each sensing element shall be designed for ease of installation, repositioning, and removal.	5.3.1 Model 231 Magnetic Detector Sensing Element		What does it mean to be "designed for ease of" anything? How is this quantified?	Inspection	Design
790	The sensing element shall be 2.25 inches maximum in diameter and have no sharp edges along its length.	5.3.1 Model 231 Magnetic Detector Sensing Element			Inspection	Design
791	The overall length [of the sensing element] shall not exceed 21 inches.	5.3.1 Model 231 Magnetic Detector Sensing Element			Inspection	Design
792	Each sensing element, including lead-in shall have a DC resistance of less than 3500 ohms.	5.3.1 Model 231 Magnetic Detector Sensing Element			Performance Test	Design
793	The sensing element shall be constructed of nonferrous material and shall be moisture proof.	5.3.1 Model 231 Magnetic Detector Sensing Element		The requirement "moisture proof" has a quantifiable range, and should be specified this way.	Inspection	Design
794	The element shall contain no moving parts or active components.	5.3.1 Model 231 Magnetic Detector Sensing Element			Inspection	Design
795	The element shall have a 50 feet lead-in cable.	5.3.1 Model 231 Magnetic Detector Sensing Element			Inspection	Design
796	Leakage resistance shall be a minimum of 10 Megohms when tested with 400 VDC between lead wire, including lead wire entrance, and the fluid of a salt-water bath after the device has been entirely immersed in the bath for a period of 24 hours at 20 degrees C (+/-3 degrees C). The salt-water bath concentrate shall be one-fourth ounce of salt per gallon of water.	5.3.1 Model 231 Magnetic Detector Sensing Element			Performance Test	Design
797	Each sensing element including lead-in shall have a DC resistance of less than 3500 Ohms and an inductance of 20 Henrys (+/-15 %).	5.3.1 Model 231 Magnetic Detector Sensing Element			Performance Test	Design
798	The Model 232 Two-Channel Magnetic Detector Sensor Unit shall provide two channels of detection.	5.3.2 Model 232 Two Channel Magnetic Detector Sensing Element			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
799	When resident in an energized cabinet Input Assembly, and each channel connected to its associated Model 231 Magnetic Detector Sensing Element(s), the channel shall produce a continuous output signal to the controller unit when a voltage is induced in the sensing element by a vehicle passing over the sensing element.	5.3.2 Model 232 Two Channel Magnetic Detector Sensing Element			Performance Test	Design
800	Each channel shall detect vehicles passing within six feet of the Model 231 Sensing Element with 1000 feet of lead-in cable, at all speeds between three and 80 miles per hour.	5.3.2 Model 232 Two Channel Magnetic Detector Sensing Element			Performance Test	Design
801	A single control knob for adjusting the sensitivity of each channel shall be mounted on the front panel and shall be readily adjustable without the use of tools.	5.3.2 Model 232 Two Channel Magnetic Detector Sensing Element			Inspection	Design
802	A momentary switch or switch position shall be provided to place a call on each channel, on an individual basis.	5.3.2 Model 232 Two Channel Magnetic Detector Sensing Element			Inspection	Design

B.24 ITS Cabinet Model 242 Two-Channel DC Isolator Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
803	The Model 242 Two-Channel DC Isolator shall contain two isolation channels which provide isolation between electrical contacts external to the module and the controller unit input.	5.4.1 General Requirements			Inspection	Design
804	The method of isolation shall be based upon a design which shall provide reliable operation.	5.4.1 General Requirements		These words amount to suggestions that cannot be quantified in any way.	Drop from the standard.	Design
805	The isolator shall have an internal power supply supplying 20 VDC (+/-4 VDC) to the field input side of the isolation channels.	5.4.1 General Requirements			Inspection	Design
806	The isolator shall not draw more than 2.5 Watts of AC power.	5.4.1 General Requirements			Performance Test	Design
807	No current shall be drawn from the cabinet power supply.	5.4.1 General Requirements			Performance Test	Design
808	A channel contact closure input of five milliseconds or less shall not cause an output (ground true) to the controller.	5.4.1 General Requirements			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
809	An input of 25 milliseconds or greater shall cause an output to the controller.	5.4.1 General Requirements			Performance Test	Design
810	An input of duration between five and 25 milliseconds may or may not cause an output to the controller.	5.4.1 General Requirements		What is the implementer to do with an "either-or" requirement such as this one?	Performance Test	Design
811	The channel circuitry shall be able to react to a new input closure within 25 milliseconds of an input opening.	5.4.1 General Requirements			Performance Test	Design
812	Each isolation channel field input shall be turned ON (TRUE) when a contact closure causes an input voltage of less than 8 VDC, and shall be turned OFF (FALSE) when the contact opening causes the input voltage to exceed 12 VDC.	5.4.1 General Requirements			Performance Test	Design
813	Each input shall deliver no less than 15 milliamperes, nor more than 40 milliamperes, to an electrical contact closure or short from the power supply.	5.4.1 General Requirements			Performance Test	Design

B.25 ITS Cabinet Model 242 Two-Channel AC Isolator Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
814	The Model 252 Two-Channel AC Isolator shall contain two isolation channels which provide isolation between external 120 VAC input circuits and the controller unit input circuits.	5.5.1 General Requirements			Inspection	Design
815	The method of isolation shall be based upon a design that provides reliable operation.	5.5.1 General Requirements		These words amount to suggestions that cannot be quantified in any way.	Drop from the standard.	Design
816	A channel input voltage "Von" of 80 VAC (+/-5 VAC) applied for a minimum duration of 120 milliseconds (+/-10 milliseconds) shall cause an output (Ground True) to the controller unit.	5.5.1 General Requirements			Performance Test	Design
817	A channel input voltage "Voff" (Von minus 10 VAC) applied for a minimum duration of 120 milliseconds (+/-10 milliseconds) shall cause an output (Ground False) to the controller unit.	5.5.1 General Requirements			Performance Test	Design
818	A two-post jumper shall be provided to select inverted output states for Von and Voff.	5.5.1 General Requirements			Inspection	Design
819	When in CLOSED position (Grounded), Von shall cause a Ground False output.	5.5.1 General Requirements			Performance Test	Design
820	An indicator shall be provided on the front panel labeled 'RR" which shall indicate a Voff input, Ground True output.	5.5.1 General Requirements			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
821	The input impedance of each channel shall be between 6,000 – 15,000 Ohms at 60 Hertz.	5.5.1 General Requirements			Inspection	Design
822	The minimum isolation shall be 1000 Megohms between the input and output terminals at 500 AC applied voltage.	5.5.1 General Requirements			Inspection	Design

B.26 ITS Cabinet Model Serial Bus Requirements

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
823	The ATC Controller Unit is serially connected to the Cabinet via two serial synchronous ports located at the Field I/O C12 Connector or the CPU-1B C13 Connector (Serial Bus 1 only).	6.1.1 General			Analysis	Design
824	These two communication links use EIA-485 Drivers/Receivers and Synchronous Data Link Control (SDLC) Protocol to interface with Serial Bus #1 and #2.	6.1.1 General			Inspection	Design
825	Serial Bus #1 shall function as a distributed real-time cabinet control and communications bus.	6.1.3 Serial Bus # 1 System			Analysis	Design
826	The Bus Commands are generated in the ATC Controller Unit.	6.1.3 Serial Bus # 1 System			Analysis	Design
827	They [the Bus Commands] shall be passed to the assembly Model 218 SIU Units and Model 212 CMU Monitor Unit using EIA 485 COMM/SDLC Protocol Frame Address/Message Packets.	6.1.3 Serial Bus # 1 System			Analysis	Design
828	The SIU Units shall read the Address Connector for Assembly Address Number.	6.1.3 Serial Bus # 1 System			Analysis	Design
829	The CMU shall read the Address Connector of the PDA.	6.1.3 Serial Bus # 1 System			Analysis	Design
830	The AMU units shall read address information as part of the Output Assembly address connector.	6.1.3 Serial Bus # 1 System			Analysis	Design

Rec	quireme	ent (Standard Docume	nt Se	ction)									Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type				
The	follow	ing Address Frame num	shall	be assi	gned	to the	assem	blies	and m	onitor	as:		6.1.3 Serial Bus # 1			Analysis	Design					
														System								
Ac	ddress	SYSTEM ASSEMBLY / UNIT				S	ΙU					AMU	=									
		ASSEMBLI / UNII	<i>A7</i>	A6	A5	A4	<i>A3</i>	A2	AI	A0	A2	AI	A0									
	0			Res	erved						0	0	0									
	1	14 Pack in position 1	0	0	0	0	0	0	0	1	0	0	1									
	2				R	Reserv	ed															
	3	14 Pack in position 3	0	0	0	0	0	0	1	1	0	1	1									
	4	6 Pack in position 4	0	0	0	0	0	1	0	0	1*	0	0									
	5	6 Pack in position 1	0	0	0	0	0	1	0	1	1*	0	1									
	6	6 Pack in position 2	0	0	0	0	0	1	1	0	1*	1	0									
	7	6 Pack in position 3	0	0	0	0	0	1	1	1	1*	1	1									
	8										1											
	9	Input #1	0	0	0	0	1	0	0	1												
	10	Input #2	0	0	0	0	1	0	1	0												
	11	Input #3	0	0	0	0	1	0	1	1	_											
	11	Input #4	0	0	0	0	1	1	0	0	4											
	13	Input #5	0	0	0	0	1	1	0	1												
	14			Ι.	1	Reserv	ed .			1 .												
	15	CMU #1	0	0	0	0	1	1	1	1												
	16	CMU #2	0	0	0	1	0	0	0	0	_							1				
	17	CMU #3	0	0	0	1	0	0	0	1	4											
	18	CMU #4	0	0	0	1	0	0	1	0												
	19	CPU	0	0	0	1	0	0	1	1	_											
 	20	FIO 2A or 8	0	0	0	1	0	1	0	0												
21 25					R	Reserv	ed	_	_		_											
	255	Broadcast All	1	1	1	1	1	1	1	1												

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
832	If the Command Address Frame matches the Unit, the Unit shall read the message for processing and response.	6.1.3 Serial Bus # 1 System			Analysis	Design
833	The Message First Byte shall be the message name.	6.1.3 Serial Bus # 1 System			Analysis	Design
834	The Unit shall set the Response Packet First Byte to Command Message plus 128 and the appropriate data.	6.1.3 Serial Bus # 1 System			Analysis	Design
835	The Cabinet Monitoring System shall use two serial Bus systems for the interface; Serial Bus #1, links the ATC Controller Unit via a Serial Bus Harness to the DC Power/Communications Assembly.	6.1.5 Cabinet Control/Emergency Override System			Analysis	Design
836	A Serial Bus Harness plugged into the DC Power/Communications Assembly shall connect to the 212 Cabinet Monitor Unit with application serial memory key resident in the PDA ITS.	6.1.5 Cabinet Control/Emergency Override System			Analysis	Design
837	Serial Bus #3 Harnesses shall provide the interconnection between the Output Assembly's 214 Auxiliary Monitor Units and the CMU.	6.1.5 Cabinet Control/Emergency Override System			Inspection	Design
838	The Bus Harnesses shall be daisy chained between the Output Assemblies and the PDA ITS.	6.1.5 Cabinet Control/Emergency Override System			Inspection	Design
839	See sections 4.4 and 4.5 (CMU and AMU) for operations, functions, protocol, Message frames and bit rate.	6.1.5 Cabinet Control/Emergency Override System			Analysis	Design

B.27 ITS Cabinet Model Housing Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
840	The housing shall be rainproof.	6.2.2 Housing Construction		What does "rainproof" mean and how is it quantified?	Analysis	Design
843	The aluminum surface shall be either coated with a Mill Finish or Anti-Graffiti Paint.	6.2.2 Housing Construction			Inspection	Design
846	The spacer supports shall have the option to use 0.059 inch minimum stainless steel sheet.	6.2.2 Housing Construction			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
847	All exterior seams for enclosure and doors shall be continuously welded and shall be smooth.	6.2.2 Housing Construction		Can "smooth" be quantified?	Inspection	Design
848	All edges shall be filled to a radius of 0.03125 inch minimum.	6.2.2 Housing Construction			Inspection	Design
866	The enclosure door frames shall be double-flanged out on all four sides and shall have strikers to hold tension on, and to form a firm seal between, the door gasketing and the frame.	6.2.2 Housing Construction			Inspection	Design
867	The dimension between the door edge and the enclosure external surface when the door is closed and locked shall be 0.156 inch (+/-0.08 inches).	6.2.2 Housing Construction			Inspection	Design
868	Gasketing shall be provided on all door openings and shall be dust-tight.	6.2.3 Gasketing		Is there a performance criterion for "dust tight" that could be used here?	Inspection	Design
869	Gaskets shall be 0.25 inches minimum thickness closed cell neoprene or silicone (BOYD R-108480 or equal) and shall be permanently bonded to the metal.	6.2.3 Gasketing			Inspection	Design
871	Cage mounting supports shall be provided on either side, level with the bottom edge of the door opening, for horizontal support and bolt attachment; side cage supports provided for the bracket cage supports; and bracket cage support attachments.	6.2.4 Cage Mounting Supports			Inspection	Design
873	Each eye opening shall have a minimum diameter of 0.75 inch.	6.2.5 Lifting Eyes and Exterior Bolt Heads			Inspection	Design
874	Each eye shall be able to support the weight load of 1000 lbs.	6.2.5 Lifting Eyes and Exterior Bolt Heads			Performance Test	Design
876	The latching handles shall have provision for padlocking in the closed position.	6.2.6 Door Latches and Locks			Inspection	Design
877	Each handle shall be 0.75 inch minimum diameter stainless steel with a minimum of 0.50 inch shank.	6.2.6 Door Latches and Locks			Inspection	Design
878	The padlocking attachment shall be placed at 4 inch from the handle shank center.	6.2.6 Door Latches and Locks			Inspection	Design
879	An additional 4 inch minimum gripping length shall be provided.	6.2.6 Door Latches and Locks			Inspection	Design
880	The latching mechanism shall be a three-point draw roller type.	6.2.6 Door Latches and Locks			Inspection	Design
881	The pushrods shall be turned edgewise at the outward supports and have a cross section of 0.25 inch thick by 0.75 inch wide minimum.	6.2.6 Door Latches and Locks			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
882	Rollers shall have a minimum diameter of 0.875 inch with nylon wheels and steel ball bearings.	6.2.6 Door Latches and Locks			Inspection	Design
883	When the door is closed and latched, the door shall be locked.	6.2.6 Door Latches and Locks			Inspection	Design
884	The lock and lock support shall be rigidly mounted on the door.	6.2.6 Door Latches and Locks		Can "rigidly mounted" be quantified?	Inspection	Design
885	The lock shall be mounted in the upper quadrant, above the handle when in it's full open position.	6.2.6 Door Latches and Locks		"It's" is a contraction, but a possessive case is needed here.	Inspection	Design
886	The locks shall be Corbin 2 type.	6.2.6 Door Latches and Locks		Need to dig up specifications for this "type."	Inspection	Design
887	One key shall be supplied with each lock.	6.2.6 Door Latches and Locks			Inspection	Design
888	The keys shall be removable in the locked position only.	6.2.6 Door Latches and Locks			Inspection	Design
889	The locks shall have rectangular, spacing loaded bolts.	6.2.6 Door Latches and Locks			Inspection	Design
890	The bolt shall have a 0.281 inch throw and shall be 0.75 inch wide by 0.375 inch thick.	6.2.6 Door Latches and Locks			Inspection	Design
891	Tolerance is 0.035 inch.	6.2.6 Door Latches and Locks			Inspection	Design
892	A swing away cover shall be placed over the key entrance to protect the lock mechanism.	6.2.6 Door Latches and Locks			Inspection	Design
893	The center latch cam shall be fabricated of a minimum thickness of 0.188 inch aluminum, or 11 gauge steel.	6.2.6 Door Latches and Locks		Manufacturing specification.	Inspection	Design
894	The bolt surface shall horizontally cover the cam thickness.	6.2.6 Door Latches and Locks			Inspection	Design
895	The cam shall be structured to only allow the door to open when the handle is moved toward the center of the door.	6.2.6 Door Latches and Locks			Inspection	Design
896	The louvered vent depth shall be a maximum of 0.25 inch.	6.2.7 Housing Ventilation			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
897	A removable and reusable air filter shall be housed behind the door vents.	6.2.7 Housing Ventilation			Inspection	Design
898	The filter filtration area shall cover the vent opening area.	6.2.7 Housing Ventilation			Inspection	Design
899	A filter shell shall be provided that fits over the filter providing mechanical support for the filter.	6.2.7 Housing Ventilation			Inspection	Design
900	This shell shall be louvered to direct the incoming air downward.	6.2.7 Housing Ventilation			Inspection	Design
901	The shell sides and top shall be bent over a minimum of 0.25 inch to house the filter.	6.2.7 Housing Ventilation			Inspection	Design
902	The filter resident in its shell shall be held firmly in place with a bottom trough and spring loaded upper clamp.	6.2.7 Housing Ventilation			Inspection	Design
903	No incoming air shall bypass the filter.	6.2.7 Housing Ventilation			Inspection	Design
904	The bottom filter trough shall be formed into a waterproof sump with drain holes to the outside housing.	6.2.7 Housing Ventilation			Inspection	Design
905	The filter shall be 16 inch wide by 12 inch high by 0.875 inch thick.	6.2.7 Housing Ventilation			Inspection	Design
906	The filter shall be an ECO-AIR Product E35S or equal.	6.2.7 Housing Ventilation		Need to dig up this specification.	Inspection	Design
907	The intake (including filter with shell) and exhaust areas shall pass a minimum of 60 cubic feet of air per minute for Housing #1; 120 cubic feet of air per minute for Housing #3; and 26 cubic feet of air per minute for Housing #2.	6.2.7 Housing Ventilation			Performance Test	Design
908	Each electric fan shall be equipped with ball or roller bearings and shall have a minimum capacity of 100 cubic feet of free air delivery per minute.	6.2.7 Housing Ventilation			Performance Test	Design
909	The fan shall be mounted within the housing and protected with a finger guard.	6.2.7 Housing Ventilation			Inspection	Design
910	Stainless Steel hinges (two bolts per leaf) shall be provided to bolt the enclosure to the doors.	6.2.8 Hinges			Inspection	Design
911	Housing #1 & Housing #3 shall have four hinges per door and Housing #2 shall have three hinges per door.	6.2.8 Hinges			Inspection	Design
912	Each hinge shall be 3.5 inch minimum length and have a fixed pin.	6.2.8 Hinges			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
913	The pin ends shall be welded to hinge and ground smooth.	6.2.8 Hinges			Inspection	Design
915	A ground strap between the door and the main cabinet housing shall be required when 120 VAC components are mounted on the door.	6.2.8 Hinges			Inspection	Design
916	Front and rear doors shall be provided with catches to hold the door open at both 90 and 165 (+/-10) degrees.	6.2.9 Door Catches			Inspection	Design
917	The catch minimum diameter shall be 0.375 inch aluminum rods.	6.2.9 Door Catches			Inspection	Design
918	The catches must be capable of holding the door open at 90 degrees in a 60 mph wind acting at an angle perpendicular to the plane of the door.	6.2.9 Door Catches			Performance Test	Design
919	A police panel assembly shall be provided to allow limited control access.	6.2.10 Police Panel		What does "limited control access" mean exactly?	Inspection	Design
921	The front and back of the panel shall be enclosed with a rigid metal covering so that no parts having live voltage are exposed.	6.2.10 Police Panel			Inspection	Design
923	The drain [in the police panel] shall be channeled to the outside.	6.2.10 Police Panel			Inspection	Design
924	The series 35X Cabinets shall have one switch provided and labeled "SIGNALS ON – OFF".	6.2.10 Police Panel			Inspection	Design
925	The series 34X Cabinets shall have one switch labeled "SIGNALS ON – OFF" and the other "FLASH/AUTO".	6.2.10 Police Panel			Inspection	Design
926	The MANUAL CONTROL ENABLE ON-OFF switch and a receptacle for the INTERVAL ADVANCE cord shall be provided.	6.2.10 Police Panel			Inspection	Design
927	A 12 VAC transformer shall be provided in advance of the INTERVAL ADVANCE receptacle.	6.2.10 Police Panel			Inspection	Design
928	An INTERVAL ADVANCE cord, six feet in length, shall be provided.	6.2.10 Police Panel			Inspection	Design
841	It shall have front and rear doors, each equipped with a lock and handle.	6.2.2 Housing Construction	P		Inspection	Performance
842	The enclosure top shall be crowned to prevent standing water.	6.2.2 Housing Construction	P	Does the angle matter?	Inspection	Performance
844	The enclosure, doors, lifting eyes, gasket channels, police panel door, spacer supports and all supports welded to the enclosure and doors shall be fabricated of 0.125 inch minimum thickness aluminum sheet.	6.2.2 Housing Construction	P	Measured with calipers.	Inspection	Performance
845	The filter shell, filter trough, fan support and police panel enclosure shall be fabricated of 0.080 inch minimum thickness aluminum sheet.	6.2.2 Housing Construction	P		Inspection	Performance
870	A gasket top and side channels shall be provided to support the top gasket on the door to prevent gasket gravitational fatigue.	6.2.3 Gasketing	P		Inspection	Performance

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Type	Requirement Type
872	The housing shall be provided with 2 lifting eyes for placing the cabinet on its foundation.	6.2.5 Lifting Eyes and Exterior Bolt Heads	P		Inspection	Performance
875	All bolt heads shall be tamperproof type.	6.2.5 Lifting Eyes and Exterior Bolt Heads	P		Inspection	Performance
914	The pins and bolts shall be covered by the door edge and not accessible when the door is closed.	6.2.8 Hinges	P		Inspection	Performance
920	The panel door shall be equipped with a lock and master police key.	6.2.10 Police Panel	P		Inspection	Performance
922	The panel assembly shall have a drain to prevent water from collecting within the assembly.	6.2.10 Police Panel	P		Inspection	Performance
849	Exterior cabinet welds shall be done by gas Tungsten arc TIG process only.	6.2.2 Housing Construction		Manufacturing process requirement. Is there a performance criterion?	Inspection	Procurement
850	ER5356 aluminum alloy bare welding electrodes conforming to AWS A5.10 requirements shall be used for welding on aluminum.	6.2.2 Housing Construction		Manufacturing process requirement. Is there a performance criterion?	Inspection	Procurement
851	Procedures, welders and welding operators shall conform to the requirements and practices in AWS B3.0 and C5.6 for aluminum.	6.2.2 Housing Construction		Need to dig up this specification.	Inspection	Procurement
852	Internal cabinet welds shall be done by gas metal arc MIG or gas Tungsten arc TIG Process.	6.2.2 Housing Construction		Manufacturing process requirement. Is there a performance criterion?	Inspection	Procurement
853	ALUMINUM SURFACE PROTECTION shall be either MILL FINISH or ANTI-GRAFFITI Paint.	6.2.2 Housing Construction		Need to dig up specifications for these designations.	Inspection	Procurement
854	The aluminum surface shall be cleaned, etched and rinsed.	6.2.2 Housing Construction		Manufacturing description. Is this appropriate for a standard?	Inspection	Procurement
855	The cleaning and etching procedure shall be to immerse in inhabited alkaline cleaner at 71 degrees C for five minutes (Oakite 61A, Diversey 909 or equivalent in mix of the 6 to 8 ounces per gallon to distilled water).	6.2.2 Housing Construction		Manufacturing process requirement that cannot be assessed after-the-fact.	Inspection	Procurement
856	Rinse in cold water.	6.2.2 Housing Construction		Manufacturing process requirement that cannot be assessed after-the-fact.	Inspection	Procurement
857	Etch in a sodium solution at 66 degrees C for 5 minutes 90.5 ounce sodium fluoride plus 5 ounces of sodium hydroxide mix per gallon to distilled water.	6.2.2 Housing Construction		Manufacturing process requirement. Is there a performance criterion?	Inspection	Procurement
858	Rinse in cold water.	6.2.2 Housing Construction		Manufacturing process requirement that cannot be assessed after-the-fact.	Inspection	Procurement
859	Desmut in a 50% by volume nitric acid solution at 20 degrees C for 2 minutes.	6.2.2 Housing Construction		Manufacturing process requirement. Is there a performance criterion?	Inspection	Procurement

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
860	Rinse in cold water.	6.2.2 Housing Construction		Manufacturing process requirement that cannot be assessed after-the-fact.	Inspection	Procurement
861	Dry surfaces by preheating in an oven for 15 minutes at 400 degrees F.	6.2.2 Housing Construction		Manufacturing process requirement that cannot be assessed after-the-fact.	Inspection	Procurement
862	Remove and coat the surfaces using TCI Wheel Silver # 9811- 0110 with a minimum film build of not more than 2 mils total thickness.	6.2.2 Housing Construction			Inspection	Procurement
863	Place back into preheated oven for 10 minutes minimum at 360 degrees F to gel the base coat.	6.2.2 Housing Construction		Manufacturing process requirement that cannot be assessed after-the-fact.	Inspection	Procurement
864	Remove and coat the surfaces using TCI Anti-graffiti Clear # 9810-0231.	6.2.2 Housing Construction			Inspection	Procurement
865	Place back into oven and fully cure at 380 degrees F for 40 minutes.	6.2.2 Housing Construction		Manufacturing process requirement that cannot be assessed after-the-fact.		Procurement

B.28 ITS Cabinet Rack Cage Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
929	A Standard Rack Cage shall be installed inside the housing for mounting of the ATC Controller Unit and cabinet assemblies.	6.3 Rack Cage			Inspection	Design
930	The EIA rack portion of the cage shall consist of four continuous, adjustable equipment mounting angles.	6.3 Rack Cage			Inspection	Design
931	The mounting angle nominal thickness shall be 11-gauge plated steel.	6.3 Rack Cage			Inspection	Design
932	The mounting angles shall be tapped with 10-32 threads with EIA universal spacing.	6.3 Rack Cage			Inspection	Design
933	The mounting angle shall comply with standard EIA-310-B and shall be supported at the top and bottom by either welded or bolted support angles to form a cage.	6.3 Rack Cage			Inspection	Design
934	The mounting angles shall provide holes to mount the "J" panels.	6.3 Rack Cage			Inspection	Design
935	Clearance between rails for mounting assemblies shall be 17.75 inch.	6.3.1 Clearance Between Rails			Inspection	Design
936	The cage(s) shall be centered within the cabinet door opening(s).	6.3.2 Cage Location			Inspection	Design

B.29 ITS Cabinet Assembly Requirements

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
937	The cabinet assemblies shall be completely removable from or installable in the cabinet cage without removing any other equipment and using only a Standard Slotted or Phillips Screwdriver.	6.4.1 Cabinet Assemblies – General			Inspection	Design
938	All fuses, circuit breakers, switches (except Police Panel Switches and Fan Fuse) and indicators shall be readily visible and accessible when the cabinet front door is open.	6.4.1 Cabinet Assemblies – General			Inspection	Design
939	All equipment in the cabinet shall be clearly and permanently labeled.	6.4.1 Cabinet Assemblies – General			Inspection	Design
940	The marker strips shall be made of material that can be easily and legibly written on using a pencil or ballpoint pen.	6.4.1 Cabinet Assemblies – General		This specification is unquantifiable.	Inspection	Design
941	Marker strips shall be located immediately below the item they are to identify and must be clearly visible with the items installed.	6.4.1 Cabinet Assemblies – General			Inspection	Design
942	Suppression shall be provided at all relay sockets (across relay coil), except for the Transfer Relays (TR) in the output assemblies where one suppression device may be common for all.	6.4.1 Cabinet Assemblies – General			Inspection	Design
943	PDA, Output and Input Assemblies Depth shall include terminal sockets, plug-in units and strain relief bar (Field Wire Support Bracket).	6.4.1 Cabinet Assemblies – General			Inspection	Design
946	The assembly housing top and bottom shall be slotted for vertical ventilation.	6.4.1 Cabinet Assemblies – General			Inspection	Design
949	The aluminum metal surface shall be treated with clear chromate.	6.4.1 Cabinet Assemblies – General			Inspection	Design
951	Guides (top and bottom) shall be provided for assembly Plug-in units (Power Supply Units guide on bottom only).	6.4.1 Cabinet Assemblies – General			Inspection	Design
952	The guides shall begin 0.50 inch from the assembly front panel face.	6.4.1 Cabinet Assemblies – General			Inspection	Design
953	The "J" Panels shall be mirror images of each other when mounted in the cabinet cage.	6.4.2 "J" Panel Assemblies			Inspection	Design
954	They [the "J" Panels] shall be bolted to the cage with the matching shelf unit bolted to the panel.	6.4.2 "J" Panel Assemblies			Inspection	Design
955	Two ten position minimum AC- Raw & Equipment Ground Copper Bus Bars shall be provided on the lower right position of the J Panel when viewed from the rear door for interconnect to the Service Panel and provide the termination of AC- Raw and Equipment Ground wiring within the Cage and Cabinet.	6.4.2 "J" Panel Assemblies			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
956	An optional Input Termination Panel shall be provided that uses ten twelve-position terminal blocks and 4 copper bus bars.	6.4.2 "J" Panel Assemblies			Inspection	Design
957	Eight of the twelve position terminal blocks and the four copper bus bars shall be used for termination of field inputs.	6.4.2 "J" Panel Assemblies			Inspection	Design
958	Two of the twelve position terminal blocks shall be used for termination of the CDC interface.	6.4.2 "J" Panel Assemblies			Inspection	Design
959	Input transient protection devices may be used for input termination.	6.4.2 "J" Panel Assemblies			Inspection	Design
960	Terminal blocks one through four provide termination for Input Assembly #1 and terminal blocks five through eight provide termination for Input Assembly #2.	6.4.2 "J" Panel Assemblies			Inspection	Design
961	A ground lug shall be provided on the panel assembly to terminate an 8 AWG green wire that is attached to the Equipment Ground copper bus bar on the "J" panel assembly.	6.4.2 "J" Panel Assemblies			Inspection	Design
962	The Input Termination Panel shall be mounted on the left side of the Rack Assembly, when viewing from the rear.	6.4.2 "J" Panel Assemblies			Inspection	Design
963	A Shelf Assembly shall be provided unless otherwise called out in the contract special provisions. One alternative is a shelf/drawer assembly.	6.4.3 Cabinet Shelf Assemblies		It is unclear why an alternative is listed.	Inspection	Design
964	A Service Panel Assembly shall be provided.	6.4.4 Service Panel Assembly			Inspection	Design
965	The assembly shall function as the entry point for AC Power to the cabinet including main and secondary circuit breakers, cabinet transient and voltage surge protection, clean power filtering, and Raw and Clean AC Power Sources.	6.4.4 Service Panel Assembly			Inspection	Design
966	The assembly shall be located on the lower right J Panel when viewed from the back door.	6.4.4 Service Panel Assembly			Inspection	Design
967	The terminals of the Block shall be labeled AC+, AC- and EG and shall be covered with a clear insulating material to prevent inadvertent contact.	6.4.4 Service Panel Assembly			Inspection	Design
968	The Terminating Lugs shall be large enough to accommodate # 2 conductors.	6.4.4 Service Panel Assembly			Inspection	Design
969	This assembly shall provide two 8 inch #8 gauge wire extensions for AC- Raw and Equipment Ground, for attachment to the AC- and Ground busses mounted on the "J" panel.	6.4.4 Service Panel Assembly			Inspection	Design
970	The DC Ground and Equipment Ground Bus shall be electrically isolated by 500 Megohms when tested at 250 VDC.	6.4.4 Service Panel Assembly			Performance Test	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
971	The AC- copper terminal bus shall not be grounded to the cabinet or connected to logic ground.	6.4.4 Service Panel Assembly			Inspection	Design
972	Nylon screws with a minimum diameter of 0.25 inch or nylon spacers shall be used for securing the bus to the J Panel.	6.4.4 Service Panel Assembly			Inspection	Design
973	This Assembly [raw/clean AC power] shall be provided in each cabinet.	6.4.5 Raw/Clean AC Power Assembly			Inspection	Design
974	It shall provide Six Clean AC Power Receptacles for assemblies and cabinet units; Raw AC Power to the Output Assemblies; and both logic and power to the Fan and Light system, door opening circuitry and logic interface (all via CCIN and CCOUT Connectors).	6.4.5 Raw/Clean AC Power Assembly			Inspection	Design
975	The Extension shall provide a minimum of five additional NEMA 5-15 receptacles with harness plug connector for plugging into the main assembly.	6.4.5 Raw/Clean AC Power Assembly			Inspection	Design
976	The extension may be an option in Housing #1, and shall be required in Cage 2 of the Housing #3.	6.4.5 Raw/Clean AC Power Assembly			Inspection	Design
977	This assembly shall function as the DC Power bus, providing Six VDC BEAU S5404-SB Receptacles and communications interface between the ATC Controller Unit and other assemblies.	6.4.6 DC Power / Communications Assembly			Inspection	Design
978	This assembly shall interface with ATC Controller Unit Logic Lines (Power Down, NRESET and LINESYNC) and Seven System Serial Bus signals via DB-25S Connectors.	6.4.6 DC Power / Communications Assembly			Inspection	Design
979	The Extension shall provide additional Serial Bus Connectors and DC Receptacles. The extension may be an option.	6.4.6 DC Power / Communications Assembly			Inspection	Design
980	A Serial Bus #1 and #2 Terminator Unit shall be provided and plugged into the DC POWER / COMMUNICATIONS ASSEMBLY DB 25S End Connector.	6.4.6 DC Power / Communications Assembly			Inspection	Design
981	The Terminator Unit shall provide a 150 ohm termination resistor between the RxD+ and RxD-, the TxD+ and TxD-, the RxC+ and RxC-, and the TxC+ and TxC- pairs for both Serial Bus #1 and Serial Bus #2.	6.4.6 DC Power / Communications Assembly			Inspection	Design
982	The Terminator Unit shall also provide 1K ohm DC bias resistors from +5VDC ISO to the RxD+, the RxC+, the TxD+, and the TxC+ of both Serial Bus #1 and Serial Bus #2.	6.4.6 DC Power / Communications Assembly			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
983	The Terminator Unit shall provide 1K ohm DC bias resistors from ISO GND to the RxD-, the RxC-, the TxD-, and the TxC- of both Serial Bus #1 and Serial Bus #2.	6.4.6 DC Power / Communications Assembly			Inspection	Design
984	 The Power Distribution Assembly ITS is an EIA-310B rack mounted assembly that provides for the protection and distribution of AC power and DC power. Additionally: Logic control circuits, including a Main Contactor for control of the load circuits; Fault sensing field Circuit Breakers, eight for Traffic applications and four for Traffic Management systems; Production and distribution of DC power, using +12VDC and 24VDC pluggable power supplies; A resident Cabinet Monitor Unit (CMU); Maintenance service, consisting of a circuit breaker in line with GFI equipment power receptacles; Two Model 204 Flasher Units, protected by a ganged two-pole 20A Circuit Breaker when operating in a Traffic Signal application; A 25-pin D Socket shall be provided for communication with the ATC Controller Unit. This Socket shall be mated with an 18-inch Communications Cable. This Cable shall be attached to the Assembly by slotted 4-40 screws. See Serial Bus Harnesses Detail 6-5-39. 	6.4.7 Power Distribution Assembly ITS			Inspection	Design
985	A four-position Address Socket and plug shall be provided to provide addressing to the CMU.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
986	A CDC Connector shall be provided on the rear panel of the Output Assembly for isolated signal outputs from the police panel.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
987	The CDC Socket is a nine-pin "D" connector that contains the Manual Control Enable, Stop Time, Interval Advance, and Manual Flash switch signals.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
988	The Manual Control Enable and Manual Flash switch signals shall be a 120 VAC signal in series with a 27K Ohm resistor.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
989	The Interval Advance and Stop Time switch signals shall be 12 VAC signals from a transformer located in the PDA.	6.4.7 Power Distribution Assembly ITS			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
990	The secondary output of the 12 VAC transformer shall be tied to AC- RAW.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
991	CDC pin 5 Common shall be referenced to AC-RAW. CDC pin 8 shall provide an interface for the external reset signal and CDC pin 9 shall provide an interface for DC Ground.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
992	The PDA shall be provided with eight field load circuit breakers and two Model 204 Flasher Units with ganged circuit beaker protection.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
993	The Load Circuit Breakers located on the PDA that are used to control the Output Assembly Model 200 Switch Pack Units shall have auxiliary switches.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
994	The auxiliary switches shall "open" when the load breaker has tripped and the system will transfer the power from the Main Contactor to the Flash or Blank condition.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
995	The Amperage Rating of breakers shall be shown on the face of the breaker or handle.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
996	Breaker function shall be labeled below the breakers on the front panel.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
997	Ganged Circuit Breakers shall be assembled by the circuit breaker manufacturer and certified that their circuit breakers shall gang trip.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
998	The maintenance equipment circuit shall include a 15-Ampere Circuit Breaker in line with GFCI receptacles on both the front and back of the assembly.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
999	The back receptacle shall be the first with GFCI Protection device as defined in the National Electrical Code.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1000	Circuit interruption shall occur on 6 milliamperes of ground fault-current and shall not occur less than four milliamperes of ground-fault current.	6.4.7 Power Distribution Assembly ITS			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
1001	The front receptacle shall be attached to the load side of the GFCI device.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1002	The AUTO/FLASH Switch when placed in FLASH position shall de-energize the Main Contactor and the Transfer Relays (TR) Coils.	6.4.7 Power Distribution Assembly ITS			Performance Test	Design
1003	When the switch is placed in the AUTO position shall energize the Main Contactor and the TR Coils.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1004	The switch shall be a SPST Control Switch.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1005	The DC Power shall be brought to the back panel using a BEAU S5404-SB Receptacle.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1006	An 18-inch DC Power (DCP) Harness, with sheath, consisting of four #18 cables, with a BEAU P5404-LAB Connector on each end, shall be provided with the Assembly.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1007	The harness shall be plugged in to an adjacent plug on the DC/COMM Assembly. See drawing 6-5-40.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1008	Three 36-inch minimum length #8 gauge wires, one black for AC+, one white for AC- and one green or green/yellow for Equipment Ground, shall be attached to the rear of the assembly at the AC Raw Power Terminating Block.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1009	The cables shall be routed between the Service Panel Assembly AC+ terminal, the AC-Bus and the Equipment Ground Bus.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1010	The PDA Assembly shall have a resident 18-inch ACP Harness with sheath and strain relief.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1011	The other end shall contain a BEAU P5412-CCE connector.	6.4.7 Power Distribution Assembly ITS			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	Pass Fail	Comments	Туре	Requirement Type
1012	This harness shall be plugged into the P1 connector on the Raw/Clean AC Power Assembly.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1013	The ACP harness shall provide Flasher input and AC power to the Switch Packs.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1014	An 18-inch CC Harness shall be provided with sheath and strain relief.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1015	When plugged into the Raw/Clean AC Power Assembly (CC IN) this harness shall provide AC Raw voltage and control logic between the ITS PDA Assembly and the Police Panel control switches.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1016	An 18-inch long ACCP power cord with strain relief and a NEMA 5-15 plug shall provide AC Clean power to the PDA ITS Assembly when plugged into the Raw/Clean Power Assembly.	6.4.7 Power Distribution Assembly ITS			Inspection	Design
1017	A capacitive load of one microFarad at 400 VAC shall be provided across each Flasher Unit Output.	6.4.7 Power Distribution Assembly ITS			Performance Test	Design
1018	The Input Assembly shall be an EIA-310B rack mounted assembly providing twelve slots of 22/44 pin PCB sockets.	6.4.8 Input Assembly			Inspection	Design
1019	A Model 218 Serial Interface Unit (SIU) shall be provided in its location mated to a DIN 96-Pin Connector.	6.4.8 Input Assembly			Inspection	Design
1020	The SIU shall provide interface and control between the ATC Controller Unit and the input units via System Serial Bus #1 and #2. See Section 26 Model 218 SIU for System Operation and Interface.	6.4.8 Input Assembly			Inspection	Design
1021	A 25-pin D Socket shall be provided for communication with the ATC Controller Unit.	6.4.8 Input Assembly			Inspection	Design
1022	This Socket shall be mated with an 18-inch Communications Cable.	6.4.8 Input Assembly			Inspection	Design
1023	This Cable shall be attached to the Assembly by slotted 4-40 screws. See Serial Bus Harnesses Detail 6-5-39.	6.4.8 Input Assembly			Inspection	Design
1024	The input assembly shall be wired to accept Model 222 and 224 ILD Sensor Units, Model 232 Magnetic Sensor Unit, Model 242 and 252 Isolator Units and Slot mounted NEMA Detectors.	6.4.8 Input Assembly			Inspection	Design
1025	Each slot connector is a PCB 22/44 Pin Socket type wired for two and four channel devices.	6.4.8 Input Assembly			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
1026	The F and W Unit Output pins shall provide the 24 Inputs to the SIU Channel 1 (Serial Bus #1).	6.4.8 Input Assembly			Inspection	Design
1027	In addition, NEMA Status inputs shall be provided on pins 7 and 20.	6.4.8 Input Assembly			Inspection	Design
1028	INBUS shall be provided on pin 19 and 21 with four slots address lines matching NEMA pin outs.	6.4.8 Input Assembly			Inspection	Design
1029	The SIU Unit shall provide six detector RESET Outputs, one for each pair of input slots.	6.4.8 Input Assembly			Inspection	Design
1030	Should the NEMA Status not be required, a RESTART Output from the SIU to the sensor units as a soft reset per channel shall be provided via pins 7-20. See Input Assembly Wiring Diagram 6-5-37.	6.4.8 Input Assembly			Inspection	Design
1031	The INBUS shall interface with the SIU Channel 2 to provide communications between "Smart Input Units" and Serial Bus #2.	6.4.8 Input Assembly			Inspection	Design
1032	The SIU functions as a hardware driver interface only between the ATC Controller Unit and Input Units installed in the Input Assembly. See Type 218 SIU section 4.	6.4.8 Input Assembly			Inspection	Design
1033	A 25-pin DB Connector shall be provided on the left assembly side (rear panel) to interface the assembly (SIU) to the DC/COMM Assembly Serial Bus #1 and #2.	6.4.8 Input Assembly			Inspection	Design
1034	A 32-pin DB (Socket) shall be provided for the Test Function. For Test Connector wiring, see Input Wiring Diagrams 6-5-37.	6.4.8 Input Assembly			Inspection	Design
1035	Four special function Inputs shall be provided via nine-position subminiature D-type connector to the SIU.	6.4.8 Input Assembly			Inspection	Design
1036	These are electrically isolated and may handle 12V DC/AC inputs and are referenced to a separate isolated ground.	6.4.8 Input Assembly			Inspection	Design
1037	Note: In the ITS Cabinet interface wiring 120 VAC inputs shall be routed to the Isolated SIU inputs through a 27K Ohm, one watt resistor located in the PDA ITS Assembly.	6.4.8 Input Assembly			Inspection	Design
1038	The assembly height shall be 5.25 inches (3U).	6.4.8 Input Assembly			Inspection	Design
1039	An 18-inch harness cable, with strain relief and sheath and terminated with a BEAU S5404-SB connector, shall be supplied for interconnect of +24/+12VDC power.	6.4.8 Input Assembly			Inspection	Design
1040	Pins D, E, J, K, and L on each PCB Connector slot shall be routed to their associated field terminal, i.e. FT1-12 Additionally, an Equipment Ground Lug shall be provided on the back panel for termination of a #8 AWG conductor.	6.4.8 Input Assembly			Inspection	Design
1041	Each Input Assembly shall contain a four-bit address code plug and socket.	6.4.8 Input Assembly			Inspection	Design
1042	The Input Assembly address shall be provided by a plug with jumpers installed to produce a binary code 1, 2, 4, and 8.	6.4.8 Input Assembly			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
1043	The address receptacle shall be installed on the back panel of the Input Assembly, Ground True Logic shall be used with Ground True equaling Logic "1". See instructions on Input Assembly Connectors detail 6-5-38.	6.4.8 Input Assembly			Inspection	Design
1044	All connectors mounted on the PCB shall be mechanically secured to the chassis or frame of the unit or assembly.	6.4.8 Input Assembly			Inspection	Design
1045	The Output Assembly shall be an EIA-310B rack mounted assembly delivered in six Switch Pack or fourteen Switch Pack configurations.	6.4.9 Output Assembly			Inspection	Design
1046	This assembly may provide 18 load circuits or 42 load circuits. Either configuration is designed to interface with a plug-in Model 200 Switch Pack Unit.	6.4.9 Output Assembly			Inspection	Design
1047	The SIU shall be provided resident in its connector to provide interface and control.	6.4.9 Output Assembly			Inspection	Design
1048	In addition, a Model 214 AMU Unit shall be provided in its connector to sense voltage and current for the CMU.	6.4.9 Output Assembly			Inspection	Design
1051	The Model 205 relay units and Program Blocks shall be provided to select control and color state of the Emergency Override State (red, yellow, or no indication output).	6.4.9 Output Assembly			Inspection	Design
1052	The programming connectors shall be Molex Type 1375 or equal.	6.4.9 Output Assembly			Inspection	Design
1053	The relay units and program blocks shall be mounted on the rear of the Output Assembly.	6.4.9 Output Assembly			Inspection	Design
1054	Program Block Pins shall be crimped and soldered.	6.4.9 Output Assembly			Inspection	Design
1055	The Model 205 transfer relays shall be accessible on the rear of the Output Assembly without the use of tools.	6.4.9 Output Assembly			Inspection	Design
1056	An Address Plug and Socket shall be provided on Output Assembly for defining the Serial Bus #1 and #3 addressing. See 4.7.16, 4.5.1.1, and 6/14 Pack Output Assembly Connectors Detail 6-5-33.	6.4.9 Output Assembly			Inspection	Design
1057	Transformers shall be provided on the incoming AC source for each Switch Pack to measure the load current. See Section 4.5.7 AMU Current Sensing.	6.4.9 Output Assembly			Inspection	Design
1058	Field Termination shall be provided on the rear panel of the assembly consisting of six-position sockets and plugs.	6.4.9 Output Assembly			Inspection	Design
1059	Transient suppression shall be provided at the field terminals, for the protection of the Switch Packs, on rear panel of the assembly consisting of three nine-position sockets and plugs for a six Pack Output Assembly.	6.4.9 Output Assembly			Inspection	Design
1063	A Serial Bus #1 DB25 female connector shall be provided on the upper left rear panel of the Output Assembly for serial interconnection to the DC Power/Communication Assembly.	6.4.9 Output Assembly			Inspection	Design

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
1064	This Socket shall be mated with an 18-inch Communications Cable.	6.4.9 Output Assembly			Inspection	Design
1065	This Cable [the serial bus connector between the Output Assembly and the DC Power Communication assembly] shall be attached to the Assembly by slotted 4-40 screws. See Serial Bus Harnesses Detail 6-5-39.	6.4.9 Output Assembly			Inspection	Design
1066	A CDC Connector shall be provided on the rear panel of the Output Assembly for signal interconnection to the unit.	6.4.9 Output Assembly			Inspection	Design
1067	The CDC Socket is a 9-pin "D" connector.	6.4.9 Output Assembly			Inspection	Design
1068	These inputs are electrically isolated and may handle 120 VAC signals when wired to the PDA ITS Assembly and 12 VAC inputs that are referenced to a separate isolated ground.	6.4.9 Output Assembly			Inspection	Design
1069	This Cable [the CDC Connector] shall be attached to the Assembly by slotted 4-40 screws.	6.4.9 Output Assembly			Inspection	Design
1070	Two RJ-11S Connectors shall be provided on the rear panel of the Output Assembly for signal interconnection of Serial Bus #3.	6.4.9 Output Assembly			Inspection	Design
1071	An Equipment Ground Lug shall be provided on the rear panel for termination of a #8 green wire.	6.4.9 Output Assembly			Inspection	Design
1072	The 6-Pack Output Assembly height shall be 5.25 inches (3 U) and the 14-Pack Output Assembly shall be 10.5 inches.	6.4.9 Output Assembly			Inspection	Design
1073	Cabinet Harnesses are supplied with each cabinet configuration. See Serial Bus and DCP Harness Details.	6.4.9 Output Assembly			Inspection	Design
944	The Width shall be 17.5 inches maximum including side screws.	6.4.1 Cabinet Assemblies – General	P		Inspection	Performance
945	The maximum Depth, including connectors, shall not exceed 14.0 inches.	6.4.1 Cabinet Assemblies – General	P		Inspection	Performance
947	Assembly Thickness - Side ends shall be fabricated of 0.080 inch minimum thickness aluminum sheet.	6.4.1 Cabinet Assemblies – General	P	No maximum is specified here. Should there be?	Inspection	Performance
948	All other surfaces [other than side sheets] shall be fabricated of 0.0625 inch minimum thickness aluminum sheet.	6.4.1 Cabinet Assemblies – General	P		Inspection	Performance
950	Flasher and Switch Pack Unit sockets shall be mounted with their front face 7.50 inch from the assembly front panel.	6.4.1 Cabinet Assemblies – General	F	The dimension is correct, but the wording is inverted. The verbiage should say, "7.50 from the back panel to the front plate of the unit.	Inspection	Performance
1049	A 25-pin D Socket shall be provided for communication with the ATC Controller Unit.	6.4.9 Output Assembly	P		Inspection	Performance

#	Requirement (Standard Document Section)	Document Section	<u>Pass</u> Fail	Comments	Туре	Requirement Type
1050	This Socket shall be mated with an 18-inch Communications Cable. This Cable shall be attached to the Assembly by slotted 4-40 screws. See Serial Bus Harnesses Detail 6-5-39.	6.4.9 Output Assembly	P		Inspection	Performance
1060	A 14 Pack Output Assembly requires seven nine-position sockets and plugs.	6.4.9 Output Assembly	P		Inspection	Performance
1061	Each socket shall provide protection for two Switch Packs.	6.4.9 Output Assembly	P		Inspection	Performance
1062	Protection devices shall be terminated to Equipment Ground.	6.4.9 Output Assembly	P		Inspection	Performance

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EDL 14476

FHWA-JPO-09-042



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